

**Chemical Name Index**

# **XI Library of Digital XPS Spectra**

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# **The Database Catalogue**

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
1	al_acac3	Aluminum Acetyl-acetonate Al(acac)3 mesh: 1mm hgt (as rec'd powder, pressed into pellet, 35 deg TOA)	12	6/1/94 0:00:00	MRS	AC-AC
2	co_acac2	Cobalt Acetyl-acetonate Co(acac)2 (powder, pressed into pellet, 1mm mesh hgt)	14	6/2/94 0:00:00	MRS	AC-AC
3	co_acac3	Cobalt tri-acetylacetonate Co(acac)3 (powder, pressed into pellet, mesh: 1mm hgt)	14	6/2/94 0:00:00	MRS	AC-AC
4	cr_acac3	Chromium Tri-acetyl acetate Cr(acac)3 (powder pressed into pellet, mesh: 1mm hgt)	12	6/2/94 0:00:00	MRS	AC-AC
5	cu_acac	Copper di-acetyl acetate Cu(acac)2-1H2O (Baker Chem Co.) powder on double-sided tape	10	11/2/85 0:00:00	MRS	AC-AC
6	cu_acac2	Copper Di-acetyl acetate Cu(acac)2 powder (pressed into pellet, mesh: 1mm hgt)	14	6/2/94 0:00:00	MRS	AC-AC
7	fe_acac3	Iron Tri-acetyl acetate Fe(acac)3 powder (pressed into pellet, Mesh: 1mm hgt)	15	6/3/94 0:00:00	MRS	AC-AC
8	hf_acac4	Hafnium Tetra-acetyl Acetonate Hf(acac)4 powder (pressed into pellet, mesh: 1mm hgt)	12	6/3/94 0:00:00	MRS	AC-AC
9	li_acac	Lithium Acetyl Acetonate Li(acac) powder (pressed into pellet, mesh: 1mm hgt)	13	6/3/94 0:00:00	MRS	AC-AC
10	mg_acac2	Magnesium Di-Acetyl Acetonate Mg(acac)2 powder (pressed into pellet, mesh: 1mm hgt)	17	6/3/94 0:00:00	MRS	AC-AC
11	mnacac3_	Mn(acac)2 (Baker Chem Co) pellet mesh 90 TOA	1	6/7/94 0:00:00	MRS	AC-AC
12	mn_acac3	Mn(acac) (J Nelson,UNR) pellet mesh 90 TOA	12	6/7/94 0:00:00	MRS	AC-AC
13	moo2acac	Molybdenum di-oxo acetyl acetate MoO2acac pellet, mesh: 1mm hgt, contaminated with Tl(acac)	12	6/7/94 0:00:00	MRS	AC-AC
14	moo2aca_	Molybdenum di-oxo acetyl acetate MoO2(acac) pellet, mesh: 1mm hgt, 90 deg TOA	2	6/7/94 0:00:00	MRS	AC-AC
15	naacac_	Sodium acetyl acetate Na(acac) 90 deg TOA (Baker Chem Co) pellet, mesh: 1mm hgt	3	6/7/94 0:00:00	MRS	AC-AC
16	na_acac	Sodium acetyl acetate Na(acac) pellet, mesh: 1mm hgt, 90 deg TOA	12	6/7/94 0:00:00	MRS	AC-AC
17	ndacac3_	Neodymium tri-acetyl acetate Nd(acac)3 (Ric/Roc Co) pellet, mesh 1mm hgt, 90 deg TOA	2	6/7/94 0:00:00	MRS	AC-AC
18	nd_acac3	Neodymium tri-acetyl acetate Nd(acac)3 90 deg (Baker Chem Co) pellet, mesh: 1mm hgt	16	6/7/94 0:00:00	MRS	AC-AC
19	niacac2_	Nickel di-acetyl acetate Ni(acac)2 pellet (Baker Chem Co) mesh: 1mm hgt, 90 deg TOA	3	6/7/94 0:00:00	MRS	AC-AC
20	ni_acac2	Ni(acac)2 but contaminated with Al(acac)x (Baker Chem co) pellet mesh: 1mm hgt, 90 deg TOA	12	6/7/94 0:00:00	MRS	AC-AC
21	pb_acac3	Lead tri-acetyl acetate Pb(acac)3 (pellet) (Baker Chem Co) Mesh: 1mm hgt, 90 TOA	7	6/7/94 0:00:00	MRS	AC-AC
22	tl_acac	Thallium acetyl acetate Tl(acac) 90 deg TOA (Baker Chem Co) pellet, mesh: 1mm hgt	7	6/7/94 0:00:00	MRS	AC-AC
23	zn_acac2	Zinc di-acetyl acetate Zn(acac)2 (Baker Chem Co) pellet, mesh: 1mm hgt, 90 deg TOA	12	6/15/94 0:00:00	MRS	AC-AC
24	zr_acac4	Zirconium tetra-acetyl acetate Zr(acac)4 (Alpha-Ventron Co) pellet, mesh 1mm hgt, 90 TOA	12	6/16/94 0:00:00	MRS	AC-AC
25	ba_oac_1	Barium Acetate (BaOAc) powder pressed onto In foil (SSI mesh)	11	6/18/87 0:00:00	MRS	ACETATE
26	rb_oac_1	Rubidium Acetate (RbOAc powder, 90 TOA, freshly ground, 1mm from mesh)	4	6/16/88 0:00:00	MRS	ACETATE
27	20_cb_3	20-CB-3 [MSC] (as received, no treatment) 90 TOA	4	1/7/94 0:00:00	MRS	ALLOYS_1
28	20_cb_3s	20-CB-3 [MSC] (scraped & ion etched at 3KV) 90 TOA	11	1/8/94 0:00:00	MRS	ALLOYS_1
29	29_4_2	29-4-2 [MSC] (as received, no treatment) 90 TOA	4	1/13/94 0:00:00	MRS	ALLOYS_1
30	29_4_2_s	29-4-2 [MSC] (scraped & ion etched 3KV) 90 TOA	8	1/13/94 0:00:00	MRS	ALLOYS_1
31	al6x1	AL-6X-1 [MSC](as received, no treatment) 35 TOA	4	1/15/94 0:00:00	MRS	ALLOYS_1
32	al6x1_s	AL-6X-1 [MSC](scraped & ion etched 3KV) 35 TOA	8	1/16/94 0:00:00	MRS	ALLOYS_1
33	al_1100	Al 1100 [MSC] (as received, no treatment) 35 TOA	4	12/18/93 0:00:00	MRS	ALLOYS_1
34	AL_1100S	Al 1100 [MSC] (scraped & etched) 35 TOA	8	12/19/93 0:00:00	MRS	ALLOYS_1
35	al_2024	Al 2024 [MSC] (as received, no treatment) 35 TOA	4	12/19/93 0:00:00	MRS	ALLOYS_1
36	AL_2024S	Al 2024 [MSC] (scraped & etched) 35 TOA	8	12/19/93 0:00:00	MRS	ALLOYS_1
37	AL_3003	Al 3003 [MSC] (as rec'd, no treatments) 35 TOA	5	7/10/93 0:00:00	MRS	ALLOYS_1
38	al_3003e	Al 3003 [MSC] (scraped, etched 10 min) 35 TOA	7	7/13/93 0:00:00	MRS	ALLOYS_1
39	AL_3003S	Al 3003 [MSC] (scraped, exposed to air 5 min)35TOA	5	7/10/93 0:00:00	MRS	ALLOYS_1
40	AL_5086	Al 5086 [MSC] (as rec'd, no treatments) 35 TOA	5	7/11/93 0:00:00	MRS	ALLOYS_1
41	al_5086e	Al 5086 [MSC] (scraped, etched 10 min) 35 TOA	5	7/12/93 0:00:00	MRS	ALLOYS_1

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
42	AL_5086S	Al 5086 [MSC] scraped,exposed to air 5 min, 35 TOA	5	7/10/93 0:00:00	MRS	ALLOYS_1
43	AL_6061	Al 6061 [MSC] (as rec'd, no treatments) 35 TOA	5	7/10/93 0:00:00	MRS	ALLOYS_1
44	AL_6061S	Al 6061 [MSC] (scraped exposed to air 5 min) 35TOA	5	7/10/93 0:00:00	MRS	ALLOYS_1
45	AL_7075	Al 7075 [MSC] (as rec'd, no treatments) 35 TOA	5	7/9/93 0:00:00	MRS	ALLOYS_1
46	AL_7075S	Al 7075 [MSC] (scraped,exposed to air 5 min) 35TOA	5	7/9/93 0:00:00	MRS	ALLOYS_1
47	au_cu_1	AuCu 25:75 ION ETCHED, 128 CH, 200 mS/CH 35 deg TOA	6	3/29/90 0:00:00	MRS	ALLOYS_1
48	au_cu_2	AuCu 50:50 ION ETCHED, 128 CH, 200 mS/CH 35 deg TOA	6	3/29/90 0:00:00	MRS	ALLOYS_1
49	au_cu_3	AuCu 75:25, ION ETCHED, 128 CH, 200 mS/CH 35 deg TOA	6	3/29/90 0:00:00	MRS	ALLOYS_1
50	au_cu_4	AuCu 25:75 (NRIM) only scraped no etch 90 TOA (S-Probe data)	7	5/19/94 0:00:00	MRS	ALLOYS_1
51	au_cu_4s	AuCu 25:75 (NRIM) scraped & etched 1 min 3KV 90TOA	7	5/20/94 0:00:00	MRS	ALLOYS_1
52	au_cu_5	AuCu 50:50 (NRIM) only scraped no etch 90 TOA	10	5/23/94 0:00:00	MRS	ALLOYS_1
53	au_cu_5s	AuCu 50:50 (NRIM) scraped & etch 1 min 3KV 90 TOA	10	5/23/94 0:00:00	MRS	ALLOYS_1
54	au_cu_6	AuCu 75:25 (NRIM) only scraped no etch 90 TOA	10	5/19/94 0:00:00	MRS	ALLOYS_1
55	au_cu_6s	AuCu 75:25 (NRIM) scraped & etched 1 min 3KV 90TOA	7	5/19/94 0:00:00	MRS	ALLOYS_1
56	cda260	CDA-260 [MSC] (as received, no treatment) 90 TOA	6	1/18/94 0:00:00	MRS	ALLOYS_1
57	cda260_s	CDA-260 [MSC] (scraped & ion etched 3KV) 90 TOA	6	1/19/94 0:00:00	MRS	ALLOYS_1
58	cda360	CDA-360 [MSC] (as received, no treatment) 90 TOA	6	1/19/94 0:00:00	MRS	ALLOYS_1
59	cda360_s	CDA-360 [MSC] (scraped & ion etched 3KV) 90 TOA	7	1/19/94 0:00:00	MRS	ALLOYS_1
60	cda443	CDA-443 [MSC] (as received, no treatment) 90 TOA	6	1/19/94 0:00:00	MRS	ALLOYS_1
61	cda443_s	CDA-443 [MSC] (scraped & ion etched 3KV) 90 TOA	7	1/20/94 0:00:00	MRS	ALLOYS_1
62	cda464	CDA-464 [MSC] (as received, no treatment) 90 TOA	6	1/23/94 0:00:00	MRS	ALLOYS_1
63	cda464_s	CDA-464 [MSC] (scraped & ion etched 3KV) 90 TOA	6	1/23/94 0:00:00	MRS	ALLOYS_1
64	cda706	CDA-706 [MSC] (as received, no treatment) 90 TOA	6	1/21/94 0:00:00	MRS	ALLOYS_1
65	cda706_s	CDA-706 [MSC] (scraped & ion etched 3KV) 90 TOA	6	1/22/94 0:00:00	MRS	ALLOYS_1
66	cda715	CDA-715 [MSC] (as received, no treatment) 90 TOA	6	1/22/94 0:00:00	MRS	ALLOYS_1
67	cda715_s	CDA-715 [MSC] (scraped & ion etched 3KV) 90 TOA	6	1/22/94 0:00:00	MRS	ALLOYS_1
68	co_ni_1	Co:Ni 75:25 NRIM mirror polished, as rec'd, 90 TOA	8	5/7/94 0:00:00	MRS	ALLOYS_1
69	co_ni_1e	Co:Ni 75:25 mirror polished, 5 min 2KV etch,90 TOA NRIM	9	5/8/94 0:00:00	MRS	ALLOYS_1
70	co_ni_1s	Co:Ni 75:25 mirror polished, knife scraped, 90 TOA	9	5/10/94 0:00:00	MRS	ALLOYS_1
71	co_ni_1z	Co:Ni 75:25 mirror plsh, scraped& 1min 3KV etch,90	8	5/10/94 0:00:00	MRS	ALLOYS_1
72	co_ni_2	Co:Ni 50:50 NRIM mirror polished, as rec'd, 90 TOA	8	5/7/94 0:00:00	MRS	ALLOYS_1
73	co_ni_2e	Co:Ni 50:50 mirror polished, 5 min 2KV etch,90 TOA NRIM	9	5/8/94 0:00:00	MRS	ALLOYS_1
74	co_ni_2s	Co:Ni 50:50 mirror polished, knife scraped, 90 TOA NRIM	9	5/10/94 0:00:00	MRS	ALLOYS_1
75	co_ni_2z	Co:Ni 50:50 mirror plsh,scraped& 1min 3KV etch 90T	8	5/11/94 0:00:00	MRS	ALLOYS_1
76	co_ni_3	Co:Ni 45:55 mirror polished, as rec'd, 90 TOA	8	5/7/94 0:00:00	MRS	ALLOYS_1
77	co_ni_3e	Co:Ni 45:55 mirror polished, 5min 2KV etch, 90 TOA	9	5/8/94 0:00:00	MRS	ALLOYS_1
78	co_ni_3s	Co:Ni 45:55 mirror polished, knife scraped, 90 TOA	9	5/10/94 0:00:00	MRS	ALLOYS_1
79	co_ni_3z	Co:Ni 45:55 mirror plshd,scraped& 1min 3KV etch 90 NRIM	8	5/11/94 0:00:00	MRS	ALLOYS_1
80	co_ni_4	Co:Ni 25:75 NRIM mirror polished, as rec'd, 90 TOA	8	5/7/94 0:00:00	MRS	ALLOYS_1
81	co_ni_4e	Co:Ni 25:75 mirror polished,5 min 2KV etch, 90 TOA NRIM	9	5/8/94 0:00:00	MRS	ALLOYS_1
82	co_ni_4s	Co:Ni 25:75 mirror polished, knife scraped, 90 TOA NRIM	9	5/10/94 0:00:00	MRS	ALLOYS_1

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
83	co_ni_4z	Co:Ni 25:75 mirror plsh,scraped& 1min 3KV etch 90T 90 TOA, NRIM	8	5/11/94 0:00:00	MRS	ALLOYS_1
84	cr_mo_1	1+1/4Cr:1/2Mo [MSC] (as rec'd, no treatment) 90TOA	4	1/25/94 0:00:00	MRS	ALLOYS_1
85	cr_mo_1s	1+1/4Cr:1/2Mo[MSC](Scraped& Ion Etched 3KV) 90 TOA	7	1/18/94 0:00:00	MRS	ALLOYS_1
86	cr_mo_2	2.25 Cr-1.0 Mo [MSC](as rec'd, no treatment)35 TOA	4	12/3/93 0:00:00	MRS	ALLOYS_1
87	cr_mo_2s	2.25 Cr-1.0 Mo [MSC](scraped,ion etched) 35 TOA	9	12/4/93 0:00:00	MRS	ALLOYS_1
88	cr_mo_3	5.0 Cr-0.5 Mo [MSC](as rec'd, no treatment)35 TOA	4	12/4/93 0:00:00	MRS	ALLOYS_1
89	cr_mo_3s	5.0 Cr-0.5 Mo [MSC](scraped,ion etched) 35 TOA	9	12/4/93 0:00:00	MRS	ALLOYS_1
90	cr_mo_4	9.0 Cr-1.0 Mo [MSC] (as rec'd, no treatment) 35 TOA	4	12/4/93 0:00:00	MRS	ALLOYS_1
91	cr_mo_4s	9.0 Cr-1.0 Mo[MSC](scraped, ion etched) 35 TOA	9	12/5/93 0:00:00	MRS	ALLOYS_1
92	cu_ni_1e	CuNi 10:90 1min 2KV etch scraped old-ground surfac	3	5/2/94 0:00:00	MRS	ALLOYS_1
93	cu_ni_1s	CuNi 10:90 scraped old-ground surface 90 TOA	9	5/2/94 0:00:00	MRS	ALLOYS_1
94	cu_ni_2e	CuNi 20:80 1min 2KV etch scraped old-ground surfac	3	5/3/94 0:00:00	MRS	ALLOYS_1
95	cu_ni_2s	CuNi 20:80 scraped old-ground surface 90 TOA	9	5/3/94 0:00:00	MRS	ALLOYS_1
96	cu_ni_3e	CuNi 30:70 1min 2KV etch scraped old-ground surfac	3	5/3/94 0:00:00	MRS	ALLOYS_1
97	cu_ni_3s	CuNi 30:70 scraped old-ground surface 90 TOA	9	5/3/94 0:00:00	MRS	ALLOYS_1
98	cu_ni_4e	CuNi 40:60 1min 2KV etch scraped old-ground surfac	3	5/3/94 0:00:00	MRS	ALLOYS_1
99	cu_ni_4s	CuNi 40:60 scraped old-ground surface 90 TOA	9	5/3/94 0:00:00	MRS	ALLOYS_1
100	cu_ni_5e	CuNi 50:50 1min 2KV etch scraped old-ground surfac	3	5/3/94 0:00:00	MRS	ALLOYS_1
101	cu_ni_5s	CuNi 50:50 scraped old-ground surface 90 TOA	9	5/4/94 0:00:00	MRS	ALLOYS_1
102	cu_ni_6e	CuNi 60:40 1min 2KV etch scraped old-ground surfac	3	5/4/94 0:00:00	MRS	ALLOYS_1
103	cu_ni_6s	CuNi 60:40 scraped old-ground surface 90 TOA	9	5/4/94 0:00:00	MRS	ALLOYS_1
104	cu_ni_7e	CuNi 70:30 1min 2KV etch scraped old-ground surfac	3	5/4/94 0:00:00	MRS	ALLOYS_1
105	cu_ni_7s	CuNi 70:30 scraped old-ground surface 90 TOA	9	5/4/94 0:00:00	MRS	ALLOYS_1
106	cu_ni_8e	CuNi 80:20 1min 2KV etch scraped old-ground surfac	3	5/4/94 0:00:00	MRS	ALLOYS_1
107	cu_ni_8s	CuNi 80:20 scraped old-ground surface 90 TOA	9	5/4/94 0:00:00	MRS	ALLOYS_1
108	cu_ti_1	Cu30:Ti70, Ion etched 6 min at 4 KeV (90 DEG TOA)	6	6/18/87 0:00:00	MRS	ALLOYS_1
109	cu_ti_1a	Cu30:Ti70, Ion etched 6 min at 4KeV (90 DEG TOA)	4	6/24/87 0:00:00	MRS	ALLOYS_1
110	cu_ti_2	CuTiSi 27:62:10, Ion etched 6 min at 4 KeV (90 TOA	7	6/18/87 0:00:00	MRS	ALLOYS_1
111	cu_ti_2a	CuTiSi 27:62:10 Ion etched 10 min at 4 KeV (90 TOA	4	6/25/87 0:00:00	MRS	ALLOYS_1
112	cu_ti_al	CuTiAl 24:56:20, Ion etched 10 min at 4 KeV	4	6/29/87 0:00:00	MRS	ALLOYS_1
113	cu_zn_1	Cu:Zn (65:35) Coating on Stainless wire (240u, CLEANED WITH ACETONE)	4	5/13/88 0:00:00	MRS	ALLOYS_1
114	cu_zn_2	CuZn 65:35 coating on stainless wire (500ANG etch)	4	5/16/88 0:00:00	MRS	ALLOYS_1
115	C_1010	C1010 [MSC] (as rec'd, no treatment) 35 TAO	4	11/22/93 0:00:00	MRS	ALLOYS_1
116	c_1010_s	C1010 [MSC] (scraped, etched 2 min) 35 TOA	7	11/21/93 0:00:00	MRS	ALLOYS_1
117	C_1020	C1020 [MSC] (as rec'd, no treatment) 35 TOA	4	11/22/93 0:00:00	MRS	ALLOYS_1
118	c_1020_s	C1020 [MSC] (scraped, etched 2 min) 35 TOA	7	11/22/93 0:00:00	MRS	ALLOYS_1
119	e_26_1	E-26-1 [MSC] (as received, no treatment) 90 TOA	4	1/18/94 0:00:00	MRS	ALLOYS_2
120	E_26_1_S	E-26-1 [MSC](Scraped & ion etched 3KV) 90 TOA	7	1/18/94 0:00:00	MRS	ALLOYS_2
121	fenimob	Fe(40) Ni(38) Mo(4) B(18) 90 DEG TOA, ion etched 3 min 4.5 KeV	1	3/11/87 0:00:00	MRS	ALLOYS_2
122	fe_cr_mo	FeCrMo (2% Mo) (Ion etched ca. 36 ANG)	5	5/18/88 0:00:00	MRS	ALLOYS_2
123	f_255	F255 [MSC] (as rec'd,no treatment) 35 TOA	4	11/21/93 0:00:00	MRS	ALLOYS_2

Serial	File Name	Description	No of Spectra	Date	Ident	SubDir.
124	f_255_s	F255 [MSC] (scraped, etched 2 min) 35 TOA	10	11/21/93 0:00:00	MRS	ALLOYS_2
125	ha_25	HA-25 [MSC] (as received, no treatment) 35 TOA	4	1/15/94 0:00:00	MRS	ALLOYS_2
126	ha_25_s	HA-25 [MSC] (scraped & ion etched 3KV) 35 TOA	9	1/15/94 0:00:00	MRS	ALLOYS_2
127	hb_2	HB-2 [MSC] (as received, no treatment) 90 TOA	4	1/12/94 0:00:00	MRS	ALLOYS_2
128	hb_2_s	HB-2 [MSC] (Scraped & Ion etched at 3KV) 90 TOA	7	1/8/94 0:00:00	MRS	ALLOYS_2
129	hc_276	HC-276 [MSC] (As received, no treatment) 90 TOA	4	1/6/94 0:00:00	MRS	ALLOYS_2
130	hc_276_s	HC-276 [MSC] (Scraped & ion etched at 3KV) 90 TOA	10	1/7/94 0:00:00	MRS	ALLOYS_2
131	hg_3	HG-3 [MSC] (as received, no treatment) 90 TOA	4	1/7/94 0:00:00	MRS	ALLOYS_2
132	HG_3_S	HG-3 [MSC] (Scraped & Ion etched at 3KV) 90 TOA	10	1/7/94 0:00:00	MRS	ALLOYS_2
133	hg_te_1	HgTe FILM 90 DEG TOA	2	11/20/86 0:00:00	MRS	ALLOYS_2
134	hg_te_1a	HgTe FILM 90 DEGREE TOA	2	11/20/86 0:00:00	MRS	ALLOYS_2
135	hx	HX [MSC] (as received, no treatment) 35 TOA	4	1/14/94 0:00:00	MRS	ALLOYS_2
136	hx_s	HX [MSC] (scraped & ion etched 3KV) 35 TOA	9	1/15/94 0:00:00	MRS	ALLOYS_2
137	i_600	I-600 [MSC] (as received, no treatment) 35 TOA	4	12/25/93 0:00:00	MRS	ALLOYS_2
138	i_600_s	I-600 [MSC] (scraped & ion etched at 3KV) 35 TOA	10	12/26/93 0:00:00	MRS	ALLOYS_2
139	i_625	I-625 [MSC] (as received, no treatment) 35 TOA	4	12/26/93 0:00:00	MRS	ALLOYS_2
140	i_625_s	I-625 [MSC] (scraped & ion etched at 3KV) 35 TOA	10	12/26/93 0:00:00	MRS	ALLOYS_2
141	i_750x	I-750X [MSC] (as rec'd, no treatment) 35 TOA	4	1/2/94 0:00:00	MRS	ALLOYS_2
142	I_750X_S	I-750X [MSC] (scraped & ion etched at 3KV) 35 TOA	10	1/3/94 0:00:00	MRS	ALLOYS_2
143	i_800	I-800 [MSC] (as received, no treatment) 35 TOA	4	12/30/93 0:00:00	MRS	ALLOYS_2
144	i_800_s	I-800 [MSC] (scraped & ion etched at 3KV) 35 TOA	12	12/31/93 0:00:00	MRS	ALLOYS_2
145	i_825	I-825 [MSC] (as received, no treatment) 35 TOA	4	12/28/93 0:00:00	MRS	ALLOYS_2
146	i_825_s	I-825 [MSC] (scraped & ion etched 3KV) 35 TOA	11	12/30/93 0:00:00	MRS	ALLOYS_2
147	monel_1	Monel (CuNi) scraped old-ground surface 90 TOA	9	5/18/94 0:00:00	MRS	ALLOYS_2
148	monel_1e	Monel (CuNi)scraped & etched 1min 3KV 90 TOA	7	5/18/94 0:00:00	MRS	ALLOYS_2
149	m_400	M-400 [MSC] (as received, no treatment) 35 TOA	4	1/1/94 0:00:00	MRS	ALLOYS_2
150	m_400_s	M-400 [MSC] (scraped & ion etched at 3KV) 35 TOA	9	1/2/94 0:00:00	MRS	ALLOYS_2
151	n_200	N-200 [MSC] (as received, no treatment) 35 TOA	4	12/24/93 0:00:00	MRS	ALLOYS_2
152	n_200_s	N-200 [MSC] (scraped & ion etched 3KV) 35 TOA	8	12/25/93 0:00:00	MRS	ALLOYS_2
153	pd_fe	Pd:Fe (73.8:26.2) for CO sensor 3min 3KV ion etch	7	6/13/94 0:00:00	MRS	ALLOYS_2
154	pd_fe_2	Pd:Fe (73.8:26.2) for CO sensor 3min 3KV ion etch	1	6/13/94 0:00:00	MRS	ALLOYS_2
155	ss_304	304 Stainless Steel: [MSC] As Rec'd, 90 TOA	7	10/26/93 0:00:00	MRS	ALLOYS_2
156	ss_304l	304L SS: As Rec'd, 90 TOA (MS Co.)	4	10/27/93 0:00:00	MRS	ALLOYS_2
157	ss_304ls	304L Stainless Steel: Filed Bulk, 90 TOA (MS Co.)	7	10/27/93 0:00:00	MRS	ALLOYS_2
158	ss_310	310 SS: As Rec'd, 90 TOA (MS Co.)	4	10/27/93 0:00:00	MRS	ALLOYS_2
159	ss_310_s	310 SS: Filed Bulk, 90 TOA (MS Co.)	7	10/28/93 0:00:00	MRS	ALLOYS_2
160	ss_316l	316L SUS tubing (OSK): electro-polished interior (as rec'd, 90 TOA)	7	3/26/92 0:00:00	MRS	ALLOYS_2
161	ss_347	SS 347 [MSC](as rec'd,no treatment) 35 TOA	4	12/11/93 0:00:00	MRS	ALLOYS_2
162	ss_347_s	SS 347 [MSC] (scraped,ion etched) 35 TOA	9	12/11/93 0:00:00	MRS	ALLOYS_2
163	ss_410	SS 410 [MSC] (as rec'd,no treatment) 35 TOA	4	12/12/93 0:00:00	MRS	ALLOYS_2
164	ss_410_s	SS 410 [MSC] (scraped,ion etched) 35 TOA	9	12/12/93 0:00:00	MRS	ALLOYS_2

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
165	ss_4140	4140 [MSC] (as rec'd no treatment) 35 TOA	4	11/23/93 0:00:00	MRS	ALLOYS_2
166	ss_4140s	4140 [MSC] (scraped, etched 2 min) 35 TOA	8	11/23/93 0:00:00	MRS	ALLOYS_2
167	ss_430	SS 430 [MSC] (as rec'd, no treatment) 35 TOA	4	11/20/93 0:00:00	MRS	ALLOYS_2
168	ss_430_s	SS 430 [MSC] (scraped, etched 2 min) 35 TOA	7	11/20/93 0:00:00	MRS	ALLOYS_2
169	ss_4340	4340 [MSC] (as rec'd, no treatment) 35 TOA	4	11/24/93 0:00:00	MRS	ALLOYS_2
170	ss_4340s	4340 [MSC] (scraped, etched 2 min) 35 TOA	10	11/24/93 0:00:00	MRS	ALLOYS_2
171	ss_904l	904L [MSC] (as rec'd, no treatment) 35 TOA	4	11/20/93 0:00:00	MRS	ALLOYS_2
172	ss_904ls	904L [MSC] (scraped, etched 2 min) 35 TOA	10	11/20/93 0:00:00	MRS	ALLOYS_2
173	TI_6AL	Ti:V:Al 1:?:6 mirror finish, as rec'd, 90 deg TOA	6	5/12/94 0:00:00	MRS	ALLOYS_2
174	TI_6AL_A	Ti:V:Al 1:?:6 mirror finish, as rec'd, 90 deg TOA	3	5/12/94 0:00:00	MRS	ALLOYS_2
175	ti_6al_b	Ti:V:Al 1:?:6 mirror finish, 1 min 3KV etch 90 deg	6	5/12/94 0:00:00	MRS	ALLOYS_2
176	ti_gr12	Ti GR-12 (as rec'd, MS Co.) 35 TOA	5	11/17/93 0:00:00	MRS	ALLOYS_2
177	ti_gr12s	Ti GR-12 [MSC] (scraped & ion etched) 35 TOA	7	11/17/93 0:00:00	MRS	ALLOYS_2
178	ti_gr2	Ti GR-02 (as rec'd, MS Co.) 35 TOA	5	11/17/93 0:00:00	MRS	ALLOYS_2
179	ti_gr2_s	Ti GR-02 [MSC] (scraped & ion etched) 35 TOA	7	11/17/93 0:00:00	MRS	ALLOYS_2
180	ti_gr7	Ti GR-07 (as rec'd, MS Co.) 35 TOA	5	11/17/93 0:00:00	MRS	ALLOYS_2
181	ti_gr7_a	Ti GR-07 (as rec'd, MS Co.) 35 TOA	3	11/17/93 0:00:00	MRS	ALLOYS_2
182	ti_gr7_s	Ti GR-07 [MSC] (scraped & ion etched) 35 TOA	7	11/16/93 0:00:00	MRS	ALLOYS_2
183	woodsmtl	WOOD'S METAL (90 DEG TOA) SCRAPED & ION ETCHED, Bi(50)Cd(12.5)Pb(25)Sn(12.5)	1	3/11/87 0:00:00	MRS	ALLOYS_2
184	almandin	Almandine (Fe3Al2(SiO4)3) Alaska USA fresh bulk	13	6/29/94 0:00:00	MRS	ALUM-SIL
185	kunzite1	Kunzite (LiAlSi2O6) Aghanistan fresh bulk clear	17	7/1/94 0:00:00	MRS	ALUM-SIL
186	pyrope_1	Pyrope (Mg3Al2(SiO4)3) Arizona USA fresh bulk red	16	6/26/94 0:00:00	MRS	ALUM-SIL
187	pyrope_2	Pyrope (Mg3Al2(SiO4)3) Arizona USA fresh bulk red	1	6/28/94 0:00:00	MRS	ALUM-SIL
188	ag_r_000	Angle Mount, 0 deg TOA, etched Ag/PET	1	4/8/93 0:00:00	MRS	ANGL-RES
189	ag_r_018	Ag/PET on Angle Mount "18" deg ROT, 0 TOA (graze)	1	4/8/93 0:00:00	MRS	ANGL-RES
190	ag_r_160	Angle Mount rotated to near 160 TOA	2	4/12/93 0:00:00	MRS	ANGL-RES
191	ag_t_035	35 deg TOA, Ag/PET ion etched clean, 160 Watts, Tilt stage	1	4/8/93 0:00:00	MRS	ANGL-RES
192	ag_t_070	70 deg TOA, Ag/PET ion etched clean, 160 Watts Tilt Stage	1	4/8/93 0:00:00	MRS	ANGL-RES
193	ag_t_100	100 deg TOA, Ag/PET ion etched clean, 160 Watts, Tilt Stage	1	4/8/93 0:00:00	MRS	ANGL-RES
194	ag_t_104	104 deg TOA, Ag/PET ion etched clean, Tilt Stage	4	4/8/93 0:00:00	MRS	ANGL-RES
195	ag_t_110	110 deg TOA, Ag/PET ion etched clean, 160 Watts, Tilt Stage	1	4/8/93 0:00:00	MRS	ANGL-RES
196	ag_t_120	120 deg TOA, Ag/PET ion etched clean, 160 Watts, Tilt Stage	1	4/8/93 0:00:00	MRS	ANGL-RES
197	ag_t_140	True Grazing: 140 TOA, Ag/PET, etched, 160 Watts, Tilt Stage	1	4/8/93 0:00:00	MRS	ANGL-RES
198	ag_t_141	True Grazing: 141 TOA, 2 deg from parallel, Ag/PET Tilt Stage	1	4/8/93 0:00:00	MRS	ANGL-RES
199	au4f_15a	Au/Si (15 deg TOA) ion etched before each spectrum	8	9/11/91 0:00:00	MRS	ANGL-RES
200	au4f_15b	Au/Si 15 deg TOA ion etched before each spectrum	4	9/11/91 0:00:00	MRS	ANGL-RES
201	au4f_15c	Au/Si 15 deg TOA ion etched before each spectrum	2	9/11/91 0:00:00	MRS	ANGL-RES
202	au4f_15d	Au/Si 15 deg TOA ion etched before each spectrum	5	9/11/91 0:00:00	MRS	ANGL-RES
203	au4f_15e	Au/Si 15 deg TOA ion etched before each spectrum	3	9/11/91 0:00:00	MRS	ANGL-RES
204	au4f_45a	Au/Si 45 deg TOA (ion etched before each scan)	8	9/12/91 0:00:00	MRS	ANGL-RES
205	au4f_45b	Au/Si 45 deg TOA (ion etched before each scan)	8	9/12/91 0:00:00	MRS	ANGL-RES

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
206	au4f_45c	Au/Si 45 deg TOA (ion etched before each scan)	6	9/12/91 0:00:00	MRS	ANGL-RES
207	crsi_10	CrSi 15 monolayers Cr/Si(111) 10 deg TOA	13	7/21/92 0:00:00	MRS	ANGL-RES
208	crsi_90a	CrSi 15 monolayers Cr/Si(111) 90 TOA	11	7/21/92 0:00:00	MRS	ANGL-RES
209	crsi_90b	CrSi 15 monolayers Cr/Si(111) 90 TOA	2	7/22/92 0:00:00	MRS	ANGL-RES
210	f_ether1	Fluoro-ether polymer on soda-lime glass (35 toa)	4	4/26/91 0:00:00	MRS	ANGL-RES
211	f_ether2	Fluoro-ether polymer on glass (90 deg TOA)	4	4/26/91 0:00:00	MRS	ANGL-RES
212	f_ether3	Fluoro-ether polymer on soda-lime glass (10 deg)	4	4/26/91 0:00:00	MRS	ANGL-RES
213	f_ether4	Fluoro-ether polymer on soda-lime glass 10 deg TOA	1	4/26/91 0:00:00	MRS	ANGL-RES
214	f_ether5	Fluoro-Ether Lube on Glass (10 deg TOA)	6	4/24/91 0:00:00	MRS	ANGL-RES
215	f_ether6	Fluoro-Ether Lube on Glass (90 deg TOA)	6	4/24/91 0:00:00	MRS	ANGL-RES
216	f_ether7	Fluor-Ether Lube on Glass (90 deg TOA)	4	4/24/91 0:00:00	MRS	ANGL-RES
217	gaas_20	20 deg TOA GaAs (as rec'd)	15	12/1/92 0:00:00	MRS	ANGL-RES
218	gaas_30	30 deg TOA GaAs (as rec'd)	15	12/1/92 0:00:00	MRS	ANGL-RES
219	gaas_45	45 deg TOA GaAs (as rec'd)	15	12/1/92 0:00:00	MRS	ANGL-RES
220	gaas_90	GaAs wafer (as rec'd, 90 deg TOA rel to surface)	4	3/27/92 0:00:00	MRS	ANGL-RES
221	gaas_bul	Freshly Exposed bulk of a GaAs WAFER (90 DEGREE TOA)	7	2/6/87 0:00:00	MRS	ANGL-RES
222	graph_10	GRAPHITE LAYER ON TAPE, TOA=10 deg (smoothed, norm)	1	11/11/90 0:00:00	MRS	ANGL-RES
223	graph_20	GRAPHITE LAYER ON TAPE, TOA=20 deg (smoothed, norm)	1	11/11/90 0:00:00	MRS	ANGL-RES
224	graph_35	GRAPHITE LAYER ON TAPE, TOA=35 deg (smoothed, norm)	1	11/11/90 0:00:00	MRS	ANGL-RES
225	graph_60	GRAPHITE LAYER ON TAPE, TOA=60 deg (smoothed, norm)	1	11/11/90 0:00:00	MRS	ANGL-RES
226	graph_90	GRAPHITE LAYER ON TAPE, TOA=90 deg (smoothed, norm)	1	11/11/90 0:00:00	MRS	ANGL-RES
227	nv_si90a	Native Oxide on Silicon (100) 90 Deg TOA	2	11/20/86 0:00:00	MRS	ANGL-RES
228	nv_si90b	Native Oxide on Silicon (100) 90 DEG TOA	1	11/20/86 0:00:00	MRS	ANGL-RES
229	nv_si_10	Native Si oxide, TOA=10 deg	1	10/19/90 0:00:00	MRS	ANGL-RES
230	nv_si_15	Native Si oxide, TOA=15 deg	1	10/19/90 0:00:00	MRS	ANGL-RES
231	nv_si_20	Native Si oxide, TOA=20 deg	1	10/19/90 0:00:00	MRS	ANGL-RES
232	nv_si_30	Native Si oxide, TOA=30 deg	1	10/19/90 0:00:00	MRS	ANGL-RES
233	nv_si_50	Native Si oxide, TOA=50 deg	1	10/19/90 0:00:00	MRS	ANGL-RES
234	nv_si_70	Native Si oxide, TOA=70 deg	1	10/19/90 0:00:00	MRS	ANGL-RES
235	nv_te_05	Native Oxide of Tellurium (Te) 5 DEGREE TOA	1	11/19/86 0:00:00	MRS	ANGL-RES
236	nv_te_10	Native Oxide of Tellurium (Te) 10 DEGREE TOA	2	11/20/86 0:00:00	MRS	ANGL-RES
237	pwdr_035	5-20u Ta2O5 Pwdr/DST 35 TOA 35 AOI FG 95% parallel	2	4/13/93 0:00:00	MRS	ANGL-RES
238	pwdr_090	5-20u Ta2O5 Pwdr/DST 90 TOA 25 AOI FG 95% parallel	2	4/13/93 0:00:00	MRS	ANGL-RES
239	pwdr_100	5-20u Ta2O5 Pwdr/DST 100 TOA 25 AOI FG 95% paralle	2	4/13/93 0:00:00	MRS	ANGL-RES
240	pwdr_110	5-20u Ta2O5 Pwdr/DST 110 TOA 25 AOI FG 95% paralle	2	4/13/93 0:00:00	MRS	ANGL-RES
241	pwdr_120	5-20u Ta2O5 Pwdr/DST 120 TOA 25 AOI FG 95% paralle	2	4/13/93 0:00:00	MRS	ANGL-RES
242	sio2_10	200 A SiO2/Si (as rec'd) 10 deg TOA	15	7/20/92 0:00:00	MRS	ANGL-RES
243	sio2_50	200 A SiO2/Si (as rec'd) 50 deg TOA	15	7/20/92 0:00:00	MRS	ANGL-RES
244	sio2_90a	200 A SiO2/Si (as rec'd) 90 deg TOA	9	7/20/92 0:00:00	MRS	ANGL-RES
245	sio2_90b	200 A SiO2/Si (as rec'd) 90 deg TOA	12	7/20/92 0:00:00	MRS	ANGL-RES
246	sio2_90c	200 A SiO2/Si (as rec'd) 90 deg TOA	2	7/20/92 0:00:00	MRS	ANGL-RES



Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
247	si_vb_90	Silicon (n-type ?) freshly exposed edge (90 toa)	3	7/16/91 0:00:00	MRS	ANGL-RES
248	pcb_bag1	ANTI-STATIC BAG FOR PC BOARD (SECO PACK 66 PPP-C-1842A INSIDE SURFACE)	8	11/2/85 0:00:00	MRS	ANTISTAT
249	pcb_bag2	ANTI-STATIC BAG FOR PC BOARDS (SEALPAK Co.)	9	11/2/85 0:00:00	MRS	ANTISTAT
250	pcb_bag3	ANTI-STATIC BAG for PC Board (3M #2100 STATIC SHIELDING BAG)	5	11/17/85 0:00:00	MRS	ANTISTAT
251	pcb_bag4	ANTI STATIC BAG FOR HANDLING PC BOARDS (ARMAND CO. (PPP-C-1842A))	8	11/17/85 0:00:00	MRS	ANTISTAT
252	pcb_bag5	ANTI-STATIC BAG FROM 3M (#2100 STATIC SHIELDING BAG) FOR PC BOARDS	2	11/17/85 0:00:00	MRS	ANTISTAT
253	static_a	Chapman Static Eliminating Spray On A Gold Platen (No Rust Formula) The Portland Co.	9	11/2/85 0:00:00	MRS	ANTISTAT
254	alz_3	HAIR SAMPLE FROM ALZ PATIENT #3	6	7/27/86 0:00:00	MRS	BIO-TECH
255	alz_4	HAIR SAMPLE FROM ALZ PATIENT #4	7	7/27/86 0:00:00	MRS	BIO-TECH
256	yeast	Freeze-dried Yeast (P.Dengis-CIFA) pellet + mesh	3	2/25/94 0:00:00	MRS	BIO-TECH
257	yeast_1	Freeze-dried Yeast (P.Dengis-CIFA) pellet + mesh	5	2/25/94 0:00:00	MRS	BIO-TECH
258	yeast_1a	Test to find true shape for Yeast	1	2/25/94 0:00:00	MRS	BIO-TECH
259	yeast_1b	Repeat on "yeast_1a" area to test for damage.	1	2/25/94 0:00:00	MRS	BIO-TECH
260	yeast_2	Freeze-dried Yeast (P.Dengis-CIFA) pressed on DST	7	2/25/94 0:00:00	MRS	BIO-TECH
261	yeast_2a	Freeze-dried Yeast (P.Dengis-CIFA) pressed on DST	1	2/25/94 0:00:00	MRS	BIO-TECH
262	yeast_3	Freeze-dried Yeast (P.Dengis-CIFA) pellet+mesh pos2	5	2/25/94 0:00:00	MRS	BIO-TECH
263	yeast_4	Freeze-dried Yeast pressed on DST mesh pos 2	4	2/25/94 0:00:00	MRS	BIO-TECH
264	yeast_5	Freeze-dried Yeast powder gently pressed on DST 35	4	2/25/94 0:00:00	MRS	BIO-TECH
265	yeast_d	Freeze-dried Yeast (P.Dengis-CIFA) pellet + mesh	5	2/25/94 0:00:00	MRS	BIO-TECH
266	crb_1	CrB JapanNewMetal Co. lot#56301 2min3KV etch 90TOA Chromium Boride	6	5/18/94 0:00:00	MRS	BORIDE
267	lab6_1	LaB6 JapanNewMetalCo. lot#851201 2min3KV etch 90TO Lanthanum Hexa-Boride	6	5/18/94 0:00:00	MRS	BORIDE
268	mob_1	MoB JapanNewMetal Co. lot#35901 2min3KV etch 90TOA Molydenum Boride	6	5/18/94 0:00:00	MRS	BORIDE
269	ni3b_1	Ni3B Kyoritsu Ceramic Mat Co. 2min 3KV etch pellet Tri-Nickel Boride	6	5/17/94 0:00:00	MRS	BORIDE
270	ni3b_c_1	Ni3B Kyoritsu Ceramic Mat Co. 2min 3KV etch 90 TOA Tri-Nickel Boride	6	5/18/94 0:00:00	MRS	BORIDE
271	wb_1	WB JapanNewMetal Co. lot#451001 2min3KV etch 90TOA Tungsten Boride	6	5/17/94 0:00:00	MRS	BORIDE
272	86_1126a	Copper Foil (90 Deg Toa, Knife Scrape, Ion Etched: 4 Kv, 1 Min (Cu 2p3 Ref E = 932.47 +/-0.07 Ev)	12	11/26/86 0:00:00	MRS	CALIBRAT
273	86_11_26	COPPER (Cu) FOIL (90 deg TOA, scraped & etched) 4 KV, 1min. (Cu (2p3) BE should be 932.47eV)	12	11/26/86 0:00:00	MRS	CALIBRAT
274	87_0710a	COPPER (Cu) FOIL 90 DEG TOA, ION ETCHED AT 4 KeV Transmission Function testing (not calibration)	12	7/10/87 0:00:00	MRS	CALIBRAT
275	87_07_10	COPPER (Cu) FOIL (90 deg TOA, 12min ion etch 4KV) (Dip in front of Cu2p3 shows detector saturated.	12	7/10/87 0:00:00	MRS	CALIBRAT
276	88_06_20	CHECK OF Cu CALIBRATION expected 932.47 +/- 0.07 according to SSI setup	2	6/20/88 0:00:00	MRS	CALIBRAT
277	88_06_28	GOLD (Au) ON MYLAR (90 deg TOA, as received) expected Au(4f7) at 83.96 eV +/-0.07 (SSI setup)	3	6/28/88 0:00:00	MRS	CALIBRAT
278	88_11_27	SILVER (Ag) FOIL (90 deg TOA, ion etched: 4KV 1min	3	11/27/86 0:00:00	MRS	CALIBRAT
279	91_02_21	Calibration check after installation of Grabber lense	21	2/21/91 0:00:00	MRS	CALIBRAT
280	91_0307a	BE and Pass Energy Calibration after service	21	3/7/91 0:00:00	MRS	CALIBRAT
281	91_0307b	Second Calibration check after service	21	3/7/91 0:00:00	MRS	CALIBRAT
282	91_03_05	COMPLETE GOLD PERFORMANCE MATRIX--S PROBE	42	3/5/91 0:00:00	MRS	CALIBRAT
283	91_03_07	COMPLETE GOLD PERFORMANCE MATRIX--S PROBE	42	3/7/91 0:00:00	MRS	CALIBRAT
284	91_03_09	Cu(3s) BE check for DAC adjustment DAC=Digital-to-Analog Conversion circuit	1	3/9/91 0:00:00	MRS	CALIBRAT
285	91_0812a	Calibration for Pure Oxide work: Au(4f7)=83.98 eV +/- 0.05 eV (SSI style)	1	8/12/91 0:00:00	MRS	CALIBRAT
286	91_0812b	Calibration for Pure Oxide work: Cu(2p3)=932.47 eV based on SSI calibration style	1	8/12/91 0:00:00	MRS	CALIBRAT
287	91_0823a	Freshly scraped copper foil 35 TOA DAC & BE check	2	8/23/91 0:00:00	MRS	CALIBRAT

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
288	91_08_12	Calibration check for pure oxide studies	1	8/12/91 0:00:00	MRS	CALIBRAT
289	91_08_23	Freshly scraped gold BE check 35 TOA	2	8/23/91 0:00:00	MRS	CALIBRAT
290	91_0906a	Gold BE calibration: Gold ion etched 35 TOA	1	9/6/91 0:00:00	MRS	CALIBRAT
291	91_0906b	Freshly ion etched copper 35 TOA DAC check	2	9/6/91 0:00:00	MRS	CALIBRAT
292	91_09_06	Gold BE check ion etched 35 TOA	1	9/6/91 0:00:00	MRS	CALIBRAT
293	91_09_11	Au/Si 15 deg TOA ion etched before each spectrum	2	9/11/91 0:00:00	MRS	CALIBRAT
294	91_09_12	Au/Si 45 deg TOA (ion etched before each scan)	8	9/12/91 0:00:00	MRS	CALIBRAT
295	92_0511a	Au calibration for handbook work on CPOs	1	5/11/92 0:00:00	MRS	CALIBRAT
296	92_0511b	Au calibration for handbook work on CPOs	1	5/11/92 0:00:00	MRS	CALIBRAT
297	92_0511c	Au calibration for handbook work on CPOs	1	5/11/92 0:00:00	MRS	CALIBRAT
298	92_0511d	Cu calibration for handbook work on CPOs	1	5/11/92 0:00:00	MRS	CALIBRAT
299	92_0511e	Cu calibrated for handbook work on CPOs	1	5/11/92 0:00:00	MRS	CALIBRAT
300	92_0511f	Found that exponents were not correct. Corrected. Made needed corrections.	1	5/11/92 0:00:00	MRS	CALIBRAT
301	92_05_11	Au calibration for handbook work on CPOs	1	5/11/92 0:00:00	MRS	CALIBRAT
302	92_0615a	Calibration using ion etched copper	8	6/15/92 0:00:00	MRS	CALIBRAT
303	92_0615c	Calibration using ion etched copper	4	6/15/92 0:00:00	MRS	CALIBRAT
304	92_06_15	Calibration using Gold/silicon	4	6/15/92 0:00:00	MRS	CALIBRAT
305	92_0911a	Lightly etched Au/Si, New Monochromator, Graz 105	3	9/11/92 0:00:00	MRS	CALIBRAT
306	92_0911b	Strongly etched Cu, New Monochromator, Grazing 105	2	9/11/92 0:00:00	MRS	CALIBRAT
307	92_09_11	Min Etch of Ag/mylar, New Monochromator, Graz 100	3	9/11/92 0:00:00	MRS	CALIBRAT
308	92_1118a	Ag Heavily Etched 5-10 deg X-ray AOI, 85 deg TOA	1	11/18/92 0:00:00	MRS	CALIBRAT
309	92_1118c	Au Heavily Etched X-ray AOI 5-10, e- TOA 85	4	11/18/92 0:00:00	MRS	CALIBRAT
310	92_1118d	Au Heavily Etched X-ray AOI 5-10, e- TOA 85	2	11/18/92 0:00:00	MRS	CALIBRAT
311	92_1118e	Cu Heavily etched 5-10 deg X-ray AOI, 85 deg TOA	2	11/18/92 0:00:00	MRS	CALIBRAT
312	92_1118f	Cu Heavily etched 5-10 deg X-ray AOI, 85 deg TOA	1	11/18/92 0:00:00	MRS	CALIBRAT
313	92_11_18	Ag Heavily Etched 5-10 deg X-ray AOI, 85 deg TOA	2	11/18/92 0:00:00	MRS	CALIBRAT
314	92_11_20	Energy Loss Function of Au (4f) with dirty Au/Si	4	11/20/92 0:00:00	MRS	CALIBRAT
315	93_0105a	Cu/Si (just after ion etch) 35 deg TOA testing NIST Ref Energy style Cu(2p3) at 932.70 eV	7	1/5/93 0:00:00	MRS	CALIBRAT
316	93_0107a	re: 8.6.2 Freshly Cleaned Ag/Si (35 deg TOA) Testing NIST Energy Ref method	8	1/7/93 0:00:00	MRS	CALIBRAT
317	93_0107b	Check of Ag/Si cleanliness after etch (test of NIST energy ref method)	1	1/7/93 0:00:00	MRS	CALIBRAT
318	93_0107c	Check of gold/silicon cleanliness (test of Powell's NIST energy Ref method)	1	1/7/93 0:00:00	MRS	CALIBRAT
319	93_0107d	re: 8.6.2 Freshly cleaned Au/Si (35 deg TOA) (test of Powell's NIST energy referencing method)	8	1/7/93 0:00:00	MRS	CALIBRAT
320	93_0107e	repeat run for Au/Si (test of NIST energy ref method)	8	1/7/93 0:00:00	MRS	CALIBRAT
321	93_0107f	Cu/Si 14 days in S-Probe after heavy ion etching (ion etched a different place for NIST tests)	7	1/5/93 0:00:00	MRS	CALIBRAT
322	93_0107g	Check for BE error due to spot size (no re-align) (still using NIST ref energies with Cu2p3=932.70eV	16	1/7/93 0:00:00	MRS	CALIBRAT
323	93_0107h	re: 8.6.2 Freshly Cleaned Ag/Si (35 deg TOA) (restarted NIST test)	1	1/7/93 0:00:00	MRS	CALIBRAT
324	93_0107i	re: 8.6.2 Freshly cleaned Au/Si (35 deg TOA) (NIST method)	1	1/7/93 0:00:00	MRS	CALIBRAT
325	93_0108a	My Normal Copper Foil Sample (fresh spot etch) (still using NIST ref energy values 932.70 eV)	8	1/8/93 0:00:00	MRS	CALIBRAT
326	93_01_05	Cu/Si ("As-Rec'd" region, 1 cm from etch crater) (start of NIST Energy Referencing tests)	1	1/5/93 0:00:00	MRS	CALIBRAT
327	93_01_07	re: 8.6.2 Freshly Cleaned Ag/Si (35 deg TOA) Testing NIST Energy Referencing values	8	1/7/93 0:00:00	MRS	CALIBRAT
328	93_01_08	Repeat of Cu/Si (freshly etched next morning) (continuing NIST test method)	8	1/8/93 0:00:00	MRS	CALIBRAT

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
329	93_02_19	spot & pe CHECK	8	2/19/93 0:00:00	MRS	CALIBRAT
330	93_0319a	Check of calibration of ion etched copper (Have decided to switch to NPL Ref E at 932.67 eV)	3	3/19/93 0:00:00	MRS	CALIBRAT
331	93_03_19	Check of calibration using gold Have decided to switch to NPL values at 83.98 eV.	3	3/19/93 0:00:00	MRS	CALIBRAT
332	93_04_08	100 deg TOA is best for 100 spot, Ag/PET etched,Tilt stage	2	4/8/93 0:00:00	MRS	CALIBRAT
333	93_09_16	2 day old ion etched Au/Si 35 TOA (still using NPL Ref energies)	10	9/16/93 0:00:00	MRS	CALIBRAT
334	93_1130a	Cal corrected by increasing PE by 0.15 (Decided to always use NPL ref energies from now.)	1	11/30/93 0:00:00	MRS	CALIBRAT
335	93_11_30	Au/Si after ion etch, before cal correction (Silicon as substrate seems unreliable)	1	11/30/93 0:00:00	MRS	CALIBRAT
336	94_02_07	Check of Ag BE with good calibration	1	2/7/94 0:00:00	MRS	CALIBRAT
337	94_0422a	Check of Cu BEs to calibrate PEs 35 deg TOA	5	4/22/94 0:00:00	MRS	CALIBRAT
338	94_0422b	check of Cu BEs to verify calibration 35 deg TOA	4	4/22/94 0:00:00	MRS	CALIBRAT
339	94_0427a	Check of Cu BEs to calibrate PEs 35 deg TOA	5	4/27/94 0:00:00	MRS	CALIBRAT
340	94_04_22	check of Cu BEs to verify calibration 35 deg TOA	4	4/22/94 0:00:00	MRS	CALIBRAT
341	94_04_27	Check of Cu BEs to verify calibration 35 deg TOA	5	4/27/94 0:00:00	MRS	CALIBRAT
342	94_0506a	Check of Calibration using Cu 90 deg TOA	1	5/6/94 0:00:00	MRS	CALIBRAT
343	94_0509a	Verification of new PEs 90 deg TOA	3	5/9/94 0:00:00	MRS	CALIBRAT
344	94_0516a	Check of Calibration using Cu 90 deg TOA	2	5/16/94 0:00:00	MRS	CALIBRAT
345	94_0530a	Check of Calibration using Cu 90 deg TOA	5	5/30/94 0:00:00	MRS	CALIBRAT
346	94_05_02	Check of Calibration using Cu 35 deg TOA	5	5/2/94 0:00:00	MRS	CALIBRAT
347	94_05_06	Check of Calibration using Cu 90 deg TOA	5	5/6/94 0:00:00	MRS	CALIBRAT
348	94_05_09	Check of Calibration using Cu 90 deg TOA	5	5/9/94 0:00:00	MRS	CALIBRAT
349	94_05_16	Check of Calibration using Cu 90 deg TOA	5	5/16/94 0:00:00	MRS	CALIBRAT
350	94_05_30	Check of Calibration using Cu 90 deg TOA	5	5/30/94 0:00:00	MRS	CALIBRAT
351	94_0610a	Verify re-Calibration using Cu 90 deg TOA	5	6/10/94 0:00:00	MRS	CALIBRAT
352	94_0610b	Check of Calibration using Cu 90 deg TOA	5	6/10/94 0:00:00	MRS	CALIBRAT
353	94_0623	Check of Calibration using Cu 90 deg TOA	5	6/23/94 0:00:00	MRS	CALIBRAT
354	94_0623a	Verification of Calibration using Cu 90 deg TOA	5	6/23/94 0:00:00	MRS	CALIBRAT
355	94_06_10	Check of Calibration using Cu 90 deg TOA	5	6/10/94 0:00:00	MRS	CALIBRAT
356	94_0720a	spot size 150x800 needed offset Why? 35 deg TOA	6	7/20/94 0:00:00	MRS	CALIBRAT
357	94_0720b	Check of Calibration using ion etched Au/Si 35 deg TOA	5	7/20/94 0:00:00	MRS	CALIBRAT
358	94_07_20	Check of Calibration using Cu 90 deg TOA	5	7/20/94 0:00:00	MRS	CALIBRAT
359	AG_CAP	Study of C & O Captured from Cryo UHV by ion etched "Silver (Ag)"	4	12/22/93 0:00:00	DPR	CAPTUR_1
360	AL_CAP_1	Study of C & O Captured from Cryo UHV by ion etched "Aluminum (Al)" Mitsubishi Foil	4	2/4/93 0:00:00	DPR	CAPTUR_1
361	AL_CAP_2	Study of C & O Captured from Cryo UHV by ion etched "Aluminum (Al)" Drop	3	10/15/91 0:00:00	DPR	CAPTUR_1
362	AS_CAP	Study of C & O capture from cryo UHV by ion etched "Arsenic (As)"	4	1/26/94 0:00:00	DPR	CAPTUR_1
363	AU_CAP	Study of C & O Captured from Cryo UHV by ion etched "Gold (Au)" (Au/Si)	3	7/21/93 0:00:00	DPR	CAPTUR_1
364	BE_CAP	Study of C & O Captured from Cryo UHV by ion etched "Beryllium (Be)"	3	3/18/93 0:00:00	DPR	CAPTUR_1
365	BI_CAP	Study of C & O Captured from Cryo UHV by ion etched "Bismuth (Bi)"	3	3/9/93 0:00:00	DPR	CAPTUR_1
366	CD_CAP	Study of C & O Captured from Cryo UHV by ion etched "Cadmium (Cd)"	3	2/26/93 0:00:00	DPR	CAPTUR_1
367	CO_CAP	Study of C & O Captured from Cryo UHV by ion etched "Cobalt (Co)"	4	12/7/93 0:00:00	DPR	CAPTUR_1
368	CR_CAP_1	Study of C & O Captured from Cryo UHV by ion etched "Chromium (Cr)"	3	7/20/93 0:00:00	DPR	CAPTUR_1
369	CR_CAP_2	Study #2 of C & O Captured from Cryo UHV by ion etched "Chromium (Cr)"	3	7/21/93 0:00:00	DPR	CAPTUR_1

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
370	CU_CAP	Study of C & O Captured from Cryo UHV by ion etched "Copper (Cu)"	3	7/23/93 0:00:00	DPR	CAPTUR_1
371	FE_CAP	Study of C & O Captured from Cryo UHV by ion etched "Iron (Fe)"	4	12/8/93 0:00:00	DPR	CAPTUR_1
372	GE_CAP	Study of C & O Captured from Cryo UHV by ion etched "Germanium (Ge)"	4	12/21/93 0:00:00	DPR	CAPTUR_1
373	HF_CAP	Study of C & O Captured from Cryo UHV by ion etched "Hafnium (Hf)"	3	12/8/93 0:00:00	DPR	CAPTUR_1
374	IN_CAP	Study of C & O Recovered from Cryo UHV by ion etched "Indium (In)"	3	12/9/93 0:00:00	DPR	CAPTUR_1
375	IR_CAP	Study of C & O Captured from Cryo UHV by ion etched "Iridium (Ir)"	5	12/24/93 0:00:00	DPR	CAPTUR_1
376	MG_CAP	Study of C & O Captured from Cryo UHV by ion etched "Magnesium (Mg)"	3	2/25/93 0:00:00	DPR	CAPTUR_1
377	MN_CAP	Study of C & O Captured from Cryo UHV by ion etched "Manganese (Mn)"	3	12/7/93 0:00:00	DPR	CAPTUR_1
378	MO_CAP	Study of C & O Captured from Cryo UHV by ion etched "Molybdenum (Mo)"	3	11/25/93 0:00:00	DPR	CAPTUR_1
379	NB_CAP	Study of C & O Captured from Cryo UHV by ion etched "Niobium (Nb)"	3	3/12/93 0:00:00	DPR	CAPTUR_1
380	NI_CAP	Study of C & O Captured from Cryo UHV by ion etched "Nickel (Ni)"	4	12/3/93 0:00:00	DPR	CAPTUR_1
381	PB_CAP	Study of C & O Captured from Cryo UHV by ion etched "Lead (Pb)"	4	12/14/93 0:00:00	DPR	CAPTUR_1
382	PD_CAP	Study of C & O Captured from Cryo UHV by ion etched "Palladium (Pd)"	4	12/16/93 0:00:00	DPR	CAPTUR_1
383	PT_CAP	Study of C & O Captured from Cryo UHV by ion etched "Platinum (Pt)"	4	12/17/93 0:00:00	DPR	CAPTUR_1
384	RE_CAP	Study of C & O Captured from Cryo UHV by ion etched "Rhenium (Re)"	3	11/30/93 0:00:00	DPR	CAPTUR_1
385	RH_CAP	Study of C & O Captured from Cryo UHV by ion etched "Rhodium (Rh)"	4	12/18/93 0:00:00	DPR	CAPTUR_1
386	RU_CAP	Study of C & O captured from cryo UHV by ion etched "Ruthenium (Ru)"	3	1/27/94 0:00:00	DPR	CAPTUR_1
387	SB_CAP	Study of C & O capture from cryo UHV by ion etched "Antimony (Sb)"	3	1/25/94 0:00:00	DPR	CAPTUR_1
388	SC_CAP	Study of C & O Capture from Cryo UHV by ion etched "Scandium (Sc)"	3	3/2/93 0:00:00	DPR	CAPTUR_1
389	SI_CAP_1	Study #1 of C & O Capture from Cryo UHV by ion etched "Silicon (Si)"	4	12/1/93 0:00:00	DPR	CAPTUR_1
390	SI_CAP_2	Study #2 of C & O Capture from Cryo UHV by ion etched "Silicon (Si)"	4	12/3/93 0:00:00	DPR	CAPTUR_1
391	SN_CAP	Study of C & O Capture from Cryo UHV by ion etched "Tin (Sn)"	3	12/11/93 0:00:00	DPR	CAPTUR_1
392	TA_CAP	Study of C & O Capture from Cryo UHV by ion etched "Tantalum (Ta)"	3	12/9/93 0:00:00	DPR	CAPTUR_1
393	TE_CAP	Study of C & O Capture from Cryo UHV by ion etched "Tellurium (Te)"	3	12/16/93 0:00:00	DPR	CAPTUR_1
394	TI_CAP	Study of C & O Capture from Cryo UHV by ion etched "Titanium (Ti)"	3	4/9/93 0:00:00	DPR	CAPTUR_1
395	tl_cap	Study of C & O Capture from Cryo UHV by ion etched "Thallium (Tl)" "Thallium (Tl)"	0	12/10/93 0:00:00	DPR	CAPTUR_1
396	V_CAP	Study of C & O Capture from Cryo UHV by ion etched "Vanadium (V)"	3	4/14/93 0:00:00	DPR	CAPTUR_1
397	W_CAP	Study of C & O Capture from Cryo UHV by ion etched "Tungsten (W)"	3	11/27/93 0:00:00	DPR	CAPTUR_1
398	y_cap_1	Study #1 of C & O Capture from Cryo UHV by ion etched "Yttrium (Y)"	2	7/13/87 0:00:00	DPR	CAPTUR_1
399	Y_CAP_2	Study #2 of C & O Capture from Cryo UHV by ion etched "Yttrium (Y)"	3	3/19/93 0:00:00	DPR	CAPTUR_1
400	ZN_CAP	Study of C & O Capture from Cryo UHV by ion etched "Zinc (Zn)"	4	4/13/93 0:00:00	DPR	CAPTUR_1
401	ZR_CAP	Study of C & O Capture from Cryo UHV by ion etched "Zirconium (Zr)"	3	3/4/93 0:00:00	DPR	CAPTUR_1
402	ag_atend	Silver (Ag) at end of C & O capture study	2	12/22/93 0:00:00	MRS	CAPTUR_2
403	as_atend	Arsenic (As) at end of C & O capture study	1	1/26/94 0:00:00	MRS	CAPTUR_2
404	co_atend	Cobalt (Co) at end of C & O capture study	2	12/7/93 0:00:00	MRS	CAPTUR_2
405	fe_atend	Iron (Fe) at end of C & O capture study	1	12/8/93 0:00:00	MRS	CAPTUR_2
406	ge_atend	Germanium (Ge) at end of C & O capture study	1	12/21/93 0:00:00	MRS	CAPTUR_2
407	hf_atend	Hafnium (Hf) 16 hr at end of C & O capture study	1	12/9/93 0:00:00	MRS	CAPTUR_2
408	mo_atend	Molybdenum (Mo) at end of C & O capture study	1	11/25/93 0:00:00	MRS	CAPTUR_2
409	ni_atend	Nickel (Ni) at end of C & O study	2	12/3/93 0:00:00	MRS	CAPTUR_2
410	pb_atend	Lead (Pb) at end of C & O capture study	1	12/14/93 0:00:00	MRS	CAPTUR_2

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
411	pd_atend	Palladium (Pd) at end of C & O capture study	2	12/16/93 0:00:00	MRS	CAPTUR_2
412	pt_atend	Platinum (Pt) at end of C & O capture study	1	12/17/93 0:00:00	MRS	CAPTUR_2
413	ru_atend	Ruthenium (Ru) at end of C & O capture study	2	1/27/94 0:00:00	MRS	CAPTUR_2
414	sb_atend	Antimony (Sb) at end of C & O capture study	1	1/25/94 0:00:00	MRS	CAPTUR_2
415	sn_atend	Tin (Sn) at end of C & O capture study	1	12/11/93 0:00:00	MRS	CAPTUR_2
416	ta_atend	Tantalum (Ta) at end of C & O capture study	2	12/9/93 0:00:00	MRS	CAPTUR_2
417	te_atend	Tellurium (Te) at end of C & O capture study	1	12/16/93 0:00:00	MRS	CAPTUR_2
418	tl_atend	Thallium (Tl) at end of C & O capture study	1	12/10/93 0:00:00	MRS	CAPTUR_2
419	nbc_2_e	Niobium Carbide (NbC,97%, Aldrich) ion etched 3KV to minimize oxygen content, pellet	8	7/28/94 0:00:00	MRS	CARBIDE
420	tac_1	Tantalum Carbide (TaC, 99%, Aldrich) as rec'd	8	7/26/94 0:00:00	MRS	CARBIDE
421	tac_1a	TaC as rec'd ???	8	7/27/94 0:00:00	MRS	CARBIDE
422	tac_2_e	Tantalum Carbide (TaC, 99%, Aldrich) Ion etched 2 min to minimize oxygen content (pressed pellet)	13	7/27/94 0:00:00	MRS	CARBIDE
423	vc_1	Vanadium Carbide (VC, powder, Aldrich) pellet as rec'd, no cleaning	6	7/25/94 0:00:00	MRS	CARBIDE
424	vc_2_e	Vanadium Carbide (VC) ion etched 3 KV 2 min until oxygen content was minimized. (Pressed pellet)	6	7/28/94 0:00:00	MRS	CARBIDE
425	AMORPH_1	AMORPHOUS (C) SHEET FRESHLY EXPOSED BULK (35 DEG) RMC SAMPLE	1	1/11/88 0:00:00	MRS	CARBON
426	AMORPH_2	AMORPHOUS (C) SHEET FRESHLY EXPOSED BULK (35 DEG)	1	1/11/88 0:00:00	MRS	CARBON
427	ar_implt	Argon Ions/Natural Graphite Crystal (90 TOA) 4KV, 10 min	3	1/12/93 0:00:00	MRS	CARBON
428	diamnd_a	DIAMOND (C) (90 DEG TOA, NO SCREEN, CLEANED WITH SOLVENTS)	1	2/18/88 0:00:00	MRS	CARBON
429	diamnd_b	DIAMOND (C) As received, no screen.	1	2/18/88 0:00:00	MRS	CARBON
430	diamnd_c	INDUSTRIAL DIAMOND (LIGHTLY ETCHED) 45 DEG TOA, SCREEN, EXPOSED BULK	3	7/15/87 0:00:00	MRS	CARBON
431	dimnd_et	INDUSTRIAL DIAMOND 45 DEG TOA, SCREEN, ION ETCH 20s 3 KeV	3	7/15/87 0:00:00	MRS	CARBON
432	dimnd_vb	INDUSTRIAL DIAMOND (C) CLEANED WITH SOLVENTS, 45 DEG TOA	1	1/20/88 0:00:00	MRS	CARBON
433	dlf_1295	Diamond-Like film (1295) 50 angstrom on amorphous SiO2/p-Silicon wafer (90 TOA) as rec	5	7/12/94 0:00:00	MRS	CARBON
434	dlf_1297	Diamond-Like film (1295) 50 angstrom on amorphous SiO2/p-Silicon wafer (90 TOA) as rec	5	7/12/94 0:00:00	MRS	CARBON
435	dlf_1298	Diamond-Like film (1298) 50 angstrom on amorphous SiO2/p-Silicon wafer (90 TOA) as rec	5	7/12/94 0:00:00	MRS	CARBON
436	dlf_1299	Diamond-Like film (1299) 50 angstrom on amorphous SiO2/p-Silicon wafer (90 TOA) as rec	5	7/12/94 0:00:00	MRS	CARBON
437	dlf_1305	Diamond-Like film (1305) 50 angstrom on amorphous SiO2/p-Silicon wafer (90 TOA) as rec	5	7/12/94 0:00:00	MRS	CARBON
438	dlf_n7	Diamond-Like film (N-7) 50 angstrom on p-Silicon wafer (90 TOA) as rec'd	4	7/12/94 0:00:00	MRS	CARBON
439	graph10	GRAPHITE LAYER ON TAPE, TOA=10deg (smoothed, norm)	1	11/11/90 0:00:00	MRS	CARBON
440	graph20	GRAPHITE LAYER ON TAPE, TOA=20deg (smoothed, norm)	1	11/11/90 0:00:00	MRS	CARBON
441	graph35	GRAPHITE LAYER ON TAPE, TOA=35deg (smoothed, norm)	1	11/11/90 0:00:00	MRS	CARBON
442	graph60	GRAPHITE LAYER ON TAPE, TOA=60deg (smoothed, norm)	1	11/11/90 0:00:00	MRS	CARBON
443	graph90	GRAPHITE LAYER ON TAPE, TOA=90deg (smoothed, norm)	1	11/11/90 0:00:00	MRS	CARBON
444	graphite	Natural Crystal of Graphite (90 TOA, as rec'd)	5	1/12/93 0:00:00	MRS	CARBON
445	graph_1a	CARBON (C) SHEET (GRAPHITE, 90 DEG TOA, SCRAPED WITH BLADE)	7	1/19/88 0:00:00	MRS	CARBON
446	graph_1b	CARBON (C) SHEET (GRAPHITE, 90 DEG TOA, SCRAPED WITH A BLADE)	1	1/19/88 0:00:00	MRS	CARBON
447	graph_1c	CARBON (C) SHEET (GRAPHITE, 90 DEG TOA, SCRAPED WITH A BLADE)	1	1/19/88 0:00:00	MRS	CARBON
448	graph_2b	GRAPHITE (C) SHEET FRESHLY EXPOSED BULK (35 DEG TOA)	1	1/11/88 0:00:00	MRS	CARBON
449	hopg_1	HOPG (freshly delaminated surface) 100 deg TOA	10	12/15/93 0:00:00	MRS	CARBON
450	hopg_1a	HOPG (freshly delaminated surface) 100 deg TOA	3	12/15/93 0:00:00	MRS	CARBON
451	hopg_1b	HOPG (freshly delaminated surface) 100 deg TOA	1	12/15/93 0:00:00	MRS	CARBON

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
452	ION_DMGI	Argon Ions/Natural Graphite Crystal (90 TOA) 4KV.	1	1/12/93 0:00:00	MRS	CARBON
453	ION_DMGI2	Argon Ions/Natural Graphite Crystal (90 TOA) 4KV.	1	1/12/93 0:00:00	MRS	CARBON
454	pe_study	TEST Of Flood Gun Stability (0.4 Mm Poly-ethylene)(90 Deg Toa, Screen (1mm), Double Sided Tape)	20	2/18/88 0:00:00	MRS	CARBON
455	pe_test1	TEST for Electron Damage on POLY-ETHYLENE (90 TOA, SCREEN (1mm), DST)	20	2/18/88 0:00:00	MRS	CARBON
456	pe_test2	TEST for Electron Damage to POLY-ETHYLENE (90 TOA, 6-8 mm FROM SCREEN, 4 V, 1 mA)	20	2/22/88 0:00:00	MRS	CARBON
457	ps_bead1	DARK-COLORED POLYSTYRENE BEAD (480u) RF PLASMA IN CF4/He ATMOSPHERE	4	2/12/87 0:00:00	MRS	CARBON
458	ps_bead2	LIGHT-COLORED POLYSTYRENE BEAD (560u) RF PLASMA IN A CF4/He ATMOSPHERE	4	2/12/87 0:00:00	MRS	CARBON
459	wax_papr	WAX PAPER FROM WAXTEX (AS REC'D)	4	10/13/85 0:00:00	MRS	CARBON
460	azurite	CuCO <sub>3</sub> ,Cu(OH) <sub>2</sub> Arizona,USA bulk 90 TOA, mesh	8	5/23/94 0:00:00	MRS	CARBONAT
461	azurite1	CuCO <sub>3</sub> :Cu(OH) <sub>2</sub> (Azurite) Arizona, USA bulk 90 TOA, mesh	8	5/23/94 0:00:00	MRS	CARBONAT
462	azurite2	Green CuCO <sub>3</sub> ,Cu(OH) <sub>2</sub> Arizona,USA bulk 90 TOA, mesh	7	5/24/94 0:00:00	MRS	CARBONAT
463	ba_co3_1	BARIUM CARBONATE (BaCO <sub>3</sub> ) POWDER/DST (90 TOA, ETCHED 10 MIN AT 4 KeV)	9	7/10/87 0:00:00	MRS	CARBONAT
464	bico3_1	Bismuth sub-carbonate (BiO) <sub>2</sub> CO <sub>3</sub> (Aldrich) pellet, mesh: 1mm hgt	9	7/21/94 0:00:00	MRS	CARBONAT
465	calcite	Calcite (CaCO <sub>3</sub> ) Iceland Spar (cleaved edge, 55 TOA	5	12/22/93 0:00:00	MRS	CARBONAT
466	CA_CO3_1	CaCO <sub>3</sub> due to CO <sub>2</sub> attack on CaO Aldr lot# 01228BW scrn 90 TOA	12	1/29/92 0:00:00	MRS	CARBONAT
467	cdco3_2	CdCO <sub>3</sub> (99.999%, Aldrich) pressed into pellet, mesh	9	7/25/94 0:00:00	MRS	CARBONAT
468	cerrusit	Cerrusite (PbCO <sub>3</sub> ) as rec'd surface	10	6/26/94 0:00:00	MRS	CARBONAT
469	cerrust2	Cerrusite (PbCO <sub>3</sub> ) as rec'd surface 90 TOA, mesh	1	6/28/94 0:00:00	MRS	CARBONAT
470	cu_co3_1	COPPER CARBONATE (CuCO <sub>3</sub> ) on DST (PERFECT PARTS Co., TECH. GRADE, 35 TOA)	6	10/20/85 0:00:00	MRS	CARBONAT
471	cu_co3_2	COPPER CARBONATE (CuCO <sub>3</sub> ) on DST (PERFECT PARTS Co., ION ETCHED)	2	10/20/85 0:00:00	MRS	CARBONAT
472	cu_co3_3	COPPER CARBONATE (CuCO <sub>3</sub> ) on DST (PERFECT PARTS Co., ION ETCHED)	7	10/20/85 0:00:00	MRS	CARBONAT
473	lay_co3	Y <sub>2</sub> (CO <sub>3</sub> ) <sub>3</sub> ON SURFACE OF LaB <sub>6</sub> AFTER ETCHED 50A 90 DEG TOA	5	10/18/88 0:00:00	MRS	CARBONAT
474	la_y_co3	Y <sub>2</sub> (CO <sub>3</sub> ) <sub>3</sub> ON SURFACE OF LaB <sub>6</sub> AFTER ION ETCHED 50A 90 DEG TOA	1	10/18/88 0:00:00	MRS	CARBONAT
475	li_co3_1	LiCO <sub>3</sub> from CO <sub>2</sub> attack on LiOH POWDER ON In FOIL (NO SCREEN, 90 DEG TOA)	4	2/9/88 0:00:00	MRS	CARBONAT
476	magnesit	MgCO <sub>3</sub> (Magnesite) Washington,USA bulk,mesh,90 TOA	8	5/26/94 0:00:00	MRS	CARBONAT
477	mg_co3_1	MgCO <sub>3</sub> from CO <sub>2</sub> attack on MgO (Aldr lot# 00616CW, screen, 90 deg TOA)	12	8/22/91 0:00:00	MRS	CARBONAT
478	mg_co3_2	MAGNESIUM CARBONATE (MgCO <sub>3</sub> )/DST (PERFECT PARTS Co.,TECH. GRADE)	8	10/20/85 0:00:00	MRS	CARBONAT
479	mn_co3	MnCO <sub>3</sub> xtl (Rhodochrosite, Argentina) fresh bulk 90	7	5/13/94 0:00:00	MRS	CARBONAT
480	sr_co3_1	SrCO <sub>3</sub> from CO <sub>2</sub> attack on SrO (99.5% RMC, #71208-30, screen, 90 TOA)	10	1/27/92 0:00:00	MRS	CARBONAT
481	sr_co3_2	SrCO <sub>3</sub> powder (90 DEG TOA, PRESSED ON In FOIL,MESH)	3	1/26/88 0:00:00	MRS	CARBONAT
482	y2co3_1	Y <sub>2</sub> (CO <sub>3</sub> ) <sub>3</sub> +nH <sub>2</sub> O pellet aldrich 90 mesh	9	7/29/94 0:00:00	MRS	CARBONAT
483	Y_CO3_1	Y <sub>2</sub> (CO <sub>3</sub> ) <sub>3</sub> from CO <sub>2</sub> attack on Y <sub>2</sub> O <sub>3</sub> (RMC #71208-13, screen, 90 TOA)	10	8/19/91 0:00:00	MRS	CARBONAT
484	al_pt_1	1.5 wt% Al and 0.5 wt% Pt on Zeolite (Zn, Na) 90 screen	1	2/2/92 0:00:00	MRS	CATALYST
485	al_pt_1a	1.5 wt% Al and 0.5 wt% Pt / Zeolite (Zn, Na) 90 screen	7	2/3/92 0:00:00	MRS	CATALYST
486	al_pt_2	1.5 wt% Al & 0.5 wt% Pt on Zeolite: repeatedly moved to avoid damage	2	2/5/92 0:00:00	MRS	CATALYST
487	crf_al_1	Showa Denko CrF/Al <sub>2</sub> O <sub>3</sub> (Mg) catalyst (bulk, green)	8	7/2/94 0:00:00	MRS	CATALYST
488	cr_al_1	Showa Denko (Cr on Al <sub>2</sub> O <sub>3</sub> ) catalyst (bulk, black)	6	7/2/94 0:00:00	MRS	CATALYST
489	cu_ni_1e	CuNi 10:90 1min 2KV etch scraped old-ground surfac	3	5/2/94 0:00:00	MRS	CATALYST
490	cu_ni_1s	CuNi 10:90 scraped old-ground surface 90 TOA	9	5/2/94 0:00:00	MRS	CATALYST
491	cu_ni_2e	CuNi 20:80 1min 2KV etch scraped old-ground surfac	3	5/3/94 0:00:00	MRS	CATALYST
492	cu_ni_2s	CuNi 20:80 scraped old-ground surface 90 TOA	9	5/3/94 0:00:00	MRS	CATALYST

Serial	File Name	Description	No of Spectra	Date	Ident	SubDir.
493	cu_ni_3e	CuNi 30:70 1min 2KV etch scraped old-ground surfac	3	5/3/94 0:00:00	MRS	CATALYST
494	cu_ni_3s	CuNi 30:70 scraped old-ground surface 90 TOA	9	5/3/94 0:00:00	MRS	CATALYST
495	cu_ni_4e	CuNi 40:60 1min 2KV etch scraped old-ground surfac	3	5/3/94 0:00:00	MRS	CATALYST
496	cu_ni_4s	CuNi 40:60 scraped old-ground surface 90 TOA	9	5/3/94 0:00:00	MRS	CATALYST
497	cu_ni_5e	CuNi 50:50 1min 2KV etch scraped old-ground surfac	3	5/3/94 0:00:00	MRS	CATALYST
498	cu_ni_5s	CuNi 50:50 scraped old-ground surface 90 TOA	9	5/4/94 0:00:00	MRS	CATALYST
499	cu_ni_6e	CuNi 60:40 1min 2KV etch scraped old-ground surfac	3	5/4/94 0:00:00	MRS	CATALYST
500	cu_ni_6s	CuNi 60:40 scraped old-ground surface 90 TOA	9	5/4/94 0:00:00	MRS	CATALYST
501	cu_ni_7e	CuNi 70:30 1min 2KV etch scraped old-ground surfac	3	5/4/94 0:00:00	MRS	CATALYST
502	cu_ni_7s	CuNi 70:30 scraped old-ground surface 90 TOA	9	5/4/94 0:00:00	MRS	CATALYST
503	cu_ni_8e	CuNi 80:20 1min 2KV etch scraped old-ground surfac	3	5/4/94 0:00:00	MRS	CATALYST
504	cu_ni_8s	CuNi 80:20 scraped old-ground surface 90 TOA	9	5/4/94 0:00:00	MRS	CATALYST
505	monel_1	Monel (CuNi) scraped old-ground surface 90 TOA	9	5/18/94 0:00:00	MRS	CATALYST
506	monel_2	Monel (CuNi)scraped & etched 1min 3KV 90 TOA	7	5/18/94 0:00:00	MRS	CATALYST
507	mo_ni_fr	Fresh Catalyst: Mo:Ni on Al2O3 (green) (SSI mesh at <1 mm hgt)	10	6/24/94 0:00:00	MRS	CATALYST
508	mo_ni_sp	Used Catalyst: Mo:Ni on Al2O3 (black) (SSI mesh at <1mm hgt)	11	6/24/94 0:00:00	MRS	CATALYST
509	niw_alum	NiW on Al2O3 (1.5x4 mm) (single pellet, MESH)	20	2/10/88 0:00:00	MRS	CATALYST
510	pd_ce_zr	0.98 wt% Pd / CeO2-ZrO2 (pellet, 90 TOA, Screen)	7	1/24/92 0:00:00	MRS	CATALYST
511	v_cat_1	0.5 wt% V2O5 cat.(WO3,TiO2,SiO2,Al2O3) before HNO3	11	4/19/94 0:00:00	MRS	CATALYST
512	v_cat_1a	0.5 wt% V2O5 cat.(WO3,TiO2,SiO2,Al2O3) before HNO3	1	4/19/94 0:00:00	MRS	CATALYST
513	v_cat_1b	0.5% V2O5 wt% Cat (freshly exposed bulk) no HNO3	1	4/19/94 0:00:00	MRS	CATALYST
514	filament	BLACK COATING ON GLASS BEAD (LH ION GUN FILAMENT, WHICH HAS A WELDING FAILURE)	1	10/19/87 0:00:00	MRS	CATHODE
515	filamnt2	BRIGHT SURFACE ON INSIDE SURFACE OF CATHODE FILAMENT	1	10/19/87 0:00:00	MRS	CATHODE
516	filamnt3	Outside Surface Of Ion Gun Cathode (Filament) (Not Exposed To Sputtering From Anode Cage ?)	1	10/20/87 0:00:00	MRS	CATHODE
517	filamnt4	INSIDE SURFACE OF METAL SUPPORT (EXPOSED TO SPUTTERING ?)	1	10/20/87 0:00:00	MRS	CATHODE
518	cdo_1	CdO (pellet pwdr M&P) Aldr #01318EV 35 TOA screen	4	6/11/91 0:00:00	MRS	CDOX_RES
519	cdo_1a	CdO (pellet after removing 80% of HC contam.)	3	6/12/91 0:00:00	MRS	CDOX_RES
520	cdo_1b	CdO (pellet, scrn, 30 sec 3KV, 10mA ion etch)	3	6/12/91 0:00:00	MRS	CDOX_RES
521	cdo_inp	CdO/InP (As received) 35 TOA	5	2/6/92 0:00:00	MRS	CDOX_RES
522	cd_co2_a	Etched Cd left in prep chamber at 10(-7) torr 60 h	6	3/1/93 0:00:00	MRS	CDOX_RES
523	cd_h2o2	Fresh Cd Surface exposed to H2O2 for 4 hours	4	6/14/91 0:00:00	MRS	CDOX_RES
524	cd_nh4oh	Fresh Cd Surface exposed to conc NH4OH 5 hours	4	6/14/91 0:00:00	MRS	CDOX_RES
525	cd_reoxd	Reoxidation Study of Cd (in UHV) after cleaning	3	2/26/93 0:00:00	DPR	CDOX_RES
526	cd_se_1	CdSe powder (as received) screen 35 TOA	5	3/13/93 0:00:00	MRS	CDOX_RES
527	cdse_01	CdSe/DST (as received, 35 TOA, mesh)	5	3/13/93 0:00:00	MRS	CHALCOGN
528	cdse_1	CdSe As rec'd	8	7/26/94 0:00:00	MRS	CHALCOGN
529	cdse_2_e	CdSe ion etched 3 KV 1 min 90 TOA	8	7/28/94 0:00:00	MRS	CHALCOGN
530	cdte_1	CdTe as rec'd Aldrich	11	7/28/94 0:00:00	MRS	CHALCOGN
531	cdte_2_e	CdTe Aldrich after 30sec 3KV ion etch TeOx gone after 10 sec	8	7/28/94 0:00:00	MRS	CHALCOGN
532	gese2_01	GeSe2/DST (as received, mesh, 35 TOA)	5	3/13/93 0:00:00	MRS	CHALCOGN
533	gese_01	GeSe/dst (as received, MESH, 35 toa)	5	3/13/93 0:00:00	MRS	CHALCOGN

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
534	hgcdte_1	HgCdTe film (gift) as rec'd 90 TOA	6	5/17/94 0:00:00	MRS	CHALCOGN
535	sbte_1	sbte	10	7/21/94 0:00:00	MRS	CHALCOGN
536	sbte_2	SbTe freshly peeled	10	7/26/94 0:00:00	MRS	CHALCOGN
537	se_1	SELENIUM (Se) PELLETT (SCRAPED, 90 TOA, ION ETCH: 10 mA, 4 KeV, 20 SEC)	3	12/13/86 0:00:00	MRS	CHALCOGN
538	se_1a	SELENIUM (Se) PELLETT (SCRAPED, 90 TOA, ION ETCH: 10 mA, 4 KeV, 20 SEC)	3	12/13/86 0:00:00	MRS	CHALCOGN
539	se_1b	SELENIUM (Se) PELLETT (SCRAPED, 90 TOA, ION ETCH: 10 mA, 4 KeV, 20 SEC)	6	12/13/86 0:00:00	MRS	CHALCOGN
540	te_1	TELLURIUM (Te) LUMP (EXPOSED BULK 90 TOA, ETCHED 3 MIN AT 5 KeV 10 mA)	10	4/20/87 0:00:00	MRS	CHALCOGN
541	znse_1	ZnSe xtal (fresh exposed bulk) scrn 90 TOA	10	5/31/94 0:00:00	MRS	CHALCOGN
542	al2o3xtl	Charge Test of Al2O3 "xtal" no mesh,at edge,90% curr,etched clean	3	3/24/93 0:00:00	DPR	CHRG_ALO
543	al_tef_1	Al Kitchen Foil (shiny side)/DST/Teflon/DST/Mnt 35 TOA no mesh	5	1/28/93 0:00:00	MRS	CHRG_ALO
544	al_tef_2	Al Kitchen Foil (shiny side)/DST/Teflon/DST/Mnt 35 TOA no mesh	5	1/28/93 0:00:00	MRS	CHRG_ALO
545	bulk_1wk	"Alfa" m6N Al pllt lot# 051283 bulk exposed & left in analysis chamber 1 week	4	2/4/93 0:00:00	MRS	CHRG_ALO
546	bulk_fg1	"Alfa" m6N Al plt lot#051283 90TOA, fresh exposed bulk, Flood Gun (FG) at 5 eV	5	1/28/93 0:00:00	MRS	CHRG_ALO
547	bulk_fg2	"Alfa" m6N Al plt lot#051283 90 TOA, fresh exposed bulk, FG at 15 eV	4	1/29/93 0:00:00	MRS	CHRG_ALO
548	bulk_fg3	"Alfa" m6N Al plt lot#051283 90TOA, fresh exposed bulk, FG at 15 eV, max curr	4	1/29/93 0:00:00	MRS	CHRG_ALO
549	bulk_fg4	"Alfa" m6N plt lot#051283 90TOA, fresh exposed bulk, FG at 2eV, 95% max current	4	1/29/93 0:00:00	MRS	CHRG_ALO
550	bulk_fg5	"Alfa" m6N plt lot#051283 90TOA, fresh exposed bulk, Min FG eV, Min Current	4	1/29/93 0:00:00	MRS	CHRG_ALO
551	bulk_fg6	"Alfa" m6N plt lot#051283 90TOA, fresh exposed bulk, FG at 15eV, min Current	4	1/29/93 0:00:00	MRS	CHRG_ALO
552	bulk_fg7	"Alfa" m6N Al plt lot#051283 90TOA, fresh exposed bulk, Flood Gun Turned OFF	4	1/29/93 0:00:00	MRS	CHRG_ALO
553	bulk_new	"Alfa" m6N Al pllt lot# 051283 90 TOA, freshly exposed bulk	5	1/28/93 0:00:00	MRS	CHRG_ALO
554	etched_1	Mitsubishi Kitchen Al foil just after etching	1	10/15/91 0:00:00	MRS	CHRG_ALO
555	fldgun10	Flood Gun Test on same Mitsub. Foil (FG ON again at 15 eV, 95% max current)	4	1/29/93 0:00:00	MRS	CHRG_ALO
556	fldgun11	Flood Gun Test on Mitsu foil. FG runed Off. Waited 10 min for chargeup	4	1/29/93 0:00:00	MRS	CHRG_ALO
557	fldgun12	Foil from Flood Gun Tests.Ion etched.2 Wks in UHV.	4	2/15/93 0:00:00	MRS	CHRG_ALO
558	fldgun13	Same Mitsub. Al foil after etching and being in UHV many days and exposed to air 1 hr	4	2/15/93 0:00:00	MRS	CHRG_ALO
559	fldgun14	Same Al foil Etched, in UHV many days, exposed air 1 hr	4	2/15/93 0:00:00	MRS	CHRG_ALO
560	fldgun15	Same Al Foil Etched, in UHV many days, exposed air 1 hr	1	2/15/93 0:00:00	MRS	CHRG_ALO
561	fldgun_1	Flood Gun Test on Mitsubishi Al Foil ( FG=OFF (in vac >15H) )	4	1/29/93 0:00:00	MRS	CHRG_ALO
562	fldgun_2	Flood Gun Test on Same Mitsubishi Foil (FG at min Volt & min Current)	4	1/29/93 0:00:00	MRS	CHRG_ALO
563	fldgun_3	Flood Gun Test on same Mitsub. Foil (FG turned OFF, Original Charge-up Returns?)	1	1/29/93 0:00:00	MRS	CHRG_ALO
564	fldgun_4	Flood Gun Test on same Mitsub. Foil (FG at 5 eV, & Minimum Current)	1	1/29/93 0:00:00	MRS	CHRG_ALO
565	fldgun_5	Same Mitsubishi Al Foil (FG at 5 eV & Min Current)	4	1/29/93 0:00:00	MRS	CHRG_ALO
566	fldgun_6	Flood Gun Test on same Mitsub.foil (FG turned OFF:Waited 10min for charge to return)	4	1/29/93 0:00:00	MRS	CHRG_ALO
567	fldgun_7	Flood Gun Test on same Mitsub. foil (FG turned back ON at FG at 15 eV, min current)	4	1/29/93 0:00:00	MRS	CHRG_ALO
568	fldgun_8	Flood Gun Test on Same Mitsub Foil: (FG turned OFF:Waited 10 min for charge again)	4	1/29/93 0:00:00	MRS	CHRG_ALO
569	fldgun_9	Flood Gun Test on Same Mitsub. Al Foil: (Waited 10 min for charge to return) cont.	1	1/29/93 0:00:00	MRS	CHRG_ALO
570	heated_1	High Purity Aluminum Drop, Bulk Exposed 3 years Ago (Heated in air,100C,1 Hr) Heated in Air on Hotplate to >100 C for 1 Hr (90 deg TOA)	3	10/17/91 0:00:00	MRS	CHRG_ALO
571	heated_2	High Purity Aluminum Drop, Freshly Exposed Today (Heated in air,100C,1 Hr) Heated in Air on Hotplate to >100 C for 1 Hr (90 deg TOA)	3	10/17/91 0:00:00	MRS	CHRG_ALO
572	heated_3	High Purity Aluminum Drop, Freshly Exposed Today (Heated in air,100C,3Hr) Heated in Air on Hotplate to >100 C for 3 Hr (90 deg TOA)	3	10/18/91 0:00:00	MRS	CHRG_ALO
573	heated_4	High Purity Aluminum Drop, Bulk Exposed 3 years Ago (Heated in air,100C,2 Hr) Heated in Air on Hotplate to >100 C for 2 Hr (90 deg TOA)	3	10/18/91 0:00:00	MRS	CHRG_ALO
574	mesh_1	NTV AIO 35 (SSI charge control mesh at 1.2 mm, FG OFF, grounded)	4	3/9/93 0:00:00	MRS	CHRG_ALO



Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
575	mesh_2	NTV AIO 35 (SSI charge control mesh at 1.2 mm, FG at min,Curr at min., grounded)	3	3/9/93 0:00:00	MRS	CHRG_ALO
576	mesh_3	NTV AIO 35 (SSI charge control mesh at 1.2 mm, FG=15eV, Curr. 90% max., grounded)	3	3/9/93 0:00:00	MRS	CHRG_ALO
577	mesh_4	NTV AIO 90 TOA (SSI charge control mesh at 1.2 mm, FG=15eV,Curr at 90% max grounded)	3	3/9/93 0:00:00	MRS	CHRG_ALO
578	mesh_5	Same conditions as in Mesh_4, but FG turned OFF 10 min ago.	3	3/9/93 0:00:00	MRS	CHRG_ALO
579	sheet_1a	2x4 cm Al sheeting (Tokyu H) Months in air, 35 TOA	4	2/19/93 0:00:00	MRS	CHRG_ALO
580	sheet_1b	2x4 cm Al sheeting (Tokyu H) Months in air, 35 TOA	2	2/19/93 0:00:00	MRS	CHRG_ALO
581	sheet_1c	2x4 cm Al sheeting (Tokyu H) Months in air, 35 TOA	3	2/19/93 0:00:00	MRS	CHRG_ALO
582	sheet_2	2x4 cm Al sheeting (Tokyu H) months in are, FG turned OFF 2 minutes ago	3	2/19/93 0:00:00	MRS	CHRG_ALO
583	tape	Scotch brand "3M" Aluminum Adhesive Tape/Teflon (Cat# NA-50) 6 mo old	5	1/28/93 0:00:00	MRS	CHRG_ALO
584	al2o3xtl	Charge Test of Al2O3 "xtal" no mesh,at edge,90% curr,etched clean	3	3/24/93 0:00:00	DPR	CHRG_C
585	al_tef_1	Al Kitchen Foil (shiny side)/DST/Teflon/DST/Mnt 35 TOA no mesh	5	1/28/93 0:00:00	MRS	CHRG_C
586	al_tef_2	Al Kitchen Foil (shiny side)/DST/Teflon/DST/Mnt 35 TOA no mesh	5	1/28/93 0:00:00	MRS	CHRG_C
587	bulk_1wk	"Alfa" m6N Al pllt lot# 051283 bulk exposed & left in analysis chamber 1 week	4	2/4/93 0:00:00	MRS	CHRG_C
588	bulk_fg1	"Alfa" m6N Al plt lot#051283 90TOA, fresh exposed bulk, Flood Gun (FG) at 5 eV	5	1/28/93 0:00:00	MRS	CHRG_C
589	bulk_fg2	"Alfa" m6N Al plt lot#051283 90 TOA, fresh exposed bulk, FG at 15 eV	4	1/29/93 0:00:00	MRS	CHRG_C
590	bulk_fg3	"Alfa" m6N Al plt lot#051283 90TOA, fresh exposed bulk, FG at 15 eV, max curr	4	1/29/93 0:00:00	MRS	CHRG_C
591	bulk_fg4	"Alfa" m6N plt lot#051283 90TOA, fresh exposed bulk, FG at 2eV, 95% max current	4	1/29/93 0:00:00	MRS	CHRG_C
592	bulk_fg5	"Alfa" m6N plt lot#051283 90TOA, fresh exposed bulk, Min FG eV, Min Current	4	1/29/93 0:00:00	MRS	CHRG_C
593	bulk_fg6	"Alfa" m6N plt lot#051283 90TOA, fresh exposed bulk, FG at 15eV, min Current	4	1/29/93 0:00:00	MRS	CHRG_C
594	bulk_fg7	"Alfa" m6N Al plt lot#051283 90TOA, fresh exposed bulk, Flood Gun Turned OFF	4	1/29/93 0:00:00	MRS	CHRG_C
595	bulk_new	"Alfa" m6N Al pllt lot# 051283 90 TOA, freshly exposed bulk	5	1/28/93 0:00:00	MRS	CHRG_C
596	etched_1	Mitsubishi Kitchen Al foil just after etching	1	10/15/91 0:00:00	MRS	CHRG_C
597	fldgun10	Flood Gun Test on same Mitsub. Foil (FG ON again at 15 eV, 95% max current)	4	1/29/93 0:00:00	MRS	CHRG_C
598	fldgun11	Flood Gun Test on Mitsu foil. FG runed Off. Waited 10 min for chargeup	4	1/29/93 0:00:00	MRS	CHRG_C
599	fldgun12	Foil from Flood Gun Tests.Ion etched.2 Wks in UHV.	4	2/15/93 0:00:00	MRS	CHRG_C
600	fldgun13	Same Mitsub. Al foil after etching and being in UHV many days and exposed to air 1 hr	4	2/15/93 0:00:00	MRS	CHRG_C
601	fldgun14	Same Al foil Etched, in UHV many days, exposed air 1 hr	4	2/15/93 0:00:00	MRS	CHRG_C
602	fldgun15	Same Al Foil Etched, in UHV many days, exposed air 1 hr	1	2/15/93 0:00:00	MRS	CHRG_C
603	fldgun_1	Flood Gun Test on Mitsubishi Al Foil ( FG=OFF (in vac >15H) )	4	1/29/93 0:00:00	MRS	CHRG_C
604	fldgun_2	Flood Gun Test on Same Mitsubishi Foil (FG at min Volt & min Current)	4	1/29/93 0:00:00	MRS	CHRG_C
605	fldgun_3	Flood Gun Test on same Mitsub. Foil (FG turned OFF, Original Charge-up Returns?)	1	1/29/93 0:00:00	MRS	CHRG_C
606	fldgun_4	Flood Gun Test on same Mitsub. Foil (FG at 5 eV, & Minimum Current)	1	1/29/93 0:00:00	MRS	CHRG_C
607	fldgun_5	Same Mitsubishi Al Foil (FG at 5 eV & Min Current)	4	1/29/93 0:00:00	MRS	CHRG_C
608	fldgun_6	Flood Gun Test on same Mitsub.foil (FG turned OFF:Waited 10min for charge to return)	4	1/29/93 0:00:00	MRS	CHRG_C
609	fldgun_7	Flood Gun Test on same Mitsub. foil (FG turned back ON at FG at 15 eV, min current)	4	1/29/93 0:00:00	MRS	CHRG_C
610	fldgun_8	Flood Gun Test on Same Mitsub Foil: (FG turned OFF:Waited 10 min for charge again)	4	1/29/93 0:00:00	MRS	CHRG_C
611	fldgun_9	Flood Gun Test on Same Mitsub. Al Foil: (Waited 10 min for charge to return) cont.	1	1/29/93 0:00:00	MRS	CHRG_C
612	heated_1	High Purity Aluminum Drop, Bulk Exposed 3 years Ago (Heated in air,100C,1 Hr) Heated in Air on Hotplate to >100 C for 1 Hr (90 deg TOA)	3	10/17/91 0:00:00	MRS	CHRG_C
613	heated_2	High Purity Aluminum Drop, Freshly Exposed Today (Heated in air,100C,1 Hr) Heated in Air on Hotplate to >100 C for 1 Hr (90 deg TOA)	3	10/17/91 0:00:00	MRS	CHRG_C
614	heated_3	High Purity Aluminum Drop, Freshly Exposed Today (Heated in air,100C,3Hr) Heated in Air on Hotplate to >100 C for 3 Hr (90 deg TOA)	3	10/18/91 0:00:00	MRS	CHRG_C
615	heated_4	High Purity Aluminum Drop, Bulk Exposed 3 years Ago (Heated in air,100C,2 Hr) Heated in Air on Hotplate to >100 C for 2 Hr (90 deg TOA)	3	10/18/91 0:00:00	MRS	CHRG_C

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
616	mesh_1	NTV AIO 35 (SSI charge control mesh at 1.2 mm, FG OFF, grounded)	4	3/9/93 0:00:00	MRS	CHRG_C
617	mesh_2	NTV AIO 35 (SSI charge control mesh at 1.2 mm, FG at min,Curr at min., grounded)	3	3/9/93 0:00:00	MRS	CHRG_C
618	mesh_3	NTV AIO 35 (SSI charge control mesh at 1.2 mm, FG=15eV, Curr. 90% max., grounded)	3	3/9/93 0:00:00	MRS	CHRG_C
619	mesh_4	NTV AIO 90 TOA (SSI charge control mesh at 1.2 mm, FG=15eV,Curr at 90% max grounded)	3	3/9/93 0:00:00	MRS	CHRG_C
620	mesh_5	Same conditions as in Mesh_4, but FG turned OFF 10 min ago.	3	3/9/93 0:00:00	MRS	CHRG_C
621	mg_rtn_2	NTV MgO recheck (after Mg_rturn file, ion gun off)	1	2/24/93 0:00:00	MRS	CHRG_C
622	mg_rturn	NTV MgO (15 min after 15 eV FG turned off)	3	2/24/93 0:00:00	MRS	CHRG_C
623	sheet_1a	2x4 cm Al sheeting (Tokyu H) Months in air, 35 TOA	4	2/19/93 0:00:00	MRS	CHRG_C
624	sheet_1b	2x4 cm Al sheeting (Tokyu H) Months in air, 35 TOA	2	2/19/93 0:00:00	MRS	CHRG_C
625	sheet_1c	2x4 cm Al sheeting (Tokyu H) Months in air, 35 TOA	3	2/19/93 0:00:00	MRS	CHRG_C
626	sheet_2	2x4 cm Al sheeting (Tokyu H) months in are, FG turned OFF 2 minutes ago	3	2/19/93 0:00:00	MRS	CHRG_C
627	si_rturn	NTV SiO (1 min after 15 eV FG turned off)	3	3/15/93 0:00:00	MRS	CHRG_C
628	tape	Scotch brand "3M" Aluminum Adhesive Tape/Teflon (Cat# NA-50) 6 mo old	5	1/28/93 0:00:00	MRS	CHRG_C
629	tl_rturn	NTV TIO (FO) (5 min after 15 eV FG turned off)	3	3/12/93 0:00:00	MRS	CHRG_C
630	y_rturn	NTV (FO) YO (1 min after 15 eV FG turned off)	3	3/18/93 0:00:00	MRS	CHRG_C
631	zn_fg_01	NTV ZnO/Zn (old) 80 TOA (FG min curr, min volt)	4	2/19/93 0:00:00	MRS	CHRG_C
632	zn_fg_02	NTV ZnO/Zn (old) 80 TOA (FG max curr, 15 volt)	4	2/19/93 0:00:00	MRS	CHRG_C
633	zn_fg_03	NTV ZnO/Zn (#2, old, 60 TOA) no FG	4	2/19/93 0:00:00	MRS	CHRG_C
634	zn_fg_04	NTV ZnO/Zn (#2, old, 60 TOA) no FG	3	2/19/93 0:00:00	MRS	CHRG_C
635	zn_fg_05	NTV ZnO/Zn (#2, old, 60 TOA) FG min curr, min volt	3	2/19/93 0:00:00	MRS	CHRG_C
636	zn_fg_06	NTV ZnO/Zn (old, 60 TOA) grnd FG max curr, 15 eV	3	2/19/93 0:00:00	MRS	CHRG_C
637	zn_fg_07	NTV ZnO/Zn (old, 60 TOA) grnd FG turned OFF	3	2/19/93 0:00:00	MRS	CHRG_C
638	zn_fg_08	NTV ZnO/Zn (old, 60 TOA) grnd FG turned OFF	2	2/19/93 0:00:00	MRS	CHRG_C
639	zr_fg_01	NTV ZrO 35 TOA grounded, FG: min volt,min curr	3	3/5/93 0:00:00	MRS	CHRG_C
640	zr_fg_02	NTV ZrO 35 TOA grounded, FG: 15 eV, 90% curr	3	3/5/93 0:00:00	MRS	CHRG_C
641	zr_fg_03	rerun NTV ZrO 35 TOA grnd, FG: min volt,min curr	3	3/5/93 0:00:00	MRS	CHRG_C
642	zr_fg_04	NTV ZrO 35 TOA grounded, FG: 5 eV, 90% curr	3	3/5/93 0:00:00	MRS	CHRG_C
643	zr_fg_05	NTV ZrO 35 TOA grounded, FG: 10 eV, 90% curr	3	3/5/93 0:00:00	MRS	CHRG_C
644	zr_fg_06	rerun NTV ZrO 35 TOA grnd, FG: 15 eV, 90% curr	3	3/5/93 0:00:00	MRS	CHRG_C
645	zr_fg_07	NTV ZrO 35 TOA grounded, FG: 15 eV, min curr	3	3/5/93 0:00:00	MRS	CHRG_C
646	zr_fg_08	NTV ZrO 35 TOA (as,rec'd, grounded, no FG)	1	3/5/93 0:00:00	MRS	CHRG_C
647	zr_rturn	rerun NTV ZrO 35 TOA grnd, FG OFF (5 min wait)	3	3/5/93 0:00:00	MRS	CHRG_C
648	al2o3_01	Al2O3 "xtal" no mesh,at edge,90% curr,etched clean	3	3/24/93 0:00:00	DPR	CHRG_GRZ
649	al2o3_02	Al2O3 "xtal" no mesh, at edge, 90% curr, as rec'd	4	3/23/93 0:00:00	MRS	CHRG_GRZ
650	al2o3_03	Al2O3"xtal"no mesh,on side(old),90%I,1mm Teflon	5	3/29/93 0:00:00	MRS	CHRG_GRZ
651	al2o3_04	35TOA,Al2O3"xtal"no mesh,flat top,90%I,1mm Teflon	4	3/29/93 0:00:00	MRS	CHRG_GRZ
652	al2o3_05	90TOA,Al2O3"xtal"no mesh,edge/side,90%I,1mm Teflon	3	3/29/93 0:00:00	MRS	CHRG_GRZ
653	mgo_01	MgO "xtal" no mesh, at edge, 90% curr, as rec'd	4	3/24/93 0:00:00	MRS	CHRG_GRZ
654	mgo_02	MgO (xtal) no mesh,at edge,90% curr,etched clean	3	3/25/93 0:00:00	DPR	CHRG_GRZ
655	mgo_03	MgO "xtal" no mesh, 90% curr, diam.scribe, 2h air	4	3/25/93 0:00:00	MRS	CHRG_GRZ
656	mgo_04	MgO "xtal" mesh, 90% curr, diam.scribed, 2h air	5	3/25/93 0:00:00	MRS	CHRG_GRZ

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
657	mgo_05	MgO "xtal" mesh, 90% curr, near center, as rec'd	5	3/25/93 0:00:00	MRS	CHRG_GRZ
658	mgo_06	MgO "xtal" SSI mesh, at edge, 90% curr, as rec'd	3	3/26/93 0:00:00	MRS	CHRG_GRZ
659	mgo_07	MgO "xtal", SSI mesh, edge, 90% curr, as rec'd, Ar 1E-7	3	3/26/93 0:00:00	MRS	CHRG_GRZ
660	mgo_08	MgO xtal mesh edge 100% curr 1.5E-7 Ar as rec'd	1	3/26/93 0:00:00	MRS	CHRG_GRZ
661	mgo_c_01	EDGE of Cleaved MgO xtl (no mesh) on top of 1mm Teflon, FG 90% max curr 55TOA	5	3/26/93 0:00:00	MRS	CHRG_GRZ
662	mgo_c_02	SIDE of Cleaved MgO xtl (no mesh) on top of 1mm Teflon, FG at 90% curr.90 TOA	3	3/26/93 0:00:00	MRS	CHRG_GRZ
663	mgo_c_03	SIDE at -48 TOA Cleaved MgO xtl (no mesh) on top of 1mm Teflon, 90% max FG curr	3	3/26/93 0:00:00	MRS	CHRG_GRZ
664	mgo_c_04	SIDE at +48 TOA Cleaved MgO xtl (no mesh) 1mm Teflon, FG at 90% max curr	3	3/26/93 0:00:00	MRS	CHRG_GRZ
665	mgo_c_05	CORNER +100 TOA Cleaved MgO xtl (no mesh) on top of 1mm Teflon, 90% max FG curr	3	3/26/93 0:00:00	MRS	CHRG_GRZ
666	mgo_c_06	AS REC'D region 100TOA Cleaved MgO xtl (no mesh) on top of 1mm Tfln 90% max FG curr	3	3/26/93 0:00:00	MRS	CHRG_GRZ
667	nacl_01	Expsd Bulk (IR) NaCl xtal (Side-Graze AOI, 55 TOA)	17	4/13/93 0:00:00	MRS	CHRG_GRZ
668	sio2_01	-55 TOA SiO2 fract fused "xtal" no mesh 90% curr	5	3/26/93 0:00:00	MRS	CHRG_GRZ
669	sio2_02	+35 TOA SiO2 unpolished fused "xtal" no mesh 90% I	5	3/29/93 0:00:00	MRS	CHRG_GRZ
670	sio2_03	-55 TOA SiO2 unplshd side fused "xtal" no mesh 90%	5	3/29/93 0:00:00	MRS	CHRG_GRZ
671	sio2_04	-23 TOA SiO2 1mm Tfln fract side "xtal" no mesh 90%	4	3/29/93 0:00:00	MRS	CHRG_GRZ
672	sio2_05	-90 TOA SiO2 1mm Tfln fract side "xtal" no mesh 90%	3	3/29/93 0:00:00	MRS	CHRG_GRZ
673	ta2o5_01	5-20u Ta2O5 Powder/DST 35 TOA 35 AOI FG at 95% max curr, parallel	2	4/13/93 0:00:00	MRS	CHRG_GRZ
674	ta2o5_02	5-20u Ta2O5 Powder/DST 90 TOA 25 AOI FG at 95% max curr., parallel	2	4/13/93 0:00:00	MRS	CHRG_GRZ
675	ta2o5_03	5-20u Ta2O5 Powder/DST 100 TOA 25 AOI FG at 95% max curr. parallel	2	4/13/93 0:00:00	MRS	CHRG_GRZ
676	ta2o5_04	5-20u Ta2O5 Powder/DST 110 TOA 25 AOI FG at 95% max curr., parallel	2	4/13/93 0:00:00	MRS	CHRG_GRZ
677	ta2o5_05	5-20u Ta2O5 Powder/DST 120 TOA 25 AOI FG at 95% max curr., parallel	2	4/13/93 0:00:00	MRS	CHRG_GRZ
678	al2o3_01	Al2O3 "xtal" no mesh, at edge, 90% curr, etched clean	3	3/24/93 0:00:00	DPR	CHRG_RES
679	al2o3_02	Al2O3 "xtal" no mesh, at edge, 90% curr, as rec'd	4	3/23/93 0:00:00	MRS	CHRG_RES
680	al2o3_03	Al2O3 "xtal" no mesh, on side (old), 90% I, 1mm Teflon	5	3/29/93 0:00:00	MRS	CHRG_RES
681	al2o3_04	35TOA, Al2O3 "xtal" no mesh, flat top, 90% I, 1mm Teflon	4	3/29/93 0:00:00	MRS	CHRG_RES
682	al2o3_05	90TOA, Al2O3 "xtal" no mesh, edge/side, 90% I, 1mm Teflon	3	3/29/93 0:00:00	MRS	CHRG_RES
683	al_tef_1	Al Kitchen Foil (shiny side)/DST/Teflon/DST/Mnt 35 TOA no mesh	5	1/28/93 0:00:00	MRS	CHRG_RES
684	al_tef_2	Al Kitchen Foil (shiny side)/DST/Teflon/DST/Mnt 35 TOA no mesh	5	1/28/93 0:00:00	MRS	CHRG_RES
685	au_pet_1	FG=0V "Charge Control" study of Au/PET, ion etched, 35 deg toa	1	6/5/91 0:00:00	MRS	CHRG_RES
686	au_pet_2	FG=0V "Charge Control" study of Au/PET, ion etched, 35 deg toa	1	6/5/91 0:00:00	MRS	CHRG_RES
687	au_si_1	FG=0V "Charge Control" study of ion etched Au/Si wafer, 35 deg toa	1	6/5/91 0:00:00	MRS	CHRG_RES
688	au_tef_1	FG=10V "Charge Control" study of gold/1mm teflon, ion etched, 35 toa	1	6/4/91 0:00:00	MRS	CHRG_RES
689	au_tef_2	FG=0 "Charge Control" study of gold/1mm teflon, ion etched, 35 toa	1	6/4/91 0:00:00	MRS	CHRG_RES
690	au_tef_3	FG=0V "Charge Control" study of gold/1mm teflon, dirty, 35 toa	1	6/5/91 0:00:00	MRS	CHRG_RES
691	au_tef_4	gold/1mm teflon/dst, no scrn, FG swtch OFF, S/W FG=0	4	6/4/91 0:00:00	MRS	CHRG_RES
692	au_tef_5	FG OFF, screen/gold/1mm Teflon/DST (ion etched)	4	6/5/91 0:00:00	MRS	CHRG_RES
693	bulk_1wk	"Alfa" m6N Al pllt lot# 051283 bulk exposed & left in analysis chamber 1 week	4	2/4/93 0:00:00	MRS	CHRG_RES
694	bulk_fg1	"Alfa" m6N Al plt lot#051283 90TOA, fresh exposed bulk, Flood Gun (FG) at 5 eV	5	1/28/93 0:00:00	MRS	CHRG_RES
695	bulk_fg2	"Alfa" m6N Al plt lot#051283 90 TOA, fresh exposed bulk, FG at 15 eV	4	1/29/93 0:00:00	MRS	CHRG_RES
696	bulk_fg3	"Alfa" m6N Al plt lot#051283 90TOA, fresh exposed bulk, FG at 15 eV, max curr	4	1/29/93 0:00:00	MRS	CHRG_RES
697	bulk_fg4	"Alfa" m6N plt lot#051283 90TOA, fresh exposed bulk, FG at 2eV, 95% max current	4	1/29/93 0:00:00	MRS	CHRG_RES

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
698	bulk_fg5	"Alfa" m6N plt lot#051283 90TOA, fresh exposed bulk, Min FG eV, Min Current	4	1/29/93 0:00:00	MRS	CHRG_RES
699	bulk_fg6	"Alfa" m6N plt lot#051283 90TOA, fresh exposed bulk, FG at 15eV, min Current	4	1/29/93 0:00:00	MRS	CHRG_RES
700	bulk_fg7	"Alfa" m6N Al plt lot#051283 90TOA, fresh exposed bulk, Flood Gun Turned OFF	4	1/29/93 0:00:00	MRS	CHRG_RES
701	bulk_new	"Alfa" m6N Al pllt lot# 051283 90 TOA, freshly exposed bulk	5	1/28/93 0:00:00	MRS	CHRG_RES
702	cc_ag2o	Ag2O powder pressed on DST (SSI mesh: 1mm) Flood Gun Off	2	11/3/93 0:00:00	MRS	CHRG_RES
703	cc_bi2o3	Bi2O3 powder pressed on DST (mesh: 1mm) FG ON vs OFF test	2	11/4/93 0:00:00	MRS	CHRG_RES
704	cc_ga2o3	Ga2O3	2	11/4/93 0:00:00	MRS	CHRG_RES
705	cc_geo2	GeO2 powder pressed on DST (mesh: 1mm) FG ON vs OFF study	2	11/4/93 0:00:00	MRS	CHRG_RES
706	cc_moo3	MoO3 powder pressed on DST (mesh: 1mm) FG ON vs OFF study	2	11/2/93 0:00:00	MRS	CHRG_RES
707	cc_nb2o5	Nb2O5 powder pressed on DST (mesh: 1mm) FG ON vs OFF study	2	11/2/93 0:00:00	MRS	CHRG_RES
708	cc_pdo	PdO powder pressed on DST (mesh: 1mm) FG ON vs OFF study	2	11/2/93 0:00:00	MRS	CHRG_RES
709	cc_ta2o5	Ta2O5 powder pressed on DST (mesh: 1mm) FG ON vs OFF study	2	11/3/93 0:00:00	MRS	CHRG_RES
710	cc_tio2	TiO2 powder pressed on DST (mesh: 1mm) FG ON vs OFF study	2	11/1/93 0:00:00	MRS	CHRG_RES
711	cc_v2o5	V2O5 powder pressed on DST (mesh: 1mm) FG ON vs OFF study	2	11/3/93 0:00:00	MRS	CHRG_RES
712	cc_wo3	WO3 powder pressed on DST (mesh: 1mm) FG ON vs OFF study	2	11/2/93 0:00:00	MRS	CHRG_RES
713	cu_tef_1	Copper on 1mm teflon, no scrn, FG swtch OFF, S/W FG=0	5	6/4/91 0:00:00	MRS	CHRG_RES
714	cu_tef_2	new Al X-ray window, cu/1mm teflon, no scrn, FG OFF	3	6/21/91 0:00:00	MRS	CHRG_RES
715	etched_1	Mitsubishi Kitchen Al foil just after etching	1	10/15/91 0:00:00	MRS	CHRG_RES
716	fldgun10	Flood Gun Test on same Mitsub. Foil (FG ON again at 15 eV, 95% max current)	4	1/29/93 0:00:00	MRS	CHRG_RES
717	fldgun11	Flood Gun Test on Mitsu foil. FG runed Off. Waited 10 min for chargeup	4	1/29/93 0:00:00	MRS	CHRG_RES
718	fldgun12	Foil from Flood Gun Tests.Ion etched.2 Wks in UHV.	4	2/15/93 0:00:00	MRS	CHRG_RES
719	fldgun13	Same Mitsub. Al foil after etching and being in UHV many days and exposed to air 1 hr	4	2/15/93 0:00:00	MRS	CHRG_RES
720	fldgun14	Same Al foil Etched, in UHV many days, exposed air 1 hr	4	2/15/93 0:00:00	MRS	CHRG_RES
721	fldgun15	Same Al Foil Etched, in UHV many days, exposed air 1 hr	1	2/15/93 0:00:00	MRS	CHRG_RES
722	fldgun_1	Flood Gun Test on Mitsubishi Al Foil ( FG=OFF (in vac >15H) )	4	1/29/93 0:00:00	MRS	CHRG_RES
723	fldgun_2	Flood Gun Test on Same Mitsubishi Foil (FG at min Volt & min Current)	4	1/29/93 0:00:00	MRS	CHRG_RES
724	fldgun_3	Flood Gun Test on same Mitsub. Foil (FG turned OFF, Original Charge-up Returns?)	1	1/29/93 0:00:00	MRS	CHRG_RES
725	fldgun_4	Flood Gun Test on same Mitsub. Foil (FG at 5 eV, & Minimum Current)	1	1/29/93 0:00:00	MRS	CHRG_RES
726	fldgun_5	Same Mitsubishi Al Foil (FG at 5 eV & Min Current)	4	1/29/93 0:00:00	MRS	CHRG_RES
727	fldgun_6	Flood Gun Test on same Mitsub.foil (FG turned OFF:Waited 10min for charge to return)	4	1/29/93 0:00:00	MRS	CHRG_RES
728	fldgun_7	Flood Gun Test on same Mitsub. foil (FG turned back ON at FG at 15 eV, min current)	4	1/29/93 0:00:00	MRS	CHRG_RES
729	fldgun_8	Flood Gun Test on Same Mitsub Foil: (FG turned OFF:Waited 10 min for charge again)	4	1/29/93 0:00:00	MRS	CHRG_RES
730	fldgun_9	Flood Gun Test on Same Mitsub. Al Foil: (Waited 10 min for charge to return) cont.	1	1/29/93 0:00:00	MRS	CHRG_RES
731	mesh_1	NTV AIO 35 (SSI charge control mesh at 1.2 mm, FG OFF, grounded)	4	3/9/93 0:00:00	MRS	CHRG_RES
732	mesh_2	NTV AIO 35 (SSI charge control mesh at 1.2 mm, FG at min,Curr at min., grounded)	3	3/9/93 0:00:00	MRS	CHRG_RES
733	mesh_3	NTV AIO 35 (SSI charge control mesh at 1.2 mm, FG=15eV, Curr. 90% max., grounded)	3	3/9/93 0:00:00	MRS	CHRG_RES
734	mesh_4	NTV AIO 90 TOA (SSI charge control mesh at 1.2 mm, FG=15eV,Curr at 90% max grounded)	3	3/9/93 0:00:00	MRS	CHRG_RES
735	mesh_5	Same conditions as in Mesh_4, but FG turned OFF 10 min ago.	3	3/9/93 0:00:00	MRS	CHRG_RES
736	mgo_01	MgO "xtal" no mesh, at edge, 90% curr, as rec'd	4	3/24/93 0:00:00	MRS	CHRG_RES
737	mgo_02	MgO (xtal) no mesh,at edge,90% curr,etched clean	3	3/25/93 0:00:00	DPR	CHRG_RES
738	mgo_03	MgO "xtal" no mesh, 90% curr, diam.scribe, 2h air	4	3/25/93 0:00:00	MRS	CHRG_RES

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
739	mgo_04	MgO "xtal" mesh, 90% curr, diam.scribed, 2h air	5	3/25/93 0:00:00	MRS	CHRG_RES
740	mgo_05	MgO "xtal" mesh, 90% curr, near center, as rec'd	5	3/25/93 0:00:00	MRS	CHRG_RES
741	mgo_06	MgO "xtal" SSI mesh, at edge, 90% curr, as rec'd	3	3/26/93 0:00:00	MRS	CHRG_RES
742	mgo_07	MgO "xtal",SSI mesh,edge,90% curr,as rec'd,Ar 1E-7	3	3/26/93 0:00:00	MRS	CHRG_RES
743	mgo_08	MgO xtal mesh edge 100% curr 1.5E-7 Ar as rec'd	1	3/26/93 0:00:00	MRS	CHRG_RES
744	mgo_c_01	EDGE of Cleaved MgO xtl (no mesh) on top of 1mm Teflon, FG 90% max curr 55TOA	5	3/26/93 0:00:00	MRS	CHRG_RES
745	mgo_c_02	SIDE of Cleaved MgO xtl (no mesh) on top of 1mm Teflon, FG at 90% curr.90 TOA	3	3/26/93 0:00:00	MRS	CHRG_RES
746	mgo_c_03	SIDE at -48 TOA Cleaved MgO xtl (no mesh) on top of 1mm Teflon, 90%max FG curr	3	3/26/93 0:00:00	MRS	CHRG_RES
747	mgo_c_04	SIDE at +48 TOA Cleaved MgO xtl (no mesh) 1mm Teflon, FG at 90% max curr	3	3/26/93 0:00:00	MRS	CHRG_RES
748	mgo_c_05	CORNER +100 TOA Cleaved MgO xtl (no mesh) on top of 1mm Teflon, 90% max FG curr	3	3/26/93 0:00:00	MRS	CHRG_RES
749	mgo_c_06	AS REC'D region 100TOA Cleaved MgO xtl (no mesh) on top of 1mm Tfln 90% max FG curr	3	3/26/93 0:00:00	MRS	CHRG_RES
750	mgo_xtl	MgO crystal (unknown source) scrn 90 deg TOA	7	10/28/93 0:00:00	MRS	CHRG_RES
751	mg_rturn	NTV MgO (15 min after 15 eV FG turned off)	3	2/24/93 0:00:00	MRS	CHRG_RES
752	nacl_01	Expsd Bulk (IR) NaCl xtal (Side-Graze AOI, 55 TOA)	17	4/13/93 0:00:00	MRS	CHRG_RES
753	nfg_cr2o	7 mm DIA, 1 mm THK Cr2O3 PLLT UNDER CLIP CLEANED BY LASER, 590 nm, 1 W, APER 12 (NO DST)	4	9/13/89 0:00:00	MRS	CHRG_RES
754	nfg_cuo	7 mm DIAM, 1 mm THICK CuO PELLETT UNDER GOLD CLIP CLEANED BY LASER, LASER OFF	4	9/14/89 0:00:00	MRS	CHRG_RES
755	nfg_paa	POLY-ACRYLIC ACID FILM ON SILICON (NO FLOOD GUN)	1	2/25/87 0:00:00	MRS	CHRG_RES
756	nfg_paa1	X-RAY DAMAGE TO POLY-ACRYLIC ACID (90 DEG TOA,FILM/AI,NO SCRIN,NO FG)	20	2/25/88 0:00:00	MRS	CHRG_RES
757	nfg_paa2	POLY-ACRYLIC ACID FILM ON SILICON (NO FLOOD GUN)	1	2/25/87 0:00:00	MRS	CHRG_RES
758	nfg_pe01	PE (28 MICRONS) MIN FLOOD GUN, DEAD CENTER OF CLIP (3 MM DIA)	1	3/18/87 0:00:00	MRS	CHRG_RES
759	nfg_pe02	PE (28 MICRONS) NO FLOOD GUN (No FG), DEAD CENTER OF CLIP HOLE (3 MM)	1	3/18/87 0:00:00	MRS	CHRG_RES
760	nfg_pe03	PE (28 MICRONS) NO FG, DEAD CENTER OF CLIP HOLE (3 MM DIAM)	1	3/18/87 0:00:00	MRS	CHRG_RES
761	nfg_pe04	PE (28 MICRONS) NO FG, DEAD CENTER OF GOLD CLIP HOLE (3 MM DIAMETER)	1	3/18/87 0:00:00	MRS	CHRG_RES
762	nfg_pe05	PE (28 MICRONS) NO FG, DEAD CENTER OF CLIP HOLE (3 MM DIAMETER)	1	3/18/87 0:00:00	MRS	CHRG_RES
763	nfg_pe06	PE (28 MICRONS), NO FG, 320 MICRONS FROM INNER-EDGE CLIP HOLE (3 MM)	1	3/18/87 0:00:00	MRS	CHRG_RES
764	nfg_pe07	PE (28 MICRONS) NO FG, 320 MICRONS FROM INNER-EDGE OF CLIP HOLE (3 MM)	1	3/18/87 0:00:00	MRS	CHRG_RES
765	nfg_pe08	PE (28 MICRONS), NO FG, 320 MICRONS FROM INNER-EDGE OF CLIP (3 MM)	1	3/18/87 0:00:00	MRS	CHRG_RES
766	nfg_pe09	PE (28 MICRONS) NO FG, 320 MICRONS FROM INNER EDGE OF CLIP HOLE (3 MM)	1	3/18/87 0:00:00	MRS	CHRG_RES
767	nfg_pe10	PE (28 MICRONS) NO FG, 0.0 MICRONS FROM INNER-EDGE OF CLIP-HOLE (3 MM)	1	3/18/87 0:00:00	MRS	CHRG_RES
768	nfg_pe11	PE (28 MICRONS) NO FG, 640 MICRONS FROM THE OUTER-EDGE OF CLIP HOLE	1	3/18/87 0:00:00	MRS	CHRG_RES
769	nfg_pe12	PE (28 MICRONS) NO FG, 320 MICRONS FROM OUTER-EDGE OF CLIP	1	3/18/87 0:00:00	MRS	CHRG_RES
770	nfg_pe13	PE (28 MICRONS), MIN FG, DEAD CENTER OF CLIP HOLE (3 MM DIAMETER)	1	3/18/87 0:00:00	MRS	CHRG_RES
771	nfg_pe14	PE (28 MICRONS) MIN FG, DEAD CENTER OF CLIP HOLE (3 MM DIAMETER)	1	3/18/87 0:00:00	MRS	CHRG_RES
772	nfg_pe15	PE (28 MICRONS) MIN FG, DEAD CENTER OF CLIP HOLE (3 MM DIAMETER)	1	3/18/87 0:00:00	MRS	CHRG_RES
773	nfg_pe16	PE (28 MICRONS) MIN FG, DEAD CENTER OF CLIP HOLE (3 MM DIAMETER)	1	3/18/87 0:00:00	MRS	CHRG_RES
774	nfg_sio2	SiO2 SAMPLE (1MM THICK) NO FLOOD GUN (ANALYZED THROUGH HOLE IN CLIP)	1	3/20/87 0:00:00	MRS	CHRG_RES
775	pet_nfg1	PET FILM (126 MICRON) NO FLOOD GUN, 640uM FROM INNER-EDGE of 2 mm HOLE	2	3/18/87 0:00:00	MRS	CHRG_RES
776	pet_nfg2	PET FILM (126 MICRON), NO FLOOD GUN, 640uM FROM INNER-EDGE OF 2 mm HOLE	2	3/18/87 0:00:00	MRS	CHRG_RES
777	sheet_1a	2x4 cm Al sheeting (Tokyu H) Months in air, 35 TOA	4	2/19/93 0:00:00	MRS	CHRG_RES
778	sheet_1b	2x4 cm Al sheeting (Tokyu H) Months in air, 35 TOA	2	2/19/93 0:00:00	MRS	CHRG_RES
779	sheet_1c	2x4 cm Al sheeting (Tokyu H) Months in air, 35 TOA	3	2/19/93 0:00:00	MRS	CHRG_RES

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
780	sheet_2	2x4 cm Al sheeting (Tokyu H) months in are, FG turned OFF 2 minutes ago	3	2/19/93 0:00:00	MRS	CHRG_RES
781	sio2_01	-55 TOA SiO2 fract fused "xtal" no mesh 90% curr	5	3/26/93 0:00:00	MRS	CHRG_RES
782	sio2_02	+35 TOA SiO2 unpolished fused "xtal" no mesh 90% I	5	3/29/93 0:00:00	MRS	CHRG_RES
783	sio2_03	-55 TOA SiO2 unpls hd side fused "xtal" no mesh 90%	5	3/29/93 0:00:00	MRS	CHRG_RES
784	sio2_04	-23 TOA SiO2 1mm Tfln fract side"xtal" no mesh 90%	4	3/29/93 0:00:00	MRS	CHRG_RES
785	sio2_05	-90 TOA SiO2 1mm Tfln fract side"xtal" no mesh 90%	3	3/29/93 0:00:00	MRS	CHRG_RES
786	sio_tef1	1000A SiO2/Si/1mm Teflon, New Al X-ray Window, FG Swtch ON, no mesh	6	6/20/91 0:00:00	MRS	CHRG_RES
787	sio_tef2	1000A SiO2/Si/1mm Teflon, New Al Window, FG Swtch OFF, no mesh	4	6/20/91 0:00:00	MRS	CHRG_RES
788	si_tef_1	Si/1mm teflon/dst, no scrn, FG Swtch OFF, S/W FG=0	4	6/4/91 0:00:00	MRS	CHRG_RES
789	si_tef_2	FG OFF, Native SiO2/Si/1mm Teflon/DST, mesh, 35 TOA, FG Switch OFF	4	6/5/91 0:00:00	MRS	CHRG_RES
790	si_tef_3	FG OFF, native SiO2/Si/1mm teflon, new Al X-ray window, no mesh	4	6/21/91 0:00:00	MRS	CHRG_RES
791	ta2o5_01	5-20u Ta2O5 Powder/DST 35 TOA 35 AOI FG at 95% max curr, parallel	2	4/13/93 0:00:00	MRS	CHRG_RES
792	ta2o5_02	5-20u Ta2O5 Powder/DST 90 TOA 25 AOI FG at 95% max curr., parallel	2	4/13/93 0:00:00	MRS	CHRG_RES
793	ta2o5_03	5-20u Ta2O5 Powder/DST 100 TOA 25 AOI FG at 95% max curr. parallel	2	4/13/93 0:00:00	MRS	CHRG_RES
794	ta2o5_04	5-20u Ta2O5 Powder/DST 110 TOA 25 AOI FG at 95% max curr., parallel	2	4/13/93 0:00:00	MRS	CHRG_RES
795	ta2o5_05	5-20u Ta2O5 Powder/DST 120 TOA 25 AOI FG at 95% max curr., parallel	2	4/13/93 0:00:00	MRS	CHRG_RES
796	tape	Scotch brand "3M" Aluminum Adhesive Tape/Teflon (Cat# NA-50) 6 mo old	5	1/28/93 0:00:00	MRS	CHRG_RES
797	tef_cc_1	1mm teflon/dst, with scrn, FG swtch ON, FG=2	4	6/4/91 0:00:00	MRS	CHRG_RES
798	tef_cc_2	1mm teflon, scrn, FG Switch "ON", FG=0	4	6/4/91 0:00:00	MRS	CHRG_RES
799	tef_cc_3	1mm Teflon, screen, FG Switch OFF, FG=0	4	6/4/91 0:00:00	MRS	CHRG_RES
800	tef_cc_4	1mm Teflon/DST, no screen, FG switch OFF	6	6/4/91 0:00:00	MRS	CHRG_RES
801	tef_cc_5	1mm Teflon/DST, no scrn, FG switch ON, FG=10	4	6/4/91 0:00:00	MRS	CHRG_RES
802	tef_cc_6	1mm teflon/DST, no scrn, FG SWITCH "ON", FG=0	4	6/4/91 0:00:00	MRS	CHRG_RES
803	tef_cc_7	1mm Teflon/DST, no screen, FG swtch OFF	6	6/4/91 0:00:00	MRS	CHRG_RES
804	zn_fg_01	NTV ZnO/Zn (old) 80 TOA (FG min curr, min volt)	4	2/19/93 0:00:00	MRS	CHRG_RES
805	zn_fg_02	NTV ZnO/Zn (old) 80 TOA (FG max curr, 15 volt)	4	2/19/93 0:00:00	MRS	CHRG_RES
806	zn_fg_03	NTV ZnO/Zn (#2, old, 60 TOA) no FG	4	2/19/93 0:00:00	MRS	CHRG_RES
807	zn_fg_04	NTV ZnO/Zn (#2, old, 60 TOA) no FG	3	2/19/93 0:00:00	MRS	CHRG_RES
808	zn_fg_05	NTV ZnO/Zn (#2, old, 60 TOA) FG min curr, min volt	3	2/19/93 0:00:00	MRS	CHRG_RES
809	zn_fg_06	NTV ZnO/Zn (old, 60 TOA) grnd FG max curr, 15 eV	3	2/19/93 0:00:00	MRS	CHRG_RES
810	zn_fg_07	NTV ZnO/Zn (old, 60 TOA) grnd FG turned OFF	3	2/19/93 0:00:00	MRS	CHRG_RES
811	zn_fg_08	NTV ZnO/Zn (old, 60 TOA) grnd FG turned OFF	2	2/19/93 0:00:00	MRS	CHRG_RES
812	zr_fg_01	NTV ZrO 35 TOA grounded, FG: min volt,min curr	3	3/5/93 0:00:00	MRS	CHRG_RES
813	zr_fg_02	NTV ZrO 35 TOA grounded, FG: 15 eV, 90% curr	3	3/5/93 0:00:00	MRS	CHRG_RES
814	zr_fg_03	rerun NTV ZrO 35 TOA grnd, FG: min volt,min curr	3	3/5/93 0:00:00	MRS	CHRG_RES
815	zr_fg_04	NTV ZrO 35 TOA grounded, FG: 5 eV, 90% curr	3	3/5/93 0:00:00	MRS	CHRG_RES
816	zr_fg_05	NTV ZrO 35 TOA grounded, FG: 10 eV, 90% curr	3	3/5/93 0:00:00	MRS	CHRG_RES
817	zr_fg_06	rerun NTV ZrO 35 TOA grnd, FG: 15 eV, 90% curr	3	3/5/93 0:00:00	MRS	CHRG_RES
818	zr_fg_07	NTV ZrO 35 TOA grounded, FG: 15 eV, min curr	3	3/5/93 0:00:00	MRS	CHRG_RES
819	zr_fg_08	NTV ZrO 35 TOA (as,rec'd, grounded, no FG)	1	3/5/93 0:00:00	MRS	CHRG_RES
820	zr_rturn	rerun NTV ZrO 35 TOA grnd, FG OFF (5 min wait)	3	3/5/93 0:00:00	MRS	CHRG_RES

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
821	BEAD3	Ligt-colored Polystyrene bead (560 uM) After plasma treatment	1	2/12/87 0:00:00	MRS	CHROMATO
822	cn_c100	Ion Exchange Resin "Cn-c100" (900 Micron Diameter)single Bead Resting On Aluminum Mount	2	12/11/86 0:00:00	MRS	CHROMATO
823	cn_c100_	Ion Exchange Resin "Cn-c100" (900 Micron Diameter)single Bead Resting On Aluminum Mount	4	12/26/86 0:00:00	MRS	CHROMATO
824	F6	ION EXCHANGE RESIN "F-A400" (650 MICRON) SINGLE BE	1	12/10/86 0:00:00	MRS	CHROMATO
825	F7	ION EXCHANGE RESIN "F-A400" (650 MICRON) SINGLE BE	1	12/10/86 0:00:00	MRS	CHROMATO
826	f_a400	Ion Exchange Resin "F-a400" (650 Micron Diameter)single Bead Adhered To Double Sided Tape	1	12/10/86 0:00:00	MRS	CHROMATO
827	f_a400_	ION EXCHANGE RESIN "F-A400" (650 MICRON) SINGLE BEAD on DST	8	12/10/86 0:00:00	MRS	CHROMATO
828	ps_bead	LIGHT-COLORED POLYSTYRENE BEAD (560u) RF PLASMA IN CF4/He ATMOSPHERE	4	2/12/87 0:00:00	MRS	CHROMATO
829	cb_01	Carbon Black (standard) on Indium foil (35 deg TOA)	1	3/13/91 0:00:00	MRS	C_BLACK
830	cb_0150	Carbon Black "CB-0150" on In foil (as rec'd, 35 TOA)	3	3/14/91 0:00:00	MRS	C_BLACK
831	cb_0300	Carbon Black "CB-300" (As rec'd on In Foil, 35 TOA)	2	4/5/91 0:00:00	MRS	C_BLACK
832	cb_0450	Carbon Black "CB-450" on In foil (as rec'd, 35 TOA)	3	3/13/91 0:00:00	MRS	C_BLACK
833	cb_1000	Carbon Black "CB-1000" on In foil (as rec'd, 35 TOA)	3	3/14/91 0:00:00	MRS	C_BLACK
834	cb_1200	Carbon Black "CB-1200" on In Foil (as rec'd, 35 TOA)	3	3/14/91 0:00:00	MRS	C_BLACK
835	cb_1400	Carbon Black "CB-1400" on In foil (as rec'd, 35 TOA)	3	3/14/91 0:00:00	MRS	C_BLACK
836	cb_l_1	Carbon Black "L-1" on indium foil (as rec'd, 35 TOA)	8	3/15/91 0:00:00	MRS	C_BLACK
837	cb_l_2	Carbon Black "L-2" on indium foil (as rec'd, 35 TOA)	4	3/13/91 0:00:00	MRS	C_BLACK
838	fbr300_0	Carbon Fibers (with sizing) F-300-0 (as rec'd)	3	4/12/91 0:00:00	MRS	C_FIBERS
839	fbr300_1	Carbon Fibers (no sizing) F-300-1 (as received)	3	4/12/91 0:00:00	MRS	C_FIBERS
840	fbr300_2	Fiber F-T-300-0 (with sizing), Xe: 1.3*E-7, 2KV, 10mA, F=5	3	4/13/91 0:00:00	DPR	C_FIBERS
841	fbr300_3	Fiber F-T-300-1 (no sizing), 2KV, 10mA, F=5, Xe:1.4*E-7	3	4/12/91 0:00:00	DPR	C_FIBERS
842	fbr300_4	Fiber F-300-1 after ion etching 3 microns	1	4/19/91 0:00:00	MRS	C_FIBERS
843	ar_implt	Argon Ions/Natural Graphite Crystal (90 TOA) 4KV, 10 min	3	1/12/93 0:00:00	MRS	DIAMOND
844	diamnd_a	DIAMOND (C) (90 DEG TOA, NO SCREEN, CLEANED WITH SOLVENTS)	1	2/18/88 0:00:00	MRS	DIAMOND
845	diamnd_b	DIAMOND (C) As received, no screen.	1	2/18/88 0:00:00	MRS	DIAMOND
846	diamnd_c	INDUSTRIAL DIAMOND (LIGHTLY ETCHED) 45 DEG TOA, SCREEN, EXPOSED BULK	3	7/15/87 0:00:00	MRS	DIAMOND
847	dimnd_et	INDUSTRIAL DIAMOND 45 DEG TOA, SCREEN, ION ETCH 20s 3 KeV	3	7/15/87 0:00:00	MRS	DIAMOND
848	dimnd_vb	INDUSTRIAL DIAMOND (C) CLEANED WITH SOLVENTS, 45 DEG TOA	1	1/20/88 0:00:00	MRS	DIAMOND
849	dlf_1295	Diamond-Like film (1295) 50 angstrom on amorphous SiO2/p-Silicon wafer (90 TOA) as rec	5	7/12/94 0:00:00	MRS	DIAMOND
850	dlf_1297	Diamond-Like film (1295) 50 angstrom on amorphous SiO2/p-Silicon wafer (90 TOA) as rec	5	7/12/94 0:00:00	MRS	DIAMOND
851	dlf_1298	Diamond-Like film (1298) 50 angstrom on amorphous SiO2/p-Silicon wafer (90 TOA) as rec	5	7/12/94 0:00:00	MRS	DIAMOND
852	dlf_1299	Diamond-Like film (1299) 50 angstrom on amorphous SiO2/p-Silicon wafer (90 TOA) as rec	5	7/12/94 0:00:00	MRS	DIAMOND
853	dlf_1305	Diamond-Like film (1305) 50 angstrom on amorphous SiO2/p-Silicon wafer (90 TOA) as rec	5	7/12/94 0:00:00	MRS	DIAMOND
854	dlf_n7	Diamond-Like film (N-7) 50 angstrom on p-Silicon wafer (90 TOA) as rec'd	4	7/12/94 0:00:00	MRS	DIAMOND
855	hopg_1	HOPG (freshly delaminated surface) 100 deg TOA	10	12/15/93 0:00:00	MRS	DIAMOND
856	hopg_1a	HOPG (freshly delaminated surface) 100 deg TOA	3	12/15/93 0:00:00	MRS	DIAMOND
857	hopg_1b	HOPG (freshly delaminated surface) 100 deg TOA	1	12/15/93 0:00:00	MRS	DIAMOND
858	na2s2o3	Test Of Flood Gun Induced Damage On Na2s2o3 Xtal 2 Ev, 0.27 Ma, Using Ssi Screen, 90 Deg Toa	19	2/1/88 0:00:00	MRS	DMG_ELEC
859	na2s2o3_	Test Of Flood Gun Induced Damage On Na2s2o3 Powder2 Ev, 0.27 Ma, No Screen, 90 Deg Toa	10	2/8/88 0:00:00	MRS	DMG_ELEC
860	nfg_paa1	X-RAY DAMAGE TO POLY-ACRYLIC ACID (90 DEG TOA,FILM/Al,NO SCR,N,NO FG)	20	2/25/88 0:00:00	MRS	DMG_ELEC
861	nfg_paa2	POLY-ACRYLIC ACID FILM ON SILICON (NO FLOOD GUN)	1	2/25/87 0:00:00	MRS	DMG_ELEC

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
862	paa_1	POLY(ACRYLIC) ACID (PAA) as THIN FILM ON SILICON WAFER, 90 DEG TOA	3	3/16/87 0:00:00	MRS	DMG_ELEC
863	paa_2	POLY(ACRYLIC) ACID (PAA) as THIN FILM ON SILICON WAFER, 90 DEG TOA	2	3/16/87 0:00:00	MRS	DMG_ELEC
864	paa_3	ELECTRON DAMAGE TO POLY-ACRYLIC ACID: 15 MIN, 10eV, 0.3mA, NO SCRNI	3	2/26/88 0:00:00	MRS	DMG_ELEC
865	paa_4	ELECTRON DAMAGE TO POLY-ACRYLIC ACID/AI (90 TOA, NO SCRNI, 1.0 mA)	3	2/25/88 0:00:00	MRS	DMG_ELEC
866	paa_5	ELECTRON DAMAGE TO POLY-ACRYLIC ACID (90 TOA,NO SCRNI,1.0 mA,20 MIN,NO X-RAYS)	3	2/25/88 0:00:00	MRS	DMG_ELEC
867	paa_6	ELECTRON DAMAGE TO POLY-ACRYLIC ACID/AI (90 TOA,NO SCRNI,1.5 mA,20 min)	2	2/25/88 0:00:00	MRS	DMG_ELEC
868	paa_7	ELECTRON DAMAGE TO POLY-ACRYLIC ACID (90 DEG TOA,NO SCRNI,1.5 mA,20 min)	2	2/25/88 0:00:00	MRS	DMG_ELEC
869	paa_8	FG Induced DeCarboxylation of PAA ON A SILICON WAFER (90 DEG TOA)	5	2/25/87 0:00:00	MRS	DMG_ELEC
870	pet_1	PET FILM MOUNTED ON DOUBLE SIDED TAPE (90 DEG TOA, 1 MM FROM SCREEN)	2	3/28/88 0:00:00	MRS	DMG_ELEC
871	pet_3	THICK FILM OF GOLD ON PET FILM (90 DEG TOA, 1 MM FROM SCREEN, MOUNTED ON TAPE)	3	3/28/88 0:00:00	MRS	DMG_ELEC
872	pe_test1	Test for Electron Damage on POLY-ETHYLENE (90 TOA, SCREEN (1mm), DST)	20	2/18/88 0:00:00	MRS	DMG_ELEC
873	pe_test2	TEST for Electron Damage to POLY-ETHYLENE (90 TOA, 6-8 mm FROM SCREEN, 4 V, 1 mA)	20	2/22/88 0:00:00	MRS	DMG_ELEC
874	ply_styr	Study Of X-ray Damage To Poly-styrene (90 Deg Toa, Screen, 3 Mm Bead, Freshly Cut, Bulk)	20	3/12/88 0:00:00	MRS	DMG_ELEC
875	teflon_2	Teflon Tape Adhered To Double Sided Tape 90 Deg Toa, Screen (1 Mm From Sample)	20	2/2/88 0:00:00	MRS	DMG_ELEC
876	cdo_02	CdO pellet (in CdO_01) after removing 80% of HC contam. by ion etching	3	6/12/91 0:00:00	MRS	DMG_ION
877	cdo_03	CdO (CdO_01) pellet, scrn, after 30 sec 3KV, 10mA ion etch	3	6/12/91 0:00:00	MRS	DMG_ION
878	cuo_1_i	30s 2KV 10mA Ar etch (90 AOI) of CuO (99.99%) RMC #70924-43	4	9/9/91 0:00:00	MRS	DMG_ION
879	c_i	Natural Graphite Crystal etched at 4KV 10 min	3	1/12/93 0:00:00	MRS	DMG_ION
880	moo3_i	60s 2KV 10mA Ar etch of MoO3 pellet	3	7/19/91 0:00:00	MRS	DMG_ION
881	mos2_000	MoS2 crystal (as rec'd) 90 TOA (no etching)	1	7/16/93 0:00:00	MRS	DMG_ION
882	mos2_010	10 sec 2 KV etch MoS2 crystal 90 TOA	1	7/16/93 0:00:00	MRS	DMG_ION
883	mos2_020	20 sec 2 KV etch MoS2 crystal 90 TOA	1	7/16/93 0:00:00	MRS	DMG_ION
884	mos2_040	40 sec 2 KV etch MoS2 crystal 90 TOA	1	7/16/93 0:00:00	MRS	DMG_ION
885	mos2_120	120 sec 2 KV etch MoS2 crystal 90 TOA	1	7/16/93 0:00:00	MRS	DMG_ION
886	mos2_300	300 sec 2 KV etch MoS2 crystal 90 TOA	1	7/16/93 0:00:00	MRS	DMG_ION
887	ntrl_c_1	Argon Ions/Natural Graphite Crystal (90 TOA) 4KV.	1	1/12/93 0:00:00	MRS	DMG_ION
888	ntrl_c_2	Argon Ions/Natural Graphite Crystal (90 TOA) 4KV.	1	1/12/93 0:00:00	MRS	DMG_ION
889	si3n4_i	240s 2KV 10mA Ar etch of old SILICON NITRIDE (Si3N4) FILM on Si	7	6/17/88 0:00:00	MRS	DMG_ION
890	si_1_i	120s 3KV 10mA Ar etch of SILICON (Si) WAFER 90 DEG TOA	12	11/26/86 0:00:00	MRS	DMG_ION
891	si_2_i	SILICON (Si) WAFER 90 DEG TOA, FRACTURED, CONT. ION ETCHING AT 1 KV	3	6/21/88 0:00:00	MRS	DMG_ION
892	si_3_i	60s 3KV 10mA Ar etch of Silicon (Si) wafer (90 DEG TOA, 100 ANG ETCH)	1	6/20/88 0:00:00	MRS	DMG_ION
893	si_4_i	30s 2KV 10mA NBS SRM 1521 B-70: p-Si(B) (35 toa)	4	6/25/91 0:00:00	MRS	DMG_ION
894	sno2_i	60s 2KV 10mA Ar etch of SnO2 pressed pellet	5	7/18/91 0:00:00	MRS	DMG_ION
895	tio2_id1	Ar ion damaged TiO2 pellet (90 TOA, 70 AOI, mesh) total 60 sec at 2 KV, 10mA, 2x2 raster, 1.5E(-7)	5	4/22/94 0:00:00	MRS	DMG_ION
896	tio2_id2	Ar ion damaged TiO2 pellet (90 TOA, 70 AOI, mesh) total 60 sec at 2 KV, 10mA, 2x2 raster, 1.5E(-7)	1	4/22/94 0:00:00	MRS	DMG_ION
897	tio2_id3	Ar ion damaged TiO2 pellet (90 TOA, 70 AOI, mesh) total 60 sec at 2 KV, 10mA, 2x2 raster, 1.5E(-7)	1	4/22/94 0:00:00	MRS	DMG_ION
898	tio2_id4	Ar ion damaged TiO2 pellet (90 TOA, 70 AOI, mesh) total 120 sec at 2 KV, 10mA, 2x2 raster, 1.5E(-7)	1	4/22/94 0:00:00	MRS	DMG_ION
899	tio2_id5	Ar ion damaged TiO2 pellet (90 TOA, 70 AOI, mesh) total 120 sec at 2 KV, 10mA, 2x2 raster, 1.5E(-7)	5	4/22/94 0:00:00	MRS	DMG_ION
900	tio2_id6	Ar ion damaged TiO2 pellet (90 TOA, 70 AOI, mesh) total 240 sec at 2 KV, 10mA, 2x2 raster, 1.5E(-7)	5	4/22/94 0:00:00	MRS	DMG_ION
901	un_si_ns	Silicon (Si) wafer, no doping, as rec'd, 90 TOA 90 deg TOA, Repeated ion etched between scans	3	3/5/94 0:00:00	MRS	DMG_ION
902	wo3_i	60s 2KV 10mA Ar etch of WO3 pressed pellet	5	7/18/91 0:00:00	MRS	DMG_ION



Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
903	y2o3_id	1 KV,10 mA ion beam damage to Y2O3 90 TOA, 70 AOI	0	4/21/94 0:00:00	DPR	DMG_ION
904	zro2_id1	Ar ion damaged ZrO2 pellet (90 TOA, 70 AOI, mesh) 60 sec, 2 KV, 10 mA, 2x2 raster, 1.5E(-7), mesh	1	4/22/94 0:00:00	MRS	DMG_ION
905	zro2_id2	Ar ion damaged ZrO2 pellet (90 TOA, 70 AOI, mesh) 60 sec, 2 KV, 10 mA, 2x2 raster, 1.5E(-7), mesh	4	4/22/94 0:00:00	MRS	DMG_ION
906	zro2_id3	Ar ion damaged ZrO2 pellet (90 TOA, 70 AOI, mesh) total 240 sec, 2 KV, 10 mA, 2x2 raster, 1.5E(-7)	5	4/22/94 0:00:00	MRS	DMG_ION
907	zro2_id4	Ar ion damaged ZrO2 pellet (90 TOA, 70 AOI, mesh) total 360 sec, 2 KV, 10 mA, 2x2 raster, 1.5E(-7)	5	4/22/94 0:00:00	MRS	DMG_ION
908	zro2_id5	Ar ion damaged ZrO2 pellet (90 TOA, 70 AOI, mesh) total 360 sec at 2 KV and then 120 sec at 4 KV	5	4/22/94 0:00:00	MRS	DMG_ION
909	acetal	POLY-ACETAL (Scientific Polymer Prod.) Freshly exposed bulk, 90 TOA, 1mm from mesh	20	3/27/88 0:00:00	MRS	DMG_XRAY
910	acrylic	POLY-ACRYLIC ACID (PolyScience Co.) Film on Aluminum foil, 90 TOA, no mesh	20	2/25/88 0:00:00	MRS	DMG_XRAY
911	amide	POLY-AMIDE RESIN (PolySciences Co.) Freshly exposed bulk, 90 TOA, 1mm from mesh	20	4/5/88 0:00:00	MRS	DMG_XRAY
912	butene	POLY-1-BUTENE (ISOTACTIC) Freshly exposed bulk, 90 TOA, 1mm above mesh	20	4/22/88 0:00:00	MRS	DMG_XRAY
913	carbonat	POLY-CARBONATE (Scientific Polymer Products Co.) Freshly Exposed bulk, 90 TOA, 1 mm from mesh	20	3/8/88 0:00:00	MRS	DMG_XRAY
914	cuso4_1	Damage Study Of Powdered Copper Sulfate (H2o?) At 2.6x10-9 Torr (Dried In Prep Chamber Overnight)	4	8/6/86 0:00:00	DPR	DMG_XRAY
915	cuso4_2	Damage Study Of "Crystalline" Copper Sulfate (H2o)at 3.2x10-9 Torr (Used Indium Foil And Ssi Screen)	4	8/7/86 0:00:00	DPR	DMG_XRAY
916	ethylen1	X-ray Damage to POLY-ETHYLENE (90 TOA, SCREEN (1mm), Fresh Bulk)	20	2/18/88 0:00:00	MRS	DMG_XRAY
917	ethylen2	X-ray Damage to POLY-ETHYLENE (90 DEG TOA, SCREEN, Fresh Bulk)	20	2/22/88 0:00:00	MRS	DMG_XRAY
918	ETHYLENE	POLY-ETHYLENE (90 TOA, SCREEN 1mm)	1	2/19/88 0:00:00	MRS	DMG_XRAY
919	isohexen	X-RAY DAMAGE TO POLY (4-METHYL-1-PENTENE)(90 TOA, SCREEN, FRESH BULK)	19	4/25/88 0:00:00	MRS	DMG_XRAY
920	kapton	Kapton (duPont) Freshly scraped film, 90 TOA, 1mm from mesh	20	3/25/88 0:00:00	MRS	DMG_XRAY
921	nitrocel	desc=Baseline: 408.24 to 399.45 eV As received surface, 90 TOA, 1mm from mesh	20	2/17/88 0:00:00	MRS	DMG_XRAY
922	nylon_6	NYLON 6 (Scientific Polymer Products) Freshly exposed bulk, 90 TOA, 1 mm from mesh	20	2/19/88 0:00:00	MRS	DMG_XRAY
923	pan	POLY-ACRYLONITRILE (PAN) As received surface of film, 90 TOA, 1mm from mesh	20	2/24/88 0:00:00	MRS	DMG_XRAY
924	peo_1	POLY-ETHYLENE OXIDE (PEO) Scientific Polymer Prod. Film cast from CHCl3, 90 TOA, 1mm from mesh	19	4/26/88 0:00:00	MRS	DMG_XRAY
925	peo_2	X-RAY DAMAGE TO POLY-ETHYLENE OXIDE (90 TOA, SCREEN 1mm, CAST FROM CHCl3)	20	4/7/88 0:00:00	MRS	DMG_XRAY
926	pet_1	X-RAY DAMAGE TO MYLAR (PET) (Washed THIN FILM, 90 TOA, 1 MM FROM SCREEN)	20	6/9/88 0:00:00	MRS	DMG_XRAY
927	pet_2	POLY-ETHYLENE TEREPHTHALATE 14 Hr under X-rays Freshly exposed bulk, 90 TOA, 0.7 mm from mesh	20	6/10/88 0:00:00	MRS	DMG_XRAY
928	pmma	POLY-METHYL METHACRYLATE Film on Aluminum foil, 90 TOA, 1 mm from mesh	20	3/17/88 0:00:00	MRS	DMG_XRAY
929	pps	POLY-PHENYLENE SULFIDE after 14 Hr under X-rays Powder on DS Tape, 90 TOA, 1 mm from mesh	20	4/1/88 0:00:00	MRS	DMG_XRAY
930	propylen	X-RAY DAMAGE TO POLY-PROPYLENE (THICK FILM SCRAPED, 90 TOA, SCREEN 1mm)	20	4/21/88 0:00:00	MRS	DMG_XRAY
931	pva	POLY-VINYL ACETATE (PVA) Scientific Polymer Prod. Freshly exposed bulk, 90 TOA, 1mm from mesh	19	3/18/88 0:00:00	MRS	DMG_XRAY
932	pvc	X-ray Damage to POLY-VINYLCHELORIDE (PVC) (Beads/DST, SCREEN, 90 DEG TOA)	20	2/12/88 0:00:00	MRS	DMG_XRAY
933	pvdF	POLY-VINYLDIENE di-FLUORIDE As received powder on DS tape, 90 TOA, 1mm mesh	20	3/28/88 0:00:00	MRS	DMG_XRAY
934	styrene	X-RAY DAMAGE TO POLY-STYRENE (90 TOA, SCREEN, 3 MM BEAD, FRESH BULK)	20	3/12/88 0:00:00	MRS	DMG_XRAY
935	sulphone	POLY-SULFONE RESIN Freshly exposed bulk, 90 TOA, 1 mm from mesh	19	2/23/88 0:00:00	MRS	DMG_XRAY
936	teflon	desc=Baseline: 690.61 to 680.10 eV As received film on DS tape, 90 TOA, 1mm from mesh	20	2/2/88 0:00:00	MRS	DMG_XRAY
937	15_aoi_1	AlTi/SbSe/BiTe/SbSe/POLYMER, 15 deg AOI Ar+, 1.5KV 10mA, 6x2 raster,	8	6/1/88 0:00:00	DPR	DPTH-PRO
938	15_aoi_2	AlTi/SbSe/BiTe/SbSe/POLYMER, 15 deg AOI Ar+, 3KV 10mA, 4x2 raster	7	5/31/88 0:00:00	DPR	DPTH-PRO
939	15_aoi_3	AlTi/SbSe/BiTe/SbSe/POLYMER, 15 deg AOI Ar+, 1.5KV 10mA, 6x2 raster (pre-etched)	6	6/10/88 0:00:00	DPR	DPTH-PRO
940	15_aoi_4	AlTi/SbSe/BiTe/SbSe/POLYMER, 15 deg AOI Ar+, 1.5KV 10mA, 6x2 raster	7	5/31/88 0:00:00	DPR	DPTH-PRO
941	15_aoi_5	AlTi/Sb2Se3/Bi2Te3/Sb2Se3/POLYMER, 3 KV, 10 mA 15 deg AOI Ar+	9	3/15/88 0:00:00	DPR	DPTH-PRO
942	304sus_1	CHEMICALLY ELECTRO-POLISHED SUS 304, 2KV, 10mA 4x2 raster, 1.3 x10-7 (Ar)	6	10/1/87 0:00:00	DPR	DPTH-PRO
943	304sus_2	CHEMICALLY ELECTRO-POLISHED SUS 304, 2KV, 10mA 2x2 raster, 1.3x10-7 Argon	6	10/1/87 0:00:00	DPR	DPTH-PRO

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
944	304sus_3	1.2 MICRON SUS 304, 2 KV, 10mA, 2x2 raster, 2x10 <sup>-7</sup> argon	5	11/24/87 0:00:00	DPR	DPTH-PRO
945	316sus	SUS 316: 2KV, 10mA, 1.5x2.5mm, 1.2E-7 Ar	0	6/18/93 0:00:00	DPR	DPTH-PRO
946	430_dull	430 SUS: ROUGH, DULL SIDE of Sample (3 KV, 10mA)	4	7/15/86 0:00:00	DPR	DPTH-PRO
947	430_shin	430 SUS, SHINY Side of Sample (3KV, 10mA)	4	7/15/86 0:00:00	DPR	DPTH-PRO
948	ag_ag_cr	Ag/AgCr/Cr/GLASS: 3KV, 10mA, 4x2mm, 1.5e-7 torr Ar	8	4/16/87 0:00:00	DPR	DPTH-PRO
949	algap1ga	100 Ang Al(0.25)Ga(0.75)P/GaP(111):2KV,10mA,4x2 1.1x10 <sup>-7</sup> torr Ar+	5	6/24/87 0:00:00	DPR	DPTH-PRO
950	algap2ga	100 Ang Al(0.75)Ga(0.25)P/GaP(110):2KV,10mA,4x2mm 1.2x10 <sup>-7</sup> torr Ar+	5	6/26/87 0:00:00	DPR	DPTH-PRO
951	algasb_1	200 Ang Al(0.28)Ga(0.72)Sb/GaSb(100):2KV,10mA,4x2 1.1x10 <sup>-7</sup> torr Ar+	5	6/26/87 0:00:00	DPR	DPTH-PRO
952	algasb_2	Depth Prof. On Al(0.28)ga(0.72)sb?gasb(100) 200ang2 Kev, 10 Ma, 4:2 Y:x Raster, 1.1x10 <sup>-7</sup> Torr (Ar)	5	7/13/87 0:00:00	DPR	DPTH-PRO
953	altisb_1	AlTi/Sb2Se3/Bi2Te3/Sb2Se3/POLYMER:4KV,10mA,2x2mm 1e(-7) torr Ar+	8	3/15/88 0:00:00	DPR	DPTH-PRO
954	altisb_2	AlTi/Sb2Se3/Bi2Te3/Sb2Se3/POLYMER:4KV,10mA,2x2mm 2e(-7) torr Ar	7	5/24/88 0:00:00	DPR	DPTH-PRO
955	al_acryl	700 Angstrom Al/ACRYL (2KeV,10mA,4x2,1.2x10 <sup>-7</sup> Ar)	3	10/26/88 0:00:00	DPR	DPTH-PRO
956	al_algap	Al/ Al(0.5)Ga(0.5)P /GaP(100): 3KV, 10mA, 4x2 mm 1.1x10 <sup>-7</sup> torr argon	5	6/29/87 0:00:00	DPR	DPTH-PRO
957	al_algas	Al/ Al(0.28)Ga(0.72)Sb /GaSb(100): 2KV, 10mA 1.1x 10(-7) torr argon	5	6/26/87 0:00:00	DPR	DPTH-PRO
958	al_gap_1	0.5:0.5 Al:GaP / GaP(100)(2KV,10mA,4x2mm,1,1x10 <sup>-7</sup> )	5	6/24/87 0:00:00	DPR	DPTH-PRO
959	al_gap_2	Al/GaP (100): 3KV, 10mA, 4x2mm, 1.2x10 <sup>-7</sup> torr Ar+	5	8/31/87 0:00:00	DPR	DPTH-PRO
960	al_gasb	Al/GaSb (100): 3KV, 10mA, 4x2mm, 1.2x10 <sup>-7</sup> torr Ar+	5	8/31/87 0:00:00	DPR	DPTH-PRO
961	bisrcacu	BiSrCaCuO THIN FILM: 2KV, 10mA, 2 Ang/min etch	4	7/18/88 0:00:00	DPR	DPTH-PRO
962	chrome_1	Cr/GLASS 4x2, 3 KeV, 10 mA, 1.2x10 <sup>-7</sup> 35 TOA	4	8/24/87 0:00:00	DPR	DPTH-PRO
963	chrome_2	Cr/GLASS 4x2, 3 KeV, 10 mA, 1.2x10 <sup>-7</sup> 35 TOA (repeat analysis on nearby area)	4	8/24/87 0:00:00	DPR	DPTH-PRO
964	chrome_3	Cr/GLASS: 3KV, 3mA, 2x0 raster, 1.2x10 <sup>-7</sup> torr	4	8/28/87 0:00:00	DPR	DPTH-PRO
965	chrome_4	Cr/GLASS: 3KV, 3mA, 2x0 raster 1.2x10 <sup>-7</sup> torr Ar+ (repeat on nearby area)	4	8/28/87 0:00:00	DPR	DPTH-PRO
966	co_nbn	Co/NbN/Co/NbN... (as deposited): 4KV, 3mA, 4x2 mm 1x10 <sup>-7</sup> torr Ar+	7	3/16/87 0:00:00	DPR	DPTH-PRO
967	c_coni_1	Normal C/CoNi/Cr MAGNETIC HARD DISC: 2KV, 10mA, 4x2 mm raster, 1.2x10 <sup>-7</sup> Torr Ar+	5	2/18/87 0:00:00	DPR	DPTH-PRO
968	c_coni_2	Abnormal C/CoNi/Cr Magnetic Hard Disk:2KV,10mA 4x2 raster, 1.2e-7 torr Ar+	5	2/20/87 0:00:00	DPR	DPTH-PRO
969	e_rate_1	Etch Rate Check: 1100 Ang Thermal SiO2/Si:2KV,10mA 4x2 raster 1.2x10 <sup>-7</sup> torr	2	8/26/86 0:00:00	DPR	DPTH-PRO
970	e_rate_2	Etch Rate Check: 1100 ANG THERMAL SiO2/Si:2KV,10mA	2	8/26/86 0:00:00	DPR	DPTH-PRO
971	e_rate_3	Etch Rate: 1010 Ang Thermal SiO2/Si: 3KV,10mA,4x2 1.1x10 <sup>-7</sup> torr Ar+	2	8/25/87 0:00:00	DPR	DPTH-PRO
972	e_rate_4	Etch Rate: 1010 Ang Thermal SiO2/Si: 3 KV,10mA,4x2 1.2x10 <sup>-7</sup> torr Ar+	2	8/26/87 0:00:00	DPR	DPTH-PRO
973	e_rate_5	Etch Rate: 1010 Ang Thermal SiO2/Si:2KV,10mA,4x2 1.4x10 <sup>-7</sup> torr Ar+	2	8/26/87 0:00:00	DPR	DPTH-PRO
974	ga_as_1	Ga/As/Ga/As/Ga/...(15 DEG TOA 2KeV,1.0 mA,4:4 RASTER, 1.1x10 <sup>-7</sup> Ar)	2	3/11/87 0:00:00	DPR	DPTH-PRO
975	harddisk1	Magnetic Disk (circa 1989) from crashed drive (35 deg TOA, 3 KV, 10 mA)	7	10/8/89 0:00:00	DPR	DPTH-PRO
976	k2cro4	Time Study Of K2cr04 Crystal (Fresh Exposed Bulk) Using Screen, Minimum Charge Neutralization	4	7/16/87 0:00:00	DPR	DPTH-PRO
977	lasermir	WITNESS PLATE (TiO2/SiO2/TiO2/SiO2...) (5KV, No Rot, 2 ANG/sec)	6	7/6/85 0:00:00	DPR	DPTH-PRO
978	magtape1	Cassette Mag Tape: CoNi/Al.../PET: 2KV,10mA,4x2 mm 1.2x10 <sup>-7</sup> torr Ar+	6	9/17/86 0:00:00	DPR	DPTH-PRO
979	magtape2	Cassette Magnetic Tape: CoNi/Al.../PET: 2KV, 10mA 4x2 raster 1.2x10 <sup>-7</sup> torr Ar+	7	8/25/87 0:00:00	DPR	DPTH-PRO
980	magtape3	Casette Mag Tape: CoNi/Al/CoNi: 3KV,10mA,4x2mm 1.2x10 <sup>-7</sup> torr Ar+	9	8/25/87 0:00:00	DPR	DPTH-PRO
981	native_c	CONTROL AREA ON COPPER STRIP: 2 KV, 10mA, 4x2 mm 1.2x10 <sup>-7</sup> torr Ar+	8	9/1/86 0:00:00	DPR	DPTH-PRO
982	ntv_crox	NATIVE CHROMIUM (Cr) OXIDE (2KeV,10mA,4:4 RASTER, 1.1x10 <sup>-7</sup> Ar)	3	4/7/87 0:00:00	DPR	DPTH-PRO
983	ntv_sio1	NATIVE SILICON DIOXIDE (2KV,10mA,4x2mm,1.2x10 <sup>-7</sup> Ar)	3	9/16/86 0:00:00	DPR	DPTH-PRO
984	ntv_sio2	NATIVE SILICON DIOXIDE (2KV,10 mA,4:2 RASTER,1.2x10 <sup>-7</sup> Ar)	3	9/16/86 0:00:00	DPR	DPTH-PRO

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
985	oil_stl	OIL BURNT ONTO COLD STEEL (10mA,3KV,6x2 RASTER,1.8 ANG/SEC)	3	5/18/88 0:00:00	DPR	DPTH-PRO
986	pad_bad	BOND PAD BAD SAMPLE (Black): 2KV,10mA,4x2,1.2x10 <sup>-7</sup>	8	11/25/86 0:00:00	DPR	DPTH-PRO
987	pad_good	Bond Pad Good (Blue): 2KV,10mA,4x2mm,1.2x10 <sup>-7</sup> torr	4	11/25/86 0:00:00	DPR	DPTH-PRO
988	plasma_c	Plasma Deposited Carbon/Si:2KV,10mA,4x2mm,1.2x10 <sup>-7</sup>	4	10/22/86 0:00:00	DPR	DPTH-PRO
989	polyest1	Plasma Treated Polyester: 1KV,10mA,4x2mm,1.2x10 <sup>-7</sup>	3	7/18/86 0:00:00	DPR	DPTH-PRO
990	propylen	POLYPROPYLENE: 1KV, 1mA, 4x2 mm 1.2e-7 torr Ar+	3	7/1/86 0:00:00	DPR	DPTH-PRO
991	rotate_1	Centered Rotation-Etch 1000Ang SiO <sub>2</sub> : 5KV,10mA 1x0 mm raster, 1.3x10 <sup>-7</sup> torr	0	5/16/91 0:00:00	DPR	DPTH-PRO
992	sicn_si1	1000 ANG SiCN / Si: 2KV, 10mA, 4x2mm 1.5x10 <sup>-7</sup> Ar+	4	1/20/88 0:00:00	DPR	DPTH-PRO
993	sicn_si2	SAMPLE #2 (1000 ANG SiCN/Si): 2KV, 10mA, 4x2 mm 1.5x10 <sup>-7</sup> torr	4	1/20/88 0:00:00	DPR	DPTH-PRO
994	sio2_tis	SiO <sub>2</sub> /TiSi/poly-Si/Si (10mA,2KV,4x2 raster, 1.5x10 <sup>-7</sup> Ar)	4	1/28/88 0:00:00	DPR	DPTH-PRO
995	sio_tisi	SiO <sub>2</sub> /TiSi/poly-Si/Si 2mA,2KV,4x2 raster,1.5x10 <sup>-7</sup> (Ar)	4	1/27/88 0:00:00	DPR	DPTH-PRO
996	tin_si	1300 ANGSTROMS TiN / Si (4Kv,3mA,4:2 RASTER,1.2x10 <sup>-7</sup> Ar)	5	7/14/86 0:00:00	DPR	DPTH-PRO
997	ag_ns	Silver (Ag) not scraped, pre-etched 20 min 90 TOA 70 deg TOA, Repeated ion etched between scans	0	2/28/94 0:00:00	DPR	ELEMETCH
998	ag_vb	Silver (Ag) not scraped, pre-etched 60 min, 90 TOA	1	3/1/94 0:00:00	MRS	ELEMETCH
999	ag_ws	Silver (Ag) not scraped, pre-etched 40 min, 90 TOA 70 deg TOA, Repeated ion etched between scans	0	3/1/94 0:00:00	DPR	ELEMETCH
1000	al_ns	Aluminum (Al) scraped & pre-etch 20 min, 90 TOA 90 deg TOA, Repeated ion etched between scans	0	3/3/94 0:00:00	DPR	ELEMETCH
1001	al_vb	Aluminum (Al) scraped & pre-etch >60 min, 90 TOA	1	3/3/94 0:00:00	MRS	ELEMETCH
1002	al_ws	Aluminum (Al) scraped & pre-etch >40min, 90 TOA 70 deg TOA, Repeated ion etched between scans	0	3/3/94 0:00:00	DPR	ELEMETCH
1003	al_ws_2	Aluminum (Al) scraped & pre-etch >60 min, 90 TOA 70 deg TOA, Repeated ion etched between scans	2	3/3/94 0:00:00	MRS	ELEMETCH
1004	as_ns	Arsenic (As) filed & etched > 20 min, 90 TOA Ion gun AOI was ca. 70 deg	4	3/9/94 0:00:00	MRS	ELEMETCH
1005	as_ws	Arsenic (As) filed & etched >20 min, 90 TOA 70 deg TOA, Repeated ion etched between scans	2	3/10/94 0:00:00	MRS	ELEMETCH
1006	au_ns	Gold (Au) not scraped, pre-etch 20 min, 90 TOA 70 deg TOA, Repeated ion etched between scans	0	2/25/94 0:00:00	DPR	ELEMETCH
1007	au_vb	Gold (Au) pre-etched >60min 90 TOA not scraped	1	2/25/94 0:00:00	MRS	ELEMETCH
1008	au_ws	Gold (Au) not scraped, pre-etched >40min 90 TOA 70 deg TOA, Repeated ion etched between scans	0	2/25/94 0:00:00	DPR	ELEMETCH
1009	be_ns	Beryllium (Be) not scraped, etched>20 min, 90 TOA 90 deg TOA, Repeated ion etched between scans	0	3/5/94 0:00:00	DPR	ELEMETCH
1010	be_vb	Beryllium (Be) not scraped, etched>60 min, 90 TOA	1	3/5/94 0:00:00	MRS	ELEMETCH
1011	be_ws	Beryllium (Be) not scraped, etched >40min, 90 TOA 70 deg TOA, Repeated ion etched between scans	0	3/5/94 0:00:00	DPR	ELEMETCH
1012	be_ws_2	Beryllium (Be) not scraped, etched >40min, 90 TOA	2	3/7/94 0:00:00	MRS	ELEMETCH
1013	bi_ns	Bismuth (Bi) not scraped, etched 5 min, 90 TOA Ion gun AOI was ca. 70 deg	4	3/7/94 0:00:00	MRS	ELEMETCH
1014	bi_vb	Bismuth (Bi) not scraped, etched 5 min, 90 TOA	1	3/7/94 0:00:00	MRS	ELEMETCH
1015	bi_vb_2	Bismuth (Bi) not scraped, etched 5 min, 90 TOA	1	3/7/94 0:00:00	MRS	ELEMETCH
1016	bi_ws	Bismuth (Bi) not scraped, etched 5 min, 90 TOA Ion gun AOI was ca. 70 deg	2	3/7/94 0:00:00	MRS	ELEMETCH
1017	b_ns	Boron (B) as rec'd, not scraped or pre-etched 90 deg TOA, Repeated ion etched between scans	0	2/24/94 0:00:00	DPR	ELEMETCH
1018	b_ws	Boron (B) after B_ns.dpr 90 TOA	2	2/24/94 0:00:00	MRS	ELEMETCH
1019	cd_ns	Cadmium (Cd) 90 TOA, Scraped, 3KV etch >3min 70 deg TOA, Repeated ion etched between scans	0	2/13/94 0:00:00	DPR	ELEMETCH
1020	cd_vb	Cadmium (Cd) 90 TOA, Scraped, 3KV etch >30 min	1	2/14/94 0:00:00	MRS	ELEMETCH
1021	cd_ws	Cadmium (Cd) 90 TOA, Scraped, 3KV etch >30 min	2	2/14/94 0:00:00	MRS	ELEMETCH
1022	cd_ws_2	Cadmium (Cd) 90 TOA, Scraped, 3KV etch >30 min	1	2/14/94 0:00:00	MRS	ELEMETCH
1023	co_ns	Cobalt (Co) 70 deg TOA, Repeated ion etched between scans	0	2/9/94 0:00:00	DPR	ELEMETCH
1024	co_vb	Cobalt (Co)	1	2/9/94 0:00:00	MRS	ELEMETCH
1025	co_ws	Cobalt (Co) 70 deg TOA, Repeated ion etched between scans	0	2/9/94 0:00:00	DPR	ELEMETCH

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
1026	cr_ns	Chromium (Cr) 90 TOA, Scraped, 3KV etch >3min 70 deg TOA, Repeated ion etched between scans	0	2/11/94 0:00:00	DPR	ELEMETCH
1027	cr_vb	Chromium (Cr) 90 TOA, Scraped, 3KV etch >3min	1	2/11/94 0:00:00	MRS	ELEMETCH
1028	cr_ws	Chromium (Cr) 90 TOA, Scraped, 3KV etch >3min 70 deg TOA, Repeated ion etched between scans	0	2/11/94 0:00:00	DPR	ELEMETCH
1029	cr_ws_2	Chromium (Cr) 90 TOA, Scraped, 3KV etch >3min	2	2/12/94 0:00:00	MRS	ELEMETCH
1030	cu_ns_1	Copper as rec'd, 90 TOA, no prior etch, 3kv,10ma 70 deg TOA, Repeated ion etched between scans	0	2/17/94 0:00:00	DPR	ELEMETCH
1031	cu_ns_2	Copper (Cu) scraped&repetitively etched 3KV,90 TOA 70 deg TOA, Repeated ion etched between scans	0	2/16/94 0:00:00	DPR	ELEMETCH
1032	cu_vb	Copper (Cu) scraped & etched more than 2 hours 90	1	2/16/94 0:00:00	MRS	ELEMETCH
1033	cu_vb_2		1	1/27/94 0:00:00	MRS	ELEMETCH
1034	cu_ws	Copper (Cu) scraped&repetitively etched 3KV,90 TOA 70 deg TOA, Repeated ion etched between scans	0	2/16/94 0:00:00	DPR	ELEMETCH
1035	c_ns	Carbon (C) scraped & etched > 20 min, 90 TOA Ion gun AOI was ca. 70 deg	4	3/13/94 0:00:00	MRS	ELEMETCH
1036	c_vb	Carbon (C) scraped & etched > 20 min, 90 TOA	1	3/13/94 0:00:00	MRS	ELEMETCH
1037	c_ws	Carbon (C) scraped & etched > 20 min, 90 TOA 70 deg TOA, Repeated ion etched between scans	2	3/13/94 0:00:00	MRS	ELEMETCH
1038	dy_ns	Dysprosium (Dy) scraped & etched > 10 min, 90 TOA 70 deg TOA, Repeated ion etched between scans	0	3/23/94 0:00:00	DPR	ELEMETCH
1039	dy_ns_2	Dysprosium (Dy) scraped & etched >30 min, 90 TOA	3	3/23/94 0:00:00	DPR	ELEMETCH
1040	dy_ws_2	Dysprosium (Dy) scraped & etched > 40 min, 90 TOA	2	3/23/94 0:00:00	MRS	ELEMETCH
1041	er_ns	Erbium (Er) filed & etched 20 min, 90 TOA 90 deg TOA, Repeated ion etched between scans	0	3/19/94 0:00:00	DPR	ELEMETCH
1042	er_ws	Erbium (Er) filed & etched >40 min, 90 TOA 70 deg TOA, Repeated ion etched between scans	0	3/19/94 0:00:00	DPR	ELEMETCH
1043	fe_2p	Fe(2p3) and Fe(2p1) signals, 90 deg TOA, sum of 20 0.05 eV/step, Measured BE for Cu(2p3) = 932.71 eV	1	1/27/94 0:00:00	MRS	ELEMETCH
1044	fe_ns	Iron (Fe) 70 deg TOA, Repeated ion etched between scans	0	2/10/94 0:00:00	DPR	ELEMETCH
1045	fe_rechk	Iron (Fe) ion etched, 90 TOA Recheck of BEs with true calibration	5	2/22/94 0:00:00	MRS	ELEMETCH
1046	fe_vb	Iron (Fe)	1	2/10/94 0:00:00	MRS	ELEMETCH
1047	fe_ws	Iron (Fe) 70 deg TOA, Repeated ion etched between scans	0	2/10/94 0:00:00	DPR	ELEMETCH
1048	gd_ns	Gadolinium (Gd) scraped & etched > 20 min, 90 TOA 90 deg TOA, Repeated ion etched between scans	0	3/16/94 0:00:00	DPR	ELEMETCH
1049	gd_ws	Gadolinium (Gd) scraped & etched > 40 min, 90 TOA 70 deg TOA, Repeated ion etched between scans	0	3/16/94 0:00:00	DPR	ELEMETCH
1050	ge_ns	Germanium (Ge) no scrape, pre-etched 2 min 90 TOA 70 deg TOA, Repeated ion etched between scans	0	2/18/94 0:00:00	DPR	ELEMETCH
1051	ge_rechk	Germanium (Ge) 90 TOA after recalibr & Ge_ns.dpr	5	2/24/94 0:00:00	MRS	ELEMETCH
1052	ge_ws	Germanium (Ge) after ion etching 90 TOA	2	2/24/94 0:00:00	MRS	ELEMETCH
1053	hf_ns	Hafnium (Hf) filed & etched >20 min, 90 TOA 90 deg TOA, Repeated ion etched between scans	0	3/9/94 0:00:00	DPR	ELEMETCH
1054	hf_vb	Hafnium (Hf) filed & etched > 60 min, 90 TOA	1	3/9/94 0:00:00	MRS	ELEMETCH
1055	hf_ws_1	Hafnium (Hf) filed & etched > 40 min, 90 TOA 70 deg TOA, Repeated ion etched between scans	0	3/9/94 0:00:00	DPR	ELEMETCH
1056	hf_ws_2	Hafnium (Hf) filed & etched > 50 min, 90 TOA 70 deg TOA, Repeated ion etched between scans	0	3/9/94 0:00:00	DPR	ELEMETCH
1057	ho_ns_2	Holmium (Ho) scraped & etched >20 min, 90 TOA	1	3/22/94 0:00:00	MRS	ELEMETCH
1058	ho_ws	Holmium (Ho) scraped & etched >20 min, 90 TOA 70 deg TOA, Repeated ion etched between scans	0	3/22/94 0:00:00	DPR	ELEMETCH
1059	in_ns	Indium (In) not scraped, etched >10 min 90 TOA 70 deg TOA, Repeated ion etched between scans	0	2/26/94 0:00:00	DPR	ELEMETCH
1060	in_vb	Indium (In) not scraped, etched > 50 min 90 TOA	1	2/26/94 0:00:00	MRS	ELEMETCH
1061	in_ws	Indium (In) not scraped, etched >30min 90 TOA 70 deg TOA, Repeated ion etched between scans	0	2/26/94 0:00:00	DPR	ELEMETCH
1062	ir_ns	Iridium (Ir) filed & etched 5 min, 90 TOA	4	3/3/94 0:00:00	MRS	ELEMETCH
1063	ir_vb	Iridium (Ir) filed & etched 5 min, 90 TOA	1	3/3/94 0:00:00	MRS	ELEMETCH
1064	ir_ws	Iridium (Ir) filed & etched 5 min, 90 TOA	2	3/3/94 0:00:00	MRS	ELEMETCH
1065	ir_ws_2	Iridium (Ir) filed & etched 5 min, 90 TOA	2	3/3/94 0:00:00	MRS	ELEMETCH
1066	lu_ns	Lutetium (Lu) filed & etched > 20 min, 90 TOA 90 deg TOA, Repeated ion etched between scans	0	3/15/94 0:00:00	DPR	ELEMETCH

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
1067	lu_ws	Lutetium (Lu) filed & etched > 40 min, 90 TOA 70 deg TOA, Repeated ion etched between scans	0	3/15/94 0:00:00	DPR	ELEMETCH
1068	mg_2p	Magnesium (Mg: 2p3, 2p1) (Sum of 20 individual spectra from depth profile)	1	1/27/94 0:00:00	MRS	ELEMETCH
1069	mg_ns	Magnesium (Mg) scraped & etched >30 min 90 TOA 70 deg TOA, Repeated ion etched between scans	0	2/27/94 0:00:00	DPR	ELEMETCH
1070	mg_vb	Magnesium (Mg) scraped & etched >70min 90 TOA	1	2/27/94 0:00:00	MRS	ELEMETCH
1071	mg_ws	Magnesium (Mg) scraped & etched >50 min 90 TOA 70 deg TOA, Repeated ion etched between scans	0	2/27/94 0:00:00	DPR	ELEMETCH
1072	mn_ns	Manganese (Mn) scraped & pre-etched 20 min 90 TOA 70 deg TOA, Repeated ion etched between scans	0	2/20/94 0:00:00	DPR	ELEMETCH
1073	mn_vb	Manganese (Mn) scraped & pre-etched >60 min 90 TOA	1	2/20/94 0:00:00	MRS	ELEMETCH
1074	mn_ws	Manganese (Mn) scraped & pre-etched >40 min 90 TOA 70 deg TOA, Repeated ion etched between scans	0	2/20/94 0:00:00	DPR	ELEMETCH
1075	mn_ws_2	Manganese (Mn) scraped & pre-etched >60 min 90 TOA	2	2/21/94 0:00:00	MRS	ELEMETCH
1076	mo_ns	Molybdenum (Mo) 70 deg TOA, Repeated ion etched between scans	0	2/17/94 0:00:00	DPR	ELEMETCH
1077	mo_vb	Molybdenum (Mo) scraped&etched more than 30 min	1	2/17/94 0:00:00	MRS	ELEMETCH
1078	mo_ws	Molybdenum (Mo) scraped&repetitively etched 3KV,90 70 deg TOA, Repeated ion etched between scans	0	2/17/94 0:00:00	DPR	ELEMETCH
1079	nb_ns	Niobium (Nb) scraped & pre-etched 20 min 90 TOA 70 deg TOA, Repeated ion etched between scans	0	2/19/94 0:00:00	DPR	ELEMETCH
1080	nb_vb	Niobium (Nb) scraped & pre-etched >60 min 90 TOA	1	2/20/94 0:00:00	MRS	ELEMETCH
1081	nb_ws	Niobium (Nb) scraped & pre-etched >40 min 90 TOA 70 deg TOA, Repeated ion etched between scans	0	2/19/94 0:00:00	DPR	ELEMETCH
1082	nb_ws_2	Niobium (Nb) scraped & pre-etched >60 min 90 TOA	2	2/20/94 0:00:00	MRS	ELEMETCH
1083	ni_ns	Nickel (Ni) scraped&repetitively etched 3KV 90 TOA 70 deg TOA, Repeated ion etched between scans	0	2/14/94 0:00:00	DPR	ELEMETCH
1084	ni_vb	Nickel (Ni) scraped&etched more than 30min	1	2/16/94 0:00:00	MRS	ELEMETCH
1085	ni_ws	Nickel (Ni) scraped&repetitively etched 3KV,90 TOA 70 deg TOA, Repeated ion etched between scans	0	2/15/94 0:00:00	DPR	ELEMETCH
1086	pb_ns	Lead (Pb) scraped & etched 10 min 90 TOA 70 deg TOA, Repeated ion etched between scans	0	2/25/94 0:00:00	DPR	ELEMETCH
1087	pb_vb	Lead (Pb) scraped & etched > 50 min 90 TOA	1	2/26/94 0:00:00	MRS	ELEMETCH
1088	pb_ws	Lead (Pb) scraped & etched >30 min 90 TOA 70 deg TOA, Repeated ion etched between scans	0	2/26/94 0:00:00	DPR	ELEMETCH
1089	pd_ns	Palladium (Pd) scraped in air, etched 5 min 4 KV 70 deg TOA, Repeated ion etched between scans	0	2/10/94 0:00:00	DPR	ELEMETCH
1090	pd_ws	Palladium (Pd) ion etched every other scan by hand	2	2/10/94 0:00:00	MRS	ELEMETCH
1091	pd_ws_2	Palladium (Pd) ion etched every other scan by hand	2	2/10/94 0:00:00	MRS	ELEMETCH
1092	pt_ns	Platinum (Pt) scraped&repetitively etched 3KV,90 70 deg TOA, Repeated ion etched between scans	0	2/18/94 0:00:00	DPR	ELEMETCH
1093	pt_vb	Platinum (Pt) scraped & etched more than 30 min	1	2/18/94 0:00:00	MRS	ELEMETCH
1094	pt_ws	Platinum (Pt) scraped&repetitively etched 3KV,90 70 deg TOA, Repeated ion etched between scans	0	2/18/94 0:00:00	DPR	ELEMETCH
1095	re_ns	Rhenium (Re) scraped & pre-etched 20 min 90 TOA 70 deg TOA, Repeated ion etched between scans	0	2/21/94 0:00:00	DPR	ELEMETCH
1096	re_ws	Rhenium (Re) scraped & pre-etched >40min 90 TOA 70 deg TOA, Repeated ion etched between scans	0	2/21/94 0:00:00	DPR	ELEMETCH
1097	rh_ns	Rhodium (Rh) not scraped,pre-etch 20 min 90 TOA 70 deg TOA, Repeated ion etched between scans	0	3/1/94 0:00:00	DPR	ELEMETCH
1098	rh_ns	Rhodium (Rh) /Ni/Al etched 3 min, 90 TOA	4	3/1/94 0:00:00	MRS	ELEMETCH
1099	rh_vb	Rhodium (Rh) /Ni/Al: only etched 3 min, 90 TOA	1	3/1/94 0:00:00	MRS	ELEMETCH
1100	rh_ws	Rhodium (Rh)/Ni/Al not scraped, etched 3 min,90TOA	2	3/1/94 0:00:00	MRS	ELEMETCH
1101	ru_1_hq	Ruthenium (Ru) Powder Pressed into Disk 70 deg TOA, Repeated ion etched between scans	0	1/28/94 0:00:00	DPR	ELEMETCH
1102	ru_1_vb	Ruthenium (Ru) powder pressed into disk 70 deg TOA	2	1/28/94 0:00:00	MRS	ELEMETCH
1103	sb_ns	Antimony (Sb) scraped & etched > 20 min, 90 TOA 90 deg TOA, Repeated ion etched between scans	0	3/12/94 0:00:00	DPR	ELEMETCH
1104	sb_vb	Antimony (Sb) scraped & etched > 60 min, 90 TOA	1	3/13/94 0:00:00	MRS	ELEMETCH
1105	sb_ws	Antimony (Sb) scraped & etched > 40 min, 90 TOA 70 deg TOA, Repeated ion etched between scans	0	3/13/94 0:00:00	DPR	ELEMETCH
1106	sc_ns	Scandium (Sc) filed & etched > 20 min, 90 TOA 90 deg TOA, Repeated ion etched between scans	0	3/14/94 0:00:00	DPR	ELEMETCH
1107	sc_ws_1	Scandium (Sc) filed & etched > 40 min, 90 TOA 70 deg TOA, Repeated ion etched between scans	0	3/14/94 0:00:00	DPR	ELEMETCH

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
1108	sc_ws_2	Scandium (Sc) filed & etched > 50 min, 90 TOA 70 deg TOA, Repeated ion etched between scans	0	3/14/94 0:00:00	DPR	ELEMETCH
1109	se_ns	Selenium (Se) not scraped, not etched, 90 TOA	4	3/7/94 0:00:00	MRS	ELEMETCH
1110	se_ws	Selenium (Se) not scraped, not etched, 90 TOA	2	3/8/94 0:00:00	MRS	ELEMETCH
1111	si_ns	Silicon (Si) wafer, no doping, no scrape, as received, 90 TOA gift from Suzuki-san	4	3/4/94 0:00:00	MRS	ELEMETCH
1112	si_ns_1	Silicon (Si) no doping, no scrape, 20min etch, 90 TOA 90 deg TOA, Repeated ion etched between scans	0	3/6/94 0:00:00	DPR	ELEMETCH
1113	si_un_ns	Silicon (Si) wafer, no doping, as rec'd, 90 TOA 90 deg TOA, Repeated ion etched between scans	3	3/5/94 0:00:00	MRS	ELEMETCH
1114	si_un_vb	Silicon (Si) wafer, no doping, as rec'd 90 TOA 90 deg TOA, Repeated ion etched between scans	1	3/5/94 0:00:00	MRS	ELEMETCH
1115	si_un_ws	Silicon (Si) wafer, no doping, as rec'd, 90 TOA 70 deg TOA, Repeated ion etched between scans	2	3/5/94 0:00:00	MRS	ELEMETCH
1116	si_vb	Silicon (Si) no scrape, no doping, etch > 60 min, 90 TOA	1	3/6/94 0:00:00	MRS	ELEMETCH
1117	si_ws	Silicon (Si) 100% no doping, pre-etch 5 min, 90 TOA	0	3/3/94 0:00:00	DPR	ELEMETCH
1118	si_ws_1	Silicon (Si) 100% no doping, as rec'd, 90 TOA	1	3/4/94 0:00:00	MRS	ELEMETCH
1119	si_ws_2	Silicon (Si) no doping, no scrape, etch > 40 min, 90 TOA 70 deg TOA, Repeated ion etched between scans	0	3/6/94 0:00:00	DPR	ELEMETCH
1120	sn_ns	Tin (Sn) scraped & etched > 10 min 90 TOA 70 deg TOA, Repeated ion etched between scans	0	2/26/94 0:00:00	DPR	ELEMETCH
1121	sn_vb	Tin (Sn) scraped & etched > 50 min 90 TOA	1	2/27/94 0:00:00	MRS	ELEMETCH
1122	sn_ws	Tin (Sn) scraped & etched > 30 min 90 TOA 70 deg TOA, Repeated ion etched between scans	0	2/27/94 0:00:00	DPR	ELEMETCH
1123	ta_ns	Tantalum (Ta) scraped & pre-etched 20 min 90 TOA 70 deg TOA, Repeated ion etched between scans	0	2/19/94 0:00:00	DPR	ELEMETCH
1124	ta_vb	Tantalum (Ta) scraped & pre-etched > 60 min 90 TOA	1	2/19/94 0:00:00	MRS	ELEMETCH
1125	ta_ws	Tantalum (Ta) scraped & pre-etched > 40 min 90 TOA 70 deg TOA, Repeated ion etched between scans	0	2/19/94 0:00:00	DPR	ELEMETCH
1126	ta_ws_2	Tantalum (Ta) scraped & pre-etched > 60 min 90 TOA	2	2/19/94 0:00:00	MRS	ELEMETCH
1127	TB_4D	Pure Terbium (Tb) metal, ion etched	1	1/27/94 0:00:00	MRS	ELEMETCH
1128	tb_hi_be	Tb metal high E BEs	1	1/27/94 0:00:00	MRS	ELEMETCH
1129	tb_ns	Terbium (Tb) filed & etched > 20 min, 90 TOA 90 deg TOA, Repeated ion etched between scans	0	3/15/94 0:00:00	DPR	ELEMETCH
1130	tb_ws	Terbium (Tb) filed & etched > 40 min, 90 TOA 70 deg TOA, Repeated ion etched between scans	0	3/15/94 0:00:00	DPR	ELEMETCH
1131	te_ns	Tellurium (Te) 90 TOA, Scraped, 3KV etch > 3 min 70 deg TOA, Repeated ion etched between scans	0	2/12/94 0:00:00	DPR	ELEMETCH
1132	te_vb	Tellurium (Te) 90 TOA, Scraped, 3KV etch > 3 min	1	2/12/94 0:00:00	MRS	ELEMETCH
1133	te_ws	Tellurium (Te) 90 TOA, Scraped, 3KV etch > 3 min 70 deg TOA, Repeated ion etched between scans	0	2/12/94 0:00:00	DPR	ELEMETCH
1134	te_ws_2	Tellurium (Te) 90 TOA, Scraped, 3KV etch > 3 min	2	2/13/94 0:00:00	MRS	ELEMETCH
1135	ti_chk_2	Titanium (Ti: 2p3, 2p1) 90 deg TOA, scraped & ion etched	2	2/22/94 0:00:00	MRS	ELEMETCH
1136	ti_ns_2	Titanium (Ti) from repetitive ion etch cleaning 90 deg TOA, Repeated ion etched between scans	0	2/23/94 0:00:00	DPR	ELEMETCH
1137	ti_rechk	Titanium (Ti) 70 deg TOA, Repeated ion etched between scans	5	2/22/94 0:00:00	MRS	ELEMETCH
1138	ti_vb	Titanium (Ti) Valence Band region (etched 20 min) (sample collected oxygen during wide scan)	1	2/8/94 0:00:00	MRS	ELEMETCH
1139	ti_ws	Titanium (Ti) (attempt to get clean surface) 70 deg TOA, Repeated ion etched between scans	0	2/7/94 0:00:00	DPR	ELEMETCH
1140	tl_ns	Thallium (Tl) scraped & etched 10 min, 90 TOA	4	3/2/94 0:00:00	MRS	ELEMETCH
1141	tl_vb	Thallium (Tl) 90 TOA, Scraped, 3KV etch > 10 min	1	3/2/94 0:00:00	MRS	ELEMETCH
1142	tl_ws	Thallium (Tl) scraped, 10 min etch, 90 TOA, overnight	2	3/2/94 0:00:00	MRS	ELEMETCH
1143	tm_ns	Thulium (Tm) filed & etched > 20 min, 90 TOA 90 deg TOA, Repeated ion etched between scans	0	3/19/94 0:00:00	DPR	ELEMETCH
1144	tm_ws	Thulium (Tm) filed & etched > 40 min, 90 TOA 70 deg TOA, Repeated ion etched between scans	0	3/20/94 0:00:00	DPR	ELEMETCH
1145	v_ns	Vanadium (V) scraped & pre-etched 20 min 90 TOA 70 deg TOA, Repeated ion etched between scans	0	2/21/94 0:00:00	DPR	ELEMETCH
1146	v_vb	Vanadium (V) scraped & pre-etched > 40 min 90 TOA	1	2/21/94 0:00:00	MRS	ELEMETCH
1147	v_ws	Vanadium (V) scraped & pre-etched > 40 min 90 TOA 70 deg TOA, Repeated ion etched between scans	0	2/21/94 0:00:00	DPR	ELEMETCH
1148	v_ws_2	Vanadium (V) scraped & pre-etched > 60 min 90 TOA	2	2/21/94 0:00:00	MRS	ELEMETCH

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
1149	w_ns	Tungsten (W) filed & pre-etched 20 min, 90 TOA	4	3/3/94 0:00:00	MRS	ELEMETCH
1150	w_ns_2	Tungsten (W) filed & etched >20 min, 90 TOA 90 deg TOA, Repeated ion etched between scans	0	3/7/94 0:00:00	DPR	ELEMETCH
1151	w_vb	Tungsten (W) filed & etched >60 min, 90 TOA	1	3/7/94 0:00:00	MRS	ELEMETCH
1152	w_ws_2	Tungsten (W) filed & etched >40 min, 90 TOA 70 deg TOA, Repeated ion etched between scans	0	3/7/94 0:00:00	DPR	ELEMETCH
1153	yb_ns_2	Ytterbium (Yb) scraped & etched > 10 min, 90 TOA	3	3/24/94 0:00:00	DPR	ELEMETCH
1154	yb_ws	Ytterbium (Yb) scraped & etched > 30 min, 90 TOA 70 deg TOA, Repeated ion etched between scans	0	3/23/94 0:00:00	DPR	ELEMETCH
1155	y_ns_1	Yttrium (Y) scraped & pre-etched 20min 90 TOA 70 deg TOA, Repeated ion etched between scans	0	3/1/94 0:00:00	DPR	ELEMETCH
1156	y_ns_2	Yttrium (Y) scraped & pre-etched 20min 90 TOA 70 deg TOA, Repeated ion etched between scans	0	3/2/94 0:00:00	DPR	ELEMETCH
1157	y_vb	Yttrium (Y) 90 TOA, Scraped, 3KV etch >80min	1	3/2/94 0:00:00	MRS	ELEMETCH
1158	y_ws	Yttrium (Y) scraped & pre-etched 60 min 90 TOA 70 deg TOA, Repeated ion etched between scans	0	3/2/94 0:00:00	DPR	ELEMETCH
1159	zn_ns	Zinc (Zn) filed & etched>20 min, 90 TOA 90 deg TOA, Repeated ion etched between scans	0	3/6/94 0:00:00	DPR	ELEMETCH
1160	zn_ns_2	Zinc (Zn) filed & etched>60 min, 90 TOA	3	3/7/94 0:00:00	MRS	ELEMETCH
1161	zn_vb	Zinc (Zn) filed & etched > 60 min, 90 TOA	1	3/6/94 0:00:00	MRS	ELEMETCH
1162	zn_ws	Zinc (Zn) filed & etched >40 min, 90 TOA 70 deg TOA, Repeated ion etched between scans	0	3/6/94 0:00:00	DPR	ELEMETCH
1163	zr_ns	Zirconium (Zr) filed & etched >20min, 90 TOA 90 deg TOA, Repeated ion etched between scans	0	3/11/94 0:00:00	DPR	ELEMETCH
1164	zr_vb	Zirconium (Zr) filed & etched >60 min, 90 TOA	1	3/11/94 0:00:00	MRS	ELEMETCH
1165	zr_ws_1	Zirconium (Zr) filed & etched > 40 min, 90 TOA 70 deg TOA, Repeated ion etched between scans	0	3/11/94 0:00:00	DPR	ELEMETCH
1166	zr_ws_2	Zirconium (Zr) filed & etched > 50 min, 90 TOA 70 deg TOA, Repeated ion etched between scans	0	3/11/94 0:00:00	DPR	ELEMETCH
1167	ag_1	SILVER (Ag) on Mylar (90 DEG TOA, ION ETCHED: 4 KeV, 1 MIN)	2	11/27/86 0:00:00	MRS	ELEM_A-L
1168	ag_1_nm	Min Etch of Ag/mylar, New Monochromator, Graz 100	3	9/11/92 0:00:00	MRS	ELEM_A-L
1169	ag_2	SILVER (Ag) FOIL (90 DEG TOA, POLISHED, ION ETCHED: 3 KeV, 30 SEC)	4	11/29/86 0:00:00	MRS	ELEM_A-L
1170	ag_vb	ION ETCHED SILVER (Ag) ON MYLAR (90 DEG TOA)	1	10/13/87 0:00:00	MRS	ELEM_A-L
1171	al_1	ALUMINUM (Al) WIRE (99.999% 90 DEG TOA, ETCHED AT 4 KV FOR 5 MIN)	2	7/1/88 0:00:00	MRS	ELEM_A-L
1172	al_2	ALUMINUM (Al) INGOT (4KV etch, Then CONT. ETCHING 90 DEG TOA)	2	6/21/88 0:00:00	MRS	ELEM_A-L
1173	al_3	ALUMINUM (Al) WIRE (99.999%, 90 DEG TOA, ETCHED, FRESHLY EXPOSED BULK)	1	1/27/88 0:00:00	MRS	ELEM_A-L
1174	argon_1	Argon Ions/Natural Graphite Crystal (90 TOA)	1	1/12/93 0:00:00	MRS	ELEM_A-L
1175	argon_1a	Argon Ions/Natural Graphite Crystal (90 TOA)	9	1/12/93 0:00:00	MRS	ELEM_A-L
1176	argon_1b	Argon Ions/Natural Graphite Crystal (90 TOA)	6	1/12/93 0:00:00	MRS	ELEM_A-L
1177	argon_1c	Argon Ions/Natural Graphite Crystal (90 TOA)	2	1/12/93 0:00:00	MRS	ELEM_A-L
1178	ar_1	ARGON (Ar) IONS IMPLANTED IN GRAPHITE FRESHLY EXPOSED BULK(35 DEG TOA)	2	1/11/88 0:00:00	MRS	ELEM_A-L
1179	ar_b_1	Argon (Ar) implanted in Boron (90 TOA, ION ETCHED: 3 KeV, 10 mA, 3 MIN)	7	1/18/88 0:00:00	MRS	ELEM_A-L
1180	ar_c_1	ARGON (Ar) IONS IMPLANTED IN GRAPHITE (35 DEG TOA)	2	1/11/88 0:00:00	MRS	ELEM_A-L
1181	ar_c_2	Argon Ions/Natural Graphite Crystal (90 TOA) 4KV	8	1/12/93 0:00:00	MRS	ELEM_A-L
1182	as_1	ARSENIC (As) CHIP: ION ETCHED 2 MIN AT 3 KeV, 90 DEG TOA	10	8/7/86 0:00:00	MRS	ELEM_A-L
1183	au_1	GOLD (Au) ON SILICON (90 DEG TOA, ION ETCHED: 2 KeV, 30 SEC)	8	11/30/86 0:00:00	MRS	ELEM_A-L
1184	au_1_nm	Lightly etched Au/Si, New Monochromator, Graz 105	3	9/11/92 0:00:00	MRS	ELEM_A-L
1185	au_2	GOLD ON MYLAR (90 DEG TOA, AS RECEIVED)	3	6/28/88 0:00:00	MRS	ELEM_A-L
1186	au_vb	GOLD (Au) ON MYLAR (AS RECEIVED, 90 DEG TOA)	4	7/28/86 0:00:00	MRS	ELEM_A-L
1187	ba_1	BARIUM (Ba) METAL (SCRAPED under CYCLOHEXANE & ETCHED 15 MIN 4 KeV)	15	8/29/87 0:00:00	MRS	ELEM_A-L
1188	ba_co3_1	BARIUM (Ba) CARBONATE/DST (90 DEG TOA, ETCHED 4 KeV 10 MIN)	9	7/10/87 0:00:00	MRS	ELEM_A-L
1189	ba_oac_1	BARIUM (Ba) ACETATE (GROUND & PRESSED ONTO INDIUM, SCREEN)	11	6/18/87 0:00:00	MRS	ELEM_A-L

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
1190	be_1	BERYLLIUM (Be) FOIL (90 DEG TOA, ION ETCHED: 5 KeV, 20 MIN)	7	11/30/86 0:00:00	MRS	ELEM_A-L
1191	bi_1	BISMUTH (Bi) SLUG (SCRAPED & ION ETCHED 3 MIN, 90 DEG TOA)	16	4/17/87 0:00:00	MRS	ELEM_A-L
1192	br_k_1	POTASSIUM BROMIDE (KBr) CRYSTAL (17 HR IN VAC, CLEAVED IN AIR, 90 TOA)	3	12/15/86 0:00:00	MRS	ELEM_A-L
1193	br_k_2	POTASSIUM BROMIDE (KBr) CRYSTAL (17 HR IN VAC, CLEAVED IN AIR, 90 TOA)	9	12/15/86 0:00:00	MRS	ELEM_A-L
1194	b_1	BORON (B) CHIP (90 DEG TOA, ION ETCHED: 3 KeV, 10 mA, 3 MIN)	7	1/18/88 0:00:00	MRS	ELEM_A-L
1195	b_2	BORON (B) CHIP (90 DEG TOA, EXPOSED BULK, LIGHTLY ION ETCHED)	3	6/20/88 0:00:00	MRS	ELEM_A-L
1196	b_2a	BORON (B) CHIP (90 DEG TOA, EXPOSED BULK, LIGHTLY ION ETCHED)	2	6/20/88 0:00:00	MRS	ELEM_A-L
1197	b_n_1	Boron (B) in BORON NITRIDE (BN) (90 TOA, ETCHED 4 KeV, 10 mA, 2 MIN)	15	12/21/86 0:00:00	MRS	ELEM_A-L
1198	b_n_2	Boron (B) in white BORON NITRIDE (BN) (45 TOA, SCREEN, EXPOSED BULK)	5	7/15/87 0:00:00	MRS	ELEM_A-L
1199	b_n_3	Boron (B) in BORON NITRIDE (BN) (45 TOA, SCREEN, EXPOSED BULK)	2	7/15/87 0:00:00	MRS	ELEM_A-L
1200	ca_1	CALCIUM (Ca) TURNING (90 DEG TOA, FILED, ION ETCHED 15 MIN AT 4.5 KV)	4	6/16/88 0:00:00	MRS	ELEM_A-L
1201	ca_f2_1	CALCIUM di-FLUORIDE (CaF2) CRYSTAL (90 DEG TOA, FRESHLY EXPOSED BULK)	13	12/20/86 0:00:00	MRS	ELEM_A-L
1202	cd_1	CADMIUM (Cd) FOIL (KNIFE-SCRAPED, 90 TOA, ETCH: 4 KeV, 10 mA, 3 MIN)	11	12/10/86 0:00:00	MRS	ELEM_A-L
1203	ce_o2_1	CERIUM (CeO2) DI-OXIDE POWDER (PRESSED ONTO INDIUM FOIL, 90 DEG TOA)	5	6/15/87 0:00:00	MRS	ELEM_A-L
1204	cl_na_1	SODIUM CHLORIDE (NaCl) CRYSTAL (24 HR IN VAC. CLEAVED IN AIR, 90 TOA)	18	12/15/86 0:00:00	MRS	ELEM_A-L
1205	co_1	COBALT (Co) ROD (SCRAPED, 90 DEG TOA, ION ETCH: 5 KeV, 10 mA, 5 MIN)	10	12/8/86 0:00:00	MRS	ELEM_A-L
1206	co_2	COBALT (Co) ROD (90 DEG TOA, SANDED, ION ETCHED 5 MIN AT 3 KV)	2	6/20/88 0:00:00	MRS	ELEM_A-L
1207	cr_1	CHROMIUM (Cr) SHEET (90 DEG TOA, ION ETCHED AT 4 KV FOR 4 MIN)	1	7/1/88 0:00:00	MRS	ELEM_A-L
1208	cr_1a	CHROMIUM (Cr) SHEET (90 DEG TOA, ION ETCHED 10 MIN AT 4 KV)	2	6/28/88 0:00:00	MRS	ELEM_A-L
1209	cr_2	CHROMIUM (Cr) LUMP (35 DEG TOA, ION ETCHED 10 MIN AT 2 KV)	5	4/7/87 0:00:00	MRS	ELEM_A-L
1210	cs_cl_1	CESIUM CHLORIDE (CsCl) CRYSTAL (FRESHLY EXPOSED SURFACE, no mesh)	10	6/13/87 0:00:00	MRS	ELEM_A-L
1211	cu_1	COPPER (Cu) FOIL (90 DEG TOA, SCRAPED, ION ETCHED: 4 KeV, 1 MIN)	11	11/26/86 0:00:00	MRS	ELEM_A-L
1212	cu_1a	COPPER (Cu) FOIL (90 DEG TOA, ION ETCHED 5 MIN AT 3 KV)	1	6/20/88 0:00:00	MRS	ELEM_A-L
1213	cu_1_nm	Strongly etched Cu, New Monochromator, Grazing 105	2	9/11/92 0:00:00	MRS	ELEM_A-L
1214	cu_2	COPPER (Cu) FOIL (90 DEG TOA, ION ETCHED AT 4 KeV FOR 12 MIN)	11	7/10/87 0:00:00	MRS	ELEM_A-L
1215	c_1	CARBON (C): INDUSTRIAL DIAMOND (LIGHTLY ETCHED) 45 DEG TOA, SCREEN, EXPOSED BULK	2	7/15/87 0:00:00	MRS	ELEM_A-L
1216	c_1_etch	INDUSTRIAL DIAMOND (C) (45 DEG TOA, SCREEN, ION ETCH 20s 3 KeV)	2	7/15/87 0:00:00	MRS	ELEM_A-L
1217	c_1_vb	INDUSTRIAL DIAMOND (C) CLEANED WITH SOLVENTS, 45 DEG TOA	1	1/20/88 0:00:00	MRS	ELEM_A-L
1218	c_2	CARBON (C) SHEET (GRAPHITE) (90 DEG TOA, SCRAPED WITH RAZOR BLADE)	6	1/19/88 0:00:00	MRS	ELEM_A-L
1219	c_2a	CARBON (C) SHEET (GRAPHITE) (90 DEG TOA, SCRAPED WITH A RAZOR BLADE)	1	1/19/88 0:00:00	MRS	ELEM_A-L
1220	c_2b	CARBON (C) SHEET (GRAPHITE) (90 DEG TOA, SCRAPED WITH RAZOR BLADE)	1	1/19/88 0:00:00	MRS	ELEM_A-L
1221	dy_1	DYSPROSIUM (Dy) SHEET (70 DEG TOA, FILED & ETCHED 3 KeV, 10 mA, 10 MIN)	3	1/15/88 0:00:00	MRS	ELEM_A-L
1222	dy_1a	DYSPROSIUM (Dy) SHEET (35 TOA, FILED & ETCHED 3 KeV, 10 mA, 10 MIN)	1	1/14/88 0:00:00	MRS	ELEM_A-L
1223	dy_1b	DYSPROSIUM (Dy) SHEET (70 DEG TOA, FILED & ETCHED 3 KeV, 10 mA, 10 MIN)	1	1/15/88 0:00:00	MRS	ELEM_A-L
1224	er_1	ERBIUM (Er) SHEET (35 TOA, FILED, WASHED in CYCLOHEXANE & ION ETCHED)	10	10/2/87 0:00:00	MRS	ELEM_A-L
1225	er_1a	ERBIUM (Er) CHUNK (35 TOA, FILED & ION ETCHED 3 KeV, 10 mA, 5 MIN)	2	1/14/88 0:00:00	MRS	ELEM_A-L
1226	f2_ca_1	FLUORINE in CaF2 Crystal (90 DEG TOA, FRESHLY CLEAVED, USED SCREEN)	2	1/21/88 0:00:00	MRS	ELEM_A-L
1227	fe_1	IRON (Fe) FOIL (SCRAPED, 90 TOA, ION ETCH: 5 KeV, 10 mA, 3 MIN)	10	12/5/86 0:00:00	MRS	ELEM_A-L
1228	fe_1a	IRON (Fe) SHEET (90 DEG TOA, ION ETCHED AT 4 KV FOR 3 MIN)	1	6/30/88 0:00:00	MRS	ELEM_A-L
1229	fe_1b	IRON (Fe) FOIL (SCRAPED, 90 TOA, 90 DEG ION ETCH: 5 KeV, 10 mA, 3 MIN)	1	12/5/86 0:00:00	MRS	ELEM_A-L
1230	f_li_1	LITHIUM FLUORIDE (LiF) POWDER (90 TOA, 1 MM FROM SCREEN, FRESH GROUND)	3	7/8/88 0:00:00	MRS	ELEM_A-L



Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
1231	ga_1	GALLIUM (Ga) SHOT FRESHLY CUT & ETCHED UNTIL SURFACE MELTED)	11	6/12/87 0:00:00	MRS	ELEM_A-L
1232	gd_1	GADOLINIUM (Gd) FOIL (SCRAPED, 90 TOA, ION ETCH: 5 KeV, 10 mA, 1 MIN)	8	12/5/86 0:00:00	MRS	ELEM_A-L
1233	gd_1a	GADOLINIUM (Gd) SHEET (90 TOA, FILED & ETCHED 3 KeV, 10 mA, 5 MIN)	1	1/15/88 0:00:00	MRS	ELEM_A-L
1234	gd_1b	GADOLINIUM (Gd) SHEET (90 TOA, FILED & ION ETCHED 3 KeV, 10 mA, 5 MIN)	1	1/15/88 0:00:00	MRS	ELEM_A-L
1235	gd_1c	GADOLINIUM (Gd) SHEET (90 TOA, FILED & ETCHED (3 KeV, 10 mA, 5 MIN)	1	1/15/88 0:00:00	MRS	ELEM_A-L
1236	ge_1	GERMANIUM (Ge) WAFER (SCRAPED, 90 TOA, ION ETCH: 5 KeV, 10 mA, 5 MIN)	15	12/7/86 0:00:00	MRS	ELEM_A-L
1237	hf_1	HAFNIUM (Hf) SPONGE (95%) FILED, 90 TOA, ETCHED: 5 KeV, 10 mA, 10 MIN	11	4/23/87 0:00:00	MRS	ELEM_A-L
1238	hf_2	HAFNIUM (Hf) SPONGE, (95%) 90 TOA, FILED & ETCHED: 5 KeV, 10 mA, 10 MIN	1	4/24/87 0:00:00	MRS	ELEM_A-L
1239	hg_1	MERCURY (Hg) BEAD (LIGHTLY ETCHED, "90 DEG" TOA)	9	12/12/86 0:00:00	MRS	ELEM_A-L
1240	ho_1	HOLMIUM (Ho) SHEET (35 TOA, SCRAPED & ETCHED AT 4 KeV FOR 3 MIN	9	10/20/87 0:00:00	MRS	ELEM_A-L
1241	ho_2	HOLMIUM (Ho) SHEET (35 TOA, FILED & ETCHED 3 KeV, 10 mA, 10 MIN)	2	1/14/88 0:00:00	MRS	ELEM_A-L
1242	ho_2a	HOLMIUM (Ho) SHEET (35 TOA, FILED & ETCHED 3 KeV, 10 mA, 10 MIN)	1	1/14/88 0:00:00	MRS	ELEM_A-L
1243	in_1	INDIUM (In) FOIL (90 TOA, EXPOSED BULK, ION ETCHED: 4 KeV, 1 MIN)	11	11/27/86 0:00:00	MRS	ELEM_A-L
1244	in_1a	INDIUM (In) FOIL (90 TOA, FRESH CUT, ION ETCHED: 4 KeV, 30 SEC)	1	11/29/86 0:00:00	MRS	ELEM_A-L
1245	ir_1	IRIDIUM (Ir) WIRE (ETCHED 3 KeV, 10 mA, 5 MIN)	6	1/15/88 0:00:00	MRS	ELEM_A-L
1246	ir_1a	IRIDIUM (Ir) WIRE (ION ETCHED 3 MIN AT 4 KeV, 10 mA, 90 DEG TOA)	1	9/3/87 0:00:00	MRS	ELEM_A-L
1247	i_k_1	Potassium Iodide (KI) FRESHLY CLEAVED IN AIR	11	10/12/85 0:00:00	MRS	ELEM_A-L
1248	i_k_1a	Potassium Iodide (KI) FRESHLY CLEAVED IN AIR	1	10/12/85 0:00:00	MRS	ELEM_A-L
1249	i_k_1b	Potassium Iodide (KI) FRESHLY CLEAVED IN AIR	1	10/13/85 0:00:00	MRS	ELEM_A-L
1250	kr_ns	Krypton (Kr) implanted in graphite, 10 min etch	3	3/10/94 0:00:00	MRS	ELEM_A-L
1251	kr_ws	Krypton (Kr) implanted in graphite, 10 min etch 90 deg TOA	1	3/10/94 0:00:00	MRS	ELEM_A-L
1252	k_br_1	POTASSIUM BROMIDE (KBr) CRYSTAL (17 HR IN VAC, CLEAVED IN AIR, 90 TOA)	3	12/15/86 0:00:00	MRS	ELEM_A-L
1253	k_br_2	POTASSIUM BROMIDE (KBr) CRYSTAL (17 HR IN VAC, CLEAVED IN AIR, 90 TOA)	9	12/15/86 0:00:00	MRS	ELEM_A-L
1254	k_i_1	Potassium Iodide (KI) FRESHLY CLEAVED IN AIR	11	10/12/85 0:00:00	MRS	ELEM_A-L
1255	k_i_1a	Potassium Iodide (KI) FRESHLY CLEAVED IN AIR	1	10/12/85 0:00:00	MRS	ELEM_A-L
1256	k_i_1b	Potassium Iodide (KI) FRESHLY CLEAVED IN AIR	1	10/13/85 0:00:00	MRS	ELEM_A-L
1257	k_i_2	IODINE in KI Crystal (KI) (90 TOA, FRESHLY CLEAVED, USED SCREEN)	2	1/21/88 0:00:00	MRS	ELEM_A-L
1258	la2o3_1	LANTHANUM OXIDE (La2O3) POWDER on DST, 35 DEG TOA (no mesh)	9	6/26/87 0:00:00	MRS	ELEM_A-L
1259	la2o3_2	LANTHANUM OXIDE (La2O3 on In FOIL, 35 DEG TOA)	8	7/17/87 0:00:00	MRS	ELEM_A-L
1260	li_1	Lithium (Li) Hydroxide (Xh2o) [1 Mm From Screen](90 Deg Toa, Freshly Ground, Thick Press On Tape)	4	6/15/88 0:00:00	MRS	ELEM_A-L
1261	li_f_1	LITHIUM FLUORIDE (LiF) POWDER (90 TOA, 1 MM FROM SCREEN, FRESH GROUND)	3	7/8/88 0:00:00	MRS	ELEM_A-L
1262	li_oh_1	LITHIUM HYDROXIDE (LiOH-xH2O) (on DST, 1 MM FROM SCREEN, 90 TOA, GROUND)	4	6/15/88 0:00:00	MRS	ELEM_A-L
1263	li_oh_2	LITHIUM HYDROXIDE (LiOH) POWDER (On In FOIL, NO SCREEN, 90 DEG TOA)	4	2/9/88 0:00:00	MRS	ELEM_A-L
1264	lu_1	LUTETIUM (Lu) CHUNK (35 DEG TOA, FILED & CONTINUOUSLY ION ETCHED)	7	1/9/88 0:00:00	MRS	ELEM_A-L
1265	lu_1a	Lutetium (Lu) Chunk (35 Deg Toa) Filed And Continuously Ion Etched At 1.5keV, 0.1ma	1	1/9/88 0:00:00	MRS	ELEM_A-L
1266	lu_1b	LUTETIUM (Lu) CHUNK (35 TOA, FILED & ION ETCHED (4 KeV, 10 mA, 5 MIN)	1	1/10/88 0:00:00	MRS	ELEM_A-L
1267	lu_1c	LUTETIUM (Lu) CHUNK (35 TOA, FILED & ION ETCHED 4 KeV, 10 mA FOR 5 MIN)	2	1/10/88 0:00:00	MRS	ELEM_A-L
1268	lu_1d	LUTETIUM (Lu) CHUNK (35 TOA, FILED & ION ETCHED 4 KeV, 10 mA FOR 5 MIN)	1	1/10/88 0:00:00	MRS	ELEM_A-L
1269	lu_2	LUTETIUM (Lu) FRAGMENT (35 TOA, CONTINUOUS ION ETCHING: 1.0 KeV)	4	9/24/87 0:00:00	MRS	ELEM_A-L
1270	lu_2a	LUTETIUM (Lu) FRAGMENT (35 TOA, WITH CONTINUOUS ION ETCHING: 1.5 KeV)	1	9/24/87 0:00:00	MRS	ELEM_A-L
1271	mg_1	MAGNESIUM (Mg) RIBBON (SCRAPED & ION ETCH: 5 KeV, 10 mA, 5 MIN)	12	12/4/86 0:00:00	MRS	ELEM_M-Z

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
1272	mg_1a	MAGNESIUM (Mg) RIBBON (SCRAPED & ION ETCH: 5 KeV, 10 mA, 3 MIN)	5	12/5/86 0:00:00	MRS	ELEM_M-Z
1273	mn_1	MANGANESE (Mn) FLAKE (FRESH EXPOSED BULK, 90 TOA, ETCHED 3 MIN AT 5 KeV)	13	4/20/87 0:00:00	MRS	ELEM_M-Z
1274	mo_1	MOLYBDENUM (Mo) FOIL (90 DEG TOA, ION ETCHED: 4 KeV, 1 MIN)	9	12/1/86 0:00:00	MRS	ELEM_M-Z
1275	mo_1a	MOLYBDENUM (Mo) FOIL (90 DEG TOA, ION ETCHED: 4 KeV, 1 MIN)	1	12/1/86 0:00:00	MRS	ELEM_M-Z
1276	na_cl_1	SODIUM CHLORIDE (NaCl) CRYSTAL (24 HR IN VAC. CLEAVED IN AIR, 90 TOA)	18	12/15/86 0:00:00	MRS	ELEM_M-Z
1277	nb_1	NIOBIUM (Nb) BAR (90 DEG TOA, 90 DEG ETCHING: 5 KeV, 10 mA)	10	12/2/86 0:00:00	MRS	ELEM_M-Z
1278	nb_1a	NIOBIUM (Nb) BAR (90 DEG TOA, 90 DEG ETCHING: 5 KeV, 10 mA)	1	12/3/86 0:00:00	MRS	ELEM_M-Z
1279	nd_1	NEODYMIUM (Nd) CHIP (90 DEG TOA, FILED, ION ETCHED)	8	6/23/88 0:00:00	MRS	ELEM_M-Z
1280	nd_1a	NEODYMIUM (Nd) CHIP (CONT ETCH, 90 TOA, FILED, IN VAC 12h, ETCHED AGAIN)	6	6/24/88 0:00:00	MRS	ELEM_M-Z
1281	nd_1b	NEODYMIUM (Nd) CHIP (CONT. ETCH, 90 TOA, FILED, IN VAC 12h, ETCHED AGAIN)	1	6/24/88 0:00:00	MRS	ELEM_M-Z
1282	ni_1	NICKEL (Ni) FOIL (90 TOA, ION ETCHED: 5 KeV, 10 mA, 6 MIN)	9	11/15/86 0:00:00	MRS	ELEM_M-Z
1283	ni_1a	NICKEL (Ni) FOIL (90 TOA, ION ETCHED: 5 KeV, 10 mA, 6 MIN)	1	11/18/86 0:00:00	MRS	ELEM_M-Z
1284	ni_2	NICKEL (Ni) FILM (90 DEG TOA, 90 DEG ION ETCH: 2 KeV, 10 mA, 3 MIN)	7	3/14/87 0:00:00	MRS	ELEM_M-Z
1285	ni_3	NICKEL FOIL (Ni) (ETCHED 10 min at 3KV & KEPT AT 10(-9) 3 DAYS)	5	11/8/86 0:00:00	MRS	ELEM_M-Z
1286	n_b_1	Nitrogen (N) as BORON NITRIDE (BN) (90 TOA, ETCHED 4 KeV, 10 mA, 2 MIN)	15	12/21/86 0:00:00	MRS	ELEM_M-Z
1287	n_b_2	Nitrogen (N) in white BORON NITRIDE (BN) (45 TOA, SCREEN, EXPOSED BULK)	5	7/15/87 0:00:00	MRS	ELEM_M-Z
1288	n_b_3	Nitrogen (N) in BORON NITRIDE (BN) (45 TOA, SCREEN, EXPOSED BULK)	2	7/15/87 0:00:00	MRS	ELEM_M-Z
1289	o_k2cro4	K2CrO4 CRYSTAL (EXPOSED BULK)	1	7/17/87 0:00:00	MRS	ELEM_M-Z
1290	o_lioh_1	LITHIUM HYDROXIDE (LiOH-xH2O) (on DST, 1 MM FROM SCREEN, 90 TOA, GROUND)	4	6/15/88 0:00:00	MRS	ELEM_M-Z
1291	pb_1	LEAD (Pb) PELLETT (90 DEG TOA, EXPOSED BULK, ION ETCHED: 5KeV,10min)	13	12/1/86 0:00:00	MRS	ELEM_M-Z
1292	pd_02	PALLADIUM (Pd) FILM (90 DEG TOA, ION ETCHED AT 4 KeV FOR 10 MIN)	2	7/10/87 0:00:00	MRS	ELEM_M-Z
1293	pd_1	PALLADIUM (Pd) FILM (90 DEG TOA, 90 DEG ION ETCH: 2 KeV, 10 mA, 3 MIN)	10	3/11/87 0:00:00	MRS	ELEM_M-Z
1294	pr_1	PRASEIODYMIUM (Pr) SHEET (90 TOA, SCRAPPED UNDER CYCLOHEXANE, ION ETCHED)	1	1/19/88 0:00:00	MRS	ELEM_M-Z
1295	pr_1a	PRASEIODYMIUM (Pr) SHEET (90 TOA, SCRAPPED UNDER CYCLOHEXANE, ION ETCHED)	6	1/19/88 0:00:00	MRS	ELEM_M-Z
1296	pr_1b	PRASEIODYMIUM (Pr) SHEET (90 TOA, SCRAPPED UNDER CYCLOHEXANE, ION ETCHED)	1	1/19/88 0:00:00	MRS	ELEM_M-Z
1297	pr_1c	PRASEIODYMIUM (Pr) SHEET (90 TOA, SCRAPPED UNDER CYCLOHEXANE, ION ETCHED)	2	1/20/88 0:00:00	MRS	ELEM_M-Z
1298	pr_1d	PRASEIODYMIUM (Pr) SHEET (90 TOA, SCRAPPED UNDER CYCLOHEXANE, ION ETCHED)	1	1/20/88 0:00:00	MRS	ELEM_M-Z
1299	pt_1	PLATINUM (Pt) FOIL (90 TOA, ION ETCHED: 5 KeV, 10 mA, 2 MIN)	4	11/15/86 0:00:00	MRS	ELEM_M-Z
1300	pt_1a	PLATINUM (Pt) FOIL (90 TOA, ION ETCHED: 5 KeV, 10mA, 2 MIN)	1	11/18/86 0:00:00	MRS	ELEM_M-Z
1301	pt_1b	PLATINUM (Pt) FOIL (90 TOA, ION ETCHED: 5 KeV, 10mA, 2 MIN)	1	11/18/86 0:00:00	MRS	ELEM_M-Z
1302	p_1	PHOSPHORUS (P) (35 DEG TOA, ION ETCHED)	2	7/5/88 0:00:00	MRS	ELEM_M-Z
1303	p_2	PHOSPHORUS (P) CHIP (90 DEG TOA, ION ETCHED AT 3 KV FOR 5 MIN)	1	7/6/88 0:00:00	MRS	ELEM_M-Z
1304	rb_oac_1	RUBIDIUM ACETATE (RbOAc) 90 TOA, FRESHLY GROUND, 1 MM FROM SCREEN	4	6/16/88 0:00:00	MRS	ELEM_M-Z
1305	re_1	RHENIUM (Re) RIBBON (90 DEG TOA, 90EG ION ETCH: 5 KeV, 10 mA, 3 MIN)	9	12/6/86 0:00:00	MRS	ELEM_M-Z
1306	re_1a	RHENIUM (Re) RIBBON (90 DEG TOA, ION ETCHED AT 3 KV FOR 5 MIN)	1	7/6/88 0:00:00	MRS	ELEM_M-Z
1307	rh_1	RHODIUM (Rh) ON ALUMINUM (90 TOA, ION ETCHED: 5 KeV, 10 mA, 1 MIN)	11	12/5/86 0:00:00	MRS	ELEM_M-Z
1308	ru_1	RUTHENIUM (Ru) POWDER on DST (GROUNDED, 90 DEG TOA & ETCHED)	10	12/9/86 0:00:00	MRS	ELEM_M-Z
1309	sb_1	ANTIMONY (Sb) CHIP (SCRAPED, 90 TOA, ION ETCH: 5 KeV, 10 mA, 7 MIN)	9	12/8/86 0:00:00	MRS	ELEM_M-Z
1310	sc_1	SCANDIUM (Sc) TURNING (ION ETCHED 10 MIN AT 4 KeV, 10 mA, 90 DEG TOA)	9	9/2/87 0:00:00	MRS	ELEM_M-Z
1311	sc_2	SCANDIUM (Sc) TURNING (CONTINUOUS ETCHING AT 1 KeV, 0.3 mA, 90 DEG TOA)	3	9/3/87 0:00:00	MRS	ELEM_M-Z
1312	se_1	SELENIUM (Se) PELLETT (SCRAPED, 90 TOA, ION ETCH: 10 mA, 4 KeV, 20 SEC)	3	12/13/86 0:00:00	MRS	ELEM_M-Z

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
1313	se_1a	SELENIUM (Se) PELLETT (SCRAPED, 90 TOA, ION ETCH: 10 mA, 4 KeV, 20 SEC)	3	12/13/86 0:00:00	MRS	ELEM_M-Z
1314	se_1b	SELENIUM (Se) PELLETT (SCRAPED, 90 TOA, ION ETCH: 10 mA, 4 KeV, 20 SEC)	6	12/13/86 0:00:00	MRS	ELEM_M-Z
1315	si_1	SILICON (Si) WAFER (90 DEG TOA, ION ETCHED: 3 KeV, 2 MIN)	11	11/26/86 0:00:00	MRS	ELEM_M-Z
1316	si_1a	ION ETCH EFFECT ON FWHM OF Si (2p) (90 DEG TOA, 100 ANG ION ETCH)	1	6/20/88 0:00:00	MRS	ELEM_M-Z
1317	si_2p_hq	Silicon (UnDoped): Si(2p3)&(2p1),BE Cu(2p3)=932.68 gift from Suzuki-san	1	3/4/94 0:00:00	MRS	ELEM_M-Z
1318	si_vb_hq	Silicon (Un-doped): Valence Bands, 0.05 eV/step	1	3/6/94 0:00:00	MRS	ELEM_M-Z
1319	si_ws_hq	Silicon (Un-Doped): 0.70 eV/step	1	3/6/94 0:00:00	MRS	ELEM_M-Z
1320	sm2_o3_1	SAMARIUM (Sm) OXIDE, PRESSED ONTO In FOIL	7	6/19/87 0:00:00	MRS	ELEM_M-Z
1321	sm2_o3_2	SAMARIUM (Sm) OXIDE (In FOIL, 35 DEG TOA)	8	7/17/87 0:00:00	MRS	ELEM_M-Z
1322	sm_1	SAMARIUM (Sm) SHEET (FILED & ION ETCHED 3 KeV, 10 mA, 5 MIN)	3	1/16/88 0:00:00	MRS	ELEM_M-Z
1323	sm_1a	SAMARIUM (Sm) SHEET (90 TOA FILED & ION ETCHED 3 KeV, 10 mA, 5 MIN)	1	1/16/88 0:00:00	MRS	ELEM_M-Z
1324	sn_1	TIN (Sn) FOIL (90 DEG TOA, POLISHED, ION ETCHED: 4 KeV, 3 MIN)	11	11/28/86 0:00:00	MRS	ELEM_M-Z
1325	sr_co3_1	STRONTIUM CARBONATE (SrCO3) 90 DEG TOA, PRESSED ON In FOIL, USING SCREEN	3	1/26/88 0:00:00	MRS	ELEM_M-Z
1326	s_1	SULFUR (S) CHIP (EXPOSED BULK, Natural Crystal, 90 DEG TOA)	10	12/14/86 0:00:00	MRS	ELEM_M-Z
1327	ta_1	TANTALUM (Ta) BAR (90 DEG TOA, 90 DEG ETCH: 5 KeV, 10 mA)	10	12/2/86 0:00:00	MRS	ELEM_M-Z
1328	tb_1	TERBIUM (Tb) CHUNK (90 DEG TOA, FILED, ION ETCHED AT 3 KV FOR 5 MIN)	5	6/20/88 0:00:00	MRS	ELEM_M-Z
1329	tb_1a	TERBIUM (Tb) CHUNK (90 DEG TOA, FILED, ION ETCHED AT 3 KV FOR 5 MIN)	2	6/20/88 0:00:00	MRS	ELEM_M-Z
1330	te_1	TELLURIUM (Te) LUMP (EXPOSED BULK 90 TOA, ETCHED 3 MIN AT 5 KeV 10 mA)	10	4/20/87 0:00:00	MRS	ELEM_M-Z
1331	ti_1	TITANIUM (Ti) FOIL (SCRAPED, 90 DEG TOA, ION ETCH: 5 KeV, 10 mA, 3 MIN)	11	12/4/86 0:00:00	MRS	ELEM_M-Z
1332	ti_1b	TITANIUM (Ti) FOIL (SCRAPED, 90 DEG TOA, ION ETCH: 5 KeV, 10 mA, 3 MIN)	1	12/5/86 0:00:00	MRS	ELEM_M-Z
1333	tl_1	THALLIUM (Tl) INGOT (90 TOA, Fresh Bulk, ION ETCHED 2 MIN 2 KeV, 10 mA)	12	4/21/87 0:00:00	MRS	ELEM_M-Z
1334	tm_1	THULIUM (Tm) FRAGMENT (35 TOA, SCRAPED & ETCHED AT 4 KeV FOR 3 MIN)	6	9/24/87 0:00:00	MRS	ELEM_M-Z
1335	tm_1b	THULIUM (Tm) CHUNK (35 TOA, FILED & ION ETCHED: 4 KeV, 10 mA FOR 5 MIN)	2	1/11/88 0:00:00	MRS	ELEM_M-Z
1336	tm_1c	THULIUM (Tm) CHUNK (35 TOA, FILED & ETCHED 4 KeV, 10 mA FOR 5 MIN)	2	1/11/88 0:00:00	MRS	ELEM_M-Z
1337	v_1	VANADIUM (V) TURNING (90 TOA, SCRAPED & ION ETCHED 5 MIN)	14	4/18/87 0:00:00	MRS	ELEM_M-Z
1338	w_1	TUNGSTEN (W) SHEET (90 DEG TOA, ION ETCHED AT 3 KV FOR 5 MIN)	1	7/4/88 0:00:00	MRS	ELEM_M-Z
1339	yb_1	YTTERBIUM (Yb) SHEET (35 DEG TOA, SCRAPED AND ION ETCHED)	11	10/5/87 0:00:00	MRS	ELEM_M-Z
1340	y_1	YTTRIUM (Y) ROD (SCRAPED, 90 TOA, ION ETCH: 10 MIN, 5 KeV, 10 mA)	10	12/11/86 0:00:00	MRS	ELEM_M-Z
1341	y_2	YTTRIUM (Y) TURNING (35 DEG TOA, ION ETCHED 15 MIN AT 4 KeV)	1	7/13/87 0:00:00	MRS	ELEM_M-Z
1342	zn_1	ZINC (Zn) INGOT (90 DEG TOA, FRESH CUT, ION ETCHED: 4 KeV, 1 MIN)	14	11/29/86 0:00:00	MRS	ELEM_M-Z
1343	zr_1	ZIRCONIUM (Zr) BLOCK (90 DEG TOA, ION ETCH: 5 KeV, 10 mA, 6 MIN)	8	12/7/86 0:00:00	MRS	ELEM_M-Z
1344	zr_1a	ZIRCONIUM (Zr) BLOCK (90 DEG TOA, ION ETCH: 5 KeV, 10 mA, 6 MIN)	1	12/7/86 0:00:00	MRS	ELEM_M-Z
1345	zr_1b	ZIRCONIUM (Zr) BLOCK (90 DEG TOA, ION ETCH: 5 KeV, 10 mA, 6 MIN)	2	12/7/86 0:00:00	MRS	ELEM_M-Z
1346	sio2_er1	1100 ANG THERMALLY GROWN SiO2 (2KeV, 10mA)	2	8/26/86 0:00:00	DPR	ETCHRATE
1347	sio2_er2	Etch Rate Check: 1100 ANG THERMALLY GROWN SiO2 (2KeV, 10mA)	2	8/26/86 0:00:00	DPR	ETCHRATE
1348	sio2_er3	1010 ANGSTROMS OF SiO2/Si 3 KeV, 10 mA, 4x2 RASTER, 1.1x10-7 TORR (Ar)	2	8/25/87 0:00:00	DPR	ETCHRATE
1349	sio2_er4	ETCh Rate Measurement On 1010 Ang SiO2/si 3kev, 10ma, 4x2 Raster, 1.2x10-7 Torr, 35 Deg Aoi	2	8/26/87 0:00:00	DPR	ETCHRATE
1350	sio2_er5	Etch Rate Measurement On 1010 Ang SiO2/si 2kev, 10ma, 4x2 Raster, 1.4x10-7 Torr, 35 Deg Aoi	2	8/26/87 0:00:00	DPR	ETCHRATE
1351	nomex	NOMEX FROM DUPONT (AS RECEIVED)	6	11/5/85 0:00:00	MRS	FABRICS
1352	tx_309	TEXWIPE CLOTH (TX-309) FOR CLEAN ROOMS (100% COTTON, AS RECEIVED)	6	10/13/85 0:00:00	MRS	FABRICS
1353	sensor3a	#325: black coating on coil (as received)	4	6/7/91 0:00:00	MRS	GAS-SNSR

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
1354	sensor3b	#325 (black coil, ACTIVE) top of shiny post	1	6/24/91 0:00:00	MRS	GAS-SNSR
1355	sensor3c	#325 (BLACK COIL, ACTIVE) shiny strip on coil	1	6/24/91 0:00:00	MRS	GAS-SNSR
1356	sensor3d	#325 (black coil, ACTIVE) normal shiny base area	1	6/24/91 0:00:00	MRS	GAS-SNSR
1357	sensor4a	#325 (passive unit) gray area on base under coil	7	6/8/91 0:00:00	MRS	GAS-SNSR
1358	sensor4b	#325 Green-gray coating on coil (passive part)	1	6/21/91 0:00:00	MRS	GAS-SNSR
1359	sensor4c	#325 (passive) gray area on base (as rec'd_	1	6/21/91 0:00:00	MRS	GAS-SNSR
1360	sensor4d	#325 (green-gray Passive) normal area on baseplate	1	6/24/91 0:00:00	MRS	GAS-SNSR
1361	sensor4e	#325 (green-gray passive) "sponge" on top of post	1	6/24/91 0:00:00	MRS	GAS-SNSR
1362	sensor4f	#325 (green-gray passive) exposed wire coil-post	1	6/24/91 0:00:00	MRS	GAS-SNSR
1363	sensor5a	#336 (ACTIVE) top of porous black coil (as rec'd)	7	6/24/91 0:00:00	MRS	GAS-SNSR
1364	sensor5b	#336 (ACTIVE, black coil) black lines on base	1	6/24/91 0:00:00	MRS	GAS-SNSR
1365	sensor6a	#336 (green coil PASSIVE) as rec'd top of coil	2	6/24/91 0:00:00	MRS	GAS-SNSR
1366	sensor6b	#336 (green PASSIVE) dark area on base	1	6/25/91 0:00:00	MRS	GAS-SNSR
1367	sensor7a	#325 Active (black coil, after 100 Ang etch)	1	7/16/91 0:00:00	MRS	GAS-SNSR
1368	sensor7b	#325 Active (black coil, 400 Ang etch)	3	7/16/91 0:00:00	MRS	GAS-SNSR
1369	sensor_1	#1 (CO sensor): Aged 1 week, Test Results: CO=21.3 H2=3.0 (4.0)	1	4/10/92 0:00:00	MRS	GAS-SNSR
1370	sensor_2	#2 (CO sensor): Aged 1 week, Test Results: CO=21.5 H2=15.5 (4.2)	1	4/10/92 0:00:00	MRS	GAS-SNSR
1371	al2o3_01	SAPPHIRE (Al2O3) AS RECEIVED (35 DEG TOA) NO SCREEN, INSIDE CLIP	4	9/22/87 0:00:00	MRS	GLASS
1372	borosil1	Soft Borosilicate Glass (Asahi, as rec'd, 90 TOA)	8	5/16/94 0:00:00	MRS	GLASS
1373	ca_p_01	Attempted synthesis of 10:85:5 CaF2:P2O5:Al2O3 (fresh bulk 55 TOA mesh)	8	12/14/93 0:00:00	MRS	GLASS
1374	ca_p_06	Attempted synthesis of 40:60 CaF2:P2O5 (fresh bulk, 55 TOA, mesh)	8	12/15/93 0:00:00	MRS	GLASS
1375	ca_p_al1	Attempted synthesis: 10:85:5 CaF2:P2O5:Al2O3 (fresh bulk, 55 TOA, mesh)	8	12/14/93 0:00:00	MRS	GLASS
1376	ca_p_al2	Attempted synthesis: 30:65:5 CaF2:P2O5:Al2O3 (fresh bulk, 55 TOA, mesh)	8	12/14/93 0:00:00	MRS	GLASS
1377	ca_p_al3	Attempted synthesis: 50:45:5 CaF2:P2O5:Al2O3 (fresh bulk, 55 TOA, mesh)	8	12/15/93 0:00:00	MRS	GLASS
1378	ca_p_al4	Attempted synthesis: 60:35:5 CaF2:P2O5:Al2O3 (IPA cleaned 35 TOA mesh)	8	12/15/93 0:00:00	MRS	GLASS
1379	cs_01	25:75 Cs2O:SiO2 ion etched 1min 3KV (with mesh)	6	12/13/93 0:00:00	MRS	GLASS
1380	cs_02	Synthesis of 25:75 Cs2O:SiO2 (exposed bulk, 35 TOA, mesh)	5	11/10/93 0:00:00	MRS	GLASS
1381	CS_02_E	Synthesis of 25:75 Cs2O:SiO2 (ion etched 1min 3KV, with mesh)	5	11/16/93 0:00:00	MRS	GLASS
1382	cs_na_02	18:7:75 Na2O:Cs2O:SiO2 ion etched 1 min 3KV (mesh)	7	12/13/93 0:00:00	MRS	GLASS
1383	cs_na_03	14:11:75 Na2O:Cs2O:SiO2 ion etched 1 min 3KV (mesh)	7	12/14/93 0:00:00	MRS	GLASS
1384	cs_na_04	12.5:12.5:75 Na2O:Cs2O:SiO2 ion etched 1 min 3KV (	7	12/14/93 0:00:00	MRS	GLASS
1385	cs_na_05	11:14:75 Na2O:Cs2O:SiO2 ion etched 1 min 3KV (mesh)	7	12/13/93 0:00:00	MRS	GLASS
1386	cs_na_06	7:18:75 Na2O:Cs2O:SiO2 ion etched 1 min 3KV (mesh)	7	12/20/93 0:00:00	MRS	GLASS
1387	cs_na_07	7:18:75 Cs2O:Na2O:SiO2 (2nd synthesis) exposed bulk, mesh	7	2/21/94 0:00:00	MRS	GLASS
1388	cs_na_08	11:14:75 Cs2O:Na2O:SiO2 (2nd synthesis attempt) exposed bulk, Mesh	7	2/21/94 0:00:00	MRS	GLASS
1389	cs_na_09	12.5:12.5:75 Cs2o:Na2O:SiO2 (2nd synthesis attempt) exposed bulk, Mesh	7	2/22/94 0:00:00	MRS	GLASS
1390	cs_na_10	14:11:75 Cs2O:Na2O:SiO2 (2nd synthesis attempt) exposed bulk, Mesh	7	2/22/94 0:00:00	MRS	GLASS
1391	cs_na_11	18:7:75 Cs2O:Na2O:SiO2 (2nd synthesis attempt) exposed bulk, Mesh	7	2/22/94 0:00:00	MRS	GLASS
1392	cs_na_12	25:75 Na2O:SiO2 (2nd synthesis attempt) exposed bulk, Mesh	6	2/22/94 0:00:00	MRS	GLASS
1393	ge_pb_01	Product from reacting: PbO:GeO2:PbF2 = 20:50:30 (mesh)	7	3/10/93 0:00:00	MRS	GLASS
1394	ge_pb_02	Attempted Synthesis of PbO:GeO2:PbF2 30:50:20 (exposed bulk)	7	3/12/93 0:00:00	MRS	GLASS

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
1395	ge_pb_03	Attempted synthesis of PbO:GeO2:PbF2 40:50:10 (exposed bulk)	7	3/12/93 0:00:00	MRS	GLASS
1396	ge_pb_04	Synthesis of PbO:GeO2 50:50 (exposed bulk)	7	3/12/93 0:00:00	MRS	GLASS
1397	ge_pb_05	Product from reacting: PbO:GeO2:PbF2 = 0:80:20 (exposed bulk, mesh)	7	3/10/93 0:00:00	MRS	GLASS
1398	ge_pb_06	Attempted synthesis of PbO:GeO2:PbF2 10:70:20 (exposed bulk)	7	3/12/93 0:00:00	MRS	GLASS
1399	ge_pb_07	Product of reacting: PbO:GeO2:PbF2 = 20:60:20 (exposed bulk, mesh)	7	3/11/93 0:00:00	MRS	GLASS
1400	ge_pb_08	Product of reacting: PbO:GeO2:PbF2 = 40:40:20 (mesh)	7	3/11/93 0:00:00	MRS	GLASS
1401	k_01	Synthesis of 25:75 K2O:SiO2 (fresh exposed bulk, 35 TOA, mesh)	5	11/10/93 0:00:00	MRS	GLASS
1402	K_01_E	Synthesis of 25:75 K2O:SiO2 (ion etched bulk, with mesh)	6	11/15/93 0:00:00	MRS	GLASS
1403	k_02	25:75 K2O:SiO2 (2nd synthesis attempt) exposed bulk, Mesh	6	2/22/94 0:00:00	MRS	GLASS
1404	li2oteo2	Li2O:TeO2 30:70 freshly exposed bulk	4	3/15/93 0:00:00	MRS	GLASS
1405	li_01	Synthesis of 25:75 Li2O:SiO2 (fresh exposed bulk, 35 TOA, mesh)	5	11/10/93 0:00:00	MRS	GLASS
1406	LI_01_E	Synthesis of 25:75 Li2O:SiO2 (ion etched bulk, with mesh)	6	11/12/93 0:00:00	MRS	GLASS
1407	li_02	25:75 Li2O:SiO2 (2nd synthesis attempt) exposed bulk, Mesh	6	2/22/94 0:00:00	MRS	GLASS
1408	na2oteo2	Na2O:TeO2 30:70 freshly exposed bulk	4	3/15/93 0:00:00	MRS	GLASS
1409	na2si3o7	Water glass (Na2Si3O7) 5% soln evap on SS, mesh	7	6/16/94 0:00:00	MRS	GLASS
1410	na_01	Synthesized 10:90 Na2O:SiO2 (fresh bulk, mesh, 35 TOA)	5	11/9/93 0:00:00	MRS	GLASS
1411	NA_01_E	Synthesis of 10:90 Na2O:SiO2 (exposed bulk, mesh, etched: 1 min 3KV)	6	11/12/93 0:00:00	MRS	GLASS
1412	na_02	Synthesized 15:85 Na2O:SiO2 (before ion etching, mesh)	5	10/22/93 0:00:00	MRS	GLASS
1413	NA_02_E	Synthesized 15:85 Na2O:SiO2 (1 min 3.5KV ion etch, mesh)	5	10/22/93 0:00:00	MRS	GLASS
1414	na_03	Synthesis of 20:80 Na2O:SiO2 (exposed bulk, 35 TOA, mesh)	5	11/9/93 0:00:00	MRS	GLASS
1415	NA_03_E	Synthesis of 20:80 Na2O:SiO2 (exposed bulk, etched 1min 3KV, mesh)	6	11/12/93 0:00:00	MRS	GLASS
1416	na_04	Synthesis of 25:75 Na2O:SiO2 (as rec'd, mesh)	5	10/22/93 0:00:00	MRS	GLASS
1417	na_04_e	Synthesis of 25:75 Na2O:SiO2 (1 min 3.5KV ion etch with mesh)	5	10/22/93 0:00:00	MRS	GLASS
1418	NA_TE_01	Synthesis of 30:70 Na2O:TeO2 (before ion etching, mesh)	5	10/25/93 0:00:00	MRS	GLASS
1419	NA_TE_02	Synthesis of 30:70 Na2O:TeO2 (1 min 3.5KV ion etch with mesh)	5	10/25/93 0:00:00	MRS	GLASS
1420	pbo_glas	PbO glass (?) Japan maker	10	8/13/94 0:00:00	MRS	GLASS
1421	pb_te_07	Product from: 80% TeO2, 16% PbO, 4% PbF2 (as rec'd, 90 TOA, mesh)	9	4/24/92 0:00:00	MRS	GLASS
1422	pb_te_08	Product from: 80% TeO2, 10% PbO, 10% PbF2 (as rec'd, 90 deg TOA, mesh)	9	4/24/92 0:00:00	MRS	GLASS
1423	pb_te_09	Product from: 80% TeO2, 7% PbO, 13% PbF2 (as rec'd, 90 deg TOA, mesh)	9	4/24/92 0:00:00	MRS	GLASS
1424	pyrex_01	Pyrex (Iwaki, fresh bulk) -55 TOA, mesh,	7	1/17/94 0:00:00	MRS	GLASS
1425	pyrex_02	Pyrex (Iwaki, fresh bulk) -55 TOA, mesh,	6	1/17/94 0:00:00	MRS	GLASS
1426	sio2_01	THERMALLY GROWN SiO2 (1100 ANGSTROMS THICK) ON Si	6	10/19/85 0:00:00	MRS	GLASS
1427	soda_01	MICROSCOPE SLIDE FROM VANLABS (VWR) AS RECEIVED CAT. #48300-036 PLAIN, SELECTED	6	11/2/85 0:00:00	MRS	GLASS
1428	soda_02	MICROSCOPE SLIDE FROM VANLABS (VWR) AS RECEIVED CAT. #48300-036 PLAIN, SELECTED	4	11/2/85 0:00:00	MRS	GLASS
1429	soda_03	Soda Lime Glass (position "A"): after leaching	1	5/8/92 0:00:00	MRS	GLASS
1430	zirconia	CUBIC ZIRCONIA (ZrO2) "Glass" Mounted on In FOIL (35 DEG TOA), NO SCREEN	4	9/22/87 0:00:00	MRS	GLASS
1431	al_contr	ALUMINUM FOIL CONTROL SAMPLE (AS RECEIVED)	3	3/16/87 0:00:00	MRS	GLOVE
1432	cot_01	CONTAMINATION FROM FINGER COT (OPAQUE YELLOW "LATEX") ON AL FOIL	1	7/21/88 0:00:00	MRS	GLOVE
1433	finger_1	FINGERPRINT ON ALUMINUM FOIL	2	4/25/88 0:00:00	MRS	GLOVE
1434	glove_01	WHITE TRANSPARENT GLOVE FROM IUCHI TOUCHED TO ALUMINUM FOIL	4	3/19/87 0:00:00	MRS	GLOVE
1435	glove_02	VINYL GLOVE TOUCHED TO ALUMINUM FOIL (THUMB AND MIDDLE FINGER ONLY)	1	6/2/88 0:00:00	MRS	GLOVE

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1436	glove_03	"CR100" GLOVE TOUCHED TO ALUMINUM FOIL (THUMB & MIDDLE FINGER ONLY)	1	6/2/88 0:00:00	MRS	GLOVE
1437	glove_04	CLEAR TRANSPARENT GLOVE FROM IUCHI TOUCHED TO ALUMINUM FOIL	4	3/19/87 0:00:00	MRS	GLOVE
1438	glove_05	LIGHT BROWN TRANSLUCENT GLOVE FROM IUCHI TOUCHED TO ALUMINUM FOIL	4	3/19/87 0:00:00	MRS	GLOVE
1439	glove_06	WHITE TRANSLUCENT GLOVE FROM IUCHI TOUCHED TO ALUMINUM FOIL	4	3/19/87 0:00:00	MRS	GLOVE
1440	glove_07	SEMICONDUCTOR CLEAN ROOM GLOVE FROM TOHOKU UNIV TOUCHED TO ALUMINUM FOIL	3	3/16/87 0:00:00	MRS	GLOVE
1441	glove_08	CONDUCTIVE GLOVE FROM QUALITY RUBBER PRODUCTS TOUCHED TO AL FOIL	3	3/16/87 0:00:00	MRS	GLOVE
1442	glove_09	UNKNOWN GLOVE "E" TOUCHED TO AL FOIL	1	12/1/87 0:00:00	MRS	GLOVE
1443	glove_10	UNKNOWN GLOVE "d" TOUCHED TO AL FOIL	1	12/1/87 0:00:00	MRS	GLOVE
1444	glove_11	UNKNOWN GLOVE "F" TOUCHED TO AL FOIL	1	12/1/87 0:00:00	MRS	GLOVE
1445	glove_12	UNKNOWN GLOVE "G" TOUCHED TO AL FOIL	1	12/2/87 0:00:00	MRS	GLOVE
1446	glove_13	UNKNOWN GLOVE "H" TOUCHED TO AL FOIL	1	12/2/87 0:00:00	MRS	GLOVE
1447	glove_14	UNKNOWN GLOVE "I" TOUCHED TO AL FOIL	1	12/2/87 0:00:00	MRS	GLOVE
1448	glove_15	UNKNOWN GLOVE "J" TOUCHED TO AL FOIL	1	12/2/87 0:00:00	MRS	GLOVE
1449	ltx_flx1	EXTERIOR OF FINTERTIP, FLEXAM LATEX GLOVE (FLOOR/EXAM) PHARMASEAL LABS	5	10/20/85 0:00:00	MRS	GLOVE
1450	ltx_flx2	INTERIOR SURFACE OF FLEXAM LATEX GLOVE FLOOR/EXAM GLOVE (PHARMASEAL LABS)	6	10/20/85 0:00:00	MRS	GLOVE
1451	mold_rel	EASE RELEASE 300 MOLD RELEASE AGENT SMEARED ON A GOLD PLATEN	6	10/13/85 0:00:00	MRS	GLOVE
1452	mpi_1	FINGER SOCK (SAMPLE #1) TOUCHED TO ALUMINUM FOIL (35 DEG TOA, AS RECEIVED)	1	6/2/88 0:00:00	MRS	GLOVE
1453	sock_01	FINGER SOCK TOUCHED TO ALUMINUM FOIL (35 DEG TOA, AS RECEIVED)	1	6/2/88 0:00:00	MRS	GLOVE
1454	vwr_insd	INSIDE FINGERTIP OF POLY GLOVE FROM VWR SCIENTIFICCAT #32915-268, LARGE, MED WEIGHT	7	10/20/85 0:00:00	MRS	GLOVE
1455	vwr_outs	OUTSIDE FINGERTIP OF POLY GLOVE FROM VWR SCIENTIFICCAT #32915-268, LARGE, MED WEIGHT	5	10/20/85 0:00:00	MRS	GLOVE
1456	45sk_090	45 ClkWs rot, 90 AOI to 10:30 pos 160 W	2	4/12/93 0:00:00	MRS	GRAZINGX
1457	45sk_100	45 ClkWs rot, 100 TOA to 10:30 pos 160 W	2	4/12/93 0:00:00	MRS	GRAZINGX
1458	45sk_110	45 ClkWs rot, 110 TOA to 10:30 pos 160 W	2	4/12/93 0:00:00	MRS	GRAZINGX
1459	45sk_140	45 ClkWs rot, 140 TOA to 10:30 pos 160 W	2	4/12/93 0:00:00	MRS	GRAZINGX
1460	45sk_150	45 ClkWs rot, 150 TOA to 10:30 pos 160 W	2	4/12/93 0:00:00	MRS	GRAZINGX
1461	ag_r_000	Angle Mount, 0 deg TOA, etched Ag/PET	1	4/8/93 0:00:00	MRS	GRAZINGX
1462	ag_r_018	Angl Mnt"18"deg ROT (Max Graze) from O TOA, Ag/PET	1	4/8/93 0:00:00	MRS	GRAZINGX
1463	ag_r_160	Angle Mount rotated to near 160 TOA	2	4/12/93 0:00:00	MRS	GRAZINGX
1464	ag_t_035	35 deg TOA, Ag/PET ion etched clean, 160 Watts, Tilt Stage	1	4/8/93 0:00:00	MRS	GRAZINGX
1465	ag_t_070	70 deg TOA, Ag/PET ion etched clean, 160 Watts Tilt Stage	1	4/8/93 0:00:00	MRS	GRAZINGX
1466	ag_t_100	100 deg TOA, Ag/PET ion etched clean, 160 Watts, Tilt Stage	1	4/8/93 0:00:00	MRS	GRAZINGX
1467	ag_t_104	104 deg TOA, Ag/PET ion etched clean, Tilt Stage	4	4/8/93 0:00:00	MRS	GRAZINGX
1468	ag_t_110	110 deg TOA, Ag/PET ion etched clean, 160 Watts, Tilt Stage	1	4/8/93 0:00:00	MRS	GRAZINGX
1469	ag_t_120	120 deg TOA, Ag/PET ion etched clean, 160 Watts, Tilt Stage	1	4/8/93 0:00:00	MRS	GRAZINGX
1470	ag_t_140	True Grazing: 140 TOA, Ag/PET, etched, 160 Watts, Tilt Stage	1	4/8/93 0:00:00	MRS	GRAZINGX
1471	ag_t_141	True Grazing: 2 deg from parallel 141 TOA, Ag/PET, Tilt Stage	1	4/8/93 0:00:00	MRS	GRAZINGX
1472	aoi_000	<25 TOA, "0" AOI, XYZR rot=00,105,00,00 160 W	2	4/12/93 0:00:00	MRS	GRAZINGX
1473	aoi_005	<25 TOA, 5 AOI, XYZR rot=00,90,00,00, 160 W	2	4/12/93 0:00:00	MRS	GRAZINGX
1474	aoi_010	<25 TOA, 10 AOI, XYZR rot=00,75,00,00, 160 W	2	4/12/93 0:00:00	MRS	GRAZINGX
1475	aoi_015	<30 TOA, 15 AOI, XYZR rot=00,60,00,00, 160 W	2	4/12/93 0:00:00	MRS	GRAZINGX
1476	aoi_020	<30 TOA, 20 AOI, XYZR rot=00,45,00,00 160 W	2	4/12/93 0:00:00	MRS	GRAZINGX

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
1477	aoi_025	<30 TOA, 25 AOI, XYZR rot=00,30,00,00 160 W	1	4/12/93 0:00:00	MRS	GRAZINGX
1478	aoi_030	<35 TOA, 30 AOI, XYZR rot=00,15,00,00, 160 W	2	4/12/93 0:00:00	MRS	GRAZINGX
1479	aoi_035	35 TOA, 35 AOI, XYZR rot=00,00,00,00 160 W	1	4/12/93 0:00:00	MRS	GRAZINGX
1480	aoi_050	<35 TOA, 50 AOI, XYZR rot=00,-45,00,00 160 W	2	4/12/93 0:00:00	MRS	GRAZINGX
1481	aoi_070	<25 TOA, 70 AOI, XYZR rot=00,-105,00,00 160 W	2	4/12/93 0:00:00	MRS	GRAZINGX
1482	aoi_080	<20 TOA, 80 AOI, XYZR rot=00,-135,00,00 160 W	2	4/12/93 0:00:00	MRS	GRAZINGX
1483	aoi_090	<20 TOA, 90 AOI, XYZR rot=00,-165,00,00 160 W	2	4/12/93 0:00:00	MRS	GRAZINGX
1484	aoi_100	<20 TOA, 100 AOI, XYZR rot=00,-195,00,00 160 W	2	4/12/93 0:00:00	MRS	GRAZINGX
1485	aoi_110	<15 TOA, 110 AOI, XYZR rot=00,-225,00,00 160 W	2	4/12/93 0:00:00	MRS	GRAZINGX
1486	aoi_120	<15 TOA, 120 AOI, XYZR rot=00,-255,00,00 160 W	2	4/12/93 0:00:00	MRS	GRAZINGX
1487	nacl_grz	Expsd Bulk (IR) NaCl xtal (Side-Graze AOI, 55 TOA) no mesh	17	4/13/93 0:00:00	MRS	GRAZINGX
1488	nptx_090	Angle Mnt nearly Parallel to X, near 90 TOA	2	4/12/93 0:00:00	MRS	GRAZINGX
1489	nptx_100	Angle Mnt nearly Parallel to X, near 100 TOA	2	4/12/93 0:00:00	MRS	GRAZINGX
1490	nptx_110	Angle Mnt nearly Parallel to X, near 110 TOA	2	4/12/93 0:00:00	MRS	GRAZINGX
1491	nptx_120	Angle Mnt nearly Parallel to X, near 120 TOA	2	4/12/93 0:00:00	MRS	GRAZINGX
1492	nptx_130	Angle Mnt nearly Parallel to X, near 130 TOA	2	4/12/93 0:00:00	MRS	GRAZINGX
1493	nptx_140	Angle Mnt nearly Parallel to X, near 140 TOA	2	4/12/93 0:00:00	MRS	GRAZINGX
1494	nptx_150	Angle Mnt nearly Parallel to X, near 150 TOA	2	4/12/93 0:00:00	MRS	GRAZINGX
1495	pwdr_035	5-20u Ta2O5 Pwdr/DST 35 TOA 35 AOI FG 95% parallel	2	4/13/93 0:00:00	MRS	GRAZINGX
1496	pwdr_090	5-20u Ta2O5 Pwdr/DST 90 TOA 25 AOI FG 95% parallel	2	4/13/93 0:00:00	MRS	GRAZINGX
1497	pwdr_100	5-20u Ta2O5 Pwdr/DST 100 TOA 25 AOI FG 95% parallel	2	4/13/93 0:00:00	MRS	GRAZINGX
1498	pwdr_110	5-20u Ta2O5 Pwdr/DST 110 TOA 25 AOI FG 95% parallel	2	4/13/93 0:00:00	MRS	GRAZINGX
1499	pwdr_120	5-20u Ta2O5 Pwdr/DST 120 TOA 25 AOI FG 95% parallel	2	4/13/93 0:00:00	MRS	GRAZINGX
1500	br_csbr1	Cesium Bromide (CsBr) Lump FRESHLY CUT (SOFT AND CLOUDY) no mesh	12	10/13/85 0:00:00	MRS	HALIDE
1501	br_kbr_1	Potassium Bromide (KBr) FRESHLY CLEAVED IN AIR	6	10/12/85 0:00:00	MRS	HALIDE
1502	br_kbr_2	Potassium Bromide (KBr) FRESHLY CLEAVED IN AIR	1	10/13/85 0:00:00	MRS	HALIDE
1503	br_kbr_3	Potassium Bromide (Kbr) Crystal (17 Hr In Vacuum) Freshly Cleaved In Air, 90 Deg Toa	4	12/15/86 0:00:00	MRS	HALIDE
1504	br_kbr_4	Potassium Bromide (Kbr) Crystal (17 Hr In Vacuum) Freshly Cleaved In Air, 90 Deg Toa	10	12/15/86 0:00:00	MRS	HALIDE
1505	cl_cscl1	CESIUM CHLORIDE (CsCl) CRYSTAL FRESHLY EXPOSED SURFACE (mesh)	11	6/13/87 0:00:00	MRS	HALIDE
1506	cl_kcl_1	Potassium Chloride (KCl) FRESHLY CLEAVED IN AIR	5	10/12/85 0:00:00	MRS	HALIDE
1507	cl_kcl_2	Potassium Chloride (KCl) FRESHLY CLEAVED IN AIR	1	10/13/85 0:00:00	MRS	HALIDE
1508	cl_kcl_3	Potassium Chloride (KCl) FRESHLY CLEAVED IN AIR	1	10/12/85 0:00:00	MRS	HALIDE
1509	cl_nacl1	SODIUM CHLORIDE (NaCl) CRYSTAL (24 HR IN VACUUM) FRESHLY CLEAVED IN AIR, 90 DEG TOA	19	12/15/86 0:00:00	MRS	HALIDE
1510	cl_nacl2	Sodium Chloride (NaCl) FRESHLY CLEAVED IN AIR	9	10/12/85 0:00:00	MRS	HALIDE
1511	cucl_1	Cu(I)Cl 99.99% Aldr# 04027AW 3mm plt conduc 90 TOA	10	5/25/94 0:00:00	MRS	HALIDE
1512	f_caf2_1	CALCIUM FLUORIDE (Ca,F) CRYSTAL 90 DEG TOA, FRESHLY EXPOSED BULK	14	12/20/86 0:00:00	MRS	HALIDE
1513	f_caf2_2	Calcium Fluoride (CaF2) FRESHLY CLEAVED IN AIR	9	10/13/85 0:00:00	MRS	HALIDE
1514	f_caf2_3	CALCIUM FLUORIDE (CaF2) (90 DEG TOA, FRESHLY CLEAVED, SCREEN)	2	1/21/88 0:00:00	MRS	HALIDE
1515	f_lif_01	LITHIUM FLUORIDE (LiF) POWDER (90 DEG TOA, 1 MM FROM SCREEN, FRESHLY GROUND)	3	7/8/88 0:00:00	MRS	HALIDE
1516	f_tbf3_1	POWDERED TbF3 ADHERED TO DOUBLE SIDED TAPE USING SCREEN (GENTLY GROUND)	7	6/11/87 0:00:00	MRS	HALIDE
1517	f_tbf3_2	POWDERED TbF3 ADHERED TO DOUBLE SIDED TAPE USING SCREEN (GENTLY GROUND)	2	6/11/87 0:00:00	MRS	HALIDE

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
1518	i_ki_01	Potassium Iodide (KI) FRESHLY CLEAVED IN AIR	11	10/12/85 0:00:00	MRS	HALIDE
1519	i_ki_01a	Potassium Iodide (KI) FRESHLY CLEAVED IN AIR	1	10/12/85 0:00:00	MRS	HALIDE
1520	i_ki_01b	POTASSIUM Iodide (KI) FRESHLY CLEAVED IN AIR	1	10/13/85 0:00:00	MRS	HALIDE
1521	i_ki_1	POTASSIUM IODINE (KI) CRYSTAL (90 DEG TOA, FRESHLY CLEAVED, USED SCREEN)	3	1/21/88 0:00:00	MRS	HALIDE
1522	kcl_1	KCl xtal (fresh exposed bulk) scrn 90 TOA	10	5/31/94 0:00:00	MRS	HALIDE
1523	kcl_1a	KCl xtal (fresh exposed bulk) scrn 90 TOA	2	5/31/94 0:00:00	MRS	HALIDE
1524	30_ang_b	30 Angstrom Coating of Braecote Type Lubricant at 35 TOA	1	12/3/92 0:00:00	MRS	HD_LUBE1
1525	36_ang_b	36 Angstrom Coating of Braecote type lubricant: 35 TOA	1	12/7/93 0:00:00	MRS	HD_LUBE1
1526	48_ang_b	48 Angstrom coating of Braecote type lubricant: 35 TOA	1	12/7/93 0:00:00	MRS	HD_LUBE1
1527	a_1_bott	pos 1, bottom, "A"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1528	a_1_top	"A" pos 1, top	1	11/24/93 0:00:00	MRS	HD_LUBE1
1529	a_2_bott	pos 2, bottom, "A"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1530	a_2_top	"A" pos 2, top	1	11/24/93 0:00:00	MRS	HD_LUBE1
1531	a_3_bott	pos 3, bottom, "A"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1532	a_3_top	"A" pos 3, top	1	11/24/93 0:00:00	MRS	HD_LUBE1
1533	b_1_bott	pos 1, bottom, "B"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1534	b_1_top	pos 1, top, "B"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1535	b_2_bott	pos 2, bottom, "B"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1536	b_2_top	pos 2, top, "B"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1537	b_3_bott	pos 3, bottom, "B"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1538	b_3_top	pos 3, top, "B"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1539	c_1_bott	pos 1, bottom, "C"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1540	c_1_top	pos 1, top, "C"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1541	c_2_bott	pos 2, bottom, "C"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1542	c_2_top	pos 2, top, "C"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1543	c_3_bott	pos 3, bottom, "C"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1544	c_3_top	pos 3, top, "C"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1545	d_1_bott	pos 1, bottom, "D"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1546	d_1_top	pos 1, top, "D"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1547	d_2_bott	pos 2, bottom, "D"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1548	d_2_top	pos 2, top, "D"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1549	d_3_bott	pos 3, bottom, "D"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1550	d_3_top	pos 3, top, "D"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1551	e_1_bott	pos 1, bottom, "E"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1552	e_1_top	pos 1, top, "E"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1553	e_2_bott	pos 2, bottom, "E"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1554	e_2_top	pos 2, top, "E"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1555	e_3_bott	pos 3, bottom, "E"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1556	e_3_top	pos 3, top, "E"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1557	f_1_bott	pos 1, bottom, "F"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1558	f_1_top	pos 1, top, "F"	1	11/24/93 0:00:00	MRS	HD_LUBE1



Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
1559	f_2_bott	pos 2, bottom, "F"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1560	f_2_top	pos 2, top, "F"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1561	f_3_bott	pos 3, bottom, "F"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1562	f_3_top	pos 3, top, "F"	1	11/24/93 0:00:00	MRS	HD_LUBE1
1563	f_ether1	Fluoro-ether polymer on soda-lime glass (35 toa)	4	4/26/91 0:00:00	MRS	HD_LUBE1
1564	f_ether2	Fluoro-ether polymer on glass at 90 deg toa	4	4/26/91 0:00:00	MRS	HD_LUBE1
1565	f_ether3	Fluoro-ether polymer on soda-lime glass, 10 deg	4	4/26/91 0:00:00	MRS	HD_LUBE1
1566	f_ether4	Fluoro-ether polymer on soda-lime glass 10 deg toa	1	4/26/91 0:00:00	MRS	HD_LUBE1
1567	f_ether5	Fluoro-Ether Lube on Glass (10 deg TOA)	6	4/24/91 0:00:00	MRS	HD_LUBE1
1568	f_ether6	Fluoro-Ether Lube on Glass (90 deg TOA)	6	4/24/91 0:00:00	MRS	HD_LUBE1
1569	f_ether7	Fluor-Ether Lube on Glass (90 deg TOA)	4	4/24/91 0:00:00	MRS	HD_LUBE1
1570	g_1_bott	"G" pos 1, bottom (spin-off test)	1	12/14/93 0:00:00	MRS	HD_LUBE1
1571	g_1_top	"G" pos 1, top (spin-off test)	1	12/14/93 0:00:00	MRS	HD_LUBE1
1572	g_2_bott	"G" pos 2, bottom (spin-off test)	1	12/14/93 0:00:00	MRS	HD_LUBE1
1573	g_2_top	"G" pos 2, top (spin-off test)	1	12/14/93 0:00:00	MRS	HD_LUBE1
1574	g_3_bott	"G" pos 3, bottom (spin-off test)	1	12/14/93 0:00:00	MRS	HD_LUBE1
1575	g_3_top	"G" pos 3, top (spin-off test)	1	12/14/93 0:00:00	MRS	HD_LUBE1
1576	g_4_bott	"G" pos 4, bottom (spin-off test)	1	12/14/93 0:00:00	MRS	HD_LUBE1
1577	g_4_top	"G" pos 4, top (spin-off test)	1	12/14/93 0:00:00	MRS	HD_LUBE1
1578	g_5_bott	"G" pos 5, bottom (spin-off test)	1	12/14/93 0:00:00	MRS	HD_LUBE1
1579	g_5_top	"G" pos 5, top (spin-off test)	1	12/14/93 0:00:00	MRS	HD_LUBE1
1580	g_6_bott	"G" pos 6, bottom (spin-off test)	1	12/14/93 0:00:00	MRS	HD_LUBE1
1581	g_6_top	"G" pos 6, top (spin-off test)	1	12/14/93 0:00:00	MRS	HD_LUBE1
1582	a_1_b	A bott 0 deg 15 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1583	a_1_t	A top 0 deg 15 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1584	a_2_b	A bott 0 deg 22 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1585	a_2_t	A top 0 deg 22 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1586	a_3_b	A bott 0 deg 29 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1587	a_3_t	A top 0 deg 29 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1588	a_4_b	A bott 90 deg 15 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1589	a_4_t	A top 90 deg 15 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1590	a_5_b	A bott 90 deg 22 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1591	a_5_t	A top 90 deg 22 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1592	a_6_b	A bott 90 deg 29 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1593	a_6_t	A top 90 deg 29 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1594	b_1_b	B bott 0 deg 15 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1595	b_1_t	B top 0 deg 15 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1596	b_2_b	B bott 0 deg 22 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1597	b_2_t	B top 0 deg 22 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1598	b_3_b	B bott 0 deg 29 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1599	b_3_t	B top 0 deg 29 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
1600	b_4_b	B bott 90 deg 15 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1601	b_4_t	B top 90 deg 15 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1602	b_5_b	B bott 90 deg 22 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1603	b_5_t	B top 90 deg 22 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1604	b_6_b	B bott 90 deg 29 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1605	b_6_t	B top 90 deg 29 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1606	c_1_b	C bott 0 deg 15 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1607	c_1_t	C top 0 deg 15 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1608	c_2_b	C bott 0 deg 22 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1609	c_2_t	C top 0 deg 22 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1610	c_3_b	C bott 0 deg 29 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1611	c_3_t	C top 0 deg 29 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1612	c_4_b	C bott 90 deg 15 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1613	c_4_t	C top 90 deg 15 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1614	c_5_b	C bott 90 deg 22 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1615	c_5_t	C top 90 deg 22 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1616	c_6_b	C bott 90 deg 29 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1617	c_6_t	C top 90 deg 29 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1618	d_1_b	D bott 0 deg 15 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1619	d_1_t	D top 0 deg 15 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1620	d_2_b	D bott 0 deg 22 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1621	d_2_t	D top 0 deg 22 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1622	d_3_b	D bott 0 deg 29 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1623	d_3_t	D top 0 deg 29 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1624	d_4_b	D bott 90 deg 15 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1625	d_4_t	D top 90 deg 15 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1626	d_5_b	D bott 90 deg 22 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1627	d_5_t	D top 90 deg 22 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1628	d_6_b	D bott 90 deg 29 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1629	d_6_t	D top 90 deg 29 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1630	e_1_b	E bott 0 deg 15 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1631	e_1_t	E top 0 deg 15 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1632	e_2_b	E bott 0 deg 22 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1633	e_2_t	E top 0 deg 22 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1634	e_3_b	E bott 0 deg 29 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1635	e_3_t	E top 0 deg 29 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1636	e_4_b	E bott 90 deg 15 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1637	e_4_t	E top 90 deg 15 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1638	e_5_b	E bott 90 deg 22 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1639	e_5_t	E top 90 deg 22 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1640	e_6_b	E bott 90 deg 29 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
1641	e_6_t	E top 90 deg 29 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1642	f_1_b	F bott 0 deg 15 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1643	f_1_t	F top 0 deg 15 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1644	f_2_b	F bott 0 deg 22 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1645	f_2_t	F top 0 deg 22 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1646	f_3_b	F bott 0 deg 29 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1647	f_3_t	F top 0 deg 29 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1648	f_4_b	F bott 90 deg 15 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1649	f_4_t	F top 90 deg 15 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1650	f_5_b	F bott 90 deg 22 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1651	f_5_t	F top 90 deg 22 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1652	f_6_b	F bott 90 deg 29 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1653	f_6_t	F top 90 deg 29 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1654	g_1_b	G bott 0 deg 15 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1655	g_1_t	G top 0 deg 15 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1656	g_2_b	G bott 0 deg 22 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1657	g_2_t	G top 0 deg 22 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1658	g_3_b	G bott 0 deg 29 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1659	g_3_t	G top 0 deg 29 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1660	g_4_b	G bott 90 deg 15 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1661	g_4_t	G top 90 deg 15 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1662	g_5_b	G bott 90 deg 22 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1663	g_5_t	G top 90 deg 22 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1664	g_6_b	G bott 90 deg 29 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1665	g_6_t	G top 90 deg 29 mm	1	12/6/93 0:00:00	MRS	HD_LUBE2
1666	al_reox3	High Purity Aluminum Drop, Bulk Exposed 3 Years Ago Heated In Air On Hotplate To >100 C For 1 Hr (90 Deg Toa)	3	10/17/91 0:00:00	MRS	HEAT_EFF
1667	al_reox4	High Purity Aluminum Drop, Freshly Exposed Today (cutting) Heated in Air on Hotplate to >100 C for 1 Hr (90 deg TOA)	3	10/17/91 0:00:00	MRS	HEAT_EFF
1668	al_reox5	High Purity Aluminum Drop, Freshly Exposed Today (cutting) Heated in Air on Hotplate to >100 C for 3 Hr (90 deg TOA)	3	10/18/91 0:00:00	MRS	HEAT_EFF
1669	al_reox6	High Purity Aluminum Drop, Bulk Exposed 3 years Ago Heated in Air on Hotplate to >100 C for 2 Hr (90 deg TOA)	3	10/18/91 0:00:00	MRS	HEAT_EFF
1670	cu_heate	BROWN WRINKLED FILM ON TOP OF COPPER SHEET (INDIRECTLY HEATED IN CRUCIBLE IN AIR - > 600 C)	5	6/29/87 0:00:00	MRS	HEAT_EFF
1671	al_oh3	ALUMINUM HYDROXIDE (Al(OH)3) on DST (no mesh, Tech grade, PERFECT PARTS Co)	6	10/20/85 0:00:00	MRS	HYDROXID
1672	cd_h2o2	Fresh Cd Surface exposed to H2O2 for 4 hours	4	6/14/91 0:00:00	MRS	HYDROXID
1673	cd_nh4oh	Fresh Cd Surface exposed to conc NH4OH 5 hours	4	6/14/91 0:00:00	MRS	HYDROXID
1674	co_oh2	Co(OH)2 (3mm pellet) 95% Aldr lot# 00820HW screen 90 TOA	10	2/16/92 0:00:00	MRS	HYDROXID
1675	cu_oh2	Cu(OH)2 (3 mm pellet, Tech grade) Aldr lot# 11715EW screen 90 TOA	11	9/10/91 0:00:00	MRS	HYDROXID
1676	fe_ooh_a	alpha-FeOOH (3mm pellet) 99.999% RMC #70924-01 screen 90 TOA	11	9/6/91 0:00:00	MRS	HYDROXID
1677	fe_ooh_b	alpha-FeOOH (3mm pellet) 99.999% RMC #70924-01 screen 90 TOA	7	9/6/91 0:00:00	MRS	HYDROXID
1678	li_oh	LITHIUM HYDROXIDE (LiOH) PRESSED ONTO In, NO SCREEN, 90 DEG TOA	4	2/9/88 0:00:00	MRS	HYDROXID
1679	mg_oh2_a	Mg(OH)2 (3mm pellet) 95% Aldr lot# 07712DY screen 90 TOA	12	2/4/92 0:00:00	MRS	HYDROXID
1680	mg_oh2_b	Mg(OH)2 (3mm pellet) 95% Aldr lot# 07712DY screen 90 TOA	12	2/3/92 0:00:00	MRS	HYDROXID
1681	ni_oh2	Ni(OH)2 (3mm pellet) 99% Aldrich lot# 90 TOA screen	9	6/2/92 0:00:00	MRS	HYDROXID

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
1682	ar_c	Argon Ions/Natural Graphite Crystal (90 TOA) 4KV, 10 min	3	1/12/93 0:00:00	MRS	ION_IMPL
1683	O_CR_1	75 KV O+ implanted into Chromium (Cr) (as rec'd)	4	10/1/92 0:00:00	MRS	ION_IMPL
1684	O_HF_1	75 KV O+ implanted into Hafnium (Hf) (as rec'd)	4	10/1/92 0:00:00	MRS	ION_IMPL
1685	O_NB_1	75 KV O+ implanted into Niobium (Nb) (as rec'd)	4	10/1/92 0:00:00	MRS	ION_IMPL
1686	O_W_1	75 KV O+ implanted into Tungsten (W) (as rec'd)	4	10/1/92 0:00:00	MRS	ION_IMPL
1687	o_w_2	O+ Implanted in Tungsten (W) Film (as rec'd, 35toa)	5		MRS	ION_IMPL
1688	o_w_2a	O+ Implanted in Tungsten (W) Film (as rec'd, 35toa)	2	4/24/91 0:00:00	MRS	ION_IMPL
1689	o_w_3	1000 ang O+/W: Xe 1.2E-7, 3 KV, 10 mA, F=5	4	4/24/91 0:00:00	DPR	ION_IMPL
1690	o_zr_1	O+ Implanted in Zirconium (Zr) film (as rec.35 toa)	5	4/24/91 0:00:00	MRS	ION_IMPL
1691	zn_si_1a	ZINC (8KV, 1*E-15) IMPLANTED INTO SILICON (35 DEG TOA, 80 ANG ION ETCH)	2	7/4/88 0:00:00	MRS	ION_IMPL
1692	zn_si_1b	ZINC (8KV, 1*E-15) IMPLANTED INTO Si WAFER (35 TOA, 200 ANG ION ETCH)	2	6/15/88 0:00:00	MRS	ION_IMPL
1693	zn_si_1c	ZINC (8KV, 1*E-15) IMPLANTED INTO SILICON (35 TOA, 500 ANG ION ETCH)	1	6/16/88 0:00:00	MRS	ION_IMPL
1694	zn_si_1d	ZINC (8KV, 1*E-15) Implanted in Silicon (5 hr study, 90 TOA, 80 ANG ETCH)	1	6/28/88 0:00:00	MRS	ION_IMPL
1695	zn_si_1e	ZINC (8KV, 1*E-15) IMPLANTED INTO SILICON (35 DEG TOA, 500 Ang etch)	1	6/17/88 0:00:00	MRS	ION_IMPL
1696	zr_fecr1	6E16 Zr/Fe5Cr (as implanted)	7	4/25/91 0:00:00	MRS	ION_IMPL
1697	zr_fecr2	6E16 Zr/Fe5Cr (Electrochem) (as received)	7	4/25/91 0:00:00	MRS	ION_IMPL
1698	zr_fecr3	6E16 Zr/Fe5Cr (as implanted) (Depth Profile)	6	4/25/91 0:00:00	DPR	ION_IMPL
1699	zr_fecr4	6E16 Zr/Fe5Cr (Electrochem) (Depth Profile)	6	4/26/91 0:00:00	DPR	ION_IMPL
1700	zr_fecr5	6E16 Zr/Fe5Cr (as implanted) (Depth Profile)	7	6/3/91 0:00:00	DPR	ION_IMPL
1701	zr_fecr6	6E16 Zr/Fe5Cr (as implanted) (Depth Profile)	7	6/3/91 0:00:00	DPR	ION_IMPL
1702	zr_fe_1	1E17 Zr (As received)	7	4/24/91 0:00:00	MRS	ION_IMPL
1703	zr_fe_1a	1E17 Zr (Ar, 3KV, 10mA, F=5, 1.2E-7)	6	4/25/91 0:00:00	DPR	ION_IMPL
1704	zr_fe_2	5E16 Zr/Fe (As Received)	7	4/25/91 0:00:00	MRS	ION_IMPL
1705	zr_fe_3	5E16 Zr/Fe (as implanted)	7	4/26/91 0:00:00	MRS	ION_IMPL
1706	zr_fe_4	6E16 Zr/Fe (as implanted area)	7	4/25/91 0:00:00	MRS	ION_IMPL
1707	zr_fe_4a	5E16 Zr/Fe (as implanted) (depth profile)	8	4/26/91 0:00:00	DPR	ION_IMPL
1708	zr_fe_5	6E16 Zr/Fe (Electrochem) (as received)	7	4/25/91 0:00:00	MRS	ION_IMPL
1709	zr_fe_5a	6E16 Zr/Fe (Electrochem) (Depth Profile)	6	4/25/91 0:00:00	DPR	ION_IMPL
1710	zr_fe_6	1E17 Zr(+)/Fe 100KV, as received, 35 toa	5	4/25/91 0:00:00	MRS	ION_IMPL
1711	zr_fe_7	1E17 Zr (Ar, 3KV, 10mA, F=5, 1.2E-7)	6	6/4/91 0:00:00	DPR	ION_IMPL
1712	au_1	200-300 ANGSTROM OF GOLD ON MYLAR FILM LASER TURNED OFF	1	9/22/89 0:00:00	MRS	LASERXP1
1713	au_2	200-300 ANGSTROM OF GOLD ON MYLAR FILM LASER ON: 590 nm, 100 mW	1	9/22/89 0:00:00	MRS	LASERXP1
1714	bao_1	BaO PELLETT UNDER GOLD CLIP BEFORE LASER EXPOSURE	3	9/25/89 0:00:00	MRS	LASERXP1
1715	bao_2	BaO PELLETT UNDER GOLD CLIP LASER TURNED ON: 598-600 nm RANGE, 900 mW	2	9/25/89 0:00:00	MRS	LASERXP1
1716	bao_3	BaO PELLETT UNDER GOLD CLIP LASER TURNED OFF	2	9/25/89 0:00:00	MRS	LASERXP1
1717	bao_4	BaO PELLETT UNDER GOLD CLIP LASER TURNED ON: 598-600 nm RANGE, 900 mW	2	9/25/89 0:00:00	MRS	LASERXP1
1718	bao_5	BaO PELLETT UNDER GOLD CLIP LASER TURNED ON: 610 nm (OFF RESONANCE), 900 mW2	2	9/25/89 0:00:00	MRS	LASERXP1
1719	bao_5a	BaO PELLETT UNDER GOLD CLIP LASER TURNED ON: 610 nm (OFF RESONANCE), 900 mW2	2	9/25/89 0:00:00	MRS	LASERXP1
1720	bao_nfg	BaO PELLETT UNDER GOLD CLIP LASER TURNED OFF, FLOOD GUN TURNED OFF	1	9/25/89 0:00:00	MRS	LASERXP1
1721	ceo2_1	CeO2 PELLETT (NO FLOOD GUN, NO SCREEN) LASER TURNED OFF AGAIN	3	9/18/89 0:00:00	MRS	LASERXP1
1722	ceo2_2	CeO2 PELLETT (FLOOD GUN ON, NO SCREEN) LASER TURN ON: 590 nm, 900 mW (AFTER M2)	2	9/18/89 0:00:00	MRS	LASERXP1

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
1723	ceo2_2a	CeO2 PELLETT (FLOOD GUN ON, NO SCREEN) LASER TURN ON: 590 nm, 900 mW (AFTER M2)	1	9/18/89 0:00:00	MRS	LASERXP1
1724	ceo2_3	CeO2 PELLETT (FLOOD GUN ON, NO SCREEN) LASER TURNED OFF	2	9/18/89 0:00:00	MRS	LASERXP1
1725	ceo2_4	CeO2 Pellet (Flood Gun On, No Screen) Laser Turned On Again: 590 Nm, 900 Mw (After M2)	2	9/18/89 0:00:00	MRS	LASERXP1
1726	ceo2_5	CeO2 Pellet (Flood Gun On, No Screen) Laser Turned On Again: 590 Nm, 1100 Mw (After M2)	3	9/18/89 0:00:00	MRS	LASERXP1
1727	ceo2_6	CeO2 Pellet (Flood Gun On, No Screen) Laser Turned Off Again	3	9/18/89 0:00:00	MRS	LASERXP1
1728	ceo2_7	CeO2 Pellet (Flood Gun On, No Screen) Laser Turned On Again: 590 Nm, 1100 Mw (After M2)	2	9/18/89 0:00:00	MRS	LASERXP1
1729	ceo2_8	CeO2 PELLETT (FLOOD GUN ON, NO SCREEN) LASER TURNED OFF AGAIN	2	9/18/89 0:00:00	MRS	LASERXP1
1730	co	NATIVE CoO ON Co METAL LASER OFF	4	9/19/89 0:00:00	MRS	LASERXP1
1731	co_1	NATIVE CoO ON Co METAL LASER ON: 70 mW, 582 nm	2	9/19/89 0:00:00	MRS	LASERXP1
1732	co_2	NATIVE CoO ON Co METAL LASER ON: 600 mW, 582 nm	2	9/19/89 0:00:00	MRS	LASERXP1
1733	co_3	NATIVE CoO ON Co METAL LASER ON: 646 nm, 100 mW	4	9/19/89 0:00:00	MRS	LASERXP1
1734	co_3a	NATIVE CoO ON Co METAL LASER ON: 646 nm, 100 mW	1	9/19/89 0:00:00	MRS	LASERXP1
1735	co_3b	NATIVE CoO ON Co METAL LASER ON: 646 nm, 180 mW (CORRECT VALUE)	1	9/19/89 0:00:00	MRS	LASERXP1
1736	co_4	NATIVE CoO ON Co METAL LASER ON: 582 nm, 300 mW (CORRECT VALUE)	1	9/19/89 0:00:00	MRS	LASERXP1
1737	co_4a	NATIVE CoO ON Co METAL LASER ON: 582 nm, 500 mW (CORRECT VALUE)	1	9/19/89 0:00:00	MRS	LASERXP1
1738	co_4b	NATIVE CoO ON Co METAL LASER OFF	1	9/19/89 0:00:00	MRS	LASERXP1
1739	co_5	NATIVE CoO ON Co METAL LASER ON: 631 nm, 300 mW (AFTER M2)	1	9/19/89 0:00:00	MRS	LASERXP1
1740	co_6	NATIVE CoO ON Co METAL LASER ON: 615 nm, 620 mW (AFTER M2)	1	9/19/89 0:00:00	MRS	LASERXP1
1741	co_scan	WAVELENGTH SCAN OF NATIVE CoO ON Co METAL 580-600nm, 0.25 nm/STEP	2	9/19/89 0:00:00	DPR	LASERXP1
1742	cr2o3ar2	Cr2O3 PELLETT UNDER GLOD CLIP (STRONG OUTGAS) LASER TURNED OFF	2	9/26/89 0:00:00	MRS	LASERXP1
1743	cr2o3ar3	Cr2O3 PELLETT UNDER GLOD CLIP (STRONG OUTGAS) ARGON MULTI-LINE ON AGAIN: 900 mW	2	9/26/89 0:00:00	MRS	LASERXP1
1744	cr2o3ar4	Cr2O3 PELLETT UNDER GLOD CLIP (STRONG OUTGAS) LASER TURNED OFF	2	9/26/89 0:00:00	MRS	LASERXP1
1745	cr2o3ar5	Cr2O3 PELLETT UNDER GLOD CLIP (STRONG OUTGAS) ARGON MULTI-LINE ON: 900 mW	2	9/26/89 0:00:00	MRS	LASERXP1
1746	cr2o3ar6	Cr2O3 PELLETT UNDER GLOD CLIP (STRONG OUTGAS) ARGON MULTI-LINE ON: 3500 mW	2	9/26/89 0:00:00	MRS	LASERXP1
1747	cr2o3_1	7 mm Diam, 1 Mm Thick Cr2o3 Under Clip (Cleaned) Check Cr2p1/2 Laser On: 590 Nm, 900 Mw, Aper 10	1	9/18/89 0:00:00	MRS	LASERXP1
1748	cr2o3_2	7 mm Diam, 1 Mm Thick Cr2o3 Under Clip (Cleaned) Check Cr2p1/2 Laser On: 150 Mw, 590 Nm	2	9/18/89 0:00:00	MRS	LASERXP1
1749	cr2o3_3	7 mm Diam, 1 Mm Thick Cr2o3 Under Clip (Cleaned) Check Vb Glitch Laser On: 900 Mw, 590 Nm	1	9/18/89 0:00:00	MRS	LASERXP1
1750	cr2o3_6a	Fresh Cr2o3 Pellet On Dst Under Screen Laser Off	4	8/31/89 0:00:00	MRS	LASERXP1
1751	cr2o3_6b	Fresh Cr2o3 Pellet On Dst Under Screen Laser On, 640 Mw, 590 Nm, Aper 4, Focussed	4	8/31/89 0:00:00	MRS	LASERXP1
1752	cr2o3_6c	Fresh Cr2o3 Pellet On Dst Under Screen Laser On, 900 Mw, 590 Nm, Aper 9, Focussed	4	8/31/89 0:00:00	MRS	LASERXP1
1753	cr2o3_6d	Fresh Cr2o3 Pellet On Dst Under Screen Laser On, 1100 Mw, 590 Nm, Aper 12, Focussed	4	8/31/89 0:00:00	MRS	LASERXP1
1754	cr2o3_6e	Fresh Cr2o3 Pellet On Dst Under Screen Laser Turned Off (After Exposed To 1100 Mw)	4	8/31/89 0:00:00	MRS	LASERXP1
1755	cr2o3_6f	(Laser Cleaned) Cr2o3 Pellet On Dst Under Screen Laser On, 95 Mw, 590 Nm, Aper 1, Focussed	1	8/31/89 0:00:00	MRS	LASERXP1
1756	cr2o3_6g	(Laser Cleaned) Cr2o3 Pellet On Dst Under Screen Laser On, 350 Mw, 590 Nm, Aper 2, Focussed	1	8/31/89 0:00:00	MRS	LASERXP1
1757	cr2o3_6h	(Laser Cleaned) Cr2o3 Pellet On Dst Under Screen Laser On, 540 Mw, 590 Nm, Aper 3, Focussed	1	8/31/89 0:00:00	MRS	LASERXP1
1758	cr2o3_6i	(Laser Cleaned) Cr2o3 Pellet On Dst Under Screen Laser On, 600 Mw, 590 Nm, Aper 4, Focussed	1	8/31/89 0:00:00	MRS	LASERXP1
1759	cr2o3_6j	(Laser Cleaned) Cr2o3 Pellet On Dst Under Screen Laser On, 690 Mw, 590 Nm, Aper 6, Focussed	1	8/31/89 0:00:00	MRS	LASERXP1
1760	cr2o3_6_	FRESH Cr2O3 PELLETT ON DST UNDER SCREEN LASER OFF	1	8/31/89 0:00:00	MRS	LASERXP1
1761	cr2o3_ar	Cr2O3 PELLETT UNDER GLOD CLIP (STRONG OUTGAS) ARGON MULTI-LINE: 900 mW	3	9/26/89 0:00:00	MRS	LASERXP1
1762	cr_1	AS RECEIVED CHROMIUM CHUNK BEFORE ANY EXPOSURE TO LASER	4	9/6/89 0:00:00	MRS	LASERXP1
1763	cr_2_a	As Received Chromium Chunk (No Outgassing !) Laser On: 700 Mw (After M2), 590 Nm, Aper 10	4	9/6/89 0:00:00	MRS	LASERXP1

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
1764	cr_2_b	As Received Chromium Chunk (No Outgassing !)	Laser On: 1100 Mw (After M2), 590 Nm, Aper 10	3	9/6/89 0:00:00	MRS LASERXP1
1765	cr_3_a	As Received Chromium Chunk (No Outgassing !)	Laser On: 280 Mw (After M2), 640 Nm, Aper 12	3	9/7/89 0:00:00	MRS LASERXP1
1766	cr_3_b	As Received Chromium Chunk (No Outgassing !)	Laser On: 440 Mw (After M2), 630 Nm, Aper 12	3	9/7/89 0:00:00	MRS LASERXP1
1767	cr_3_c	As Received Chromium Chunk (No Outgassing !)	Laser On: 850 Mw (After M2), 620 Nm, Aper 12	3	9/7/89 0:00:00	MRS LASERXP1
1768	cr_3_d	As Received Chromium Chunk (No Outgassing !)	Laser On: 12000 Mw (After M2), 610 Nm, Aper 12	3	9/7/89 0:00:00	MRS LASERXP1
1769	cr_3_e	As Received Chromium Chunk (No Outgassing !)	Laser On: 1300 Mw (After M2), 600 Nm, Aper 12	3	9/7/89 0:00:00	MRS LASERXP1
1770	cr_3_f	As Received Chromium Chunk (No Outgassing !)	Laser On: 320 Mw (After M2), 570 Nm, Aper 12	3	9/7/89 0:00:00	MRS LASERXP1
1771	cr_ar_1	CHROMIUM CHUNK	ARGON MULTI-LINE: 3500 mW	2	9/26/89 0:00:00	MRS LASERXP1
1772	cu2o_1	Cu2O (RED) PELLETT UNDER CLIP	BEFORE EXPOSED TO LASER	3	9/20/89 0:00:00	MRS LASERXP1
1773	cu2o_2	Cu2O (RED->BLACK AT 200 mW) PELLETT UNDER CLIP	LASER ON: 609 nm (NEAR R LINE), 800 mW	4	9/20/89 0:00:00	MRS LASERXP1
1774	cu2o_3	Cu2O (RED->BLACK AT 200 mW) PELLETT UNDER CLIP	LASER TURNED OFF	4	9/20/89 0:00:00	MRS LASERXP1
1775	cu2o_4	Cu2O (RED->BLACK AT 200 mW) PELLETT UNDER CLIP	LASER TURNED ON: 609 nm, 800 mW	2	9/20/89 0:00:00	MRS LASERXP1
1776	cu2o_5	Cu2o (Red->black At 200 Mw) Pellet Under Clip	Laser Turned On: 609 Nm, 800 Mw Flood Gun Off	2	9/20/89 0:00:00	MRS LASERXP1
1777	cu2o_6	Cu2O (RED->BLACK AT 200 mW) PELLETT UNDER CLIP	LASER TURNED OFF FLOOD GUN OFF	2	9/20/89 0:00:00	MRS LASERXP1
1778	cu2o_7	Cu2O (RED->BLACK AT 200 mW) PELLETT UNDER CLIP		2	9/20/89 0:00:00	MRS LASERXP1
1779	cu2o_ar2	Cu2O PELLETT UNDER GLOD CLIP (VERY STRONG OUTGAS)	LASER TURNED OFF	2	9/26/89 0:00:00	MRS LASERXP1
1780	cu2o_ar3	Cu2O PELLETT UNDER GLOD CLIP (VERY STRONG OUTGAS)	ARGON MULTI-LINE ON: 900 mW	2	9/26/89 0:00:00	MRS LASERXP1
1781	cu2o_ar_	Cu2O PELLETT UNDER GLOD CLIP (VERY STRONG OUTGAS)	ARGON MULTI-LINE ON: 900 mW	2	9/26/89 0:00:00	MRS LASERXP1
1782	cuo_1	"LASER-CLEANED" CuO PELLETT/DST UNDER SCREEN	LASER OFF	5	9/8/89 0:00:00	MRS LASERXP1
1783	cuo_10	LASER CLEANED CuO PELLETT/DST UNDER SCREEN	LASER OFF	1	9/8/89 0:00:00	MRS LASERXP1
1784	cuo_1a	"LASER-CLEANED" CuO PELLETT/DST UNDER SCREEN	LASER OFF	4	9/8/89 0:00:00	MRS LASERXP1
1785	cuo_2	"Laser-cleaned" Cuo Pellet/dst Under Screen	Laser On: 380mw (After M2), 590nm, Aper 2, 3 Min	3	9/8/89 0:00:00	MRS LASERXP1
1786	cuo_3	"Laser-cleaned" Cuo Pellet/dst Under Screen	Laser On: 550mw (After M2), 590nm, Aper 4, 3 Min	3	9/8/89 0:00:00	MRS LASERXP1
1787	cuo_4	"Laser-cleaned" Cuo Pellet/dst Under Screen	Laser On: 660mw (After M2), 590nm, Aper 6, 3 Min	3	9/8/89 0:00:00	MRS LASERXP1
1788	cuo_5	"Laser-cleaned" Cuo Pellet/dst Under Screen	Laser On: 750mw (After M2), 590nm, Aper 8, 3 Min	3	9/8/89 0:00:00	MRS LASERXP1
1789	cuo_6	"Laser-cleaned" Cuo Pellet/dst Under Screen	Laser On: 900mw (After M2), 590nm, Aper 10, 3 Min	3	9/8/89 0:00:00	MRS LASERXP1
1790	cuo_7	"Laser-cleaned" Cuo Pellet/dst Under Screen	Laser On: 1000mw (After M2), 590nm, Aper 12, 3 Min	3	9/8/89 0:00:00	MRS LASERXP1
1791	cuo_8	"Laser-cleaned" Cuo Pellet/dst Under Screen	Laser On: 750mw (After M2), 590nm, Aper 8, Repeat	2	9/8/89 0:00:00	MRS LASERXP1
1792	cuo_9	"LASER-CLEANED" CuO PELLETT/DST UNDER SCREEN	LASER OFF	2	9/8/89 0:00:00	MRS LASERXP1
1793	cuo_agai	CuO PELLETT PIECE, NO SCREEN, NO DST		1	9/13/89 0:00:00	MRS LASERXP1
1794	cuo_agin	CuO PELLETT PIECE, NO SCREEN, NO DST, 590 nm, 700 mW		1	9/13/89 0:00:00	MRS LASERXP1
1795	cuo_aper	7 mm Diam, 1 Mm Thick Cuo Pellet Under Gold Clip	Cleaned By Laser, Laser On: 590 Nm, 700 Mw, Ape	1	9/14/89 0:00:00	MRS LASERXP1
1796	cuo_aper7	7 mm Diam, 1 Mm Thick Cuo Pellet Under Gold Clip	Cleaned By Laser, Laser On: 590 Nm, 800 Mw, Aper 7	1	9/14/89 0:00:00	MRS LASERXP1
1797	cuo_ap_1	7 mm Diam, 1 Mm Thick Cuo Pellet Under Gold Clip	Cleaned By Laser, Laser On: 590 Nm, 900 Mw, Ap 10	2	9/14/89 0:00:00	MRS LASERXP1
1798	cuo_ar_1	CuO PELLETT UNDER GLOD CLIP (STRONG OUTGAS)	ARGON MULTI-LINE ON: 900 mW	3	9/26/89 0:00:00	MRS LASERXP1
1799	cuo_ar_2	CuO PELLETT UNDER GLOD CLIP (STRONG OUTGAS)	LASER TURNED OFF	3	9/26/89 0:00:00	MRS LASERXP1
1800	cuo_lsr0	7 mm Diam, 1 Mm Thick Cuo Pellet Under Gold Clip	Cleaned By Laser Again, Laser Off After 900 Mw	2	9/14/89 0:00:00	MRS LASERXP1
1801	cuo_off2	7 mm DIAM, 1 mm THICK CuO PELLETT UNDER GOLD CLIP	LASER OFF AGAIN	1	9/14/89 0:00:00	MRS LASERXP1
1802	cuo_offa	7 mm DIAM, 1 mm THICK CuO PELLETT UNDER GOLD CLIP	LASER OFF AGAIN	2	9/14/89 0:00:00	MRS LASERXP1
1803	cuo_off_	7 mm DIAM, 1 mm THICK CuO PELLETT UNDER GOLD CLIP	LASER OFF AGAIN	1	9/14/89 0:00:00	MRS LASERXP1
1804	cuo_on2	7 mm DIAM, 1 mm THICK CuO PELLETT UNDER GOLD CLIP	LASER ON AGAIN: 590 nm, 900 mW	1	9/14/89 0:00:00	MRS LASERXP1

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
1805	cuo_on_2	7 mm DIAM, 1 mm THICK CuO PELLETT UNDER GOLD CLIP LASER ON AGAIN: 590 nm, 900 mW	1	9/14/89 0:00:00	MRS	LASERXP1
1806	cuo_on_a	7 mm DIAM, 1 mm THICK CuO PELLETT UNDER GOLD CLIP LASER ON AGAIN: 590 nm, 900 mW	2	9/14/89 0:00:00	MRS	LASERXP1
1807	fe2o310a	7 mm DIAM, 1 mm THICK Fe2O3 ON DST UNDER SCREEN LASER ON AGAIN: 590 nm, 1 W , APER 12	1	9/16/89 0:00:00	MRS	LASERXP1
1808	fe2o313a	7 mm DIAM, 1 mm THICK Fe2O3 ON DST UNDER SCREEN LASER ON AGAIN: 590 nm, 1 W, APER 12	1	9/16/89 0:00:00	MRS	LASERXP1
1809	fe2o319a	7 mm Diam, 1 Mm Thick Fe2o3 On Dst Under Screen Laser Off, Shock Treatment Gave Gray Color Film	1	9/16/89 0:00:00	MRS	LASERXP1
1810	fe2o3_1	7 mm DIAM, 1 mm THICK Fe2O3 ON DST UNDER SCREEN LASER ON: 590 nm, 1 W, APER 12	4	9/14/89 0:00:00	MRS	LASERXP1
1811	fe2o3_10	7 mm DIAM, 1 mm THICK Fe2O3 ON DST UNDER SCREEN LASER ON AGAIN: 590 nm, 1 W , APER 12	2	9/16/89 0:00:00	MRS	LASERXP1
1812	fe2o3_11	7 mm DIAM, 1 mm THICK Fe2O3 ON DST UNDER SCREEN LASER OFF AGAIN	2	9/16/89 0:00:00	MRS	LASERXP1
1813	fe2o3_12	7 mm DIAM, 1 mm THICK Fe2O3 ON DST UNDER SCREEN NEARBY AREA NOT EXPOSED TO LASER	5	9/16/89 0:00:00	MRS	LASERXP1
1814	fe2o3_13	7 mm DIAM, 1 mm THICK Fe2O3 ON DST UNDER SCREEN LASER ON AGAIN: 590 nm, 1 W, APER 12	3	9/16/89 0:00:00	MRS	LASERXP1
1815	fe2o3_14	7 mm DIAM, 1 mm THICK Fe2O3 ON DST UNDER SCREEN LASER OFF AGAIN	3	9/16/89 0:00:00	MRS	LASERXP1
1816	fe2o3_15	7 mm DIAM, 1 mm THICK Fe2O3 ON DST UNDER SCREEN LASER ON AGAIN: 590 nm, 1 W, APER 12	2	9/16/89 0:00:00	MRS	LASERXP1
1817	fe2o3_16	7 mm Diam, 1 Mm Thick Fe2o3 On Dst Under Screen Laser Continuously On For 2+ Hr, 610 Nm, 1 W	2	9/16/89 0:00:00	MRS	LASERXP1
1818	fe2o3_17	7 mm Diam, 1 Mm Thick Fe2o3 On Dst Under Screen Laser Continuously On For 2+ Hr, 610 Nm, 1 W	2	9/16/89 0:00:00	MRS	LASERXP1
1819	fe2o3_18	7 mm Diam, 1 Mm Thick Fe2o3 On Dst Under Screen Laser Continuously On For 2+ Hr, 590 Nm, 1 W	2	9/16/89 0:00:00	MRS	LASERXP1
1820	fe2o3_19	7 mm DIAM, 1 mm THICK Fe2O3 ON DST UNDER SCREEN LASER OFF	2	9/16/89 0:00:00	MRS	LASERXP1
1821	fe2o3_2	7 mm DIAM, 1 mm THICK Fe2O3 ON DST UNDER SCREEN CLEANED BY LASER, NOW LASER OFF	2	9/14/89 0:00:00	MRS	LASERXP1
1822	fe2o3_3	7 mm DIAM, 1 mm THICK Fe2O3 ON DST UNDER SCREEN LASER ON AGAIN: 590 nm, 1 W, APER 12	2	9/14/89 0:00:00	MRS	LASERXP1
1823	fe2o3_4	7 mm Diam, 1 Mm Thick Fe2o3 On Dst Under Screen Laser Off (After Exposed To 1 W At 590 Nm)	2	9/14/89 0:00:00	MRS	LASERXP1
1824	fe2o3_5	7 mm Diam, 1 Mm Thick Fe2o3 On Dst Under Screen Laser Off (In Uhv For One Day, No Laser Cleaning)	2	9/16/89 0:00:00	MRS	LASERXP1
1825	fe2o3_5a	7 mm Diam, 1 Mm Thick Fe2o3 On Dst Under Screen Laser Off (In Uhv For One Day, No Laser Cleaning)	1	9/16/89 0:00:00	MRS	LASERXP1
1826	fe2o3_6	7 mm DIAM, 1 mm THICK Fe2O3 ON DST UNDER SCREEN LASER ON AGAIN: 590 nm, 1 W , APER 12	3	9/16/89 0:00:00	MRS	LASERXP1
1827	fe2o3_7	7 mm Diam, 1 Mm Thick Fe2o3 On Dst Under Screen Laser Off Again (Exposed To 1 W At 590 Nm)	3	9/16/89 0:00:00	MRS	LASERXP1
1828	fe2o3_8	7 mm DIAM, 1 mm THICK Fe2O3 ON DST UNDER SCREEN LASER ON AGAIN: 590 nM, 1 W, APER 12	2	9/16/89 0:00:00	MRS	LASERXP1
1829	fe2o3_9	7 mm DIAM, 1 mm THICK Fe2O3 ON DST UNDER SCREEN LASER OFF AGAIN	2	9/16/89 0:00:00	MRS	LASERXP1
1830	fe2o3_sc	WAVELENGTH SCAN OF Fe2O3 PELLETT/DST UNDER SCREEN 590-610nm, 0.5 nm/STEP, MAX POWER	2	9/16/89 0:00:00	DPR	LASERXP1
1831	fe_1_a	RUSTED AREA ON IRON SHEET/DST (MODERATE OUTGASSING) LASER OFF	4	9/7/89 0:00:00	MRS	LASERXP1
1832	fe_1_b	Rusted Area On Iron Sheet/dst (Moderate Outgassing) laser On: 940 Mw (After M2), 590 Nm, Aper 12	3	9/7/89 0:00:00	MRS	LASERXP1
1833	fe_1_c	RUSTED AREA ON IRON SHEET (Maximized Outgassing) Laser On: 1000 Mw (After M2), 591 Nm, Aper 12	3	9/7/89 0:00:00	MRS	LASERXP1
1834	fe_1_d	RUSTED AREA ON IRON SHEET LASER TURNED OFF TO TEST FOR RECOVERY	3	9/7/89 0:00:00	MRS	LASERXP1
1835	fe_1_e	RUSTED AREA ON IRON SHEET LASER ON: 650 mW (AFTER M2), 580 nm, APER 12	3	9/7/89 0:00:00	MRS	LASERXP1
1836	fe_1_f	RUSTED AREA ON IRON SHEET LASER ON: 380 mW (AFTER M2), 630 nm, APER 12	3	9/7/89 0:00:00	MRS	LASERXP1
1837	gaas_1	GaAs WAFER (VERY SLIGHT OUTGAS) LASER TURNED ON : 590 nm, 900 mW	4	9/23/89 0:00:00	MRS	LASERXP1
1838	gaas_2	GaAs WAFER (VERY SLIGHT OUTGAS) LASER TURNED OFF	3	9/23/89 0:00:00	MRS	LASERXP1
1839	gaas_3	GaAs WAFER (VERY SLIGHT OUTGAS) LASER TURNED ON: 590 nm, 900 mW	3	9/23/89 0:00:00	MRS	LASERXP1
1840	gaas_4	GaAs WAFER (VERY SLIGHT OUTGAS) LASER TURNED OFF	3	9/23/89 0:00:00	MRS	LASERXP1
1841	gap_1	GaP (100) WAFER (VERY SLIGHT OUTGAS) LASER TURNED ON: 590 nm, 900 mW	3	9/23/89 0:00:00	MRS	LASERXP1
1842	gap_1a	GaP (100) WAFER (VERY SLIGHT OUTGAS) LASER TURNED ON: 590 nm, 900 mW	2	9/23/89 0:00:00	MRS	LASERXP1
1843	gap_2	GaP (100) WAFER (VERY SLIGHT OUTGAS) LASER TURNED OFF	3	9/23/89 0:00:00	MRS	LASERXP1
1844	gap_ar_1	GaP (100) WAFER (NO BE SHIFT USING "R6G") ARGON MULTI-LINE: 900 mW	3	9/26/89 0:00:00	MRS	LASERXP1
1845	ge_1	Ge FILM ON ALUMINUM BLOCK BEFORE LASER EXPOSURE	3	9/25/89 0:00:00	MRS	LASERXP1

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1846	ge_2	Ge FILM ON ALUMINUM BLOCK LASER TURNED ON: 590 nm, 900 mW	2	9/25/89 0:00:00	MRS	LASERXP1
1847	ge_3	Ge FILM ON ALUMINUM BLOCK LASER TURNED OFF	2	9/25/89 0:00:00	MRS	LASERXP1
1848	graphit2	FLOATED "LASER CLEANED" SINGLE CRYSTAL GRAPHITE LASER OFF	1	9/8/89 0:00:00	MRS	LASERXP1
1849	graphit3	FLOATED "Laser Cleaned" Single Crystal Graphite Laser On: 850 Mw, (After M2), 590 Nm, Aper 10	2	9/8/89 0:00:00	MRS	LASERXP1
1850	graphite	Floated "Laser Cleaned" Single Crystal Graphite Laser On: 850mw (After M2), 590nm, Aper 10	1	9/8/89 0:00:00	MRS	LASERXP1
1851	graphit_	GRAPHITE (CRYSTAL) BEFORE EXPOSURE TO LASER	1	9/21/89 0:00:00	MRS	LASERXP1
1852	grpht_1	GRAPHITE (CRYSTAL) BEFORE EXPOSURE TO LASER	3	9/21/89 0:00:00	MRS	LASERXP1
1853	grpht_2	GRAPHITE (CRYSTAL) LASER ON: 590 nm, 800 mW	3	9/21/89 0:00:00	MRS	LASERXP1
1854	grpht_3	GRAPHITE (CRYSTAL) LASER TURNED OFF	1	9/21/89 0:00:00	MRS	LASERXP1
1855	grpht_3a	GRAPHITE (CRYSTAL) LASER TURNED OFF	1	9/21/89 0:00:00	MRS	LASERXP1
1856	grpht_4	GRAPHITE (CRYSTAL) LASER TURNED ON: 618 nm, 250 mW	1	9/21/89 0:00:00	MRS	LASERXP1
1857	inp_1	InP (111) WAFER (NO OUTGASSING) LASER TURNED ON: 590 nm, 900 mW	4	9/23/89 0:00:00	MRS	LASERXP1
1858	inp_2	InP (111) WAFER (NO OUTGASSING) LASER TURNED OFF	3	9/23/89 0:00:00	MRS	LASERXP1
1859	inp_ar_1	InP (111) WAFER (NO BE SHIFT USING "R6G") ARGON MULTI-LINE: 3500 mW	3	9/26/89 0:00:00	MRS	LASERXP1
1860	kbr_1	CLEAVED KBr CRYSTAL LASER TURNED OFF	2	9/25/89 0:00:00	MRS	LASERXP1
1861	kbr_2	CLEAVED KBr CRYSTAL LASER TURNED ON: 640 nm, 240 mW	2	9/25/89 0:00:00	MRS	LASERXP1
1862	kbr_3	CLEAVED KBr CRYSTAL LASER TURNED OFF	2	9/25/89 0:00:00	MRS	LASERXP1
1863	kbr_4	CLEAVED KBr CRYSTAL LASER TURNED ON: 590 nm, 900 mW	1	9/25/89 0:00:00	MRS	LASERXP1
1864	kcl_1	CLEAVED KCl CRYSTAL LASER TURNED ON: 590 nm, 900 mW	2	9/25/89 0:00:00	MRS	LASERXP1
1865	kcl_2	CLEAVED KCl CRYSTAL LASER TURNED OFF	2	9/25/89 0:00:00	MRS	LASERXP1
1866	mg_uv_1	FRESHLY SCRAPED Mg ARGON UV LINES: 200 mW	3	9/28/89 0:00:00	MRS	LASERXP1
1867	mg_uv_2	FRESHLY SCRAPED Mg LASER TURNED OFF	3	9/28/89 0:00:00	MRS	LASERXP1
1868	mg_uv_3	FRESHLY SCRAPED Mg ARGON UV LINES : 480 mW	3	9/28/89 0:00:00	MRS	LASERXP1
1869	mg_uv_4	FRESHLY SCRAPED Mg LASER TURNED OFF	2	9/28/89 0:00:00	MRS	LASERXP1
1870	mn_1	NATIVE OXIDE FILM ON MANGANESE FLAKE (MOD OUTGAS) LASER ON: 590 nm, 900 mW	3	9/22/89 0:00:00	MRS	LASERXP1
1871	mn_1_a	As Received Manganese Chip (Severe Outgassing) Laser On: 1000 Mw (After M2), 590 Nm, Aper 12	4	9/7/89 0:00:00	MRS	LASERXP1
1872	mn_1_b	LASER CLEANED MANGANESE CHIP (SEVERE OUTGASSING) LASER OF	4	9/7/89 0:00:00	MRS	LASERXP1
1873	mn_1_c	AS RECEIVED MANGANESE CHIP THIS AREA NOT EXPOSED TO LASER	4	9/7/89 0:00:00	MRS	LASERXP1
1874	mn_2	NATIVE OXIDE FILM ON MANGANESE FLAKE (MOD OUTGAS) LASER TURNED OFF	2	9/22/89 0:00:00	MRS	LASERXP1
1875	mn_3	NATIVE OXIDE FILM ON MANGANESE FLAKE (MOD OUTGAS) LASER TURNED ON: 590 nm, 900 mW	2	9/22/89 0:00:00	MRS	LASERXP1
1876	mn_4	NATIVE OXIDE FILM ON MANGANESE FLAKE (MOD OUTGAS) LASER TURNED OFF	2	9/22/89 0:00:00	MRS	LASERXP1
1877	mn_5	NATIVE OXIDE FILM ON MANGANESE FLAKE (MOD OUTGAS) LASER TURNED ON : 630 nm, 350 mW	2	9/22/89 0:00:00	MRS	LASERXP1
1878	mn_6	NATIVE OXIDE FILM ON MANGANESE FLAKE (MOD OUTGAS) LASER TURNED ON : 590 nm, 350 mW	2	9/22/89 0:00:00	MRS	LASERXP1
1879	nat_co_1	"LASER-CLEANED" COBALT ROD SECTION LASER ON: 950 mW (AFTER M2), 590 nm, APER 103	3	9/8/89 0:00:00	MRS	LASERXP2
1880	nat_co_2	"LASER-CLEANED" COBALT ROD SECTION LASER OFF	3	9/8/89 0:00:00	MRS	LASERXP2
1881	nat_cr_1	Floated "Laser-cleaned" Chromium Chip (No Screen) Laser On: 1300 Mw (After M2), 590 Nm, Aper 12	3	9/8/89 0:00:00	MRS	LASERXP2
1882	nat_cr_2	FLOATED "LASER-CLEANED" CHROMIUM CHIP (NO SCREEN) LASER OFF	3	9/8/89 0:00:00	MRS	LASERXP2
1883	nat_cr_3	Floated "Laser-cleaned" Chromium Chip (No Screen) Laser On: 400 Mw (After M2), 630 Nm, Aper 12	3	9/8/89 0:00:00	MRS	LASERXP2
1884	nat_cr_4	Floated "Laser-cleaned" Chromium Chip (No Screen) Laser On: 1100 Mw (After M2), 585 Nm, Aper 12	3	9/8/89 0:00:00	MRS	LASERXP2
1885	nat_cr_5	FLOATED "LASER-CLEANED" CHROMIUM CHIP (NO SCREEN) LASER OFF (NEW AREA)	3	9/8/89 0:00:00	MRS	LASERXP2
1886	nio_1	NiO PELLETT UNDER CLIP BEFORE EXPOSED TO LASER	2	9/20/89 0:00:00	MRS	LASERXP2



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1887	nio_2	NiO PELLETT UNDER CLIP LASER ON: 590 nm, 900 mW (AFTER M2)	3	9/20/89 0:00:00	MRS	LASERXP2
1888	nio_3	NiO PELLETT UNDER CLIP LASER TURNED OFF (NOW NEED FLOOD GUN !!! )	2	9/20/89 0:00:00	MRS	LASERXP2
1889	nio_4	NiO PELLETT UNDER CLIP LASER TURNED ON: 590 nm, 900 mW	2	9/20/89 0:00:00	MRS	LASERXP2
1890	nio_5	NiO PELLETT UNDER CLIP LASER TURNED OFF	2	9/20/89 0:00:00	MRS	LASERXP2
1891	nio_6	NiO PELLETT UNDER CLIP LASER TURNED ON: 590 nm, 900 mW (CORRECT VALUE)	2	9/20/89 0:00:00	MRS	LASERXP2
1892	nio_7	New Area On Nio Pellet Under Clip Laser Turned On: 590 Nm, 900 Mw (Correct Value)	2	9/20/89 0:00:00	MRS	LASERXP2
1893	nio_8	Original Area On Nio Pellet Under Clip Laser Turned On: 590 Nm, 900 Mw (Correct Value)	3	9/20/89 0:00:00	MRS	LASERXP2
1894	nio_9	ORIGINAL AREA ON NiO PELLETT UNDER CLIP LASER TURNED OFF	2	9/20/89 0:00:00	MRS	LASERXP2
1895	nio_ar_1	NiO PELLETT (BACK SIDE OF ORIGINAL) UNDER CLIP ARGON MULTI-LINE ON: 900 mW	2	9/27/89 0:00:00	MRS	LASERXP2
1896	nio_ar_2	NiO PELLETT (BACK SIDE OF ORIGINAL) UNDER CLIP LASER TURNED OFF	2	9/27/89 0:00:00	MRS	LASERXP2
1897	nio_ar_3	NiO PELLETT (BACK SIDE OF ORIGINAL) UNDER CLIP ARGON MULTI-LINE ON AGAIN: 900 mW	2	9/27/89 0:00:00	MRS	LASERXP2
1898	nio_ar_4	NiO PELLETT (BACK SIDE OF ORIGINAL) UNDER CLIP ARGON MULTI-LINE ON AGAIN: 1500 mW	2	9/27/89 0:00:00	MRS	LASERXP2
1899	nio_ar_5	NiO Pellet (Back Side Of Original) Under Clip Argon Multi-line On Again: 3000 Mw (Can See Ni)	2	9/27/89 0:00:00	MRS	LASERXP2
1900	no_fg_cr	7 mm Diam, 1 Mm Thick Cr2o3 Pellet Under Gold Clipcleaned By Laser, 590 Nm, 1 W, Aper 12 (No Dst)	4	9/13/89 0:00:00	MRS	LASERXP2
1901	no_fg_cu	7 mm DIAM, 1 mm THICK CuO PELLETT UNDER GOLD CLIP CLEANED BY LASER, LASER OFF	4	9/14/89 0:00:00	MRS	LASERXP2
1902	pcls_ar2	POLY CHLORO STYRENE FILM UNDER CLIP (NO DST) ARGON MULTI-LINE ON: 800 mW	2	9/27/89 0:00:00	MRS	LASERXP2
1903	pcls_ar3	POLY CHLORO STYRENE FILM UNDER CLIP (NO DST) LASER TURNED OFF	2	9/27/89 0:00:00	MRS	LASERXP2
1904	pcls_ar4	POLY CHLORO STYRENE FILM UNDER CLIP (NO DST) ARGON MULTI-LINE ON AGAIN: 800 mW	2	9/27/89 0:00:00	MRS	LASERXP2
1905	pcls_ar5	POLY CHLORO STYRENE FILM UNDER CLIP (NO DST) ARGON MULTI-LINE ON AGAIN: 1300 mW	2	9/27/89 0:00:00	MRS	LASERXP2
1906	pcls_ara	POLY CHLORO STYRENE FILM UNDER CLIP (NO DST) BEFORE EXPOSING TO LASER	1	9/27/89 0:00:00	MRS	LASERXP2
1907	pcls_ar_	POLY CHLORO STYRENE FILM UNDER CLIP (NO DST) BEFORE EXPOSING TO LASER	2	9/27/89 0:00:00	MRS	LASERXP2
1908	pellet1a	LASER CLEANED Cr2O3 PELLETT ON DST UNDER SCREEN LASER ON: 30 mW, 590 nm, APER 1	2	9/6/89 0:00:00	MRS	LASERXP2
1909	pellet_1	LASER CLEANED Cr2O3 PELLETT ON DST UNDER SCREEN LASER OFF (EXPOSED TO 600 mW BEAM)4		9/6/89 0:00:00	MRS	LASERXP2
1910	pellet_2	Laser Cleaned Cr2o3 Pellet On Dst Under Screen Laser On: 850 Mw (After M2), 600 Nm, Aper 10	5	9/6/89 0:00:00	MRS	LASERXP2
1911	pellet_3	Laser Cleaned Cr2o3 Pellet On Dst Under Screen Laser On: 520 Mw (After M2), 610 Nm, Aper 10	3	9/6/89 0:00:00	MRS	LASERXP2
1912	pellet_4	Laser Cleaned Cr2o3 Pellet On Dst Under Screen Laser On: 580 Mw (After M2), 620 Nm, Aper 11	3	9/6/89 0:00:00	MRS	LASERXP2
1913	pellet_5	Laser Cleaned Cr2o3 Pellet On Dst Under Screen Laser On: 280 Mw (After M2), 630 Nm, Aper 11	3	9/6/89 0:00:00	MRS	LASERXP2
1914	pellet_6	Laser Cleaned Cr2o3 Pellet On Dst Under Screen Laser On: 620 Mw (After M2), 580 Nm, Aper 10	3	9/6/89 0:00:00	MRS	LASERXP2
1915	pellet_7	Laser Cleaned Cr2o3 Pellet On Dst Under Screen Laser On: 340 Mw (After M2), 570 Nm, Aper 12	3	9/6/89 0:00:00	MRS	LASERXP2
1916	pellet_8	Laser Cleaned Cr2o3 Pellet On Dst Under Screen Laser On: 700 Mw (After M2), 591 Nm, Aper 8	3	9/6/89 0:00:00	MRS	LASERXP2
1917	pellet_9	Laser Cleaned Cr2o3 Pellet On Dst Under Screen Laser On: 700 Mw (After M2), 592 Nm, Aper 8	3	9/6/89 0:00:00	MRS	LASERXP2
1918	pell_1	LASER CLEANED Cr2O3 PELLETT UNDER SCREEN LASER ON: 600mW, 590 nm, APER 6	1	9/6/89 0:00:00	MRS	LASERXP2
1919	pell_2	Laser Cleaned Cr2o3 Pellet Under Screen Laser Off (Sample Exposed Once To 600mw)	1	9/6/89 0:00:00	MRS	LASERXP2
1920	pet_ar_1	PET FILM UNDER CLIP (NO DST) BEFORE EXPOSURE TO ARGON LASER	2	9/27/89 0:00:00	MRS	LASERXP2
1921	pet_ar_2	PET FILM UNDER CLIP (NO DST) ARGON MULTI-LINE ON: 1500 mW	2	9/27/89 0:00:00	MRS	LASERXP2
1922	pet_ar_3	PET FILM UNDER CLIP (NO DST) LASER TURNED OFF	2	9/27/89 0:00:00	MRS	LASERXP2
1923	pet_ar_4	PET FILM UNDER CLIP (NO DST) ARGON MULTI-LINE: 3000 mW	2	9/27/89 0:00:00	MRS	LASERXP2
1924	pet_ar_5	PET FILM UNDER CLIP (NO DST) MELTED AREA ARGON MULTI-LINE: 3000 mW	2	9/27/89 0:00:00	MRS	LASERXP2
1925	pet_ar_6	PET FILM UNDER CLIP (NO DST) MELTED AREA #2 ARGON MULTI-LINE: 3000 mW	2	9/27/89 0:00:00	MRS	LASERXP2
1926	pet_ar_7	PET FILM UNDER CLIP (NO DST) MELTED AREA #2 LASER TURNED OFF	2	9/27/89 0:00:00	MRS	LASERXP2
1927	pllet_10	Laser Cleaned Cr2o3 Pellet On Dst Under Screen Laser On: 700 Mw (After M2), 593 Nm, Aper 8	3	9/6/89 0:00:00	MRS	LASERXP2

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
1928	pllet_11	Laser Cleaned Cr2o3 Pellet On Dst Under Screen	Laser On: 700 Mw (After M2), 594 Nm, Aper 8	3	9/6/89 0:00:00	MRS LASERXP2
1929	pllet_12	Laser Cleaned Cr2o3 Pellet On Dst Under Screen	Laser On: 700 Mw (After M2), 595 Nm, Aper 8	3	9/6/89 0:00:00	MRS LASERXP2
1930	pllet_13	Laser Cleaned Cr2o3 Pellet On Dst Under Screen	Laser On: 700 Mw (After M2), 596 Nm, Aper 8	3	9/6/89 0:00:00	MRS LASERXP2
1931	pllet_14	Laser Cleaned Cr2o3 Pellet On Dst Under Screen	Laser On: 700 Mw (After M2), 597 Nm, Aper 8	3	9/6/89 0:00:00	MRS LASERXP2
1932	pllet_15	Laser Cleaned Cr2o3 Pellet On Dst Under Screen	Laser On: 700 Mw (After M2), 598 Nm, Aper 8	3	9/6/89 0:00:00	MRS LASERXP2
1933	pllet_16	Laser Cleaned Cr2o3 Pellet On Dst Under Screen	Laser On: 700 Mw (After M2), 599 Nm, Aper 8	3	9/6/89 0:00:00	MRS LASERXP2
1934	pllet_1b	Laser Cleaned Cr2o3 Pellet On Dst Under Screen	Laser On: 170 Mw (After M2), 590 Nm, Aper 2	3	9/6/89 0:00:00	MRS LASERXP2
1935	pllet_1c	Laser Cleaned Cr2o3 Pellet On Dst Under Screen	Laser On: 290 Mw (After M2), 590 Nm, Aper 3	3	9/6/89 0:00:00	MRS LASERXP2
1936	pllet_1d	Laser Cleaned Cr2o3 Pellet On Dst Under Screen	Laser On: 380 Mw (After M2), 590 Nm, Aper 4	3	9/6/89 0:00:00	MRS LASERXP2
1937	pllet_1e	Laser Cleaned Cr2o3 Pellet On Dst Under Screen	Laser On: 560 Mw (After M2), 590 Nm, Aper 6	3	9/6/89 0:00:00	MRS LASERXP2
1938	pllet_1f	Laser Cleaned Cr2o3 Pellet On Dst Under Screen	Laser On: 780 Mw (After M2), 590 Nm, Aper 10	3	9/6/89 0:00:00	MRS LASERXP2
1939	pllet_1g	Laser Cleaned Cr2o3 Pellet On Dst Under Screen	Laser On: 960 Mw (After M2), 590 Nm, Aper 10	3	9/6/89 0:00:00	MRS LASERXP2
1940	pllet_1h	Laser Cleaned Cr2o3 Pellet On Dst Under Screen	Laser Off: After Being Exposed To 960 Mw Beam	5	9/6/89 0:00:00	MRS LASERXP2
1941	ps_ar11a	PS FILM UNDER CLIP (NO DST) LASER TURNED OFF AFTER EXPOSURE TO 7500 mW ARGON		2	9/27/89 0:00:00	MRS LASERXP2
1942	ps_arnf2	POLY STYRENE FILM UNDER CLIP (NO DST) NO FLOOD GUN, LASER OFF		1	9/27/89 0:00:00	MRS LASERXP2
1943	ps_ar_1	POLYSTYRENE FILM/DST UNDER SCREEN ARGON MULTI-LINE: 1000 mW		3	9/26/89 0:00:00	MRS LASERXP2
1944	ps_ar_10	PS FILM UNDER CLIP (NO DST) ARGON MULTI-LINE ON: 7500 mW		1	9/27/89 0:00:00	MRS LASERXP2
1945	ps_ar_11	PS FILM UNDER CLIP (NO DST) LASER TURNED OFF AFTER EXPOSURE TO 7500 mW ARGON		1	9/27/89 0:00:00	MRS LASERXP2
1946	ps_ar_2	POLYSTYRENE FILM/DST UNDER SCREEN (OUTGASSING) ARGON MULTI-LINE: 3500 mW		1	9/26/89 0:00:00	MRS LASERXP2
1947	ps_ar_3	POLYSTYRENE FILM/DST UNDER SCREEN (OUTGASSING) LASER TURNED OFF		1	9/26/89 0:00:00	MRS LASERXP2
1948	ps_ar_4	PS FILM UNDER CLIP (NO DST) BEFORE EXPOSURE TO ARGON MULTI-LINE		1	9/27/89 0:00:00	MRS LASERXP2
1949	ps_ar_5	PS FILM UNDER CLIP (NO DST) ARGON MULTI-LINE ON: 2300 mW		1	9/27/89 0:00:00	MRS LASERXP2
1950	ps_ar_6	PS FILM UNDER CLIP (NO DST) ARGON MULTI-LINE ON: 3000 mW		1	9/27/89 0:00:00	MRS LASERXP2
1951	ps_ar_7	PS FILM UNDER CLIP (NO DST) LASER TURNED OFF		1	9/27/89 0:00:00	MRS LASERXP2
1952	ps_ar_8	PS FILM UNDER CLIP (NO DST) ARGON MULTI-LINE ON: 4000 mW		1	9/27/89 0:00:00	MRS LASERXP2
1953	ps_ar_8a	PS FILM UNDER CLIP (NO DST) ARGON MULTI-LINE ON: 4000 mW		1	9/27/89 0:00:00	MRS LASERXP2
1954	ps_ar_9	PS FILM UNDER CLIP (NO DST) ARGON MULTI-LINE ON: 5300 mW		1	9/27/89 0:00:00	MRS LASERXP2
1955	ps_ar_nf	POLY STYRENE FILM UNDER CLIP (NO DST) NO FLOOD GUN, ARGON MULTI-LINE AT 7300 mW		2	9/27/89 0:00:00	MRS LASERXP2
1956	ps_uv_1	POLY STYRENE FILM UNDER CLIP (NO DST) ARGON UV LINES: 500+ mW		1	9/28/89 0:00:00	MRS LASERXP2
1957	ps_uv_2	POLY STYRENE FILM UNDER CLIP (NO DST) LASER TURNED OFF		1	9/28/89 0:00:00	MRS LASERXP2
1958	ps_uv_3	POLY STYRENE FILM UNDER CLIP (NO DST) ARGON UV LINES AGAIN: 500+ mW		1	9/28/89 0:00:00	MRS LASERXP2
1959	ps_uv_4	POLY STYRENE FILM UNDER CLIP (NO DST) LASER TURNED OFF		1	9/28/89 0:00:00	MRS LASERXP2
1960	pvmk_ar2	POLY VINYL METHYL KETONE/GLASS UNDER CLIP (NO DST) ARGON MULTI-LINE ON: 900 mW		2	9/27/89 0:00:00	MRS LASERXP2
1961	pvmk_ar3	POLY VINYL METHYL KETONE/GLASS UNDER CLIP (NO DST) ARGON MULTI-LINE ON: 1300 mW		2	9/27/89 0:00:00	MRS LASERXP2
1962	pvmk_ar4	Poly Vinyl Methyl Ketone/glass Under Clip (No Dst) argon Multi-line On: 3000 Mw (Does Glass Min Heat?		2	9/27/89 0:00:00	Mrs Laserxp2
1963	Pvmk_ar5	Poly Vinyl Methyl Ketone/glass Under Clip (No Dst) argon Multi-line On: 5000 Mw (Does Glass Min Heat?		2	9/27/89 0:00:00	MRS LASERXP2
1964	pvmk_ar6	Poly Vinyl Methyl Ketone/glass Under Clip (No Dst) argon Multi-line On: 6000 Mw (Does Glass Min Heat?		2	9/27/89 0:00:00	MRS LASERXP2
1965	pvmk_ar7	Poly Vinyl Methyl Ketone/glass Under Clip (No Dst) turned Laser Off (After Exposure To 6000 Mw)		2	9/27/89 0:00:00	MRS LASERXP2
1966	pvmk_ar8	Poly Vinyl Methyl Ketone/glass Under Clip (No Dst) argon Multi-line On Again: 6000 Mw		2	9/27/89 0:00:00	MRS LASERXP2
1967	pvmk_ar9	Poly Vinyl Methyl Ketone/glass Under Clip (No Dst) argon Multi-line On Again: 7300 Mw		1	9/27/89 0:00:00	MRS LASERXP2
1968	pvmk_ar_	Poly Vinyl Methyl Ketone/glass Under Clip (No Dst) before Exposing To Argon Multi-line		3	9/27/89 0:00:00	MRS LASERXP2

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
1969	pvnuv14a	Poly Vinyl Napthalene Film/glass Under Clip Orig Pos, Flood Gun On, Uv Laser On: 500 Mw	1	9/28/89 0:00:00	MRS	LASERXP2
1970	pvnuv15a	POLY VINYL NAPHTHALENE FILM/GLASS UNDER CLIP LASER OFF	1	9/28/89 0:00:00	MRS	LASERXP2
1971	pvnuv15b	POLY VINYL NAPHTHALENE FILM/GLASS UNDER CLIP LASER OFF	1	9/28/89 0:00:00	MRS	LASERXP2
1972	pvn_1	WAVELENGTH SCAN OF POLY-VINYL NAPHTHALENE 570-600nm, 0.125 nm/STEP, MAX POWER	1	9/13/89 0:00:00	DPR	LASERXP2
1973	pvn_uv10	Poly Vinyl Napthalene Film/glass Under Clip Centered, Flood Gun Off, Laser On : 300 Mw	1	9/28/89 0:00:00	MRS	LASERXP2
1974	pvn_uv11	Poly Vinyl Napthalene Film/glass Under Clip Centered, Flood Gun On, Laser On : 300 Mw	1	9/28/89 0:00:00	MRS	LASERXP2
1975	pvn_uv12	Poly Vinyl Napthalene Film/glass Under Clip Orig Pos, Flood Gun On, Laser On : 400 Mw	1	9/28/89 0:00:00	MRS	LASERXP2
1976	pvn_uv13	POLY VINYL NAPHTHALENE FILM/GLASS UNDER CLIP ORIG POS, FLOOD GUN ON, LASER OFF	1	9/28/89 0:00:00	MRS	LASERXP2
1977	pvn_uv14	Poly Vinyl Napthalene Film/glass Under Clip Orig Pos, Flood Gun On, Uv Laser On: 500 Mw	1	9/28/89 0:00:00	MRS	LASERXP2
1978	pvn_uv15	POLY VINYL NAPHTHALENE FILM/GLASS UNDER CLIP LASER OFF	1	9/28/89 0:00:00	MRS	LASERXP2
1979	pvn_uv16	POLY VINYL NAPHTHALENE FILM/GLASS UNDER CLIP ARGON UV LINES: 500+ mW	1	9/28/89 0:00:00	MRS	LASERXP2
1980	pvn_uv17	ORIGINAL PVN/GLASS SAMPLE UNDER SSI SCREEN (1 mm) ARGON UV LINES: 500+ mW	3	9/28/89 0:00:00	MRS	LASERXP2
1981	pvn_uv18	ORIGINAL PVN/GLASS SAMPLE UNDER SSI SCREEN (1 mm) LASER TURNED OFF	2	9/28/89 0:00:00	MRS	LASERXP2
1982	pvn_uv19	Original Pvn/glass Sample Under Ssi Screen (1 Mm) Fresh Area Near Exposed Area, Unexposed To UV	2	9/28/89 0:00:00	MRS	LASERXP2
1983	pvn_uv20	ORIGINAL PVN/GLASS SAMPLE UNDER SSI SCREEN (1 mm) ARGON UV LINES: 500+ mW	2	9/28/89 0:00:00	MRS	LASERXP2
1984	pvn_uv_1	POLY VINYL NAPHTHALENE FILM UNDER CLIP (NO DST) BEFORE EXPOSED TO UV LASER	1	9/28/89 0:00:00	MRS	LASERXP2
1985	pvn_uv_2	POLY VINYL NAPHTHALENE FILM UNDER CLIP (NO DST) ARGON UV LINES: 300 mW	1	9/28/89 0:00:00	MRS	LASERXP2
1986	pvn_uv_3	POLY VINYL NAPHTHALENE FILM UNDER CLIP (NO DST) LASER TURNED OFF	1	9/28/89 0:00:00	MRS	LASERXP2
1987	pvn_uv_4	POLY VINYL NAPHTHALENE FILM UNDER CLIP (NO DST) ARGON UV LINES: 70 mW	1	9/28/89 0:00:00	MRS	LASERXP2
1988	pvn_uv_5	POLY VINYL NAPHTHALENE FILM UNDER CLIP (NO DST) LASER TURNED OFF	1	9/28/89 0:00:00	MRS	LASERXP2
1989	pvn_uv_6	Poly Vinyl Napthalene Film/glass Under Clip Argon Uv Lines: 150 Mw (White Glow In Darkness)	2	9/28/89 0:00:00	MRS	LASERXP2
1990	pvn_uv_7	Poly Vinyl Napthalene Film/glass Under Clip Argon Uv Lines: 300 Mw (Blue Glow In Darkness)	1	9/28/89 0:00:00	MRS	LASERXP2
1991	pvn_uv_8	POLY VINYL NAPHTHALENE FILM/GLASS UNDER CLIP LASER TURNED OFF	1	9/28/89 0:00:00	MRS	LASERXP2
1992	pvn_uv_9	POLY VINYL NAPHTHALENE FILM/GLASS UNDER CLIP FLOOD GUN OFF, LASER ON : 300 mW	1	9/28/89 0:00:00	MRS	LASERXP2
1993	si3n4_1	Si3N4 ON Si (111) WAFER (SLIGHT BRIEF OUTGASSING) LASER TURNED ON: 590 nm, 900 mW	4	9/23/89 0:00:00	MRS	LASERXP2
1994	si3n4_2	Si3N4 ON Si (111) WAFER (SLIGHT BRIEF OUTGASSING) LASER TURNED OFF	3	9/23/89 0:00:00	MRS	LASERXP2
1995	si3n4_3	Si3N4 ON Si (111) WAFER (SLIGHT BRIEF OUTGASSING) LASER TURNED ON: 590 nm, 900 mW	1	9/23/89 0:00:00	MRS	LASERXP2
1996	sio2_1	SiO2 PLATE (5 mm THICK) NO SCREEN	3	9/18/89 0:00:00	MRS	LASERXP2
1997	sio2_1a	SiO2 PLATE (5 mm THICK) INSIDE CLIP HOLE LASER ON: 590 nm, 900 mW	2	9/18/89 0:00:00	MRS	LASERXP2
1998	sio2_2	SiO2 PLATE (5 mm THICK) INSIDE CLIP HOLE LASER TURNED OFF	2	9/18/89 0:00:00	MRS	LASERXP2
1999	sio2_3	1000 ANGSTROMS OF SiO2 ON SILICON WAFER LASER TURNED ON: 599 nm, 1 W	2	9/21/89 0:00:00	MRS	LASERXP2
2000	sio2_4	1000 ANGSTROMS OF SiO2 ON SILICON WAFER LASER TURNED OFF	2	9/21/89 0:00:00	MRS	LASERXP2
2001	si_1	SILICON WAFER WITH NATIVE OXIDE LASER TURNED ON: 630 nm, 1 W, (SLIGHT OUTGAS)4	4	9/21/89 0:00:00	MRS	LASERXP2
2002	si_2	SILICON WAFER WITH NATIVE OXIDE LASER TURNED ON: 630 nm, 1 W, (SLIGHT OUTGAS)2	2	9/21/89 0:00:00	MRS	LASERXP2
2003	si_3	SILICON WAFER WITH NATIVE OXIDE LASER TURNED ON: 660 nm, 1 W, (SLIGHT OUTGAS)2	2	9/21/89 0:00:00	MRS	LASERXP2
2004	si_4	SILICON WAFER WITH NATIVE OXIDE LASER TURNED ON: 600 nm, 5 mW	2	9/21/89 0:00:00	MRS	LASERXP2
2005	si_5	SILICON WAFER WITH NATIVE OXIDE LASER TURNED ON: 599 nm (2.07 eV), 1 W	2	9/21/89 0:00:00	MRS	LASERXP2
2006	si_6	SILICON WAFER WITH NATIVE OXIDE LASER TURNED OFF	2	9/21/89 0:00:00	MRS	LASERXP2
2007	si_ar_1	SILICON WAFER (100) WITH NATIVE OXIDE (NO OUTGAS) ARGON MULTI-LINE: 1000 mW	4	9/26/89 0:00:00	MRS	LASERXP2
2008	si_ar_2	SILICON WAFER (100) WITH NATIVE OXIDE (NO OUTGAS) ARGON MULTI-LINE: 3500 mW	4	9/26/89 0:00:00	MRS	LASERXP2
2009	si_ar_3	SILICON WAFER (100) WITH NATIVE OXIDE (NO OUTGAS) ARGON MULTI-LINE: 5500 mW	2	9/26/89 0:00:00	MRS	LASERXP2

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
2010	si_ar_4	SILICON WAFER (100) WITH NATIVE OXIDE (NO OUTGAS) LASER TURNED OFF (ALLOWED TO COOL 1 MIN)	1	19/26/89 0:00:00	MRS	LASERXP2
2011	sm2o3_1	Sm2O3 PELLETT UNDER CLIP LASER ON: 590 nm, 900 mW (AFTER M2)	3	9/20/89 0:00:00	MRS	LASERXP2
2012	sm2o3_2	Sm2O3 PELLETT UNDER CLIP LASER OFF AFTER EXPOSURE TO 900 mW AT 590 nm	2	9/20/89 0:00:00	MRS	LASERXP2
2013	s_1	CLEAVED SULFUR CRYSTAL LASER TURNED ON: 590 nm, 800 mW	1	9/25/89 0:00:00	MRS	LASERXP2
2014	s_2	CLEAVED SULFUR CRYSTAL LASER TURNED OFF	1	9/25/89 0:00:00	MRS	LASERXP2
2015	test_a	LASER CLEANED Cr2O3 PELLETT UNDER SCREEN LASER OFF (SAMPLE EXPOSED ONCE TO 600mw)	1	9/6/89 0:00:00	MRS	LASERXP2
2016	test_b	LASER CLEANED Cr2O3 PELLETT UNDER SCREEN LASER ON: 600mW, 590 nm, APER 6	1	9/6/89 0:00:00	MRS	LASERXP2
2017	tio2_1	TiO2 PELLETT (NO FLOOD GUN, NO SCREEN) LASER ON: 590 nm, 900 mW (AFTER M2)	3	9/18/89 0:00:00	MRS	LASERXP2
2018	tio2_2	TiO2 PELLETT (NO FLOOD GUN, NO SCREEN) LASER TURNED OFF	3	9/18/89 0:00:00	MRS	LASERXP2
2019	tio2_3	TiO2 PELLETT (NO FLOOD GUN, NO SCREEN) LASER TURNED ON AGAIN: 590 nm, 900 mW (AFTER M2)	2	9/18/89 0:00:00	MRS	LASERXP2
2020	tio2_4	TiO2 PELLETT (NO FLOOD GUN, NO SCREEN) LASER TURNED OFF AGAIN	2	9/18/89 0:00:00	MRS	LASERXP2
2021	tio2_5	TiO2 PELLETT (NO FLOOD GUN, NO SCREEN) LASER TURNED ON AGAIN: 590 nm, 900 mW (AFTER M2)	2	9/18/89 0:00:00	MRS	LASERXP2
2022	tio2_6	TiO2 PELLETT (NO FLOOD GUN, NO SCREEN) LASER TURNED OFF AGAIN	2	9/18/89 0:00:00	MRS	LASERXP2
2023	tio2_ar2	TiO2 PELLETT UNDER GLOD CLIP (STRONG OUTGAS) LASER TURNED OFF	2	9/26/89 0:00:00	MRS	LASERXP2
2024	tio2_ar3	TiO2 PELLETT UNDER GLOD CLIP (STRONG OUTGAS) ARGON MULTI-LINE: 900 mW	2	9/26/89 0:00:00	MRS	LASERXP2
2025	tio2_ar4	TiO2 PELLETT UNDER GLOD CLIP (STRONG OUTGAS) ARGON MULTI-LINE: 3000 mW	2	9/26/89 0:00:00	MRS	LASERXP2
2026	tio2_ar5	TiO2 PELLETT UNDER GLOD CLIP (STRONG OUTGAS) LASER TURNED OFF	2	9/26/89 0:00:00	MRS	LASERXP2
2027	tio2_ar_	TiO2 PELLETT UNDER GLOD CLIP (STRONG OUTGAS) ARGON MULTI-LINE ON: 900 mW	2	9/26/89 0:00:00	MRS	LASERXP2
2028	ybacuo_1	CPS YBaCuO SAMPLE (STRONG OUTGASSING) LASER ON 590 nm, 400 mW	6	9/23/89 0:00:00	MRS	LASERXP2
2029	ybacuo_2	CPS YBaCuO SAMPLE (STRONG OUTGASSING) LASER ON 590 nm, 700 mW	6	9/23/89 0:00:00	MRS	LASERXP2
2030	ybacuo_3	CPS YBaCuO SAMPLE (STRONG OUTGASSING) LASER TURNED OFF	5	9/23/89 0:00:00	MRS	LASERXP2
2031	ybacuo_a	CPS YBaCuO SAMPLE NO EXPOSURE	1	9/23/89 0:00:00	MRS	LASERXP2
2032	ybacuo_o	CPS YBaCuO SAMPLE NO EXPOSURE	1	9/23/89 0:00:00	MRS	LASERXP2
2033	zno_1	ZnO PELLETT UNDER GOLD CLIP BEFORE EXPOSED TO LASER	4	9/24/89 0:00:00	MRS	LASERXP2
2034	zno_1a	ZnO PELLETT UNDER GOLD CLIP BEFORE EXPOSED TO LASER	2	9/25/89 0:00:00	MRS	LASERXP2
2035	zno_1b	ZnO PELLETT UNDER GOLD CLIP BEFORE EXPOSED TO LASER	1	9/25/89 0:00:00	MRS	LASERXP2
2036	zno_2	ZnO PELLETT UNDER GOLD CLIP (NO OUTGASSING) LASER TURNED ON: 590 nm, 900 mW	4	9/25/89 0:00:00	MRS	LASERXP2
2037	zno_3	ZnO PELLETT UNDER GOLD CLIP (NO OUTGASSING) LASER TURNED OFF	2	9/25/89 0:00:00	MRS	LASERXP2
2038	zno_3a	ZnO PELLETT UNDER GOLD CLIP (NO OUTGASSING) LASER TURNED OFF	2	9/25/89 0:00:00	MRS	LASERXP2
2039	zno_4	ZnO PELLETT UNDER GOLD CLIP (NO OUTGASSING) LASER TURNED ON: 590 nm, 900 mW	2	9/25/89 0:00:00	MRS	LASERXP2
2040	mos2_01	MOLYBDENUM DI-SULFIDE (Mo_S2) FRESHLY EXPOSED SURFACE OF A POLYMORPHIC SHEET	2	7/21/87 0:00:00	MRS	LUBRICNT
2041	wd_40	WD-40 LUBRICANT SMEARED ON A GOLD PLATEN	4	10/13/85 0:00:00	MRS	LUBRICNT
2042	30_ang_k	30 Angstrom Coating of Krytox Type Lubricant at 35 TOA	1	12/3/92 0:00:00	MRS	MAG_MEM
2043	36_ang_k	36 Angstrom Coating of Krytox type lubricant: 35 TOA	1	12/7/93 0:00:00	MRS	MAG_MEM
2044	48_ang_k	48 Angstrom coating of Krytox type lubricant: 35 TOA	1	12/7/93 0:00:00	MRS	MAG_MEM
2045	after_1	#1: Heat treated (150C, 1hr), 10X thermal cycles	1	4/10/92 0:00:00	MRS	MAG_MEM
2046	after_2	#2: No heat treatment, 10X thermal cycles	1	4/10/92 0:00:00	MRS	MAG_MEM
2047	after_3	#3: Heat treated (150C, 1hr), 10X thermal cycles	1	4/10/92 0:00:00	MRS	MAG_MEM
2048	after_3a	Lubricant on sample "#3" removed by minimum ion etching	1	4/21/92 0:00:00	MRS	MAG_MEM
2049	after_4	#4: Heat treated (150C, 1hr), 10X thermal cycles	1	4/10/92 0:00:00	MRS	MAG_MEM
2050	after_5a	Lubricant on sample "#5" removed by minimum ion etching	1	4/21/92 0:00:00	MRS	MAG_MEM

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
2051	AFTER_5B	Lubricant on sample "#5" heavily ion etched over large area.	1	4/21/92 0:00:00	MRS	MAG_MEM
2052	alumite1	Corrosion Tested Cu/Alumite Disk (as rec'd, 90 TOA)	3	5/20/92 0:00:00	MRS	MAG_MEM
2053	ALUMITE2	Corrosion Tested Cu/Alumite Disk #2 (as rec, 90 TOA)	3	5/20/92 0:00:00	MRS	MAG_MEM
2054	before_1	#1: Heat treated (150C, 1hr), No heat cycles	1	4/10/92 0:00:00	MRS	MAG_MEM
2055	before_2	#2: No heat treatment, No heat cycles	1	4/10/92 0:00:00	MRS	MAG_MEM
2056	before_3	#3: Heat treated (150C, 1hr), No heat cycles	1	4/10/92 0:00:00	MRS	MAG_MEM
2057	before_5	#5: Heat treated (150C, 1hr), No heat cycles	1	4/10/92 0:00:00	MRS	MAG_MEM
2058	black1	Black Color Lubricant on Magnetic hard disk	4	7/21/91 0:00:00	MRS	MAG_MEM
2059	black1e	Black Color Lub/Disk (5 sec 2KV etch,"F" down 90%)	2	7/19/91 0:00:00	MRS	MAG_MEM
2060	brown2	Brown Color Lub/Disk (carbon deposition check)	4	7/19/91 0:00:00	MRS	MAG_MEM
2061	brown2a	Brown Color Lub/Disk (carbon deposition check)	1	7/19/91 0:00:00	MRS	MAG_MEM
2062	brown2e	Brown Color Lub/Disk (5 sec 2KV ion etch)	2	7/19/91 0:00:00	MRS	MAG_MEM
2063	disk_01	3.5 MM FROM "OD" OF UN-NUMBERED SIDE OF DISC	2	5/19/88 0:00:00	MRS	MAG_MEM
2064	dkk_01	10 MM FROM ID EDGE OF "DKK" DISC	1	5/19/88 0:00:00	MRS	MAG_MEM
2065	dkk_02	10 MM FROM ID EDGE OF "DKK" DISC	1	5/19/88 0:00:00	MRS	MAG_MEM
2066	dkk_03	30 MM FROM ID EDGE OF "DKK" DISC	1	5/19/88 0:00:00	MRS	MAG_MEM
2067	new_head	New Type Mag Head (middle of rail) 35 TOA, light etch	3	12/17/93 0:00:00	MRS	MAG_MEM
2068	normal_1	Disk #1 (normal area > 5mm away from scratch)	3	7/19/91 0:00:00	MRS	MAG_MEM
2069	normal_2	Disk #2 (normal area > 5mm away from scratch)	3	7/19/91 0:00:00	MRS	MAG_MEM
2070	normal_3	Disk #3 (normal area > 5 mm away from scratch)	3	7/19/91 0:00:00	MRS	MAG_MEM
2071	normal_4	Disk #4 (normal area > 5 mm away from scratch)	3	7/19/91 0:00:00	MRS	MAG_MEM
2072	scratc1a	Head Scratch Disk #1 (center of inside ABS track)	2	7/19/91 0:00:00	MRS	MAG_MEM
2073	scratch1	Head Scratch Disk #1 (center of inside ABS track)	3	7/19/91 0:00:00	MRS	MAG_MEM
2074	scratch2	Head Scratch Disk #2 (center, inside ABS track)	3	7/19/91 0:00:00	MRS	MAG_MEM
2075	scratch3	Head Scratch Disk #3 (center of inside track)	3	7/19/91 0:00:00	MRS	MAG_MEM
2076	scratch4	Head Scratch Disk #4 (center of inside track)	3	7/19/91 0:00:00	MRS	MAG_MEM
2077	tape_01	M2 Tape #4.0 (As rec'd, NO Damage from Non-Mono)	1	10/27/92 0:00:00	MRS	MAG_MEM
2078	tape_02	M2 Tape #4.0 (exposed to 100W source in Inspector)	7	10/27/92 0:00:00	MRS	MAG_MEM
2079	tape_03	M2 Tape #4.0 (As rec'd, NO Damage from Non-Mono)	7	10/27/92 0:00:00	MRS	MAG_MEM
2080	tape_04	M2 Tape #4.0 (exposed to 100W source in Inspector)	1	10/27/92 0:00:00	MRS	MAG_MEM
2081	xg31_id	10 MM FROM ID EDGE OF 95-XG-31 SAMPLE #2	2	5/19/88 0:00:00	MRS	MAG_MEM
2082	xg31_md	20 MM FROM ID EDGE OF 95-XG-31 SAMPLE #2	2	5/19/88 0:00:00	MRS	MAG_MEM
2083	xg31_od	30 MM FROM ID EDGE OF 95-XG-31 SAMPLE #2	2	5/19/88 0:00:00	MRS	MAG_MEM
2084	almandin	Almandine (Fe3Al2(SiO4)3) Alaska USA fresh bulk	13	6/29/94 0:00:00	MRS	MINERAL
2085	anatase1	Anatase (beta-TiO2) on Magnetite (Arkansas, USA)	9	6/17/94 0:00:00	MRS	MINERAL
2086	anatase2	Anatase (beta-TiO2) on Magnetite (Arkansas, USA)	3	6/17/94 0:00:00	MRS	MINERAL
2087	argentit	Ag2S (Argentite, Guanajuato, Mex.) filed bulk	10	6/15/94 0:00:00	MRS	MINERAL
2088	argntite	Ag2S (Argentite, Guanajuato, Mex.) filed bulk	5	6/15/94 0:00:00	MRS	MINERAL
2089	azurite	CuCO3,Cu(OH)2 Arizona,USA bulk 90 TOA, mesh	8	5/23/94 0:00:00	MRS	MINERAL
2090	azurite1	CuCO3:Cu(OH)2 (Azurite) Arizona, USA bulk 90 TOA, mesh	8	5/23/94 0:00:00	MRS	MINERAL
2091	azurite2	Green CuCO3,Cu(OH)2 Arizona,USA bulk 90 TOA, mesh	7	5/24/94 0:00:00	MRS	MINERAL

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
2092	brookit2	Brookite (gamma-TiO <sub>2</sub> ) Arkansas,USA (black, conduc)	4	6/17/94 0:00:00	MRS	MINERAL
2093	brookite	Brookite (gamma-TiO <sub>2</sub> ) Arkansas,USA (black, conduc)	10	6/17/94 0:00:00	MRS	MINERAL
2094	calcite	Calcite (CaCO <sub>3</sub> ) Iceland Spar (cleaved edge, 55 TOA	5	12/22/93 0:00:00	MRS	MINERAL
2095	cassitr	SnO <sub>2</sub> (Cassiterite, Minas Gerais, Brazil) bulk, 90T	7	6/10/94 0:00:00	MRS	MINERAL
2096	cerrusit	Cerrusite (PbCO <sub>3</sub> ) as rec'd surface	10	6/26/94 0:00:00	MRS	MINERAL
2097	cerrust2	Cerrusite (PbCO <sub>3</sub> ) as rec'd surface 90 TOA, mesh	1	6/28/94 0:00:00	MRS	MINERAL
2098	chrysobe	Chrysoberyl (BeAl <sub>2</sub> O <sub>4</sub> ) Brazil fresh bulk	12	6/30/94 0:00:00	MRS	MINERAL
2099	cinnabar	Cinnabar (HgS) lg xtl,fresh bulk,mesh, Ukraine Rus	11	6/17/94 0:00:00	MRS	MINERAL
2100	corundm1	Corundum (Al <sub>2</sub> O <sub>3</sub> red/pink) India fresh bulk	11	6/27/94 0:00:00	MRS	MINERAL
2101	corundm2	Corundum (Al <sub>2</sub> O <sub>3</sub> red/pink) India fresh bulk	1	6/29/94 0:00:00	MRS	MINERAL
2102	covellit	CuS (Covellite dk blue polished natl xtl)EtOH wipe	11	6/9/94 0:00:00	MRS	MINERAL
2103	covellit2	CuS (Covellite dk blue polished natl xtl)20s 2KV	14	6/10/94 0:00:00	MRS	MINERAL
2104	cuprite1	Cu <sub>2</sub> O (cuprite natl xtal, Zaire, Africa) fract bulk	10	6/8/94 0:00:00	MRS	MINERAL
2105	cuprite2	Cu <sub>2</sub> O (cuprite natl xtal, Zaire, Africa) fract bulk	8	6/8/94 0:00:00	MRS	MINERAL
2106	cuprite3	Cu <sub>2</sub> O (Cuprite,dk red natl xtl,Zaire,Africa) fract	17	6/9/94 0:00:00	MRS	MINERAL
2107	cuprite4	Cu <sub>2</sub> O (Cuprite,dk red natl xtl,Zaire,Africa) fract	4	6/9/94 0:00:00	MRS	MINERAL
2108	cuprite5	Cuprite fract bulk ion etched 20s at 2KV,10ma	6	6/9/94 0:00:00	MRS	MINERAL
2109	diaspore	Diaspore (AlOOH = Al <sub>2</sub> O <sub>3</sub> -1H <sub>2</sub> O) crystal bulk	9	8/14/94 0:00:00	MRS	MINERAL
2110	galena	PbS xtl (Galena) Missouri,USA, fresh bulk, 35 TOA	10	5/13/94 0:00:00	MRS	MINERAL
2111	halite_1	Halite (NaCl + ?) crystal bulk	13	8/15/94 0:00:00	MRS	MINERAL
2112	hausmann	Mn <sub>3</sub> O <sub>4</sub> (Hausmannite, S. Africa) fresh bulk	9	6/14/94 0:00:00	MRS	MINERAL
2113	hematit2	alpha-Fe <sub>2</sub> O <sub>3</sub> (Hematite) Arizona,USA bulk 90 TOA	3	5/24/94 0:00:00	MRS	MINERAL
2114	hematite	alpha-Fe <sub>2</sub> O <sub>3</sub> (Hematite) Arizona,USA bulk 90 TOA	8	5/24/94 0:00:00	MRS	MINERAL
2115	kunzite1	Kunzite (LiAlSi <sub>2</sub> O <sub>6</sub> ) Aghanistan fresh bulk clear	17	7/1/94 0:00:00	MRS	MINERAL
2116	magnesit	MgCO <sub>3</sub> (Magnesite) Washington,USA bulk,mesh,90 TOA	8	5/26/94 0:00:00	MRS	MINERAL
2117	opal_1	Opal (SiO <sub>2</sub> -nH <sub>2</sub> O) Mexico	10	8/14/94 0:00:00	MRS	MINERAL
2118	orpiment	As <sub>2</sub> S <sub>3</sub> (Orpiment) Nevada,USA bulk, mesh, 90 TOA	10	5/24/94 0:00:00	MRS	MINERAL
2119	orpimnt1	As <sub>2</sub> S <sub>3</sub> (Orpiment) bulk Nevada, USA, mesh 90 TOA	10	5/26/94 0:00:00	MRS	MINERAL
2120	orpimnt2	As <sub>2</sub> S <sub>3</sub> (Orpiment) bulk Nevada, USA, mesh 90 TOA	2	5/26/94 0:00:00	MRS	MINERAL
2121	perovskt	CaTiO <sub>3</sub> xtal (freshly exposed bulk, 90 TOA, scrn)	9	6/23/94 0:00:00	MRS	MINERAL
2122	pyrite	FeS <sub>2</sub> xtl (Pyrite, Mexico) fresh bulk, 80 TOA	10	5/13/94 0:00:00	MRS	MINERAL
2123	pyrope_1	Pyrope (Mg <sub>3</sub> Al <sub>2</sub> (SiO <sub>4</sub> ) <sub>3</sub> ) Arizona USA fresh bulk red	16	6/26/94 0:00:00	MRS	MINERAL
2124	pyrope_2	Pyrope (Mg <sub>3</sub> Al <sub>2</sub> (SiO <sub>4</sub> ) <sub>3</sub> ) Arizona USA fresh bulk red	1	6/28/94 0:00:00	MRS	MINERAL
2125	realgar	As <sub>2</sub> S <sub>2</sub> (Realgar) bulk Nevada,USA mesh 90 TOA	10	5/26/94 0:00:00	MRS	MINERAL
2126	realgar2	As <sub>2</sub> S <sub>2</sub> (Realgar) bulk Nevada,USA mesh 90 TOA	2	5/26/94 0:00:00	MRS	MINERAL
2127	rhochrst	MnCO <sub>3</sub> xtl (Rhodochrosite, Argentina) fresh bulk 90	7	5/13/94 0:00:00	MRS	MINERAL
2128	rtl_qrtz	TiO <sub>2</sub> -SiO <sub>2</sub> (Rutile-Quartz) Brazil mesh, 90 TOA	10	5/24/94 0:00:00	MRS	MINERAL
2129	rutile_1	Rutile (alpha-TiO <sub>2</sub> ) on Hematite (Bahia,Brazil) F?	9	6/16/94 0:00:00	MRS	MINERAL
2130	sapphir1	Sapphire (Al <sub>2</sub> O <sub>3</sub> ) dk grn fresh bulk Sri Lanka	11	6/25/94 0:00:00	MRS	MINERAL
2131	sapphir2	Sapphire (Al <sub>2</sub> O <sub>3</sub> ) dk grn fresh bulk Sri Lanka	1	6/28/94 0:00:00	MRS	MINERAL
2132	scheeite	Scheelite (CaWO <sub>4</sub> ) crystal bulk	11	8/14/94 0:00:00	MRS	MINERAL

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
2133	spinel_1	Spinel (MgAl <sub>2</sub> O <sub>4</sub> ) Sri Lanka fresh bulk (purple/whit	14	6/27/94 0:00:00	MRS	MINERAL
2134	spinel_2	Spinel (MgAl <sub>2</sub> O <sub>4</sub> ) Sri Lanka fresh bulk (purple/whit	1	6/29/94 0:00:00	MRS	MINERAL
2135	tantalit	Tantalite (Nb? Ta?) Minas Gerais,Brazil fresh bulk	10	6/14/94 0:00:00	MRS	MINERAL
2136	tausnit1	SrTiO <sub>3</sub> xtal (freshly exposed bulk, 90 TOA, scrn)	10	5/30/94 0:00:00	MRS	MINERAL
2137	tausnit2	SrTiO <sub>3</sub> xtal (as received, 90 TOA, scrn)	8	6/1/94 0:00:00	MRS	MINERAL
2138	xenotime	Xenotime (YPO <sub>4</sub> )	11	8/13/94 0:00:00	MRS	MINERAL
2139	zircon_1	Zircon (ZrSiO <sub>4</sub> ) Brazil red/brown fresh bulk	12	7/1/94 0:00:00	MRS	MINERAL
2140	bcnalmg1	Si <sub>3</sub> N <sub>4</sub> +MgAl <sub>2</sub> O <sub>4</sub> +B <sub>2</sub> O <sub>3</sub> PELLET AFTER ETCHED 500A	4	10/24/88 0:00:00	MRS	MISC
2141	bcnalmg2	Si <sub>3</sub> N <sub>4</sub> +MgAl <sub>2</sub> O <sub>4</sub> +B <sub>2</sub> O <sub>3</sub> PELLET AS RECEIVED Ni MESH USED	3	10/24/88 0:00:00	MRS	MISC
2142	bcnalmg3	Si <sub>3</sub> N <sub>4</sub> +MgAl <sub>2</sub> O <sub>4</sub> +B <sub>2</sub> O <sub>3</sub> PELLET AFTER ETCHED 500A	4	10/31/88 0:00:00	MRS	MISC
2143	bcnalmg4	Si <sub>3</sub> N <sub>4</sub> POWDER AFTER ION ETCHED 500A	2	11/1/88 0:00:00	MRS	MISC
2144	cleaner	MICRO LAB CLEANING SOLUTION SMEARED ON A GOLD PLATEN	8	10/19/85 0:00:00	MRS	MISC
2145	cu_heate	Brown Wrinkled Film On Top Of Copper Sheet (Indirectly Heated In Crucible In Air - > 600 C)	5	6/29/87 0:00:00	MRS	MISC
2146	cu_pc_1	Copper Phenyl Cyanine: 1 LAYER (AS RECEIVED, 90 DEG TOA)	6	3/15/88 0:00:00	MRS	MISC
2147	cu_pc_2	Coper Phenyl Cyanine: 4 LAYERS (AS RECEIVED, 90 DEG TOA)	6	3/16/88 0:00:00	MRS	MISC
2148	dbl_side	DOUBLE STICK TAPE FROM SCOTCH (3M) CAT. #136	4	10/13/85 0:00:00	MRS	MISC
2149	dhm_1	DHM powder pressed onto DST with screen	5	11/4/92 0:00:00	MRS	MISC
2150	display2	WHITE DISPLAY AS RECEIVED TOP LEFT ( RERUN )	6	10/25/88 0:00:00	MRS	MISC
2151	display_	WHITE DISPLAY AS RECEIVED	5	10/25/88 0:00:00	MRS	MISC
2152	jewelry1	Metal Ball On A Ring Which Became Black After Being Cleaned With Jewelry Cleanser	1	10/20/87 0:00:00	MRS	MISC
2153	jewelry2	Metal Ball On A Ring Which Became Gray After Being Cleaned With Jewelry Cleanser	1	10/20/87 0:00:00	MRS	MISC
2154	jewelry3	EDGE OF GOLD RING (CLEANED WITH JEWELRY CLEANSER ?)	1	10/20/87 0:00:00	MRS	MISC
2155	loc_403	LOCTITE SUPER BONDER #493 (CYANOACRYLATE ADHESIVE)LET AIR DRY FOR ONE DAY	6	10/13/85 0:00:00	MRS	MISC
2156	loc_414	LOCTITE 414 ON GLASS	4	11/9/85 0:00:00	MRS	MISC
2157	loc_414a	LOCTITE 414 ON GLASS	1	11/9/85 0:00:00	MRS	MISC
2158	loc_416	Loctite Super Bonder #416 (Cyanoacrylate Adhesive) Allowed To Air Dry For 1 Day	6	10/13/85 0:00:00	MRS	MISC
2159	loc_493	LOCTITE SUPER BONDER #493 (CYANOACRYLATE) LET AIR DRY 1 DAY (no mesh)	6	10/13/85 0:00:00	MRS	MISC
2160	mold_rel	EASE RELEASE 300 MOLD RELEASE AGENT SMEARED ON A GOLD PLATEN	6	10/13/85 0:00:00	MRS	MISC
2161	plasma_cu	PLASMA TREATED COPPER PIN (TOP OF PIN WAS ARRANGED TO 90 DEG TOA)	6	3/25/88 0:00:00	MRS	MISC
2162	purecu62	Time dependence after PureCu_61	20	4/25/91 0:00:00	MRS	MISC
2163	purecu72	Time dependence after Ar 5*10-8Torr 5KV 1mA	20	4/26/91 0:00:00	MRS	MISC
2164	purecu73	Time dependence after PureCu_72	20	4/26/91 0:00:00	MRS	MISC
2165	purecu81	Time dependence after Ar spt 5*10-8Torr 5KV 1mA	20	4/30/91 0:00:00	MRS	MISC
2166	purecu82	Time dependence after PureCu_81	20	4/30/91 0:00:00	MRS	MISC
2167	scat_ion	Aes Data Generated By Ion Etching Cu Foil, 45 Deg Toa, X-rays Off, 1 Ma, 1 Kev, 4x4 Raster, 1.0x10-7	2	10/14/87 0:00:00	MRS	MISC
2168	sil_rmvr	SLIDE SILICONE REMOVER SMEARED ONTO A GOLD PLATEN	6	11/2/85 0:00:00	MRS	MISC
2169	sn_coat1	BAD SAMPLE (WRONG COLOR) OF TIN PLATED WIRE (AS RECEIVED)	4	4/26/88 0:00:00	MRS	MISC
2170	sn_coat2	GOOD SAMPLE (NORMAL COLOR) OF TIN PLATED WIRE (AS RECEIVED)	4	4/26/88 0:00:00	MRS	MISC
2171	spider	BLACK WIDOW SPIDER WEB (NON-STICKY) (HAS BEEN USED FOR GUN SIGHTS)	5	10/20/85 0:00:00	MRS	MISC
2172	taox_1	Ta Oxide/glass (35 TOA, as rec'd) (used SSI mesh)	1	2/22/94 0:00:00	MRS	MISC
2173	taox_1a	Ta Oxide/glass (35 TOA, as rec'd) (used SSI mesh)	1	2/22/94 0:00:00	MRS	MISC

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
2174	taox_1b	Ta Oxide/glass (35 TOA, as rec'd) (used SSI mesh)	3	2/22/94 0:00:00	MRS	MISC
2175	taox_2	Ta Oxide/polymer/glass (as rec'd, 35 TOA) (used SSI mesh)	5	2/22/94 0:00:00	MRS	MISC
2176	taox_2a	Ta Oxide/polymer/glass (35 TOA, as rec'd) (used SSI mesh)	4	2/22/94 0:00:00	MRS	MISC
2177	taox_3	Ta Oxide/polymer/glass (as rec'd, 35 TOA) (used SSI mesh)	5	2/22/94 0:00:00	MRS	MISC
2178	taox_4	Ta Oxide/polymer/glass (as rec'd, 35 TOA) (used SSI mesh)	5	2/22/94 0:00:00	MRS	MISC
2179	ge_pb_01	Product from reacting: PbO:GeO2:PbF2 = 20:50:30 (mesh)	7	3/10/93 0:00:00	MRS	MIXED_OX
2180	ge_pb_02	Product from reacting: PbO:GeO2:PbF2 = 30:50:20 (mesh)	7	3/10/93 0:00:00	MRS	MIXED_OX
2181	ge_pb_03	Product from reacting: PbO:GeO2:PbF2 = 40:50:10 (mesh)	7	3/10/93 0:00:00	MRS	MIXED_OX
2182	ge_pb_04	Product from reacting: PbO:GeO2:PbF2 = 50:50:0 (no F) (mesh)	7	3/10/93 0:00:00	MRS	MIXED_OX
2183	ge_pb_05	Product from reacting: PbO:GeO2:PbF2 = 0:80:20 (exposed bulk, mesh)	7	3/10/93 0:00:00	MRS	MIXED_OX
2184	ge_pb_06	Product from reacting: PbO:GeO2:PbF2 = 10:70:20 (mesh)	7	3/10/93 0:00:00	MRS	MIXED_OX
2185	ge_pb_07	Product of reacting: PbO:GeO2:PbF2 = 20:60:20 (exposed bulk, mesh)	7	3/11/93 0:00:00	MRS	MIXED_OX
2186	ge_pb_08	Product of reacting: PbO:GeO2:PbF2 = 40:40:20 (mesh)	7	3/11/93 0:00:00	MRS	MIXED_OX
2187	k2cro4_1	K2cro4 Crystal (Exposed Bulk, Same Crystal) Screenexposed 10 Hr To Flood Gun, But Not To X-rays	5	7/17/87 0:00:00	MRS	MIXED_OX
2188	k2ti4o9	PURE POTASSIUM TITANATE (K2Ti4O9) ADHERED TO DOUBLE SIDED TAPE	4	12/8/86 0:00:00	MRS	MIXED_OX
2189	li2oteo2	Li2O:TeO2 30:70 freshly exposed bulk	4	3/15/93 0:00:00	MRS	MIXED_OX
2190	li2wo4_1	Lithium Tungstate (Li2WO4) freshly cleaved (mesh)	9	8/18/92 0:00:00	MRS	MIXED_OX
2191	na2oteo2	Na2O:TeO2 30:70 freshly exposed bulk	4	3/15/93 0:00:00	MRS	MIXED_OX
2192	na2s2o3	Test Of Flood Gun Induced Damage On Na2s2o3 Powder2 Ev, 0.27 Ma, No Screen, 90 Deg Toa	10	2/8/88 0:00:00	MRS	MIXED_OX
2193	na2w2o7	Na2W2O7 (scraped as rec'd pressed sheet, 90 TOA)	4	3/15/93 0:00:00	MRS	MIXED_OX
2194	na2wo4_1	Sodium Tungstate (Na2WO4) freshly scraped (mesh)	9	8/18/92 0:00:00	MRS	MIXED_OX
2195	pb_te_07	Product from: 80% TeO2, 16% PbO, 4% PbF2 (as rec'd, 90 TOA, mesh)	9	4/24/92 0:00:00	MRS	MIXED_OX
2196	pb_te_08	Product from: 80% TeO2, 10% PbO, 10% PbF2 (as rec'd, 90 deg TOA, mesh)	9	4/24/92 0:00:00	MRS	MIXED_OX
2197	pb_te_09	Product from: 80% TeO2, 7% PbO, 13% PbF2 (as rec'd, 90 deg TOA, mesh)	9	4/24/92 0:00:00	MRS	MIXED_OX
2198	aln_1	Aluminum Nitride (AlN, 98+%, Aldrich) powder pressed into pellet, used SSI mesh	10	7/21/94 0:00:00	MRS	NITRIDE
2199	al_n_1	AlN coating (as rec'd, 35 deg TOA) Conductive	5	6/11/91 0:00:00	MRS	NITRIDE
2200	al_n_2	=1000 A AlN/glass (3 KV, 10mA, X:Y=1:3, F=5, 3A/sec"	5	6/11/91 0:00:00	DPR	NITRIDE
2201	al_n_3	Bottom of Al_N coating Ion Etch Crater (200 ang depth)	5	6/11/91 0:00:00	MRS	NITRIDE
2202	al_n_3a	Quick etch to check true concentration of oxygen in AlN coating	1	6/11/91 0:00:00	MRS	NITRIDE
2203	al_n_4	AlN (bottom of crater) high resolution check	2	6/11/91 0:00:00	MRS	NITRIDE
2204	al_n_4a	AlN (bottom of crater) high resolution check	1	6/11/91 0:00:00	MRS	NITRIDE
2205	al_n_4b	AlN (bottom of crater) high resolution check	1	6/11/91 0:00:00	MRS	NITRIDE
2206	b_n_1	BORON NITRIDE (BN) CERAMIC PART (90 DEG TOA, ION ETCH 90 DEG: 4 KeV, 10 mA, 2 MIN)	15	12/21/86 0:00:00	MRS	NITRIDE
2207	b_n_2	BORON NITRIDE (B_N) WHITE SOLID 45 DEG TOA, SCREEN, EXPOSED BULK	5	7/15/87 0:00:00	MRS	NITRIDE
2208	b_n_2a	BORON NITRIDE (B_N) WHITE SOLID 45 DEG TOA, SCREEN, EXPOSED BULK	2	7/15/87 0:00:00	MRS	NITRIDE
2209	cr_n_1	CrN film (old, as rec'd) 35 TOA	8	5/13/94 0:00:00	MRS	NITRIDE
2210	cr_n_2	CrN film (old, 2 min 3 KV etch) 35 TOA	8	5/13/94 0:00:00	MRS	NITRIDE
2211	si3n4_01	Si3N4/Si (5min conc H2O2:HCl:H2O 3:2:5) metal blue 90 toa	8	4/27/94 0:00:00	MRS	NITRIDE
2212	si3n4_02	Si3N4/Si (10min conc HF:MeOH 2:50 cc) metal blue 90 toa	8	4/27/94 0:00:00	MRS	NITRIDE
2213	si3n4_03	Si3N4/Si as rec'd, only gray color seen 90 toa	8	4/27/94 0:00:00	MRS	NITRIDE
2214	si3n4_04	Si3N4/Si etched 10 min at 2KV 6E(-8) Ar, gray type 90 toa	1	4/27/94 0:00:00	MRS	NITRIDE



Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
2215	si3n4_5a	SILICON NITRIDE COATED WAFER (90 DEG TOA, EXPOSED TO AIR MANY MONTHS)	6	6/17/88 0:00:00	MRS	NITRIDE
2216	si3n4_5b	Si3N4+CoAl2O4+MgAl2O4 PELLETT AS RECEIVED AS RECEIVED; Ni MESH USED	3	10/24/88 0:00:00	MRS	NITRIDE
2217	si3n4_5c	Silicon Nitride Coated Wafer (Ion Etch: 2kv,4 Min)(90 Deg Toa, Exposed To Air Many Months)	7	6/17/88 0:00:00	MRS	NITRIDE
2218	tin_1	TiN film (gold color,old,as rec'd, 35 TOA)	8	5/15/94 0:00:00	MRS	NITRIDE
2219	tin_1_e	TiN film (gold color, old, 2 min 3KV etch, 35 TOA)	8	5/15/94 0:00:00	MRS	NITRIDE
2220	ag_fl_15	NTV AgO 35 TOA floating, FG: 15eV, 90% max curr	3	5/7/93 0:00:00	MRS	NTVOXFG1
2221	ag_fl_2v	NTV AgO 35 TOA floating, FG: min volt,min curr	3	5/6/93 0:00:00	MRS	NTVOXFG1
2222	ag_g_15v	NTV AgO 35 TOA grounded, FG: 15 eV, 90% curr	3	3/17/93 0:00:00	MRS	NTVOXFG1
2223	ag_g_2ev	NTV AgO 35 TOA grounded, FG: min volt,min curr	3	3/17/93 0:00:00	MRS	NTVOXFG1
2224	ag_nfg	NTV AgO 35 TOA (as,rec'd, grounded, no FG)	4	3/17/93 0:00:00	MRS	NTVOXFG1
2225	alf115cc	NTV AIO 35 TOA floating, FG: 15 volts, 90% max cur (charge corrected +16.97 eV to align Al BE)	1	1/28/93 0:00:00	MRS	NTVOXFG1
2226	alf115vc	NTV AIO 35 TOA floating, FG: 15 volts, 90% max cur (charge corrected +16.97 eV to align Al BE)	1	1/28/93 0:00:00	MRS	NTVOXFG1
2227	alf15vc	NTV AIO 35 TOA floating, FG: 5 volts, min curr (charge corrected by +7.35 eV to align Al BE)	1	1/28/93 0:00:00	MRS	NTVOXFG1
2228	alf15v_c	NTV AIO 35 TOA floating, FG: 5 volts, min curr (charge corrected +7.35 eV to align Al BE)	1	1/28/93 0:00:00	MRS	NTVOXFG1
2229	al_fl_15	NTV AIO 35 TOA floating, FG: 15 volts, 90% max curr	5	1/28/93 0:00:00	MRS	NTVOXFG1
2230	al_fl_5v	NTV AIO 35 TOA floating, FG: 5 volts, min curr	5	1/28/93 0:00:00	MRS	NTVOXFG1
2231	al_g_15v	Same Mitsu Foil (FG at 15 eV, 95% max current)	4	1/29/93 0:00:00	MRS	NTVOXFG1
2232	al_g_2ev	Same Mitsubishi Foil (FG ON min FG Volt & Current)	4	1/29/93 0:00:00	MRS	NTVOXFG1
2233	al_nfg	Charge study of Mitsubishi Al Foil 35TOA FG OFF:OFF (in vac >15H)	4	1/29/93 0:00:00	MRS	NTVOXFG1
2234	as_fl_15	NTV AsO 90 TOA floating, FG: 15eV, 90% max curr	3	4/30/93 0:00:00	MRS	NTVOXFG1
2235	as_fl_2v	NTV AsO 90 TOA floating, FG: min volt, min curr	3	4/27/93 0:00:00	MRS	NTVOXFG1
2236	as_g_15v	NTV (FO) AsO 35 TOA grounded, FG: 15 eV, 90% curr	3	3/19/93 0:00:00	MRS	NTVOXFG1
2237	as_g_2ev	NTV (FO) AsO 35 TOA grounded, FG: min volt,min cur	3	3/19/93 0:00:00	MRS	NTVOXFG1
2238	as_nfg	NTV AsO (FO) 35 TOA (as,rec'd, grounded, no FG)	3	3/19/93 0:00:00	MRS	NTVOXFG1
2239	au_cal_n	Check of calibration using gold	3	3/19/93 0:00:00	MRS	NTVOXFG1
2240	au_g_15v	NTV AuO 35 TOA grounded, FG: 15 eV, 90% curr	3	3/23/93 0:00:00	MRS	NTVOXFG1
2241	au_g_2ev	NTV AuO 35 TOA grounded, FG: min volt,min curr	3	3/23/93 0:00:00	MRS	NTVOXFG1
2242	au_nfg	NTV AuO 35 TOA (as,rec'd, grounded, no FG)	4	3/23/93 0:00:00	MRS	NTVOXFG1
2243	befl15vc	NTV BeO 35 TOA floating, FG: 15eV, 90% max curr (charge corrected +16.8 eV based on Be BE)	1	3/13/93 0:00:00	MRS	NTVOXFG1
2244	befl2v_c	NTV BeO 35 TOA floating, FG: min volt,min curr (charge corrected +3.3 eV to align Be BE)	1	3/13/93 0:00:00	MRS	NTVOXFG1
2245	beofl15c	NTV BeO 35 TOA floating, FG: 15eV, 90% max curr (charge corrected to Be BE)	1	3/13/93 0:00:00	MRS	NTVOXFG1
2246	beofl2vc	NTV BeO 35 TOA floating, FG: min volt,min curr (charge corrected to NFG Be BE)	1	3/13/93 0:00:00	MRS	NTVOXFG1
2247	be_fl_15	NTV BeO 35 TOA floating, FG: 15eV, 90% max curr	3	3/13/93 0:00:00	MRS	NTVOXFG1
2248	be_fl_2v	NTV BeO 35 TOA floating, FG: min volt,min curr	3	3/13/93 0:00:00	MRS	NTVOXFG1
2249	be_g_15v	NTV BeO 35 TOA grounded, FG: 15 eV, 90% curr	3	3/10/93 0:00:00	MRS	NTVOXFG1
2250	be_g_2ev	NTV BeO 35 TOA grounded, FG: min volt,min curr	3	3/10/93 0:00:00	MRS	NTVOXFG1
2251	be_nfg	NTV BeO 35 TOA (as,rec'd, grounded, no FG)	4	3/10/93 0:00:00	MRS	NTVOXFG1
2252	bifl1c	NTV BiO 35 TOA floating, FG: 15eV, 90% max curr (charge shifted to give Bi at 157.01 eV)	1	3/8/93 0:00:00	MRS	NTVOXFG1
2253	bifl_1a	NTV BiO 35 TOA floating, FG: min volt,min curr (charge shifted to give Bi at 157.01 eV)	1	3/8/93 0:00:00	MRS	NTVOXFG1
2254	bifl_1b	NTV BiO 35 TOA floating, FG: min volt,min curr (charge shifted to give Bi at 157.01 eV)	1	3/8/93 0:00:00	MRS	NTVOXFG1
2255	bifl_1d	NTV BiO 35 TOA floating, FG: 15eV, 90% max curr (charge shifted to give Bi at 157.01 eV)	1	3/8/93 0:00:00	MRS	NTVOXFG1

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
2256	bi_fl_15	NTV BiO 35 TOA floating, FG: 15eV, 90% max curr	3	3/8/93 0:00:00	MRS	NTVOXFG1
2257	bi_fl_2v	NTV BiO 35 TOA floating, FG: min volt,min curr	3	3/8/93 0:00:00	MRS	NTVOXFG1
2258	bi_g_15v	NTV BiO 35 TOA grounded, FG: 15 eV, 90% curr	3	3/8/93 0:00:00	MRS	NTVOXFG1
2259	bi_g_2ev	NTV BiO 35 TOA grounded, FG: min volt,min curr	3	3/8/93 0:00:00	MRS	NTVOXFG1
2260	bi_nfg	NTV BiO 35 TOA (as,rec'd, grounded, no FG)	4	3/8/93 0:00:00	MRS	NTVOXFG1
2261	b_g_15v	NTV BO 90 TOA grounded, FG: 15 eV, 90% curr	3	3/18/93 0:00:00	MRS	NTVOXFG1
2262	b_g_2ev	NTV BO 90 TOA grounded, FG: min volt,min curr	3	3/18/93 0:00:00	MRS	NTVOXFG1
2263	b_nfg	NTV BO 90 TOA (as,rec'd, grounded, no FG)	4	3/18/93 0:00:00	MRS	NTVOXFG1
2264	cd_fl_15	NTV CdO 90 TOA floating FG: 15eV, 90%max curr	4	2/23/93 0:00:00	MRS	NTVOXFG1
2265	cd_fl_2v	NTV CdO 90 TOA floating FG: min volt,min curr	5	2/23/93 0:00:00	MRS	NTVOXFG1
2266	cd_g_15v	NTV CdO 40 TOA grounded, FG: 15eV, 90% curr	3	2/23/93 0:00:00	MRS	NTVOXFG1
2267	cd_g_2ev	NTV CdO 40 TOA grounded, FG: min volt,min curr	3	2/23/93 0:00:00	MRS	NTVOXFG1
2268	cd_nfg	NTV CdO (grounded, no FG)	3	2/23/93 0:00:00	MRS	NTVOXFG1
2269	co_fl_15	NTV CoO 35 TOA floating, FG: 15eV, 90% max curr	3	5/6/93 0:00:00	MRS	NTVOXFG1
2270	co_fl_2v	NTV CoO 35 TOA floating, FG: min volt, min curr	3	4/28/93 0:00:00	MRS	NTVOXFG1
2271	co_g_15v	NTV CoO 35 TOA grounded, FG: 15 eV, 90% curr	3	3/13/93 0:00:00	MRS	NTVOXFG1
2272	co_g_2ev	NTV CoO 35 TOA grounded, FG: min volt,min curr	3	3/13/93 0:00:00	MRS	NTVOXFG1
2273	co_nfg	NTV CoO 35 TOA (as,rec'd, grounded, no FG)	4	3/13/93 0:00:00	MRS	NTVOXFG1
2274	crfl_1a	NTV CrO 35 TOA floating, FG: min volt,min curr (charge shifted to give Cr at 574.25 eV)	1	4/21/93 0:00:00	MRS	NTVOXFG1
2275	crfl_1b	NTV CrO 35 TOA floating, FG: min volt,min curr (charge shifted to give Cr at 574.25 eV)	1	4/21/93 0:00:00	MRS	NTVOXFG1
2276	crfl_1c	NTV CrO 35 TOA floating, FG: 15eV, 90% max curr (charge shifted to give Cr at 574.25 eV)	1	4/26/93 0:00:00	MRS	NTVOXFG1
2277	crfl_1d	NTV CrO 35 TOA floating, FG: 15eV, 90% max curr (charge shifted to give Cr at 574.25 eV)	1	4/26/93 0:00:00	MRS	NTVOXFG1
2278	cr_fl_15	NTV CrO 35 TOA floating, FG: 15eV, 90% max curr	3	4/26/93 0:00:00	MRS	NTVOXFG1
2279	cr_fl_2v	NTV CrO 35 TOA floating, FG: min volt,min curr	3	4/21/93 0:00:00	MRS	NTVOXFG1
2280	cr_g_15v	NTV CrO 45 TOA grounded, FG: 15 eV, 90% curr	3	3/13/93 0:00:00	MRS	NTVOXFG1
2281	cr_g_2ev	NTV CrO 45 TOA grounded, FG: min volt,min curr	3	3/13/93 0:00:00	MRS	NTVOXFG1
2282	cr_nfg	NTV CrO 45 TOA (as,rec'd, grounded, no FG)	4	3/13/93 0:00:00	MRS	NTVOXFG1
2283	cu_cal_n	Check of calibration of ion etched copper	3	3/19/93 0:00:00	MRS	NTVOXFG1
2284	cu_fl_15	NTV CuO 35 TOA floating, FG: 15eV, 90% max curr	3	2/24/93 0:00:00	MRS	NTVOXFG1
2285	cu_fl_2v	NTV CuO 35 TOA floating, FG: min volt,min curr	3	2/24/93 0:00:00	MRS	NTVOXFG1
2286	cu_g_15v	NTV CuO 35 TOA grounded, FG: 15 eV, 90% curr	3	3/19/93 0:00:00	MRS	NTVOXFG1
2287	cu_g_2ev	NTV CuO 35 TOA grounded, FG: min volt,min curr	3	3/19/93 0:00:00	MRS	NTVOXFG1
2288	cu_nfg	NTV CuO 35 TOA (as,rec'd, grounded, no FG)	4	3/19/93 0:00:00	MRS	NTVOXFG1
2289	c_g_2ev	NTV CO(graph) 35 TOA grounded, FG: min volt,min cur	3	3/23/93 0:00:00	MRS	NTVOXFG1
2290	c_nfg	NTV CO(graphite) 35 TOA (as,rec'd, grounded, no FG)	4	3/23/93 0:00:00	MRS	NTVOXFG1
2291	c_nfg_a	NTV CO(graphite) 35 TOA (as,rec'd, grounded, no FG)	3	3/23/93 0:00:00	MRS	NTVOXFG1
2292	fe_fl_15	NTV FeO 35 TOA floating, FG: 15eV, 90% max curr	3	4/30/93 0:00:00	MRS	NTVOXFG1
2293	fe_fl_2v	NTV FeO 35 TOA floating, FG: min volt, min curr	3	4/27/93 0:00:00	MRS	NTVOXFG1
2294	fe_g_15v	NTV FeO 35 TOA grounded, FG: 15 eV, 90% curr	3	3/12/93 0:00:00	MRS	NTVOXFG1
2295	fe_g_2ev	NTV FeO 35 TOA grounded, FG: min volt,min curr	3	3/12/93 0:00:00	MRS	NTVOXFG1
2296	fe_nfg	NTV FeO 35 TOA (as,rec'd, grounded, no FG)	4	3/12/93 0:00:00	MRS	NTVOXFG1

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
2297	ga_g_15v	NTV GaO(liq) 35 TOA grounded, FG: 15 eV, 90% curr	3	3/19/93 0:00:00	MRS	NTVOXFG1
2298	ga_g_2ev	NTV GaO(liq)35 TOA grounded, FG: min volt,min cur	3	3/19/93 0:00:00	MRS	NTVOXFG1
2299	ga_nfg	NTV GaO (melted)35 TOA (as,rec'd, grounded, no FG)	4	3/19/93 0:00:00	MRS	NTVOXFG1
2300	ge_fl_15	NTV GeO 35 TOA floating, FG: 15eV, 90% max curr	4	4/27/93 0:00:00	MRS	NTVOXFG1
2301	ge_fl_2v	NTV GeO 35 TOA floating, FG: min volt,min curr	4	4/27/93 0:00:00	MRS	NTVOXFG1
2302	ge_g_15v	NTV GeO 35 TOA grounded, FG: 15 eV, 90% curr	4	3/12/93 0:00:00	MRS	NTVOXFG1
2303	ge_g_2ev	NTV GeO 35 TOA grounded, FG: min volt,min curr	4	3/12/93 0:00:00	MRS	NTVOXFG1
2304	ge_nfg	NTV GeO 35 TOA (as,rec'd, grounded, no FG)	5	3/12/93 0:00:00	MRS	NTVOXFG1
2305	hf_fl_15	NTV HfO 35 TOA floating, FG: 15eV, 90% max curr	3	2/26/93 0:00:00	MRS	NTVOXFG1
2306	hf_fl_2v	NTV HfO 35 TOA floating, FG: min volt,min curr	3	2/26/93 0:00:00	MRS	NTVOXFG1
2307	hf_g_15v	NTV HfO 90 TOA grounded, FG: 15 eV, 90% curr	3	3/5/93 0:00:00	MRS	NTVOXFG1
2308	hf_g_2ev	NTV HfO 90 TOA grounded, FG: min volt,min curr	3	3/5/93 0:00:00	MRS	NTVOXFG1
2309	hf_nfg	NTV HfO 90 TOA (as,rec'd, grounded, no FG)	4	3/5/93 0:00:00	MRS	NTVOXFG1
2310	in_fl_15	NTV InO 35 TOA floating, FG: 15eV, 90% max curr	3	3/9/93 0:00:00	MRS	NTVOXFG1
2311	in_fl_2v	NTV InO 35 TOA floating, FG: min volt,min curr	3	3/9/93 0:00:00	MRS	NTVOXFG1
2312	in_g_15a	NTV InO 35 TOA grounded, FG: 15 eV, 90% curr	1	3/1/93 0:00:00	MRS	NTVOXFG1
2313	in_g_15v	NTV InO 35 TOA grounded, FG: 15 eV, 90% curr	3	3/1/93 0:00:00	MRS	NTVOXFG1
2314	in_g_2ev	NTV InO 35 TOA grounded, FG: min volt,min curr	3	3/1/93 0:00:00	MRS	NTVOXFG1
2315	in_nfg	NTV InO 35 TOA (as,rec'd, grounded, no FG)	4	3/1/93 0:00:00	MRS	NTVOXFG1
2316	ir_fl_15	NTV IrO 90 TOA floating, FG: 15eV, 90% max curr	3	6/24/93 0:00:00	MRS	NTVOXFG1
2317	ir_fl_2v	NTV IrO 90 TOA floating, FG: min volt,min curr	3	6/24/93 0:00:00	MRS	NTVOXFG1
2318	ir_g_15v	NTV IrO 90 TOA grounded, FG: 15 eV, 90% curr	3	3/17/93 0:00:00	MRS	NTVOXFG1
2319	ir_g_2ev	NTV IrO 90 TOA grounded, FG: min volt,min curr	3	3/17/93 0:00:00	MRS	NTVOXFG1
2320	ir_nfg	NTV IrO 90 TOA (as,rec'd, grounded, no FG)	4	3/17/93 0:00:00	MRS	NTVOXFG1
2321	lu_g_15v	NTV LuO 35 TOA grounded, FG: 15 eV, 90% curr	3	3/16/93 0:00:00	MRS	NTVOXFG1
2322	lu_g_2ev	NTV LuO 35 TOA grounded, FG: min volt,min curr	3	3/16/93 0:00:00	MRS	NTVOXFG1
2323	lu_nfg	NTV LuO 35 TOA (as,rec'd, grounded, no FG)	4	3/16/93 0:00:00	MRS	NTVOXFG1
2324	mgfl_1a	NTV MgO 35 TOA floating, FG: min volt,min curr (charge shifted to give Mg at 49.74 eV)	1	2/24/93 0:00:00	MRS	NTVOXFG1
2325	mgfl_1b	NTV MgO 35 TOA floating, FG: min volt,min curr (charge shifted to give Mg at 49.74 eV)	1	2/24/93 0:00:00	MRS	NTVOXFG1
2326	mgfl_1c	Fresh NTV MgO 35 TOA floating, FG: 15eV, 90% curr (charge shifted to give Mg at 49.74 eV)	1	2/24/93 0:00:00	MRS	NTVOXFG1
2327	mgfl_1d	Fresh NTV MgO 35 TOA floating, FG: 15eV, 90% curr (charge shifted to give Mg at 49.74 eV)	1	2/24/93 0:00:00	MRS	NTVOXFG1
2328	mg_fl_15	Fresh NTV MgO 35 TOA floating, FG: 15eV, 90% curr	3	2/24/93 0:00:00	MRS	NTVOXFG1
2329	mg_fl_2v	NTV MgO 35 TOA floating, FG: min volt,min curr	3	2/24/93 0:00:00	MRS	NTVOXFG1
2330	mg_g_15v	NTV MgO 35 TOA grounded, FG: 15 eV, 90% curr	3	2/24/93 0:00:00	MRS	NTVOXFG1
2331	mg_g_1a	NTV MgO 35 TOA grounded, FG: min volt,min curr (charge shifted to give Mg at 49.74 eV)	1	2/24/93 0:00:00	MRS	NTVOXFG1
2332	mg_g_2ev	NTV MgO 35 TOA grounded, FG: min volt,min curr	3	2/24/93 0:00:00	MRS	NTVOXFG1
2333	mg_nfg	NTV MgO (grounded, no FG)	4	2/24/93 0:00:00	MRS	NTVOXFG1
2334	mn_fl_15	NTV MnO 35 TOA floating, FG: 15eV, 90% max curr	3	4/30/93 0:00:00	MRS	NTVOXFG1
2335	mn_fl_2v	NTV MnO 35 TOA floating, FG: min volt, min curr	3	4/27/93 0:00:00	MRS	NTVOXFG1
2336	mn_g_15v	NTV MnO 35 TOA grounded, FG: 15 eV, 90% curr	3	3/10/93 0:00:00	MRS	NTVOXFG1
2337	mn_g_2ev	NTV MnO 35 TOA grounded, FG: min volt,min curr	3	3/10/93 0:00:00	MRS	NTVOXFG1

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
2338	mn_nfg	NTV MnO 35 TOA (as,rec'd, grounded, no FG)	4	3/10/93 0:00:00	MRS	NTVOXFG1
2339	mofl_1a	NTV MoO 35 TOA floating, FG: min volt,min curr (charge shifted to give Mo at 228.09 eV)	1	2/26/93 0:00:00	MRS	NTVOXFG1
2340	mofl_1b	NTV MoO 35 TOA floating, FG: min volt,min curr (charge shifted to give Mo at 228.09 eV)	1	2/26/93 0:00:00	MRS	NTVOXFG1
2341	mofl_1c	NTV MoO 35 TOA floating, FG: 15eV, 90% max curr (charge shifted to give Mo at 228.09 eV)	1	2/26/93 0:00:00	MRS	NTVOXFG1
2342	mofl_1d	NTV MoO 35 TOA floating, FG: 15eV, 90% max curr (charge shifted to give Mo at 228.09 eV)	1	2/26/93 0:00:00	MRS	NTVOXFG1
2343	mo_fl_15	NTV MoO 35 TOA floating, FG: 15eV, 90% max curr	3	2/26/93 0:00:00	MRS	NTVOXFG1
2344	mo_fl_2v	NTV MoO 35 TOA floating, FG: min volt,min curr	3	2/26/93 0:00:00	MRS	NTVOXFG1
2345	mo_g_15v	NTV MoO 35 TOA grounded, FG: 15 eV, 90% curr	3	2/26/93 0:00:00	MRS	NTVOXFG1
2346	mo_g_2ev	NTV MoO 35 TOA grounded, FG: min volt,min curr	3	2/26/93 0:00:00	MRS	NTVOXFG1
2347	mo_nfg	NTV MoO 35 TOA (as,rec'd, grounded, no FG)	4	2/26/93 0:00:00	MRS	NTVOXFG1
2348	nb_fl_15	NTV NbO 35 TOA floating, FG: 15eV, 90% max curr	3	4/9/93 0:00:00	MRS	NTVOXFG1
2349	nb_fl_2v	NTV NbO 35 TOA floating, FG: min volt,min curr	3	4/9/93 0:00:00	MRS	NTVOXFG1
2350	nb_g_15v	NTV NbO 35 TOA grounded, FG: 15 eV, 90% curr	3	3/11/93 0:00:00	MRS	NTVOXFG1
2351	nb_g_2ev	NTV NbO 35 TOA grounded, FG: min volt,min curr	3	3/11/93 0:00:00	MRS	NTVOXFG1
2352	nb_nfg	NTV NbO 35 TOA (as,rec'd, grounded, no FG)	4	3/11/93 0:00:00	MRS	NTVOXFG1
2353	ni_fl_15	NTV NiO 35 TOA floating, FG: 15eV, 90% max curr	4	6/28/93 0:00:00	MRS	NTVOXFG1
2354	ni_fl_2v	NTV NiO 35 TOA floating, FG: min volt,min curr	4	6/24/93 0:00:00	MRS	NTVOXFG1
2355	ni_g_15v	NTV NiO 65 TOA grounded, FG: 15 eV, 90% curr	3	3/15/93 0:00:00	MRS	NTVOXFG1
2356	ni_g_2ev	NTV NiO 65 TOA grounded, FG: min volt,min curr	3	3/15/93 0:00:00	MRS	NTVOXFG1
2357	ni_nfg	NTV NiO 65 TOA (as,rec'd, grounded, no FG)	4	3/15/93 0:00:00	MRS	NTVOXFG1
2358	pb_fl_15	NTV PbO 35 TOA floating, FG: 15eV, 90% max curr	3	3/8/93 0:00:00	MRS	NTVOXFG2
2359	pb_fl_2v	NTV PbO 35 TOA floating, FG: min volt,min curr	3	3/8/93 0:00:00	MRS	NTVOXFG2
2360	pb_g_15v	NTV PbO 35 TOA grounded, FG: 15 eV, 90% curr	3	3/8/93 0:00:00	MRS	NTVOXFG2
2361	pb_g_2ev	NTV PbO 35 TOA grounded, FG: min volt,min curr	3	3/8/93 0:00:00	MRS	NTVOXFG2
2362	pb_nfg	NTV PbO 35 TOA (as,rec'd, grounded, no FG)	4	3/8/93 0:00:00	MRS	NTVOXFG2
2363	pd_fl_15	NTV PdO 35 TOA floating, FG: 15eV, 90% max curr	3	4/30/93 0:00:00	MRS	NTVOXFG2
2364	pd_fl_2v	NTV PdO 35 TOA floating, FG: min volt, min curr	3	4/28/93 0:00:00	MRS	NTVOXFG2
2365	pd_g_15v	NTV PdO 35 TOA grounded, FG: 15 eV, 90% curr	3	3/17/93 0:00:00	MRS	NTVOXFG2
2366	pd_g_2ev	NTV PdO 35 TOA grounded, FG: min volt,min curr	3	3/17/93 0:00:00	MRS	NTVOXFG2
2367	pd_nfg	NTV PdO 35 TOA (as,rec'd, grounded, no FG)	4	3/17/93 0:00:00	MRS	NTVOXFG2
2368	pt_fl_15	NTV PtO 35 TOA floating, FG: 15eV, 90% max curr	3	5/11/93 0:00:00	MRS	NTVOXFG2
2369	pt_fl_2v	NTV PtO 35 TOA floating, FG: min volt,min curr	3	5/10/93 0:00:00	MRS	NTVOXFG2
2370	pt_g_15v	NTV PtO 35 TOA grounded, FG: 15 eV, 90% curr	3	3/17/93 0:00:00	MRS	NTVOXFG2
2371	pt_g_2ev	NTV PtO 35 TOA grounded, FG: min volt,min curr	3	3/17/93 0:00:00	MRS	NTVOXFG2
2372	pt_nfg	NTV PtO 35 TOA (as,rec'd, grounded, no FG)	4	3/17/93 0:00:00	MRS	NTVOXFG2
2373	p_g_15v	NTV PO(blk) 35 TOA grounded, FG: 15eV, 90% max cur	3	3/19/93 0:00:00	MRS	NTVOXFG2
2374	p_g_2ev	NTV PO(blk) 35 TOA grounded, FG: min volt,min curr	3	3/19/93 0:00:00	MRS	NTVOXFG2
2375	p_nfg_1	NTV PO 35 TOA (as,rec'd, grounded, no FG)	4	3/19/93 0:00:00	MRS	NTVOXFG2
2376	p_nfg_2	NTV PO 35 TOA (as,rec'd, grounded, no FG)	2	3/19/93 0:00:00	MRS	NTVOXFG2
2377	p_nfg_3	NTV PO 35 TOA (as,rec'd, grounded, no FG)	1	3/19/93 0:00:00	MRS	NTVOXFG2
2378	re_fl_15	NTV ReO 35 TOA floating, FG: 15eV, 90% max curr	3	4/27/93 0:00:00	MRS	NTVOXFG2

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
2379	re_fl_2v	NTV ReO 35 TOA floating, FG: min volt,min curr	3	4/27/93 0:00:00	MRS	NTVOXFG2
2380	re_g_15v	NTV ReO 35 TOA grounded, FG: 15 eV, 90% curr	3	3/16/93 0:00:00	MRS	NTVOXFG2
2381	re_g_2ev	NTV ReO 35 TOA grounded, FG: min volt,min curr	3	3/16/93 0:00:00	MRS	NTVOXFG2
2382	re_nfg	NTV ReO 35 TOA (as,rec'd, grounded, no FG)	4	3/15/93 0:00:00	MRS	NTVOXFG2
2383	rh_fl_15	NTV RhO 55 TOA floating, FG: 15eV, 90% max curr	3	4/27/93 0:00:00	MRS	NTVOXFG2
2384	rh_fl_2v	NTV RhO 55 TOA floating, FG: min volt,min curr	3	4/27/93 0:00:00	MRS	NTVOXFG2
2385	rh_g_15v	NTV RhO 35 TOA grounded, FG: 15 eV, 90% curr	3	3/12/93 0:00:00	MRS	NTVOXFG2
2386	rh_g_2ev	NTV RhO 35 TOA grounded, FG: min volt,min curr	3	3/12/93 0:00:00	MRS	NTVOXFG2
2387	rh_nfg	NTV RhO 35 TOA (as,rec'd, grounded, no FG)	4	3/12/93 0:00:00	MRS	NTVOXFG2
2388	ru_fl_15	NTV RuO (powdr) 35 TOA float FG: 15eV, 90% max curr	2	6/24/93 0:00:00	MRS	NTVOXFG2
2389	ru_fl_2v	NTV RuO(powdr)35 TOA float, FG: min volt,min curren	3	6/24/93 0:00:00	MRS	NTVOXFG2
2390	ru_g_15v	NTV RuO(powdr) 35 TOA grounded, FG: 15 eV, 90% curr	2	3/19/93 0:00:00	MRS	NTVOXFG2
2391	ru_g_2ev	NTV RuO (powdr) 35 TOA grnded, FG: min volt & curr	2	3/19/93 0:00:00	MRS	NTVOXFG2
2392	ru_nfg	NTV RuO (powdr) 35 TOA (as,rec'd, grounded, no FG)	3	3/19/93 0:00:00	MRS	NTVOXFG2
2393	sb_fl_15	NTV SbO 35 TOA floating, FG: 15eV, 90% max curr	2	4/26/93 0:00:00	MRS	NTVOXFG2
2394	sb_fl_2v	NTV SbO 35 TOA floating, FG: min volt,min curr	2	4/26/93 0:00:00	MRS	NTVOXFG2
2395	sb_g_15v	NTV SbO 35 TOA grounded, FG: 15 eV, 90% curr	2	3/12/93 0:00:00	MRS	NTVOXFG2
2396	sb_g_2ev	NTV SbO 35 TOA grounded, FG: min volt,min curr	2	3/12/93 0:00:00	MRS	NTVOXFG2
2397	sb_nfg	NTV SbO 35 TOA (as,rec'd, grounded, no FG)	3	3/12/93 0:00:00	MRS	NTVOXFG2
2398	sc_fl_15	NTV ScO 35 TOA floating FG: 15 rV, 90% curr	3	2/23/93 0:00:00	MRS	NTVOXFG2
2399	sc_fl_2v	NTV ScO 35 TOA floating FG: min volt,min curr	4	2/23/93 0:00:00	MRS	NTVOXFG2
2400	sc_g_15v	NTV ScO 60 TOA grounded, FG: 15 eV, 90% curr	3	3/13/93 0:00:00	MRS	NTVOXFG2
2401	sc_g_2ev	NTV ScO 60 TOA grounded, FG: min volt,min curr	3	3/13/93 0:00:00	MRS	NTVOXFG2
2402	sc_nfg	NTV ScO ca. 80 TOA (grounded, no FG)	3	2/23/93 0:00:00	MRS	NTVOXFG2
2403	se_fl_15	NTV SeO 90 TOA floating, FG: 15eV, 90% max curr	3	4/27/93 0:00:00	MRS	NTVOXFG2
2404	se_fl_2v	NTV SeO 90 TOA floating, FG: min volt,min curr	3	4/27/93 0:00:00	MRS	NTVOXFG2
2405	se_g_15v	NTV SeO 35 TOA grounded, FG: 15 eV, 90% curr	3	3/16/93 0:00:00	MRS	NTVOXFG2
2406	se_g_2ev	NTV SeO 35 TOA grounded, FG: min volt,min curr	3	3/16/93 0:00:00	MRS	NTVOXFG2
2407	se_nfg	NTV SeO 35 TOA (as,rec'd, grounded, no FG)	4	3/16/93 0:00:00	MRS	NTVOXFG2
2408	sifl1c	NTV SiO 35 TOA floating, FG: 15eV, 90% max curr (charge shifted to give Si at 82.44 eV)	1	4/21/93 0:00:00	MRS	NTVOXFG2
2409	sifl_1a	NTV SiO 35 TOA floating, FG: min volt,min curr (charge shifted to give Si at 99.31 eV)	1	4/21/93 0:00:00	MRS	NTVOXFG2
2410	sifl_1b	NTV SiO 35 TOA floating, FG: min volt,min curr (charge shifted to give Si at 99.31 eV)	1	4/21/93 0:00:00	MRS	NTVOXFG2
2411	sifl_1d	NTV SiO 35 TOA floating, FG: 15eV, 90% max curr (charge shifted to give Si at 99.31 eV)	1	4/21/93 0:00:00	MRS	NTVOXFG2
2412	si_fl_15	NTV SiO 35 TOA floating, FG: 15eV, 90% max curr	3	4/21/93 0:00:00	MRS	NTVOXFG2
2413	si_fl_2v	NTV SiO 35 TOA floating, FG: min volt,min curr	3	4/21/93 0:00:00	MRS	NTVOXFG2
2414	si_g_15v	NTV SiO 35 TOA grounded, FG: 15 eV, 90% curr	3	3/15/93 0:00:00	MRS	NTVOXFG2
2415	si_g_1a	NTV SiO 35 TOA grounded, FG: min volt,min curr (charge shifted to give Si at 99.31 eV)	1	3/15/93 0:00:00	MRS	NTVOXFG2
2416	si_g_1b	NTV SiO 35 TOA grounded, FG: min volt,min curr (charge shifted to give Si at 99.31 eV)	1	3/15/93 0:00:00	MRS	NTVOXFG2
2417	si_g_1c	NTV SiO 35 TOA grounded, FG: 15 eV, 90% curr (charge shifted to give Si at 99.31 eV)	1	3/15/93 0:00:00	MRS	NTVOXFG2
2418	si_g_1d	NTV SiO 35 TOA grounded, FG: 15 eV, 90% curr (charge shifted to give Si at 99.31 eV)	1	3/15/93 0:00:00	MRS	NTVOXFG2
2419	si_g_2ev	NTV SiO 35 TOA grounded, FG: min volt,min curr	3	3/15/93 0:00:00	MRS	NTVOXFG2

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
2420	si_nfg	NTV SiO 35 TOA (as,rec'd, grounded, no FG)	4	3/15/93 0:00:00	MRS	NTVOXFG2
2421	sn_fl_15	NTV SnO 35 TOA floating, FG: 15eV, 90% max curr	3	4/21/93 0:00:00	MRS	NTVOXFG2
2422	sn_fl_2v	NTV SnO 35 TOA floating, FG: min volt,min curr	3	4/21/93 0:00:00	MRS	NTVOXFG2
2423	sn_g_15v	rerun NTV SnO 90 TOA grounded, FG: 15 eV, 90% curr	3	3/13/93 0:00:00	MRS	NTVOXFG2
2424	sn_g_2ev	rerun SnO 90 TOA grounded, FG: min volt,min curr	3	3/13/93 0:00:00	MRS	NTVOXFG2
2425	sn_nfg	Rerun SnO 90 TOA (as,rec'd, grounded, no FG)	4	3/13/93 0:00:00	MRS	NTVOXFG2
2426	ta_fg_f1	NTV TaO 35 TOA floating, FG: min volt,min curr	3	2/26/93 0:00:00	MRS	NTVOXFG2
2427	ta_fg_f2	NTV TaO 35 TOA floating, FG: 15eV, 90% max curr	3	2/26/93 0:00:00	MRS	NTVOXFG2
2428	ta_fl_15	NTV TaO 35 TOA floating, FG: 15eV, 90% max curr	3	2/26/93 0:00:00	MRS	NTVOXFG2
2429	ta_fl_2v	NTV TaO 35 TOA floating, FG: min volt,min curr	3	2/26/93 0:00:00	MRS	NTVOXFG2
2430	ta_g_15v	NTV TaO 35 TOA grounded, FG: 15 eV, 90% curr	3	3/1/93 0:00:00	MRS	NTVOXFG2
2431	ta_g_2ev	NTV TaO 35 TOA grounded, FG: min volt,min curr	3	3/1/93 0:00:00	MRS	NTVOXFG2
2432	ta_nfg	NTV TaO 35 TOA (as,rec'd, grounded, no FG)	4	3/1/93 0:00:00	MRS	NTVOXFG2
2433	te_fl_15	NTV TeO 35 TOA floating, FG: 15eV, 90% max curr	3	4/27/93 0:00:00	MRS	NTVOXFG2
2434	te_fl_2v	NTV TeO 35 TOA floating, FG: min volt,min curr	3	4/26/93 0:00:00	MRS	NTVOXFG2
2435	te_g_15v	NTV TeO 90 TOA grounded, FG: 15 eV, 90% curr	3	3/9/93 0:00:00	MRS	NTVOXFG2
2436	te_g_2ev	NTV TeO 90 TOA grounded, FG: min volt,min curr	3	3/9/93 0:00:00	MRS	NTVOXFG2
2437	te_nfg	NTV TeO 90 TOA (as,rec'd, grounded, no FG)	4	3/9/93 0:00:00	MRS	NTVOXFG2
2438	ti_fl_15	NTV TiO 35 TOA floating, FG: 15eV, 90% max curr	3	4/9/93 0:00:00	MRS	NTVOXFG2
2439	ti_fl_2	NTV TiO 35 TOA floating, FG: min volt,min curr	3	4/9/93 0:00:00	MRS	NTVOXFG2
2440	ti_g_15v	NTV TiO 35 TOA grounded, FG: 15 eV, 90% curr	3	3/8/93 0:00:00	MRS	NTVOXFG2
2441	ti_g_2ev	NTV TiO 35 TOA grounded, FG: min volt,min curr	3	3/8/93 0:00:00	MRS	NTVOXFG2
2442	ti_nfg	NTV TiO 35 TOA (as,rec'd, grounded, no FG)	4	3/8/93 0:00:00	MRS	NTVOXFG2
2443	tl_fl_15	NTV TlO 35 TOA floating, FG: 15eV, 90% max curr	3	5/6/93 0:00:00	MRS	NTVOXFG2
2444	tl_fl_2v	NTV TlO 35 TOA floating, FG: min volt, min curr	3	4/28/93 0:00:00	MRS	NTVOXFG2
2445	tl_g_15v	NTV TlO (FO) 35 TOA grounded, FG: 15 eV, 90% curr	3	3/12/93 0:00:00	MRS	NTVOXFG2
2446	tl_g_2ev	NTV TlO (FO) 35 TOA grounded, FG: min volt,min curr	3	3/12/93 0:00:00	MRS	NTVOXFG2
2447	tl_nfg	NTV TlO (FO) 35 TOA (as,rec'd, grounded, no FG)	4	3/12/93 0:00:00	MRS	NTVOXFG2
2448	vfl_1a	NTV VO 35 TOA floating, FG: min volt,min curr (charge shifted to give V at 512.07 eV)	1	4/13/93 0:00:00	MRS	NTVOXFG2
2449	vfl_1b	NTV VO 35 TOA floating, FG: min volt,min curr (charge shifted to give V at 512.07 eV)	1	4/13/93 0:00:00	MRS	NTVOXFG2
2450	vfl_1c	NTV VO 35 TOA floating, FG: 15eV, 90% max curr (charge shifted to give V at 512.07 eV)	1	4/13/93 0:00:00	MRS	NTVOXFG2
2451	vfl_1d	NTV VO 35 TOA floating, FG: 15eV, 90% max curr (charge shifted to give V at 512.07 eV)	1	4/13/93 0:00:00	MRS	NTVOXFG2
2452	v_fl_15	NTV VO 35 TOA floating, FG: 15eV, 90% max curr	3	4/13/93 0:00:00	MRS	NTVOXFG2
2453	v_fl_2v	NTV VO 35 TOA floating, FG: min volt,min curr	3	4/13/93 0:00:00	MRS	NTVOXFG2
2454	v_g_15v	NTV (FO) VO 35 TOA grounded, FG: 15 eV, 90% curr	2	3/18/93 0:00:00	MRS	NTVOXFG2
2455	v_g_2ev	NTV (FO) VO 35 TOA grounded, FG: min volt,min curr	2	3/18/93 0:00:00	MRS	NTVOXFG2
2456	v_nfg	NTV (FO) VO 35 TOA (as,rec'd, grounded, no FG)	3	3/18/93 0:00:00	MRS	NTVOXFG2
2457	v_nfg_2	NTV (FO) VO 35 TOA (as,rec'd, grounded, no FG)	1	3/18/93 0:00:00	MRS	NTVOXFG2
2458	wfl_1a	NTV WO 35 TOA floating, FG: min volt,min curr (charge shifted to give W at 31.38 eV)	1	4/21/93 0:00:00	MRS	NTVOXFG2
2459	wfl_1b	NTV WO 35 TOA floating, FG: min volt,min curr (charge shifted to give W at 31.38 eV)	1	4/21/93 0:00:00	MRS	NTVOXFG2
2460	wfl_1c	NTV WO 35 TOA floating, FG: 15eV, 90% max curr (charge shifted to give W at 31.38 eV)	1	4/21/93 0:00:00	MRS	NTVOXFG2

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
2461	wfl_1d	NTV WO 35 TOA floating, FG: 15eV, 90% max curr (charge shifted to give W at 31.38 eV)	1	4/21/93 0:00:00	MRS	NTVOXFG2
2462	w_fl_15a	NTV WO 35 TOA floating, FG: 15eV, 90% max curr	3	4/21/93 0:00:00	MRS	NTVOXFG2
2463	w_fl_15b	NTV WO 35 TOA floating, FG: 15eV, 90% max curr	1	4/21/93 0:00:00	MRS	NTVOXFG2
2464	w_fl_2_a	NTV WO 35 TOA floating, FG: min volt,min curr	3	4/21/93 0:00:00	MRS	NTVOXFG2
2465	w_fl_2_b	NTV WO 35 TOA floating, FG: min volt,min curr	1	4/21/93 0:00:00	MRS	NTVOXFG2
2466	w_g_15v	NTV WO 35 TOA grounded, FG: 15 eV, 90% curr	3	3/18/93 0:00:00	MRS	NTVOXFG2
2467	w_g_2ev	NTV WO 35 TOA grounded, FG: min volt,min curr	3	3/18/93 0:00:00	MRS	NTVOXFG2
2468	w_nfg	NTV WO 35 TOA (as,rec'd, grounded, no FG)	4	3/18/93 0:00:00	MRS	NTVOXFG2
2469	w_nfg_xx	NTV WO 35 TOA (as,rec'd, grounded, no FG)	1	3/18/93 0:00:00	MRS	NTVOXFG2
2470	y_fl_15v	NTV YO 35 TOA floating, FG: 15eV, 90% max curr	3	5/10/93 0:00:00	MRS	NTVOXFG2
2471	y_fl_2ev	NTV YO 35 TOA floating, FG: min volt,min curr	3	5/10/93 0:00:00	MRS	NTVOXFG2
2472	y_g_15v	NTV (FO) YO 35 TOA grounded, FG: 15 eV, 90% curr	3	3/18/93 0:00:00	MRS	NTVOXFG2
2473	y_g_2ev	NTV (FO) YO 35 TOA grounded, FG: min volt,min curr	3	3/18/93 0:00:00	MRS	NTVOXFG2
2474	y_nfg	NTV (fresh) YO 35 TOA (as,rec'd, grounded, no FG)	4	3/18/93 0:00:00	MRS	NTVOXFG2
2475	zn_fl_15	NTV ZnO/Zn (old) 80 TOA (floating, FG max curr, 15 volt)	4	2/19/93 0:00:00	MRS	NTVOXFG2
2476	zn_fl_2v	NTV ZnO/Zn (old) 80 TOA (floating, FG min curr, min volt)	4	2/19/93 0:00:00	MRS	NTVOXFG2
2477	zn_g_15v	NTV ZnO/Zn (old, 60 TOA) grounded, FG max curr, 15 eV	3	2/19/93 0:00:00	MRS	NTVOXFG2
2478	zn_g_2ev	NTV ZnO/Zn (old, 60 TOA) grounded, FG min curr, min volt	3	2/19/93 0:00:00	MRS	NTVOXFG2
2479	zn_nfg_1	NTV ZnO/Zn (#2, old, 60 TOA) no FG	4	2/19/93 0:00:00	MRS	NTVOXFG2
2480	zn_nfg_2	NTV ZnO/Zn (#2, old, 60 TOA) no FG	4	2/19/93 0:00:00	MRS	NTVOXFG2
2481	zr_fl_2v	NTV ZrO 35 TOA floating, FG: min volt,min curr	4	2/24/93 0:00:00	MRS	NTVOXFG2
2482	zr_g_15v	NTV ZrO 35 TOA grounded, FG: 15 eV, 90% curr	3	3/5/93 0:00:00	MRS	NTVOXFG2
2483	zr_g_2ev	NTV ZrO 35 TOA grounded, FG: min volt,min curr	3	3/5/93 0:00:00	MRS	NTVOXFG2
2484	zr_nfg_1	NTV ZrO 35 TOA (as,rec'd, grounded, no FG)	4	3/5/93 0:00:00	MRS	NTVOXFG2
2485	zr_nfg_2	rerun NTV ZrO 35 TOA grnd, FG OFF (5 min wait)	3	3/5/93 0:00:00	MRS	NTVOXFG2
2486	ag_no_1	NATIVE SILVER OXIDE / SILVER (Ag) NODULE (90 DEG TOA, AS RECEIVED)	6	6/2/88 0:00:00	MRS	NTV_OX
2487	al_no_1	NATIVE ALUMINUM OXIDE / ALUMINUM (Al) Nodule (90 DEG TOA, AS RECEIVED)	3	4/27/88 0:00:00	MRS	NTV_OX
2488	as_no_1	NATIVE ARSENIC OXIDE/ARSENIC (As) CHIP (90 TOA,SCRAPED,AIR-EXPOSED 14 HR)	5	6/8/88 0:00:00	MRS	NTV_OX
2489	be_no_1	NATIVE BERYLLIUM OXIDE / BERYLLIUM (Be) Foil (90 DEG TOA, AS RECEIVED)	3	4/27/88 0:00:00	MRS	NTV_OX
2490	be_no_2	Native BeO 35 TOA (as rec'd, grounded, no FG)	4	3/10/93 0:00:00	MRS	NTV_OX
2491	bi_no_1	NATIVE BISMUTH OXIDE / BISMUTH (Bi) Slug (90 DEG TOA, AS RECEIVED)	6	4/27/88 0:00:00	MRS	NTV_OX
2492	b_no_1	NATIVE BORON OXIDE / BORON (B) LUMP (AS RECEIVED, 90 DEG TOA)	5	5/16/88 0:00:00	MRS	NTV_OX
2493	cd_no_1	NATIVE CADMIUM OXIDE / CADMIUM (Cd) SHEET (90 DEG TOA, AS RECEIVED)	3	5/10/88 0:00:00	MRS	NTV_OX
2494	cd_no_1a	NATIVE CADMIUM OXIDE / CADMIUM (Cd) SHEET (90 DEG TOA, AS RECEIVED)	1	5/10/88 0:00:00	MRS	NTV_OX
2495	co_no_1	NATIVE COBALT OXIDE / COBALT (Co) ROD (35 TOA, AS RECEIVED)	6	5/13/88 0:00:00	MRS	NTV_OX
2496	cr_no_1	NATIVE CHROMIUM OXIDE / CHROMIUM (Cr) SHEET (90 DEG TOA, AS RECEIVED)	4	5/10/88 0:00:00	MRS	NTV_OX
2497	cu_no_1	NATIVE COPPER OXIDE / COPPER SHEET (35 TOA,ION ETCHED,AIR-EXPOSED 2 DAYS)	4	5/11/88 0:00:00	MRS	NTV_OX
2498	fe_no_1	NATIVE IRON OXIDE / IRON (Fe) SHEET (AS RECEIVED, 90 DEG TOA)	4	5/16/88 0:00:00	MRS	NTV_OX
2499	fe_no_1a	NATIVE IRON OXIDE / IRON (Fe) SHEET (90 DEG TOA, AS RECEIVED)	3	6/7/88 0:00:00	MRS	NTV_OX
2500	ga_no_1	NATIVE GALIUM OXIDE / GALLIUM (Ga) NODULE (AS RECEIVED, 90 DEG TOA)	4	6/7/88 0:00:00	MRS	NTV_OX
2501	ge_no_1	NATIVE GERMANIUM OXIDE / GERMANIUM (Ge) ON Al (90 DEG TOA, AS RECEIVED)	6	5/11/88 0:00:00	MRS	NTV_OX

Serial	File Name	Description	No of Spectra	Date	Ident	SubDir.
2502	ge_no_2	NATIVE GERMANIUM OXIDE / GERMANIUM (Ge) ON Al (90 DEG TOA, AS RECEIVED)	4	5/13/88 0:00:00	MRS	NTV_OX
2503	hf_no_1	NATIVE HAFNIUM OXIDE / HAFNIUM (Hf) SPONGE (90 DEG TOA, FILED MONTHS AGO)	4	6/6/88 0:00:00	MRS	NTV_OX
2504	in_no_1	NATIVE INDIUM OXIDE / INDIUM (In) SHEET (AS RECEIVED, 90 DEG TOA)	5	5/20/88 0:00:00	MRS	NTV_OX
2505	ir_no_1	NATIVE IRIDIUM OXIDE / IRIDIUM (Ir) WIRE (90 DEG TOA, AS RECEIVED)	6	6/7/88 0:00:00	MRS	NTV_OX
2506	ir_no_1a	NATIVE IRIDIUM OXIDE / IRIDIUM (Ir) WIRE (90 DEG TOA, AS RECEIVED)	2	5/24/88 0:00:00	MRS	NTV_OX
2507	mg_no_1	NATIVE MAGNESIUM OXIDE/MAGNESIUM (Mg)(90 TOA,SCRAPED,AIR-EXPOSED 5 MIN)	6	6/1/88 0:00:00	MRS	NTV_OX
2508	mn_no_1	NATIVE MANGANESE OXIDE / MANGANESE (Mn) FLAKE (AS RECEIVED, 90 DEG TOA)	6	6/6/88 0:00:00	MRS	NTV_OX
2509	mo_no_1	NATIVE MOLYBDENUM OXIDE / MOLYBDENUM (Mo) SHEET (90 DEG TOA, AS RECEIVED)	5	5/20/88 0:00:00	MRS	NTV_OX
2510	nb_no_1	NATIVE NIOBIUM OXIDE / NIOBIUM (Nb) SHEET (AS RECEIVED, 90 DEG TOA)	4	5/20/88 0:00:00	MRS	NTV_OX
2511	ni_no_1	NATIVE NICKEL OXIDE / NICKEL (Ni) SHEET (AS RECEIVED, 90 DEG TOA)	5	5/20/88 0:00:00	MRS	NTV_OX
2512	pb_no_1	NATIVE LEAD OXIDE / LEAD (Pb) SHEET (90 DEG TOA, AS RECEIVED)	7	5/30/88 0:00:00	MRS	NTV_OX
2513	pb_no_1a	NATIVE LEAD OXIDE / LEAD (Pb) SHEET (35 DEG TOA, AIR-EXPOSED >1 HR)	3	5/31/88 0:00:00	MRS	NTV_OX
2514	pd_no_1	NATIVE PALLADIUM OXIDE / PALLADIUM (Pd) SHEET (90 DEG TOA, AS RECEIVED)	4	5/27/88 0:00:00	MRS	NTV_OX
2515	pt_no_1	NATIVE PLATINUM OXIDE / PLATINUM (Pt) SHEET (90 DEG TOA, AS RECEIVED)	6	5/27/88 0:00:00	MRS	NTV_OX
2516	re_no_1	NATIVE RHENIUM OXIDE / RHENIUM (Re) RIBBON (AS RECEIVED, 90 DEG TOA)	5	5/23/88 0:00:00	MRS	NTV_OX
2517	rh_no_1	NATIVE RHODIUM OXIDE / RHODIUM (Rh) PLATED ON Al (90 TOA, AS RECEIVED)	5	5/24/88 0:00:00	MRS	NTV_OX
2518	ru_no_1	NATIVE RUTHENIUM OXIDE/RUTHENIUM (Ru) POWDER (AS REC'D, 90 TOA, ON In)	4	6/2/88 0:00:00	MRS	NTV_OX
2519	sb_no_1	NATIVE ANTIMONY OXIDE / ANTIMONY (90 TOA, SCRAPED, AIR-EXPOSED >5 MIN)	3	6/7/88 0:00:00	MRS	NTV_OX
2520	sc_no_1	NATIVE SCANDIUM OXIDE / SCANDIUM TURNING (90 DEG TOA, AS RECEIVED)	6	6/1/88 0:00:00	MRS	NTV_OX
2521	se_no_1	NATIVE SELENIUM OXIDE / SELENIUM NODULE (90 DEG TOA, AS RECEIVED)	4	6/2/88 0:00:00	MRS	NTV_OX
2522	si_no_1	NATIVE SILICON OXIDE / SILICON WAFER (90 DEG TOA, AS RECEIVED)	6	6/2/88 0:00:00	MRS	NTV_OX
2523	sn_no_1	NATIVE TIN OXIDE / TIN LUMP (60 DEG TOA, AS RECEIVED)	3	5/26/88 0:00:00	MRS	NTV_OX
2524	sn_no_1a	NATIVE TIN OXIDE / TIN SHEET (90 DEG TOA, AS RECEIVED)	4	5/31/88 0:00:00	MRS	NTV_OX
2525	ta_no_1	NATIVE TANTALUM OXIDE / TANTALUM (Ta) SHEET (90 DEG TOA, AS RECEIVED)	5	5/25/88 0:00:00	MRS	NTV_OX
2526	te_no_1	NATIVE TELLURIUM OXIDE / TELLURIUM (Te) FRAGMENT (90 TOA, AS RECEIVED)	4	5/30/88 0:00:00	MRS	NTV_OX
2527	ti_no_1	NATIVE TITANIUM OXIDE / TITANIUM (Ti) SHEET (90 DEG TOA, AS RECEIVED)	4	5/27/88 0:00:00	MRS	NTV_OX
2528	tl_no_1	NATIVE THALLIUM OXIDE / THALLIUM (Tl) LUMP (90 TOA, AIR-EXPOSED >15 MIN)	4	6/6/88 0:00:00	MRS	NTV_OX
2529	tl_no_2	NATIVE THALLIUM OXIDE/THALLIUM (Tl) LUMP (90 TOA, AIR-EXPOSED MANY DAYS)	6	6/17/88 0:00:00	MRS	NTV_OX
2530	v_no_1	NATIVE VANADIUM OXIDE / VANADIUM (V) TURNING (90 TOA, AIR-EXPOSED 5 MIN)	4	6/3/88 0:00:00	MRS	NTV_OX
2531	w_no_1	NATIVE TUNGSTEN OXIDE / TUNGSTEN (W) SHEET (90 DEG TOA, AS RECEIVED)	6	5/23/88 0:00:00	MRS	NTV_OX
2532	y_no_1	NATIVE YTTRIUM OXIDE / YTTRIUM (Y) BLOCK (90 TOA, AIR-EXPOSED >5 MIN)	4	6/6/88 0:00:00	MRS	NTV_OX
2533	zn_no_1	NATIVE ZINC OXIDE / ZINC (Zn) NODULE (<60 DEG TOA, AS RECEIVED)	4	6/3/88 0:00:00	MRS	NTV_OX
2534	zr_no_1	NATIVE ZIRCONIUM OXIDE / ZIRCONIUM (Zr) BLOCK (90 DEG TOA, AS RECEIVED)	4	5/30/88 0:00:00	MRS	NTV_OX
2535	ag2o_ws	Ag2O	2	11/3/93 0:00:00	MRS	OX_REDO
2536	Bi2O3_03	Bi2O3 pellet 99.999% Aldr Lot# 04124HV scrn	1	11/4/93 0:00:00	MRS	OX_REDO
2537	bi2o3_ws	Bi2O3	2	11/4/93 0:00:00	MRS	OX_REDO
2538	cdo_r	CdO clean pellet redo for insert	2	3/25/94 0:00:00	MRS	OX_REDO
2539	cu2o_r	Cu2O clean pellet redo for insert	2	3/24/94 0:00:00	MRS	OX_REDO
2540	CUOH2_R	Cu(OH)2 clean pellet redo for insert	2	3/24/94 0:00:00	MRS	OX_REDO
2541	FE2O3A_R	alpha Fe2O3 clean pellet redo for insert	2	4/27/94 0:00:00	MRS	OX_REDO
2542	FE3O4_R	Fe3O4 clean pellet redo for insert	2	3/24/94 0:00:00	MRS	OX_REDO



Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
2543	feoo_h_r	FeOOH clean pellet redo for insert	2	3/24/94 0:00:00	MRS	OX_REDO
2544	ga2o3_ws	ga2o3 wide scan redo	1	1/25/94 0:00:00	MRS	OX_REDO
2545	geo2_ws	GeO2 wide scan redo	1	1/25/94 0:00:00	MRS	OX_REDO
2546	GFE2O3_R	gamma-Fe2O3 clean pellet redo for insert	2	3/24/94 0:00:00	MRS	OX_REDO
2547	hfo2_ws	HfO2 wide scan redo	1	1/25/94 0:00:00	MRS	OX_REDO
2548	iro2_r	IrO2 clean pellet redo for insert	2	4/28/94 0:00:00	MRS	OX_REDO
2549	mgo_xtl	MgO crystal (unknown source) scrn 90 deg TOA	7	10/28/93 0:00:00	MRS	OX_REDO
2550	moo3_r	MoO3 clean pellet redo for insert	2	4/27/94 0:00:00	MRS	OX_REDO
2551	moo3_ws	MoO3	2	11/2/93 0:00:00	MRS	OX_REDO
2552	nb2o5_r	Nb2O5 clean pellet redo for insert	2	4/28/94 0:00:00	MRS	OX_REDO
2553	nb2o5_ws	Nb2O5	2	11/2/93 0:00:00	MRS	OX_REDO
2554	NiO_R	NiO clean pellet redo for insert	2	4/28/94 0:00:00	MRS	OX_REDO
2555	pbo2_r	PbO2 clean pellet redo for insert	2	4/28/94 0:00:00	MRS	OX_REDO
2556	pdo_r	PdO clean pellet redo for insert	2	4/28/94 0:00:00	MRS	OX_REDO
2557	pdo_ws	PdO	2	11/2/93 0:00:00	MRS	OX_REDO
2558	pto2_r	PtO2-nH2O clean pellet redo for insert	2	4/21/94 0:00:00	MRS	OX_REDO
2559	rh2o3_r	Rh2O3 clean pellet redo for insert	2	4/20/94 0:00:00	MRS	OX_REDO
2560	ruo2_r	RuO2 clean pellet redo for insert	2	4/21/94 0:00:00	MRS	OX_REDO
2561	SC2O3_R	Sc2O3 clean pellet redo for insert	2	4/20/94 0:00:00	MRS	OX_REDO
2562	SNO_R	SnO clean pellet redo for insert	2	4/20/94 0:00:00	MRS	OX_REDO
2563	ta2o5_ws	Ta2O5	2	11/3/93 0:00:00	MRS	OX_REDO
2564	tio2_r	TiO2 clean pellet redo for insert	2	4/20/94 0:00:00	MRS	OX_REDO
2565	tio2_ws	TiO2	2	11/1/93 0:00:00	MRS	OX_REDO
2566	V2O5_R	V2O5 clean pellet redo for insert	2	4/20/94 0:00:00	MRS	OX_REDO
2567	v2o5_ws	V2O5	2	11/3/93 0:00:00	MRS	OX_REDO
2568	WO3_R	WO3 clean pellet redo for insert	2	3/25/94 0:00:00	MRS	OX_REDO
2569	wo3_ws	WO3	2	11/2/93 0:00:00	MRS	OX_REDO
2570	Y2O3_R	Y2O3 clean pellet redo for insert	2	4/21/94 0:00:00	MRS	OX_REDO
2571	ZNO_R	ZnO clean pellet redo for insert	2	3/25/94 0:00:00	MRS	OX_REDO
2572	ZRO2_R	ZrO2 clean pellet redo for insert	2	3/25/94 0:00:00	MRS	OX_REDO
2573	alumitx1	ALUMITEX (35 lb SINGLE PLY KRAFT) "DAUBERT COATED PRODUCTS Co."	1	11/17/85 0:00:00	MRS	PAPR&INK
2574	alumitx2	ALUMITEX (35 lb SINGLE PLY KRAFT) "DAUBERT COATED PRODUCTS Co."	3	11/17/85 0:00:00	MRS	PAPR&INK
2575	antistat	"Chapman Co." Static-eliminating Spray On A Gold Platen (No Rust Formula) The Portland Co.	9	11/2/85 0:00:00	MRS	PAPR&INK
2576	canon_1	Second Orig Copy Ppr Canon "SM-1 Daini Genshi" 90T	8	5/27/94 0:00:00	MRS	PAPR&INK
2577	cellulos	CELLULOSE PROPIONATE (Sci. Polymer Prod.) EXPOSED BULK (90 TOA, SCREEN)	7	1/12/88 0:00:00	MRS	PAPR&INK
2578	clean_rm	Clean Rm Prntr Ppr Sakurai Co. Class 1000 (PPC)	8	5/26/94 0:00:00	MRS	PAPR&INK
2579	clndr_01	No ink area on year calendar paper #1 (as rec'd, screen, 35 TOA)	4	3/24/92 0:00:00	MRS	PAPR&INK
2580	copptrx1	COPPERTEX (35 lb SINGLE PLY KRAFT) "DAUBERT COATED PRODUCTS Co."	2	11/17/85 0:00:00	MRS	PAPR&INK
2581	copptrx2	COPPERTEX (35 lb SINGLE PLY KRAFT) "DAUBERT COATED PRODUCTS Co."	4	11/17/85 0:00:00	MRS	PAPR&INK
2582	dbl_side	DOUBLE STICK TAPE (SCOTCH 3M Co.) CAT. #136	4	10/13/85 0:00:00	MRS	PAPR&INK
2583	envlp_1	CENTURY ENVELOP (INTERIOR) WHITE WOVE SUB. 20 (QUALITY PARK PRODUCTS)	5	11/2/85 0:00:00	MRS	PAPR&INK

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
2584	filter_1	Filter Paper Toyo Roshi Co. #131 18.5cm Qual.90TOA	8	5/26/94 0:00:00	MRS	PAPR&INK
2585	fox_rivr	FOX RIVER Co. BOND ENVELOP (INSIDE) #10, SUB. 24, ARCTIC WHITE	6	10/13/85 0:00:00	MRS	PAPR&INK
2586	hoto_1	Word Proc Ppr (Hoto Co.) Ribbon Type "HT-5001"	10	5/30/94 0:00:00	MRS	PAPR&INK
2587	hp_papr1	SIDE "A" OF HP 8-Pen PLOTTER PAPER (90 DEG TOA, SCREEN)	2	1/13/88 0:00:00	MRS	PAPR&INK
2588	hp_papr2	SIDE "B" OF HP (8-pen) PLOTTER PAPER (90 DEG TOA, SCREEN)	3	1/14/88 0:00:00	MRS	PAPR&INK
2589	inkjet_1	Paintjet Ppr (front) HP Co. Prod# HP51630P 90TOA	8	5/27/94 0:00:00	MRS	PAPR&INK
2590	inkjet_2	Paintjet Ppr (back) HP Co. Prod#HP51630P 90 TOA	8	5/27/94 0:00:00	MRS	PAPR&INK
2591	ink_01	Black ink (#1) on Calendar paper #2 (as rec'd, screen, 35)	1	3/24/92 0:00:00	MRS	PAPR&INK
2592	ink_02	Black ink (#02) on Calendar paper #1 (as rec'd, screen, 35 TOA)	5	3/24/92 0:00:00	MRS	PAPR&INK
2593	ink_03	Red ink (#03) on Calendar paper #1 (as rec'd, screen, 35 TOA)	4	3/24/92 0:00:00	MRS	PAPR&INK
2594	ink_04	No ink area on calendar paper #1 (as rec'd, screen, 35 TOA)	4	3/24/92 0:00:00	MRS	PAPR&INK
2595	ink_05	Black ink (#05) area on Calendar Paper #2 (as rec'd, screen, 35)	4	3/24/92 0:00:00	MRS	PAPR&INK
2596	ink_06	Black ink (#06) on calendar paper (0.8 mm scrn-hgt, 35 TOA)	3	3/30/92 0:00:00	MRS	PAPR&INK
2597	kimwipe	KimWipe Wipers S-200 Kimberly Clark Co.	10	5/30/94 0:00:00	MRS	PAPR&INK
2598	kokuyo_1	Word Proc Ppr (Kokuyo Co.) Tai-1010N-W Thrml&Typew	10	5/28/94 0:00:00	MRS	PAPR&INK
2599	lintfre1	Lint Free Wiper-Cotton BEMCOT M-3 (Asahi Co.)	10	5/30/94 0:00:00	MRS	PAPR&INK
2600	lintfre2	Lint-Free Wiper (Asahi Chem Co) Cotton BEMCOT M-3	4	5/30/94 0:00:00	MRS	PAPR&INK
2601	nakabaya	Word Proc Ppr (Nakabayashi Co.) "Yo W-12" PPC LOS	10	5/28/94 0:00:00	MRS	PAPR&INK
2602	nitrocel	X-ray Damage to NITRO-CELLULOSE Paper (SCREEN, 90 TOA, TOYO Co)	20	2/17/88 0:00:00	MRS	PAPR&INK
2603	pilot_1	Word Proc Ppr (Pilot Co.) Economy K-ECA4100 Front	10	5/28/94 0:00:00	MRS	PAPR&INK
2604	pilot_2	Word Proc Ppr (Pilot Co.) Economy K-ECA4100 Backsd	10	5/29/94 0:00:00	MRS	PAPR&INK
2605	pilot_3	Word Proc Ppr (Pilot)SuperHiGrade K-SHGA4100 front	10	5/29/94 0:00:00	MRS	PAPR&INK
2606	pilot_4	Word Proc Ppr (Pilot) SuperHiGrade K-SHGA4100 back	10	5/29/94 0:00:00	MRS	PAPR&INK
2607	rice_1	Shiny side rice straw paper "Br" (as rec'd, 90 TOA, used mesh for charge control)	4	2/23/94 0:00:00	MRS	PAPR&INK
2608	rice_2	Dull side rice straw paper "Br" (as rec'd, 90 TOA, used mesh for charge control)	1	2/23/94 0:00:00	MRS	PAPR&INK
2609	rice_2a	Dull side rice straw paper "Br" (as rec'd, 90 TOA, used mesh for charge control)	4	2/23/94 0:00:00	MRS	PAPR&INK
2610	rice_3	Shiny side rice straw paper "White" (as rec'd, 90 TOA, used mesh for charge control)	3	2/23/94 0:00:00	MRS	PAPR&INK
2611	rice_3a	Shiny side rice straw paper "White" (as rec'd, 90 TOA, used mesh for charge control)	1	2/23/94 0:00:00	MRS	PAPR&INK
2612	rice_4	Dull side rice straw paper "White" (as rec'd, 90 TOA, used mesh for charge control)	3	2/23/94 0:00:00	MRS	PAPR&INK
2613	rice_4a	Dull side rice straw paper "White" (as rec'd, 90 TOA, used mesh for charge control)	1	2/23/94 0:00:00	MRS	PAPR&INK
2614	rice_4b	Dull side rice straw paper "White" (as rec'd, 90 TOA, used mesh for charge control)	1	2/23/94 0:00:00	MRS	PAPR&INK
2615	rice_5	Rice Leaf (outside of stem, dried plant) (as rec'd, 90 TOA, used mesh for charge control)	4	2/23/94 0:00:00	MRS	PAPR&INK
2616	rice_6	Rice Straw (outside of stem, dried plant) (as rec'd, 90 TOA, used mesh for charge control)	4	2/23/94 0:00:00	MRS	PAPR&INK
2617	sealant	Sealant on Flap of FOX RIVER Co. BOND ENVELOP #10, SUB. 24, ARCTIC WHITE	4	10/13/85 0:00:00	MRS	PAPR&INK
2618	silvr_sv	SILVER SAVER PAPER (USED TO WRAP LEAD FRAMES) (DAUBERT COATED PROD Co.)	4	10/13/85 0:00:00	MRS	PAPR&INK
2619	thermal1	Thermal Prntr Ppr (front) HP Co. Part#92160N 90TOA	8	5/27/94 0:00:00	MRS	PAPR&INK
2620	thremal2	Thermal Prntr Ppr (back) HP Co. Part#92160N 90 TOA	8	5/27/94 0:00:00	MRS	PAPR&INK
2621	tokusa	Tokusa [scouring rush] (outside of stem, green) (as rec'd, 90 TOA, used mesh for charge control)	4	2/23/94 0:00:00	MRS	PAPR&INK
2622	wax_papr	WAX PAPER FROM WAXTEX Co. (AS RECEIVED, no mesh)	4	10/13/85 0:00:00	MRS	PAPR&INK
2623	wheat_a	Wheat Straw (outside of stem, dried plant) (as rec'd, 90 TOA, used mesh for charge control)	4	2/23/94 0:00:00	MRS	PAPR&INK
2624	al_cvr_1	SS KBr press anvil covered by: Aluminum kitchen foil, as rec'd, no cleaning, Mesh.	1	6/1/94 0:00:00	MRS	PELLET_R

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
2625	al_cvr_2	SS KBr press anvil covered by: Aluminum kitchen foil, as rec'd, no cleaning. Mesh	1	6/1/94 0:00:00	MRS	PELLET_R
2626	cu_cvr_1	SS Kbr press anvil covered by: 0.1mm Cu foil, as rec'd, no cleaning (mesh)	1	6/1/94 0:00:00	MRS	PELLET_R
2627	gly_cvr1	SS KBr press anvil covered by: Glycine "weighing" paper, (SSI mesh used.)	4	1/7/94 0:00:00	MRS	PELLET_R
2628	gly_cvr2	SS KBr press anvil covered by: Glycine paper. V.Strong Hand Pressure used. (SSI Mesh)	4	1/12/94 0:00:00	MRS	PELLET_R
2629	gly_cvr3	SS KBr press anvil covered by: Glycine paper. (No SSI mesh) 70 TOA	4	1/7/94 0:00:00	MRS	PELLET_R
2630	hdpe_cvr	SS KBr press anvil covered by: HDPE film (hard press) 90 TOA, mesh, FG:20%I,5eV	4	1/14/94 0:00:00	MRS	PELLET_R
2631	tape_cvr	SS KBr press anvil covered by: Scotch Magic Tape, scrubbed with EtOH (mesh)	1	6/1/94 0:00:00	MRS	PELLET_R
2632	tef_cvr1	SS KBr press anvil covered by: 1mm Teflon sheet. (SSI mesh used)	1	6/1/94 0:00:00	MRS	PELLET_R
2633	tef_cvr2	SS KBr press anvil covered by: Teflon sheet (1mm) no mesh,70 TOA	4	1/7/94 0:00:00	MRS	PELLET_R
2634	tef_cvr3	SS KBr press anvil covered by: Teflon sheet, used SSI mesh, 90 TOA	3	1/7/94 0:00:00	MRS	PELLET_R
2635	wax_cvr1	SS KBr press anvil covered by: Brown 1-sided Wax Paper, 90TOA, SSI mesh	2	1/14/94 0:00:00	MRS	PELLET_R
2636	wax_cvr2	SS KBr press anvil covered by: Translucent Wax Paper,90TOA,mesh,min FG: I,V	4	1/14/94 0:00:00	MRS	PELLET_R
2637	_ref_plt	Reference Pellet: Y2O3 powder pressed with SS KBr press: No Cover. Mesh.	10	8/19/91 0:00:00	MRS	PELLET_R
2638	gap100_a	GaP <100> 90 TOA as rec'd	8	5/16/94 0:00:00	MRS	PHOSPHID
2639	gap100_b	GaP <100> 90 TOA after 1 min 3 KV etch	8	5/18/94 0:00:00	MRS	PHOSPHID
2640	gap100_c	GaP <100> 90 TOA after 1 min 3 KV etch	1	5/18/94 0:00:00	MRS	PHOSPHID
2641	gap100_d	GaP <100> 90 TOA after 1 min 3 KV etch	1	5/18/94 0:00:00	MRS	PHOSPHID
2642	gap111_a	GaP <111> 90 TOA as rec'd	7	5/16/94 0:00:00	MRS	PHOSPHID
2643	gap111_b	GaP <111> exposed fract. bulk, not etched, 90 TOA	5	5/23/94 0:00:00	MRS	PHOSPHID
2644	gap111_c	GaP <111> exposed fract. bulk, not etched, 90 TOA	4	5/23/94 0:00:00	MRS	PHOSPHID
2645	gap111_d	GaP <111> exposed fract. bulk, 1 min 3KV etch 90T	5	5/23/94 0:00:00	MRS	PHOSPHID
2646	inp_01	FRESHLY EXPOSED BULK OF AN InP (111) WAFER (90 DEG TOA)	5	8/12/87 0:00:00	MRS	PHOSPHID
2647	inp_02	FRESHLY EXPOSED BULK OF AN InP (111) WAFER (90 DEG TOA)	2	8/12/87 0:00:00	MRS	PHOSPHID
2648	inp_ar	InP <111> as rec'd Sumitomo Elec 700321-01a	14	4/26/94 0:00:00	MRS	PHOSPHID
2649	inp_blk	InP xtal bulk Sumitomo Elec(90TOA,air fract 700321	14	4/24/94 0:00:00	MRS	PHOSPHID
2650	inp_b_e	InP xtal etched bulk Sumitomo Elec(90TOA,air fract	6	4/26/94 0:00:00	MRS	PHOSPHID
2651	inp_m_e	InP <111> mirror etched Sumitomo Elec 700321-01a	6	4/27/94 0:00:00	MRS	PHOSPHID
2652	inp_vb	InP (111) (Sumitomo Electric, 90 TOA, Fresh Bulk)	1	6/8/87 0:00:00	MRS	PHOSPHID
2653	acetal	X-RAY DAMAGE TO POLY-ACETAL (90 TOA, 1 MM FROM SCREEN, FRESH BULK)	20	3/27/88 0:00:00	MRS	POLYMER
2654	acrylic	X-RAY DAMAGE TO POLY-ACRYLIC ACID (90 TOA,FILM/AI,NO SCREEN,NO FLOOD GUN)	20	2/25/88 0:00:00	MRS	POLYMER
2655	amide	X-RAY DAMAGE TO POLY-AMIDE RESIN (90 DEG TOA, SCREEN (1mm), FRESH BULK)	20	4/5/88 0:00:00	MRS	POLYMER
2656	butene	X-RAY DAMAGE TO POLY-1-BUTENE (ISOTACTIC)(EXPOSED BULK, 90 TOA, mesh(1mm)	20	4/22/88 0:00:00	MRS	POLYMER
2657	carbonat	X-RAY DAMAGE TO POLY-CARBONATE (90 TOA, SCREEN, 2 MM BEAD, FRESH BULK)	20	3/8/88 0:00:00	MRS	POLYMER
2658	cellulos	CELLULOSE PROPIONATE (Sci. Polymer Prod.) (FRESH BULK, 90 TOA, SCREEN)	7	1/12/88 0:00:00	MRS	POLYMER
2659	ETFE_01	Ethylene Tetra-Fluoro Ethylene (ETFE) copolymer (as rec'd, 90 TOA, mesh)	6	11/19/92 0:00:00	MRS	POLYMER
2660	etfe_02	Ethylene Tetra-Fluoro Ethylene (ETFE) copolymer (as rec'd, 90 TOA, mesh)	6	11/19/92 0:00:00	MRS	POLYMER
2661	ethylen1	X-ray Damage to POLY-ETHYLENE (90 TOA, SCREEN (1mm), Fresh Bulk)	20	2/18/88 0:00:00	MRS	POLYMER
2662	ethylen2	X-ray Damage to POLY-ETHYLENE (90 DEG TOA, SCREEN, Fresh Bulk)	20	2/22/88 0:00:00	MRS	POLYMER
2663	ethylene	POLY-ETHYLENE (90 TOA, SCREEN 1mm)	1	2/19/88 0:00:00	MRS	POLYMER
2664	gladwrap	POLYETHYLENE FILM (GLAD WRAP) (AS RECEIVED, no mesh)	7	10/13/85 0:00:00	MRS	POLYMER
2665	isohexen	X-RAY DAMAGE TO POLY (4-METHYL-1-PENTENE)(90 TOA, SCREEN, FRESH BULK)	19	4/25/88 0:00:00	MRS	POLYMER

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
2666	kapton	X-RAY DAMAGE TO KAPTON (90 DEG TOA, 1 MM FROM SCREEN, SCRAPED FILM)	20	3/25/88 0:00:00	MRS	POLYMER
2667	LLDPE_01	Linear Low Density Poly-Ethylene (LLDPE) film, No Treatment, mesh	3	8/26/92 0:00:00	MRS	POLYMER
2668	LLDPE_OX	Linear Low Density PE (LLDPE) film after O2 plasma treatment (mesh)	3	8/26/92 0:00:00	MRS	POLYMER
2669	mylar_s1	S-Probe, mylar under screen (spot 250x1000um)	1	9/28/90 0:00:00	MRS	POLYMER
2670	mylar_s2	S-Probe, 10eV pass energy, 200x1000um spot	1	9/28/90 0:00:00	MRS	POLYMER
2671	nitrocel	X-ray Damage to NITRO-CELLULOSE Paper (SCREEN, 90 TOA, TOYO Co)	20	2/17/88 0:00:00	MRS	POLYMER
2672	nomex_01	NOMEX FROM DUPONT (AS RECEIVED, no mesh)	7	11/5/85 0:00:00	MRS	POLYMER
2673	nomex_02	NOMEX FROM DUPONT (AS RECEIVED, no mesh)	7	11/5/85 0:00:00	MRS	POLYMER
2674	nomex_03	NOMEX FROM DUPONT (AS RECEIVED, no mesh)	1	11/5/85 0:00:00	MRS	POLYMER
2675	nomex_04	NOMEX FROM DUPONT (AS RECEIVED, no mesh)	1	11/5/85 0:00:00	MRS	POLYMER
2676	nylon_6	X-RAY DAMAGE TO NYLON 6 (90 DEG TOA, SCREEN, 2 MM BEAD, FRESH BULK)	20	2/19/88 0:00:00	MRS	POLYMER
2677	paa_01	POLY(ACRYLIC) ACID (THIN FILM ON SILICON WAFER, 90 DEG TOA, no mesh)	3	3/16/87 0:00:00	MRS	POLYMER
2678	paa_02	POLY(ACRYLIC) ACID (THIN FILM ON SILICON WAFER, 90 DEG TOA, no mesh)	2	3/16/87 0:00:00	MRS	POLYMER
2679	paa_nfg	POLY-ACRYLIC ACID FILM ON SILICON (NO FLOOD GUN, no mesh)	1	2/25/87 0:00:00	MRS	POLYMER
2680	pan	X-RAY DAMAGE TO POLY-ACRYLONITRILE (PAN) (90 TOA, FILM, SCREEN, AS REC'D)	20	2/24/88 0:00:00	MRS	POLYMER
2681	pan_01	POLYACRYLONITRILE (PAN) FILM (no mesh)	5	10/19/85 0:00:00	MRS	POLYMER
2682	pcb_bag1	ANTI-STATIC BAG FOR PC BOARD (SECO PACK 66 PPP-C-1842A INSIDE SURFACE)	8	11/2/85 0:00:00	MRS	POLYMER
2683	pcb_bag2	ANTI-STATIC BAG FOR PC BOARDS (SEALPAK Co.)	9	11/2/85 0:00:00	MRS	POLYMER
2684	pcb_bag3	ANTI-STATIC BAG for PC Board (3M #2100 STATIC SHIELDING BAG)	5	11/17/85 0:00:00	MRS	POLYMER
2685	pcb_bag4	ANTI STATIC BAG FOR HANDLING PC BOARDS (ARMAND CO. (PPP-C-1842A))	8	11/17/85 0:00:00	MRS	POLYMER
2686	pcls_ar2	POLY CHLORO STYRENE FILM UNDER CLIP (NO DST) ARGON MULTI-LINE ON: 800 mW	2	9/27/89 0:00:00	MRS	POLYMER
2687	peo_1	X-RAY DAMAGE TO POLY-ETHYLENE OXIDE (CAST FROM CHCl3, SCREEN, 90 DEG TOA)	19	4/26/88 0:00:00	MRS	POLYMER
2688	peo_2	X-RAY DAMAGE TO POLY-ETHYLENE OXIDE (90 TOA, SCREEN 1mm, CAST FROM CHCl3)	20	4/7/88 0:00:00	MRS	POLYMER
2689	pet_02	PET (Mylar) film (as rec'd) center (90 TOA, mesh)	14	11/19/92 0:00:00	MRS	POLYMER
2690	pet_03	PET (Mylar) film (as rec'd) center (90 TOA, mesh)	6	11/19/92 0:00:00	MRS	POLYMER
2691	pet_04	PET (Mylar) film (as rec'd) center (90 TOA, mesh)	7	11/19/92 0:00:00	MRS	POLYMER
2692	pet_05	SCANNED ANALYSIS OF MYLAR PELLET (FRESHLY CUT IN HALF TO EXPOSE BULK)	2	10/6/86 0:00:00	MRS	POLYMER
2693	pet_07	PET (MYLAR) FILM (35 DEG TOA, NO SCREEN, INSIDE CLIP)	3	9/22/87 0:00:00	MRS	POLYMER
2694	pet_1	X-RAY DAMAGE TO MYLAR (PET) (Washed THIN FILM, 90 TOA, 1 MM FROM SCREEN)	20	6/9/88 0:00:00	MRS	POLYMER
2695	pet_2	X-RAY DAMAGE TO PET (MYLAR)(90 TOA, EXPOSED BULK, 0.7 MM FROM SCREEN)	20	6/10/88 0:00:00	MRS	POLYMER
2696	pe_if	Freshly Exposed Interface Surface of PE Film #6	5	7/19/91 0:00:00	MRS	POLYMER
2697	pmma	X-RAY DAMAGE TO PMMA (CAST FROM CHCl3, 90 TOA, SCREEN (1mm), THIN FILM)	20	3/17/88 0:00:00	MRS	POLYMER
2698	pps	X-RAY DAMAGE TO POLY-PHENYLENE SULFIDE (90 TOA, POWDER/TAPE, SCREEN)	20	4/1/88 0:00:00	MRS	POLYMER
2699	pp_asrec	As Received Outer Surface of PE Bead	3	7/24/91 0:00:00	MRS	POLYMER
2700	pp_bulk	Freshly Exposed bulk of PE pellet	3	7/24/91 0:00:00	MRS	POLYMER
2701	propylen	X-RAY DAMAGE TO POLY-PROPYLENE (THICK FILM SCRAPED, 90 TOA, SCREEN 1mm)	20	4/21/88 0:00:00	MRS	POLYMER
2702	ps_contr	Poly-Styrene Film: no treatment (mesh)	3	8/26/92 0:00:00	MRS	POLYMER
2703	PS_GAMMA	Poly-Styrene Film after Gamma-Ray irradiation	3	8/26/92 0:00:00	MRS	POLYMER
2704	PS_OX	Poly-Styrene Film after O2 plasma (mesh)	3	8/26/92 0:00:00	MRS	POLYMER
2705	ps_ox_ga	Poly-Styrene film after gamma-ray and O2 plasma treatments	3	8/26/92 0:00:00	MRS	POLYMER
2706	pva	X-RAY DAMAGE TO POLY-VINYL ACETATE (PVA) (90 TOA, SCREEN, FRESH BULK)	19	3/18/88 0:00:00	MRS	POLYMER

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
2707	pvc	X-ray Damage to POLY-VINYLCHLORIDE (PVC) (Beads/DST, SCREEN, 90 DEG TOA)	20	2/12/88 0:00:00	MRS	POLYMER
2708	pvdF	X-RAY DAMAGE TO POLY-VINYLDIENE di-FLUORIDE (Powder/DST, 90TOA, SCREEN)	20	3/28/88 0:00:00	MRS	POLYMER
2709	pvmk_ar_	Poly Vinyl Methyl Ketone/glass Under Clip (No Dst)before Exposing To Argn Multi-line	3	9/27/89 0:00:00	MRS	POLYMER
2710	pvn_uv17	ORIGINAL PVN/GLASS SAMPLE UNDER SSI SCREEN (1 mm) ARGON UV LINES: 500+ mW	3	9/28/89 0:00:00	MRS	POLYMER
2711	pvn_uv_1	POLY VINYL NAPHTHALENE FILM UNDER CLIP (NO DST) BEFORE EXPOSED TO UV LASER	1	9/28/89 0:00:00	MRS	POLYMER
2712	pvpyridn	POLYVINYLPYRIDINE (SINGLE BEAD) (BD) #337 UNKNOWN SOURCE (REILLY?)	5	10/19/85 0:00:00	MRS	POLYMER
2713	saran	SARAN WRAP FROM DOW (FOOD WRAP, 52.2 yd x 11.5 in) AS RECEIVED, no mesh	4	10/13/85 0:00:00	MRS	POLYMER
2714	silicone	DIMETHYL SILICONE REFERENCE SAMPLE (35 DEG TOA, NO SCREEN, INSIDE CLIP)	4	9/22/87 0:00:00	MRS	POLYMER
2715	spider	BLACK WIDOW SPIDER WEB (NON-STICKY) no mesh	5	10/20/85 0:00:00	MRS	POLYMER
2716	styrene	X-RAY DAMAGE TO POLY-STYRENE (90 TOA, SCREEN, 3 MM BEAD, FRESH BULK)	20	3/12/88 0:00:00	MRS	POLYMER
2717	styrene2	Poly-Styrene Film: No treatment	3	8/26/92 0:00:00	MRS	POLYMER
2718	sulphone	X-RAY DAMAGE TO POLY-SULFONE RESIN (90 TOA, SCREEN, FRESH Bulk)	19	2/23/88 0:00:00	MRS	POLYMER
2719	teflon	X-ray Damage to TEFLON (Tape/DST, 90 DEG TOA, SCREEN 1 mm)	20	2/2/88 0:00:00	MRS	POLYMER
2720	teflon_1	TEFLON TAPE (90 DEG TOA, SCREEN, 1 mm FROM SAMPLE)	2	2/2/88 0:00:00	MRS	POLYMER
2721	vpYridin	POLY-VINYL-PYRIDINE (SINGLE BEAD) no mesh	5	10/19/85 0:00:00	MRS	POLYMER
2722	ziploc	ZIPLOC SANDWICH BAG (INTERIOR, no mesh)	5	11/2/85 0:00:00	MRS	POLYMER
2723	psg_001	PSG (0% P, 8,982 Ang) 1 min dilute HF etched 35 TOA, SSI mesh for charge control	7	6/18/94 0:00:00	MRS	PSG_SI
2724	psg_002	PSG (1% P, 9,517 ang SiO2) 1min in dilute HF 35 TOA, SSI mesh for charge control	7	6/18/94 0:00:00	MRS	PSG_SI
2725	psg_003	PSG (2% P, 9,680 Ang SiO2/P) after 1 min dilue HF 35 TOA, SSI mesh for charge control	7	6/18/94 0:00:00	MRS	PSG_SI
2726	psg_004	PSG (4% P, 8,903 Angstrom SiO2/Si) 1 min dil. HF 35 TOA, SSI mesh for charge control	7	6/18/94 0:00:00	MRS	PSG_SI
2727	psg_10_p	PSG (10% P,10683 Ang) 1min dil HF etch (35 TOA)mes	6	7/3/94 0:00:00	MRS	PSG_SI
2728	psg_6_p	PSG (6% P, 9564 Ang) 1min dil HF etch (35 TOA)mesh	6	7/2/94 0:00:00	MRS	PSG_SI
2729	psg_7_p	PSG (7% P,11533 Ang) 1min dil HF etch (35 TOA)mesh	6	7/2/94 0:00:00	MRS	PSG_SI
2730	psg_8_p	PSG (8% P, 9758 Ang) 1min dil HF etch (35 TOA)mesh	6	7/3/94 0:00:00	MRS	PSG_SI
2731	psg_9_p	PSG (9% P,10683 Ang) 1min dil HF etch (35 TOA)mesh	6	7/3/94 0:00:00	MRS	PSG_SI
2732	ag2o_02	Ag2O 5mm plit 99.99% Aldr Lot# 00105CV scrn 35TOA	7	6/25/91 0:00:00	MRS	PURE_OX1
2733	ago_01	AgO (99% + Ag2O) Aldrich lot# 00108JV, 3mm pellet, CONDUCTIVE, 90 DEG TOA	11	9/9/91 0:00:00	MRS	PURE_OX1
2734	al2o3_01	SAPPHIRE (Al2O3) (AS RECEIVED, 35 DEG TOA, NO MESH, INSIDE CLIP)	4	9/22/87 0:00:00	MRS	PURE_OX1
2735	al2o3_02	Fused Al2O3 (as rec'd surface of 1 mm thick plate, screen, 90 DEG TOA)	10	8/20/91 0:00:00	MRS	PURE_OX1
2736	al2o3_03	ACTIVATED ALUMINUM OXIDE (Al2O3) CHROM. GRADE (no mesh, 35 TOA)	6	10/20/85 0:00:00	MRS	PURE_OX1
2737	al2o3_04	ALUMINA (Al2O3) POWDER on DST (35 deg TOA, no mesh)	20	8/18/84 0:00:00	MRS	PURE_OX1
2738	al2o3_06	Aluminum Oxide powder on DST (90 deg TOA, screen)	8	3/17/92 0:00:00	MRS	PURE_OX1
2739	anatase1	Anatase (beta-TiO2) on Magnetite (Arkansas, USA)	9	6/17/94 0:00:00	MRS	PURE_OX1
2740	anatase2	Anatase (beta-TiO2) on Magnetite (Arkansas, USA)	3	6/17/94 0:00:00	MRS	PURE_OX1
2741	as2o3_01	As2O3 (99.995+%) Aldrich lot# 04445CW, 3mm pellet, screen, 90 TOA	11	1/28/92 0:00:00	MRS	PURE_OX1
2742	as2o3_1	As2O3 99.995% Aldr# 04445CW 3mm plt 90 TOA mesh	10	5/25/94 0:00:00	MRS	PURE_OX1
2743	au2o3_01	Au2O3 (Au 86%) Aldr 00306AW, 3 mm pellet, 90 TOA, Semi-Conductive	10	1/25/92 0:00:00	MRS	PURE_OX1
2744	b2o3_01	B2O3 (99.999%) crystal, Aldrich lot# 02829BV, screen, 90 TOA	9	8/23/91 0:00:00	MRS	PURE_OX1
2745	b2o3_02	B2O3 (99.999%) crystal, Aldrich lot# 02829BV, screen, 90 TOA	3	8/23/91 0:00:00	MRS	PURE_OX1
2746	beo_01	BeO (99.99%) 3mm pellet, Aldrich lot# 00213JX, screen, 90 TOA	10	1/28/92 0:00:00	MRS	PURE_OX1
2747	beo_02	BeO 99.99% Aldr lot# 00213JX scrn 90 TOA	3	6/13/94 0:00:00	MRS	PURE_OX1

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
2748	BI2O3_01	Bi2O3 pellet 99.999% Aldrich lot# 04124HV (screen)	1	3/25/94 0:00:00	MRS	PURE_OX1
2749	bi2o3_02	Bi2O3 (99.999%) 3mm pellet, Aldr Lot# 04124HV, screen, 35 TOA	3	6/25/91 0:00:00	MRS	PURE_OX1
2750	bi2o3_04	Bi2O3 pellet 99.999% Aldr Lot# 04124HV scrn	1	3/25/94 0:00:00	MRS	PURE_OX1
2751	brookit2	Brookite (gamma-TiO2) Arkansas,USA (black, conduc)	4	6/17/94 0:00:00	MRS	PURE_OX1
2752	brookite	Brookite (gamma-TiO2) Arkansas,USA (black, conduc)	10	6/17/94 0:00:00	MRS	PURE_OX1
2753	cao_01	CaO (99.995%) Aldr lot# 01228BW, 3mm pellet, screen, 90 TOA	12	1/29/92 0:00:00	MRS	PURE_OX1
2754	cassitr	SnO2 (Cassiterite, Minas Gerais, Brazil) bulk, 90T	7	6/10/94 0:00:00	MRS	PURE_OX1
2755	cdo_01	CdO (99.99+%) Aldrich lot #01318EV, 3mm pellet, 35 TOA, screen	4	6/11/91 0:00:00	MRS	PURE_OX1
2756	cdo_01a	CdO (99.99+%) Aldrich lot #0138EV 3mm pellet, 35 TOA, screen screen	1	6/11/91 0:00:00	MRS	PURE_OX1
2757	cdo_02	CdO pellet (in CdO_01) after removing 80% of HC contam. by ion etching	3	6/12/91 0:00:00	MRS	PURE_OX1
2758	cdo_03	CdO (CdO_01) pellet, scrn, after 30 sec 3KV, 10mA ion etch	3	6/12/91 0:00:00	MRS	PURE_OX1
2759	ceo2_01	CERIUM DI-OXIDE (CeO2) POWDER PRESSED ONTO IN FOIL, 90 DEG TOA, no mesh	5	6/15/87 0:00:00	MRS	PURE_OX1
2760	co3o4_01	Co3O4 (99.995%) Aldrich lot# 01325AX, 3mm pellet, Conductive, 90 TOA	10	2/15/92 0:00:00	MRS	PURE_OX1
2761	coo_01	CoO (99+%) Aldrich lot#10029MX, 3mm pellet, Conductive, 90 TOA	9	6/2/92 0:00:00	MRS	PURE_OX1
2762	corundm1	Corundum (Al2O3 red/pink) India fresh bulk	11	6/27/94 0:00:00	MRS	PURE_OX1
2763	corundm2	Corundum (Al2O3 red/pink) India fresh bulk	1	6/29/94 0:00:00	MRS	PURE_OX1
2764	cr2o3_01	Cr2O3 (99.999%) Aldr lot# 06417HV, 3mm pellet, Semi-conductive, scrn 90 TOA	12	8/19/91 0:00:00	MRS	PURE_OX1
2765	cro3_1	CrO3 (Cr trioxide)99.9% Aldr#05227MV 90TOA mesh	8	5/24/94 0:00:00	MRS	PURE_OX1
2766	cu2o_01	Cu2O (natural "Cuprite" xtl, from Zaire, Africa) fractured in air	10	6/8/94 0:00:00	MRS	PURE_OX1
2767	cu2o_02	Cu2O (97%) dk red,3mm plt,Aldr lot#04602BW,Conduct.,90 TOA, stabilized w PbOx&SnOx	12	8/23/91 0:00:00	MRS	PURE_OX1
2768	cu2o_03	Cu2O (Rare Metallics) Powder/In FOIL,90 TOA,Conductive,no mesh,seems to be CuO	4	10/7/87 0:00:00	MRS	PURE_OX1
2769	cuo_03	CuO (99.99%) Rare Metallics Co. #70924-43, 3mm pellet, CONDUCTIVE, 90 TOA	12	9/7/91 0:00:00	MRS	PURE_OX1
2770	cuo_04	CuO (99.99%) Rare Metallics Co. #70924-43 3mm pellet, CONDUCTIVE, 90 TOA	1	9/9/91 0:00:00	MRS	PURE_OX1
2771	cuprite1	Cu2O (cuprite natl xtal, Zaire, Africa) fract bulk	10	6/8/94 0:00:00	MRS	PURE_OX1
2772	cuprite2	Cu2O (cuprite natl xtal, Zaire, Africa) fract bulk	8	6/8/94 0:00:00	MRS	PURE_OX1
2773	cuprite3	Cu2O (Cuprite,dk red natl xtl,Zaire,Africa) fract	17	6/9/94 0:00:00	MRS	PURE_OX1
2774	cuprite4	Cu2O (Cuprite,dk red natl xtl,Zaire,Africa) fract	4	6/9/94 0:00:00	MRS	PURE_OX1
2775	cuprite5	Cuprite fract bulk ion etched 20s at 2KV,10ma	6	6/9/94 0:00:00	MRS	PURE_OX1
2776	eu2o3_01	Eu2O3 STANDARD SCRAPED WITH A RAZOR BLADE (no mesh)	4	9/7/87 0:00:00	MRS	PURE_OX1
2777	eu2o3_02	Eu2O3 "STANDARD" SCRAPED WITH A RAZOR BLADE (no mesh)	2	9/7/87 0:00:00	MRS	PURE_OX1
2778	fe2o3_a	alpha-Fe2O3 (99.99+%) Rare Metallics #70924-60H Semi-Conduct., screen, 90 TOA	11	8/23/91 0:00:00	MRS	PURE_OX1
2779	fe2o3_g	gamma-Fe2O3 (95%, Mg) RMC #70924-10, 3mm pellet, CONDUCTIVE, 90 TOA	11	9/6/91 0:00:00	MRS	PURE_OX1
2780	fe3o4_01	Fe3O4 (99.9%) RMC #70924-10 CONDUCTIVE 90 TOA	12	9/11/91 0:00:00	MRS	PURE_OX1
2781	fe3o4_02	Fe3O4 (99.9%) RARE METALLIC, 90 TOA, PRESSED ON In FOIL, USED SCREEN	2	1/26/88 0:00:00	MRS	PURE_OX1
2782	fe3o4_03	Fe3O4 (99.9%) RARE METALLIC, 90 DEG TOA, PRESSED ON In FOIL, USED SCREEN	2	1/26/88 0:00:00	MRS	PURE_OX1
2783	feo_01	FeO (99.9%) Cerac lot# 60539-A-1-4, 3mm pellet, CONDUCTIVE, 90 TOA	12	1/30/92 0:00:00	MRS	PURE_OX1
2784	feo_02	FeO (99.9%) Cerac, 2min dil HF, 5min ion etch 90TO	8	6/14/94 0:00:00	MRS	PURE_OX1
2785	feo_03	FeO 99.9% Cerac lot#60539a1-4 2min dil HF 10min Ar	1	6/16/94 0:00:00	MRS	PURE_OX1
2786	ga2o3_01	Ga2O3 (99.999+%) Aldrich lot# 09325MV, 3mm pellet, screen, 90 TOA	12	8/17/91 0:00:00	MRS	PURE_OX1
2787	geo2_01	GeO2 (99.999%) Aldrich lot# 02904BW, 3mm pellet, screen, 90 TOA	11	8/13/91 0:00:00	MRS	PURE_OX1
2788	geo2_02	GeO2 (99.999%) Aldr lot# 02904BW, 3mm pellet, screen, 90 TOA	4	8/13/91 0:00:00	MRS	PURE_OX1

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
2789	hausmann	Mn3O4 (Hausmannite, S. Africa) fresh bulk	9	6/14/94 0:00:00	MRS	PURE_OX1
2790	hematit2	alpha-Fe2O3 (Hematite) Arizona,USA bulk 90 TOA	3	5/24/94 0:00:00	MRS	PURE_OX1
2791	hematite	alpha-Fe2O3 (Hematite) Arizona,USA bulk 90 TOA	8	5/24/94 0:00:00	MRS	PURE_OX1
2792	hfo2_01	HfO2 (99.9%, Zr <1%) Aldr lot# 00921JV, 3mm pellet, screen, 90 TOA	8	8/15/91 0:00:00	MRS	PURE_OX1
2793	hgo_01	HgO (99.999%) Aldrich lot# 00515TV, 3mm pellet, screen, 90 TOA	10	8/15/91 0:00:00	MRS	PURE_OX1
2794	in2o3_01	In2O3 (99.999%) Aldrich lot# 07528HY, 3mm pellet, 90 TOA, CONDUCTIVE	10	1/26/92 0:00:00	MRS	PURE_OX1
2795	iro2_01	IrO2 (99+%) Aldrich lot# 05301DV, CONDUCTIVE, Screen, 90 TOA	8	8/14/91 0:00:00	MRS	PURE_OX1
2796	la2o3_01	La2O3 (99%) Rare Metallics (on In FOIL, 35 DEG TOA, no mesh)	9	7/17/87 0:00:00	MRS	PURE_OX1
2797	mgo_01	MgO (99.99%) Aldrich lot# 00616CW, screen, 90 deg TOA	12	8/22/91 0:00:00	MRS	PURE_OX1
2798	mgo_02	MgO (99.99%) Aldrich lot# 00616CW, screen, 90 TOA	13	8/23/91 0:00:00	MRS	PURE_OX1
2799	mgo_03	MgO "single crystal" as rec'd, no mesh, at edge, 90% flood-gun current	4	3/24/93 0:00:00	MRS	PURE_OX1
2800	mgo_04	MgO "single crystal" (unknown source), screen, 90 deg TOA	7	10/28/93 0:00:00	MRS	PURE_OX1
2801	mgo_05	MgO powder/DST (PERFECT PARTS Co.) TECH. GRADE, no mesh	8	10/20/85 0:00:00	MRS	PURE_OX1
2802	mn2o3_01	Mn2O3 (?) Rare Metallics Co., screen	9	6/2/92 0:00:00	MRS	PURE_OX1
2803	mno2_01	MnO2 (99.99%) (chip) Aldrich lot# 04728PV, CONDUCTIVE, 90 TOA	11	8/21/91 0:00:00	MRS	PURE_OX1
2804	mno_01	MnO (99.9%) RMC lot# 10924-30, 3mm pellet, SemiConductive, 90 TOA	11	2/3/92 0:00:00	MRS	PURE_OX1
2805	moo2_01	MoO2 (?) Cerac, 3mm pellet, screen, Conductive, 90 TOA	9	6/2/92 0:00:00	MRS	PURE_OX1
2806	moo3_01	MoO3 (99.99%) Aldrich lot #02715CM AV, 3mm pellet, screen, 90 TOA	8	7/18/91 0:00:00	MRS	PURE_OX1
2807	moo3_02	MoO3 (99.99%) Aldrich lot# 02715CM AV, 3mm pellet, screen, 90 TOA	2	7/19/91 0:00:00	MRS	PURE_OX1
2808	nb2o5_01	Nb2O5 (99.99%) Aldrich Lot# KW 09701KW, 3mm pellet, screen, 90 TOA	7	8/13/91 0:00:00	MRS	PURE_OX1
2809	nb2o5_02	Nb2O5 (99.99%) Aldrich Lot# KW 09701KW, 3 mm pellet, screen, 90 TOA	1	8/13/91 0:00:00	MRS	PURE_OX1
2810	nbo2_01	NbO2 (99.9%) Cerac lot# 59352-A-1+2, 3mm pellet, Semi-Conductive, 90 TOA	10	2/16/92 0:00:00	MRS	PURE_OX1
2811	nbo_01	NbO (99.9%) Cerac lot# 31668-A-1-5 Chips/In, Screen, Conductive, 90 TOA	10	2/16/92 0:00:00	MRS	PURE_OX1
2812	nio_01	NiO (99.99%) Aldr lot# 00503CW, 3mm pellet, CONDUCTIVE, 90 TOA	11	8/23/91 0:00:00	MRS	PURE_OX1
2813	pb2o3_01	Pb2O3 (99.9%) RMC lot# 80310-04, 3mm pellet, screen, 90 TOA	10	2/2/92 0:00:00	MRS	PURE_OX1
2814	pb3o4_01	Pb3O4 (99%) Aldrich Lot# 07922CY, 3mm pellet, screen, 90 TOA	10	2/2/92 0:00:00	MRS	PURE_OX1
2815	pbo2_01	PbO2 (95+%) Aldrich Lot# 06811JW, 3mm pellet, CONDUCTIVE, 90 TOA	8	8/14/91 0:00:00	MRS	PURE_OX1
2816	pbo_01	PbO (99.999%) Aldrich Lot# 04911PV, 3mm pellet, Semi-Con, screen, 90 TOA	8	1/25/92 0:00:00	MRS	PURE_OX1
2817	pdo_01	PdO (99.999%) Aldrich Lot# 03219JV, 3mm pellet, Semi-Con, screen, 90 TOA	9	8/15/91 0:00:00	MRS	PURE_OX1
2818	pdo_02	PdO (99.999%) Aldrich Lot# 03219JV, 3mm pellet, Semi-Con, screen, 90 TOA	1	8/15/91 0:00:00	MRS	PURE_OX1
2819	pto2_01	PtO2-xH2O (99.99%) Aldrich Lot# 09605EV, 3mm pellet, Semi-con, 90 TOA	10	8/19/91 0:00:00	MRS	PURE_OX1
2820	re2o7_01	Re2O7 (99.9+%) Aldrich lot# 04418PV, 3mm pellet, screen, 35 DEG, air-exposed	10	8/22/91 0:00:00	MRS	PURE_OX1
2821	rh2o3_01	Rh2O3 (99.8%) Aldrich lot# 05318TW, 3mm pellet, CONDUCTIVE, screen, 90 TOA	9	8/15/91 0:00:00	MRS	PURE_OX1
2822	rtl_qrtz	TiO2-SiO2 (Rutile-Quartz) Brazil mesh, 90 TOA	10	5/24/94 0:00:00	MRS	PURE_OX1
2823	ruo2_01	RuO2 (99.9%) Aldrich lot# 06522PV, 3mm pellet, CONDUCTIVE, screen, 90 TOA	5	8/21/91 0:00:00	MRS	PURE_OX1
2824	ruo2_02	RuO2 99.9% Aldr lot# 06522PV CONDUCTIVE 90 TOA	11	8/20/91 0:00:00	MRS	PURE_OX1
2825	rutile_1	Rutile (alpha-TiO2) on Hematite (Bahia,Brazil) F?	9	6/16/94 0:00:00	MRS	PURE_OX1
2826	sapphir1	Sapphire (Al2O3) dk grn fresh bulk Sri Lanka	11	6/25/94 0:00:00	MRS	PURE_OX1
2827	sapphir2	Sapphire (Al2O3) dk grn fresh bulk Sri Lanka	1	6/28/94 0:00:00	MRS	PURE_OX1
2828	sb2o3_01	Sb2O3 (99.999%) Aldrich Lot# 06924HV, 3mm pellet, Screen, 90 TOA	33	5/28/91 0:00:00	MRS	PURE_OX1
2829	sb2o5_1	Sb2O5 99.995% Aldr# 02413JW 3mm plt mesh 90 TOA	7	5/25/94 0:00:00	MRS	PURE_OX1

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
2830	sc2o3_01	Sc2O3 (99.99%) Aldrich lot# 06010BT, 3mm pellet, screen, 90 TOA	10	8/14/91 0:00:00	MRS	PURE_OX1
2831	sio2_01	(-) SiO2 (10x10x2 mm, polished, from Brazil, screen, 90 TOA, as rec'd)	12	8/21/91 0:00:00	MRS	PURE_OX1
2832	sio2_02	(-) SiO2 FRESHLY EXPOSED BULK (from Brazil, 35 DEG TOA, with mesh)	4	10/14/87 0:00:00	MRS	PURE_OX1
2833	sio2_03	(-) SiO2 (FROM BRAZIL, ROUGH CUT, UNPOLISHED Surface, with MESH)	4	10/13/87 0:00:00	MRS	PURE_OX1
2834	sio2_04	(+?) SiO2, NATURAL CRYSTAL (from USA, TRANSPARENT, Clear, 65 TOA, mesh, as rec'd)	4	10/13/87 0:00:00	MRS	PURE_OX1
2835	sio_1	SiO 1:1 RMC 99.99% lot 70924-70 8min 3KV no mesh	7	5/17/94 0:00:00	MRS	PURE_OX1
2836	sno2_01	SnO2 (99.995+%) Aldrich Lot# 05903PV, 3mm pellet, screen, 90 TOA	5	7/18/91 0:00:00	MRS	PURE_OX1
2837	sno_01	SnO (99+%) Aldrich Lot# 14613HW, 3mm pellet, CONDUCTIVE, screen, 90 TOA	10	9/9/91 0:00:00	MRS	PURE_OX1
2838	sro_01	SrO (99.5%) RMC #71208-30, 3mm pellet, screen, 90 TOA	10	1/27/92 0:00:00	MRS	PURE_OX1
2839	ta2o5_01	Ta2O5 (99.99%) Aldrich lot# 09322CV, 3mm pellet, screen, 90 deg TOA	11	8/22/91 0:00:00	MRS	PURE_OX1
2840	teo2_01	TeO2 (99.995%) Aldrich lot# 07812JV, 3mm pellet, screen, 90 TOA	10	8/22/91 0:00:00	MRS	PURE_OX1
2841	test	Cr2O3 (99.999%) Aldr lot# 06417HV, 3mm pellet, Sem	1	8/19/91 0:00:00	MRS	PURE_OX1
2842	ti2o3_01	Ti2O3 (99.9%) RMC lot# 10920-30T, 3mm pellet, Conductive, black, 90 TOA	13	1/31/92 0:00:00	MRS	PURE_OX1
2843	tio2_01	TiO2 (99.999%) Aldrich lot# 06306MV, 3mm pellet, Semi-conductive, 90 TOA	13	8/18/91 0:00:00	MRS	PURE_OX1
2844	tio2_02	TiO2 POWDER/DST (35 TOA, no mesh)	4	1/29/88 0:00:00	MRS	PURE_OX1
2845	tio_01	TiO (99.9%) RMC lot# 10920-30, 3mm pellet, Semi-Conductive, gray, 90 TOA	13	1/31/92 0:00:00	MRS	PURE_OX1
2846	tl2o3_01	Tl2O3 (99.99%) Aldrich Lot# 06128MV, 3mm pellet, CONDUCTIVE, 90 TOA	6	8/14/91 0:00:00	MRS	PURE_OX1
2847	tl2o3_02	Tl2O3 99.99% Aldr lot# 06128MV scrn 90 TOA	8	8/14/91 0:00:00	MRS	PURE_OX1
2848	v2o3_1	V2O3 (99%) Aldr#04304DP 3mm plt mesh 90 TOA conduc	8	5/24/94 0:00:00	MRS	PURE_OX1
2849	v2o5_01	V2O5 (99.99%) Aldrich Lot# 02330EW, 3mm pellet, CONDUCTIVE, 90 TOA	9	8/13/91 0:00:00	MRS	PURE_OX1
2850	vo2_1	VO2 99.9% Aldr# 05310AY 3mm plt conduc mesh 90 TOA	8	5/25/94 0:00:00	MRS	PURE_OX1
2851	wo3_01	WO3 (99.995%) Aldrich Lot# 00107KM JV, 3mm pellet, screen, 90 TOA	5	7/18/91 0:00:00	MRS	PURE_OX1
2852	y2o3_01	Y2O3 (99.9%) RMC #71208-13 (exposed to air), screen, 90 TOA	10	8/19/91 0:00:00	MRS	PURE_OX1
2853	zno_01	ZnO (99.999%) Aldrich Lot# HW 04629KV, 3mm pellet, screen, 90 TOA	9	8/13/91 0:00:00	MRS	PURE_OX1
2854	zno_02	ZnO (as rec'd) SSI screen, 90 deg TOA	7	12/3/92 0:00:00	MRS	PURE_OX1
2855	zro2_01	ZrO2 (99.9%, HfO2 <100ppm) Aldrich lot# 02310BV, 3mm pellet, screen, 90 TOA	9	8/15/91 0:00:00	MRS	PURE_OX1
2856	ag2o_02	Ag2O (99.99%) Aldrich Lot# 00105CV (3mm pellet, screen, 35 TOA)	2	3/25/94 0:00:00	MRS	PURE_OX2
2857	bi2o3_03	Bi2O3 pellet 99.999% Aldr Lot# 04124HV scrn	1	11/4/93 0:00:00	MRS	PURE_OX2
2858	BI2O3_04	Bi2O3 pellet 99.999% Aldr Lot# 04124HV scrn	1	3/25/94 0:00:00	MRS	PURE_OX2
2859	CDO_01A	CdO (99.99+%) Aldrich lot #0138EV 3mm plt 35 TOA screen	1	3/25/94 0:00:00	MRS	PURE_OX2
2860	cdo_04	CdO (99.99+%) Aldrich lot #0138EV 3mm plt 35 TOA screen	2	3/25/94 0:00:00	MRS	PURE_OX2
2861	cu2o_03	Cu2O 97% (dark red) Aldr lot# 04602BW conduct	2	3/24/94 0:00:00	MRS	PURE_OX2
2862	cuoh2_02	Cu(OH)2 (tech) Aldr lot# 11715EW scrn 90 TOA	2	3/24/94 0:00:00	MRS	PURE_OX2
2863	fe2o3a03	alpha-Fe2O3 99.99% RMC #70924-60H semi-con scrn 90	2	4/27/94 0:00:00	MRS	PURE_OX2
2864	fe2o3g03	gamma-Fe2O3 95% (Mg?) RMC #70924-10 conduct 90	2	3/24/94 0:00:00	MRS	PURE_OX2
2865	fe3o4_04	Fe3O4 (99.9%) RMC #70924-10 conductive 90 TOA	2	3/24/94 0:00:00	MRS	PURE_OX2
2866	feooh_02	alpha-FeOOH 99.999% RMC #70924-01 scrn 90 TOA	2	3/24/94 0:00:00	MRS	PURE_OX2
2867	ga2o3_02	Ga2O3 99.999+% Aldr lot# 09325MV scrn 90 TOA	1	1/25/94 0:00:00	MRS	PURE_OX2
2868	geo2_03	GeO2 99.999% Aldr lot# 02904BW scrn 90 TOA	1	1/25/94 0:00:00	MRS	PURE_OX2
2869	hfo2_02	HfO2 99.9% (Zr <1%) Aldr lot# 00921JV scrn 90 TOA	1	1/25/94 0:00:00	MRS	PURE_OX2
2870	iro2_02	IrO2 ( %) Aldr lot# 05301DV CONDUCTIVE 90 TOA	2	4/28/94 0:00:00	MRS	PURE_OX2



Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
2871	moo3_03	MoO3 99.99% Aldr lot# 02715CM scrn 90 TOA	2	4/27/94 0:00:00	MRS	PURE_OX2
2872	nb2o5_03	Nb2O5 99.99% Aldr Lot# 09701KW scrn 90 TOA	2	4/28/94 0:00:00	MRS	PURE_OX2
2873	nio_02	NiO 99.99% Aldr lot# 00503CW CONDUCTIVE 90 TOA	2	4/28/94 0:00:00	MRS	PURE_OX2
2874	pbo2_03	PbO2 95+% Aldr lot# 06811JW CONDUCTIVE 90 TOA	2	4/28/94 0:00:00	MRS	PURE_OX2
2875	pdo_03	PdO 99.999% Aldr lot# 03219JV Semi-con scrn 90	2	4/28/94 0:00:00	MRS	PURE_OX2
2876	pto2_02	PtO2-nH2O (99.99%) Aldr lot# 09605EV Semi-con 90 TOA	2	4/21/94 0:00:00	MRS	PURE_OX2
2877	rh2o3_02	Rh2O3 99.8% Aldr lot# 05318TW CONDUCTIVE 90 TOA	2	4/20/94 0:00:00	MRS	PURE_OX2
2878	ruo2_03	RuO2 99.9% Aldr lot# 06522PV CONDUCTIVE 90 TOA	2	4/21/94 0:00:00	MRS	PURE_OX2
2879	sc2o3_02	Sc2O3 99.99% Aldr lot# 06010BT scrn 90 TOA	2	4/20/94 0:00:00	MRS	PURE_OX2
2880	sno_02	SnO (99+%) Aldr lot# 14613HW CONDUCTIVE 90 TOA	2	4/20/94 0:00:00	MRS	PURE_OX2
2881	tio2_03	TiO2 99.999% aLDR LOT# 06306mv Semi-con 90 TOA	2	4/20/94 0:00:00	MRS	PURE_OX2
2882	v2o5_02	V2O5 99.99% Aldr lot# 02330EW Semi-con 90 TOA	2	4/20/94 0:00:00	MRS	PURE_OX2
2883	wo3_02	WO3 99.995% 3mm plt Aldr 00107KM 90 TOA scrn	2	3/25/94 0:00:00	MRS	PURE_OX2
2884	y2o3_02	Y2O3 99.9% RMC #71208-13 (exposed to air) scrn	2	4/21/94 0:00:00	MRS	PURE_OX2
2885	zno_01	ZnO (99.999%) Aldrich Lot# HW 04629KV, 3mm pellet, screen, 90 TOA	9	8/13/91 0:00:00	MRS	PURE_OX2
2886	zno_03	ZnO 99.999% (Aldr lot# HW 04629KV) scrn 90 TOA	2	3/25/94 0:00:00	MRS	PURE_OX2
2887	ZRO2_02	ZrO2 99.9% (HfO2 <100ppm) Aldr lot# 02310BV scrn	1	3/25/94 0:00:00	MRS	PURE_OX2
2888	ceo2	CeO2 RMC 3mm plt 90 TOA #70202-13	8	5/18/94 0:00:00	MRS	RARE_OX
2889	dy2o3	Dy2O3 99.99% Aldr lot#02803KV 3mm plt 90TOA mesh	8	5/22/94 0:00:00	MRS	RARE_OX
2890	er2o3_1	Er2O3 99.99% Aldrich#02413KV 3mm plt mesh 90 TOA	7	5/19/94 0:00:00	MRS	RARE_OX
2891	er2o3_2	Er2O3 99.99% Aldr lot#02413KV 3mm plt 90TOA mesh	7	5/21/94 0:00:00	MRS	RARE_OX
2892	eu2o3_1	Eu2O3 99.95% Aldr lot#02914LV 3mm plt 90TOA mesh	8	5/21/94 0:00:00	MRS	RARE_OX
2893	gd2o3_1	Gd2O3 (Aldrich) 90 TOA,3mm plt, ms	8	5/19/94 0:00:00	MRS	RARE_OX
2894	gd2o3_2	Gd2O3 99.9% Aldr lot#04005LX 3mm plt 90TOA mesh	2	5/21/94 0:00:00	MRS	RARE_OX
2895	ho2o3	Ho2O3 99.999% Aldrich 07918TX 3mm plt mesh 90 TOA	7	5/19/94 0:00:00	MRS	RARE_OX
2896	lu2o3	Lu2O3 99.99% Aldr lot#003208AV 3mm plt 90TOA mesh	6	5/22/94 0:00:00	MRS	RARE_OX
2897	pr2o5	Pr(III,IV)oxide 99.999% Aldrich#09826LX 90TOA plt	8	5/19/94 0:00:00	MRS	RARE_OX
2898	sm2o3	Sm2O3 RMC 3mm plt mesh 90 TOA #70202-13	8	5/19/94 0:00:00	MRS	RARE_OX
2899	tb3o7	Tb3O7 (brown,gift) 3mm plt 90 TOA mesh	1	5/19/94 0:00:00	MRS	RARE_OX
2900	tb3o7_1	Tb3O7 (brown lump) 3mm plt 90 TOA mesh	8	5/19/94 0:00:00	MRS	RARE_OX
2901	tb3o7_2	Tb3O7 99% (gift) 3mm plt 90TOA mesh	3	5/21/94 0:00:00	MRS	RARE_OX
2902	tm2o3	Tm2O3 99% RMC lot# 70202-13 3mm plt 90TOA mesh	7	5/21/94 0:00:00	MRS	RARE_OX
2903	yb2o3	Yb2O3 99.99% Aldr lot#05719PM 3mm plt 90TOA mesh	6	5/21/94 0:00:00	MRS	RARE_OX
2904	al_reox3	High Purity Aluminum Drop, Bulk Exposed 3 Years Ago Heated In Air On Hotplate To >100 C For 1 Hr (90 Deg Toa)	3	10/17/91 0:00:00	MRS	RE-OXID
2905	al_reox4	High Purity Aluminum Drop, Freshly Exposed Today (cutting) Heated in Air on Hotplate to >100 C for 1 Hr (90 deg TOA)	3	10/17/91 0:00:00	MRS	RE-OXID
2906	al_reox5	High Purity Aluminum Drop, Freshly Exposed Today (cutting) Heated in Air on Hotplate to >100 C for 3 Hr (90 deg TOA)	3	10/18/91 0:00:00	MRS	RE-OXID
2907	al_reox6	High Purity Aluminum Drop, Bulk Exposed 3 years Ago Heated in Air on Hotplate to >100 C for 2 Hr (90 deg TOA)	3	10/18/91 0:00:00	MRS	RE-OXID
2908	y_reoxid	STUDY OF YTTRIUM (Y) OXIDATION IN UHV (ION ETCHED: 20 MIN AT 4 KeV, THEN ANALYSED)	2	7/13/87 0:00:00	DPR	RE-OXID
2909	ag_3d_hq	Silver: Ag (3d5) & Ag (3d3), BE Cu(2p3)= 932.67eV 0.05 eV/step, Sum of 15 repetitive etch/scans	1	2/28/94 0:00:00	MRS	REF_BE_1
2910	ag_vb_hq	Silver (Ag): Valence Bands, 0.05 eV/step Sum of 10 repetitive scan/etch cycles	1	2/28/94 0:00:00	MRS	REF_BE_1
2911	ag_ws_hq	Silver (Ag), 0.7 eV/step Sum of 15 individual spectra from repetitive etch	1	3/1/94 0:00:00	MRS	REF_BE_1

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
2912	al_2p_hq	Aluminium: Al(2p3) & Al(2p1), BE Cu(2p3)=932.64eV 0.05 eV/step, Sum of 11 repetitive etch/scans	1	3/2/94 0:00:00	MRS	REF_BE_1
2913	al_vb_hq	Aluminium (Al): Valence Bands, 0.05 eV/step	1	3/3/94 0:00:00	MRS	REF_BE_1
2914	al_ws_hq	Aluminium (Al): 0.5 eV/step, 90 deg TOA Sum of 10 spectra from repetitive etch/scans	1	3/3/94 0:00:00	MRS	REF_BE_1
2915	AR_2P_01	Argon Ions/Natural Graphite Crystal (90 TOA)	1	1/12/93 0:00:00	MRS	REF_BE_1
2916	AR_2P_02	Argon Ions/Natural Graphite Crystal (90 TOA)	1	1/12/93 0:00:00	MRS	REF_BE_1
2917	AR_2S	Argon Ions/Natural Graphite Crystal (90 TOA)	1	1/12/93 0:00:00	MRS	REF_BE_1
2918	AR_C1S	Argon Ions/Natural Graphite Crystal (90 TOA)	1	1/12/93 0:00:00	MRS	REF_BE_1
2919	AR_VB	Argon Ions/Natural Graphite Crystal (90 TOA)	1	1/12/93 0:00:00	MRS	REF_BE_1
2920	AR_WS	Argon Ions/Natural Graphite Crystal (90 TOA)	1	1/12/93 0:00:00	MRS	REF_BE_1
2921	as_3d_hq	Arsenic: As (3d5) & As (3d3), BE Cu(2p3)= 932.67eV Ion gun AOI was ca. 70 deg	1	3/9/94 0:00:00	MRS	REF_BE_1
2922	as_vb_hq	Arsenic (As): Valenc Bands, 0.05 eV/step Ion gun AOI was ca. 70 deg	1	3/9/94 0:00:00	MRS	REF_BE_1
2923	as_ws_hq	Arsenic (As): 0.70 eV/step =70 deg TOA, Repeated ion etched between scans"	1	3/10/94 0:00:00	MRS	REF_BE_1
2924	au_4f_hq	Gold: Au(4f7) & Au(4f5), Cu(2p3) BE= 932.65eV 0.05 eV/step, 90 deg TOA, 15 repetitive etch/scans	1	2/24/94 0:00:00	MRS	REF_BE_1
2925	au_vb_hq	Gold (Au) on Mylar: Valence Bands, 0.05 eV/step	1	7/28/86 0:00:00	MRS	REF_BE_1
2926	au_vb_lo	Gold (Au): Valence Bands, low res, 0.10 eV/step	1	2/25/94 0:00:00	MRS	REF_BE_1
2927	au_ws_hq	Gold (Au): 0.7 eV/step, 90 deg TOA Sum of 15 repetitive etch/scans	1	2/25/94 0:00:00	MRS	REF_BE_1
2928	be_1s_hq	Beryllium: BE (1s), BE of Cu(2p3) = 932.65 eV 0.05 eV/step, Sum of 15 repetitive etch/scans	1	3/4/94 0:00:00	MRS	REF_BE_1
2929	be_vb_hq	Beryllium: Be(1s), BE Cu(2p3) = 932.65 eV 0.05 eV/step, sum of 14 etch/scans	1	3/4/94 0:00:00	MRS	REF_BE_1
2930	be_ws_hq	Beryllium (Be): 0.70 eV/step	1	3/7/94 0:00:00	MRS	REF_BE_1
2931	bi_4f_hq	Bismuth: Bi (4f7) & Bi (4f5), BE Cu(2p3)= 932.74eV Ion gun AOI was ca. 70 deg	1	3/7/94 0:00:00	MRS	REF_BE_1
2932	bi_vb_hq	Bismuth (Bi): Valence Bands, 0.05 eV/step	1	3/7/94 0:00:00	MRS	REF_BE_1
2933	bi_ws_hq	Bismuth (Bi): 0.70 eV/step Ion gun AOI was ca. 70 deg	1	3/7/94 0:00:00	MRS	REF_BE_1
2934	b_1s_hq	Boron: B (1s) signal, BE Cu(2p3) = 932.69 eV 0.05 eV/step, Sum of 15 etch/scans	1	2/24/94 0:00:00	MRS	REF_BE_1
2935	b_vb_hq	Boron: B(1s), BE Cu(2p3) = 932.67 eV 0.10 eV/step, 90 deg TOA, sum of 15 etch/scans	1	2/24/94 0:00:00	MRS	REF_BE_1
2936	b_ws_hq	Boron (B) after B_ns.dpr 90 TOA	1	2/24/94 0:00:00	MRS	REF_BE_1
2937	cd_3d_hq	5admium: Cd(3d5) & Cd(3d3), BE Cu(2p3)= 932.65 eV 0.05 eV/step, Sum or 15 repetitive etch/scans	1	2/13/94 0:00:00	MRS	REF_BE_1
2938	cd_vb_hq	Cadmium: Valence Band data, 0.20 eV/step Sum of 10 repetitive etch/scans	1	2/13/94 0:00:00	MRS	REF_BE_1
2939	cd_ws_hq	Cadmium (Cd) 90 TOA, Scraped, 3KV etch >30 min	1	2/14/94 0:00:00	MRS	REF_BE_1
2940	co_2p_hq	Cobalt: Co(2p3) & Co(2p1), BE Cu(2p3)= 932.74 eV 0.05 eV/step, Sum of 15 repetitive etch/scans	1	2/8/94 0:00:00	MRS	REF_BE_1
2941	co_vb_hq	Cobalt (Co): Valence Band data, 0.20 eV/step Sum of 15 repetitive etch/scans	1	2/8/94 0:00:00	MRS	REF_BE_1
2942	co_vb_lo	Cobalt (Co): Low Resolution Valence Band data	1	2/9/94 0:00:00	MRS	REF_BE_1
2943	co_ws_hq	Cobalt (Co): 0.70 eV/step, 90 deg TOA Sum of 10 repetitive etch/scans	1	2/9/94 0:00:00	MRS	REF_BE_1
2944	cr_2p_hq	Chromium: Cr(2p3) & Cr(2p1), BE Cu(2p3)= 932.69 eV 0.05 eV/step, Sum of 15 repetitive etch/scans	1	2/10/94 0:00:00	MRS	REF_BE_1
2945	cr_vb_hq	Chromium (Cr): Valence Band data, 0.20 eV/step Sum of 15 repetitive etch/scan cycles	1	2/10/94 0:00:00	MRS	REF_BE_1
2946	cr_vb_lo	Chromium (Cr) 90 TOA, Scraped, 3KV etch >3min 0.20 eV/step, Low Resolution Valence Band data	1	2/11/94 0:00:00	MRS	REF_BE_1
2947	cr_ws_hq	Chromium (Cr): 0.70 eV/step Sum of 20 repetitive etch/scans	1	2/11/94 0:00:00	MRS	REF_BE_1
2948	cu_2p_hq	Copper: Cu(2p3) & Cu(2p1), BE Cu(2p3) = 932.62 eV 0.05 eV/step, Sum of 15 repetitive etch/scans	1	2/16/94 0:00:00	MRS	REF_BE_1
2949	cu_vb_hq	Copper (Cu): 0.10 eV/step, Valence Band data Sum of 13 repetitive etch/scans	1	2/16/94 0:00:00	MRS	REF_BE_1
2950	cu_vb_lo	Copper (Cu) scraped & etched more than 2 hours 90 0.10 eV/step, Low Resolution Valence Band data	1	2/16/94 0:00:00	MRS	REF_BE_1
2951	cu_ws_hq	Copper (Cu): 0.70 eV/step Sum of 15 repetitive etch/scans	1	2/16/94 0:00:00	MRS	REF_BE_1
2952	c_1s_hq	Carbon (amorphous): C (1s), BE Cu (2p3)= 932.63 eV Ion gun AOI was ca. 70 deg	1	3/13/94 0:00:00	MRS	REF_BE_1

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
2953	c_vb_hq	Carbon (amorphous): Valence Bands, 0.05 eV/step Ion gun AOI was ca. 70 deg	1	3/13/94 0:00:00	MRS	REF_BE_1
2954	c_ws_hq	Carbon (C) [amorphous]: 0.70 eV/step 70 deg TOA, Repeated ion etched between scans	1	3/13/94 0:00:00	MRS	REF_BE_1
2955	dy_4d_hq	Dysprosium: Dy (4d5) & (4d3), BE Cu(2p3)= 932.63eV	1	3/23/94 0:00:00	MRS	REF_BE_1
2956	dy_vb_hq	Dysprosium (Dy): Valence Bands, 0.10 eV/step	1	3/23/94 0:00:00	MRS	REF_BE_1
2957	dy_ws_hq	Dysprosium (Dy): 0.70 eV/step	1	3/23/94 0:00:00	MRS	REF_BE_1
2958	er_4d_hq	Erbium: Er (4d5) & (4d3), BE Cu(2p3)= 932.68 eV	1	3/18/94 0:00:00	MRS	REF_BE_1
2959	er_vb_hq	Erbium (Er): Valence Bands, 0.05 eV/step	1	3/18/94 0:00:00	MRS	REF_BE_1
2960	er_ws_hq	Erbium (Er): 0.70 eV/step	1	3/19/94 0:00:00	MRS	REF_BE_1
2961	fe_2p_hq	Iron (Fe): Fe(2p3) & Fe(2p1), BE Cu(2p3)= 932.65eV 0.05 eV/step, Sum of 20 repetitive etch/scans	1	2/9/94 0:00:00	MRS	REF_BE_1
2962	fe_2p_lo	Iron: Fe(2p3); Fe(2p1), BE Cu(2p3) = 932.71 eV 0.05 eV/step, 90 deg TOA, ion etched >30 min	1	2/9/94 0:00:00	MRS	REF_BE_1
2963	fe_vb_hq	Iron (Fe): Valence Band data, 0.2 eV/step Sum of 20 repetitive etch/scans	1	2/9/94 0:00:00	MRS	REF_BE_1
2964	fe_vb_lo	Iron (Fe): Low Resolution Valence Band data 0.20 eV/step	1	2/10/94 0:00:00	MRS	REF_BE_1
2965	fe_ws_hq	Iron (Fe): 0.70 eV/step, 90 deg TOA Sum of 15 repetitive etch/scans	1	2/10/94 0:00:00	MRS	REF_BE_1
2966	gd_4d_hq	Gadolinium: Gd(4d5) & (4d3), BE Cu(2p3)= 932.68 eV	1	3/15/94 0:00:00	MRS	REF_BE_1
2967	gd_vb_hq	Gadolinium (Gd): Valence Bands, 0.05 eV/step	1	3/15/94 0:00:00	MRS	REF_BE_1
2968	gd_ws_hq	Gadolinium (Gd): 0.70 eV/step	1	3/16/94 0:00:00	MRS	REF_BE_1
2969	ge_3d_hq	Germanium: Ge(3d5) & Ge(3d3), BE Cu(2p3)= 932.69 eV 0.05 eV/step, Sum of 20 repetitive etch/scans	1	2/23/94 0:00:00	MRS	REF_BE_1
2970	ge_vb_hq	Germanium (Ge): Valence Band data, 0.20 eV/step	1	2/23/94 0:00:00	MRS	REF_BE_1
2971	ge_ws_hq	Germanium (Ge): 0.70 eV/step 90 deg TOA	1	2/24/94 0:00:00	MRS	REF_BE_1
2972	hf_4f_hq	Hafnium: Hf (4f7) & Hf (4f5), BE Cu(2p3)=932.67 eV	1	3/9/94 0:00:00	MRS	REF_BE_1
2973	hf_vb_hq	Hafnium (Hf): Valence Bands, 0.05 eV/step	1	3/9/94 0:00:00	MRS	REF_BE_1
2974	hf_ws_hq	Hafnium (Hf): 0.70 eV/step	1	3/9/94 0:00:00	MRS	REF_BE_1
2975	ho_4d_hq	Holmium: Ho (4d5) & (4d3), BE Cu(2p3)= 932.68 eV	1	3/22/94 0:00:00	MRS	REF_BE_1
2976	ho_ws_hq	Holmium (Ho): 0.70 eV/step	1	3/22/94 0:00:00	MRS	REF_BE_1
2977	in_3d_hq	Indium: In(3d5) & In(3d3), BE Cu(2p3)= 932.66eV 0.05 eV/step, Sum of 15 repetitive etch/scans	1	2/26/94 0:00:00	MRS	REF_BE_1
2978	in_vb_hq	Indium (In) not scraped, etched > 50 min 90 TOA	1	2/26/94 0:00:00	MRS	REF_BE_1
2979	in_ws_hq	Indium (In): 0.70 eV/step, 90 deg TOA Sum of 15 repetitive etch/scans	1	2/26/94 0:00:00	MRS	REF_BE_1
2980	ir_4f_hq	Iridium: Ir(4f7) & Ir(4f5), BE Cu(2p3)= 932.61 eV 0.05 eV/step, Filed & etched 5 min, 90 deg TOA	1	3/3/94 0:00:00	MRS	REF_BE_1
2981	ir_vb_hq	Iridium (Ir): Valence Band data, 0.05 eV/step Sum of 15 repetitive etch/scans	1	3/3/94 0:00:00	MRS	REF_BE_1
2982	ir_ws_hq	Iridium (Ir): 0.70 eV/step, filed & etched 5 min,	1	3/3/94 0:00:00	MRS	REF_BE_1
2983	kr_3d_hq	Krypton (Kr) implanted in graphite, 10 min etch 0.05 eV/step	1	3/10/94 0:00:00	MRS	REF_BE_1
2984	kr_ws_hq	=Krypton (Kr) implanted in graphite, 10 min etch" 1 eV/step, 90 deg TOA	1	3/10/94 0:00:00	MRS	REF_BE_1
2985	lu_4f_hq	Lutetium: Lu (4f7) & (4f5), BE Cu (2p3)=932.68 eV	1	3/14/94 0:00:00	MRS	REF_BE_1
2986	lu_vb_hq	Lutetium (Lu): Valence Bands, 0.05 eV/step	1	1/27/94 0:00:00	MRS	REF_BE_1
2987	lu_ws_hq	Lutetium (Lu): 0.70 eV/step	1	3/15/94 0:00:00	MRS	REF_BE_1
2988	mg_2p_hq	Magnesium: Mg(2p), BE Cu(2p3) = 932.66 eV 0.05 eV/step, Sum of 15 repetitive etch/scans	1	2/27/94 0:00:00	MRS	REF_BE_1
2989	mg_vb_hq	Magnesium (Mg): Valence Band data, 0.10 eV/step Scraped/etched > 70min, 90 TOA	1	2/27/94 0:00:00	MRS	REF_BE_1
2990	mg_ws_hq	Magnesium (Mg): 0.70 eV/step Sum of 10 repetitive etch/scans, after 70 min etch	1	2/27/94 0:00:00	MRS	REF_BE_1
2991	mn_2p_hq	Manganese: Mn(2p3) & Mn(2p1), BE Cu(2p3)= 932.69eV 0.05 eV/step, Sum of 15 repetitive etch/scans	1	2/20/94 0:00:00	MRS	REF_BE_1
2992	mn_vb_hq	Manganese (Mn): Valence Band data 0.10 eV/step, scraped and etched > 60 min	1	2/20/94 0:00:00	MRS	REF_BE_1
2993	mn_ws_hq	Manganese (Mn): 0.70 eV/step, 90 deg TOA Sum of 15 repetitive etch/scans	1	2/20/94 0:00:00	MRS	REF_BE_1

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
2994	mo_3d_hq	Molybdenum: Mo(3d5) & Mo(3d3), BE Cu(2p3)=932.71eV 0.05 eV/step, Sum of 15 repetitive etch/scans	1	2/16/94 0:00:00	MRS	REF_BE_1
2995	mo_vb_hq	Molybdenum (Mo): Valence Band data, 0.10 eV/step Sum of 15 repetitive etch/scans	1	2/16/94 0:00:00	MRS	REF_BE_1
2996	mo_vb_lo	Molybdenum (Mo) scraped&etched more than 30 min Low Resolution Valence Band data	1	2/17/94 0:00:00	MRS	REF_BE_1
2997	mo_ws_hq	Molybdenum (Mo): 0.70 eV/step, 90 deg TOA Sum of 15 repetitive etch/scans	1	2/17/94 0:00:00	MRS	REF_BE_1
2998	nb_3d_hq	Niobium: Nb(3d5) & Nb(3d3), BE Cu(2p3)= 932.69 eV 0.05 eV/step, Sum of 18 repetitive etch/scans	1	2/19/94 0:00:00	MRS	REF_BE_1
2999	nb_vb_hq	Niobium (Nb): Valence Band data, 0.10 eV/step Sum of 15 repetitive etch/scans	1	1/27/94 0:00:00	MRS	REF_BE_1
3000	nb_vb_lo	Niobium (Nb): scraped & pre-etched >60 min 90 TOA Lower Resolution Valence Band data (oxide contam)	1	2/20/94 0:00:00	MRS	REF_BE_1
3001	nb_ws_hq	Niobium (Nb): 0.70 eV/step, 90 deg TOA Sum of 15 repetitive etch/scans	1	2/19/94 0:00:00	MRS	REF_BE_1
3002	ni_2p_hq	Nickel: Ni(2p3) & Ni(2p1), BE Cu(2p3) = 932.65 eV 0.05 eV/step, Sum of 15 repetitive etch/scans	1	2/14/94 0:00:00	MRS	REF_BE_1
3003	ni_2p_sq	Nickel: Ni(2p3) & Ni(2p1), BE Cu(2p3) = 932.68 eV 0.05 eV/step, Sum of 15 repetitive etch/scans	1	1/27/94 0:00:00	MRS	REF_BE_1
3004	ni_vb_hq	Nickel Ni): Valence Band data, 0.10 eV/step Sum of 15 repetitive etch/scans, 90 deg TOA	1	2/14/94 0:00:00	MRS	REF_BE_1
3005	ni_vb_lo	Nickel (Ni): Low Resolution Valence Band data 0.20 eV/step, scraped & etched more than 30 min	1	2/16/94 0:00:00	MRS	REF_BE_1
3006	ni_ws_hq	Nickel (Ni): 0.70 eV/step, 90 deg TOA Sum of 10 repetitive etch/scans	1	2/15/94 0:00:00	MRS	REF_BE_1
3007	pb_4f_hq	Lead (Pb): Pb (4f7) & Pb (4f5),BE Cu(2p3)=932.66eV	1	2/25/94 0:00:00	MRS	REF_BE_1
3008	pb_vb_hq	Lead (Pb): Valence Band data, 0.10 eV/step	1	2/26/94 0:00:00	MRS	REF_BE_1
3009	pb_ws_hq	Lead (Pb): 0.70 eV/step	1	2/25/94 0:00:00	MRS	REF_BE_1
3010	pd_3d_hq	Palladium: Pd (3d5) & Pd (3d3),BE Cu(2p3)=932.69eV	1	2/10/94 0:00:00	MRS	REF_BE_1
3011	pd_vb_hq	Palladium (Pd): Valence Bands, 0.20 eV/step	1	2/10/94 0:00:00	MRS	REF_BE_1
3012	pd_ws_hq	Palladium (Pd): 0.70 eV/step	1	2/10/94 0:00:00	MRS	REF_BE_1
3013	pt_4f_hq	Platinum: Pt (4f7) & Pt (4f5), BE Cu(2p3)=932.70eV	1	2/17/94 0:00:00	MRS	REF_BE_1
3014	pt_vb_hq	Platinum (Pt): Valenc Bands, 0.10 eV/step	1	2/17/94 0:00:00	MRS	REF_BE_1
3015	pt_vb_lo	Platinum (Pt): Valence Band, Low Res, 0.1eV/step	1	2/18/94 0:00:00	MRS	REF_BE_1
3016	pt_ws_hq	Platinum (Pt): 0.70 eV/step	1	2/18/94 0:00:00	MRS	REF_BE_1
3017	re_4f_hq	Rhenium: Re (4f7) & Re (4f5), BE Cu(2p3)=932.69eV	1	2/21/94 0:00:00	MRS	REF_BE_1
3018	re_vb_hq	Rhenium (Re): Valence Bands, 0.10 eV/step	1	2/21/94 0:00:00	MRS	REF_BE_1
3019	re_ws_hq	Rhenium (Re): 0.7 eV/step	1	2/21/94 0:00:00	MRS	REF_BE_1
3020	rh_3d_hq	Rhodium: Rh (3d5) & Rh (3d3), BE Cu(2p3)=932.64 eV	1	3/1/94 0:00:00	MRS	REF_BE_1
3021	rh_vb_hq	Rhodium (Rh): Valence Bands, 0.1 eV/step	1	3/1/94 0:00:00	MRS	REF_BE_1
3022	rh_ws_hq	Rhodium (Rh): 0.70 eV/step	1	3/1/94 0:00:00	MRS	REF_BE_1
3023	ru_3d_hq	Ruthenium: Ru (3d5) & Ru (3d3), BE Cu(2p3)= 932.69	1	1/27/94 0:00:00	MRS	REF_BE_1
3024	ru_vb_hq	Ruthenium (Ru): Valence Bands, 0.20 eV/step 70 deg TOA	1	1/28/94 0:00:00	MRS	REF_BE_1
3025	ru_ws_hq	Ruthenium (Ru): 0.70 eV/step	1	1/27/94 0:00:00	MRS	REF_BE_1
3026	sb_3d_hq	Antimony: Sb (3d5) & Sb (3d3), BE Cu(2p3)=932.63eV	1	3/12/94 0:00:00	MRS	REF_BE_1
3027	sb_vb_hq	Antimony (Sb): Valence Bands, 0.05 eV/step	1	3/13/94 0:00:00	MRS	REF_BE_1
3028	sb_ws_hq	Antimony (Sb): 0.70 eV/step	1	3/13/94 0:00:00	MRS	REF_BE_1
3029	sc_2p_hq	Scandium: Sc (2p3) & Sc (2p1), BE Cu(2p3)=932.63eV	1	3/13/94 0:00:00	MRS	REF_BE_1
3030	sc_vb_hq	Scandium (Sc): Valence Bands, 0.05 eV/step	1	3/13/94 0:00:00	MRS	REF_BE_1
3031	sc_ws_hq	Scandium (Sc): 0.70 eV/step	1	3/14/94 0:00:00	MRS	REF_BE_1
3032	se_3d_hq	Selenium: Se (3d5) & Se (3d3), BE Cu(2p3)=932.66eV	1	3/7/94 0:00:00	MRS	REF_BE_1
3033	se_vb_hq	Selenium (Se): Valence Bands, 0.05 eV/step	1	3/7/94 0:00:00	MRS	REF_BE_1
3034	se_ws_hq	Selenium (Se): 0.70 eV/step	1	3/8/94 0:00:00	MRS	REF_BE_1

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
3035	si_2p_hq	Silicon (UnDoped): Si(2p3)&(2p1),BE Cu(2p3)=932.68 gift from Suzuki-san	1	3/4/94 0:00:00	MRS	REF_BE_1
3036	si_vb_hq	Silicon (Un-doped): Valence Bands, 0.05 eV/step	1	3/6/94 0:00:00	MRS	REF_BE_1
3037	si_ws_hq	Silicon (Un-Doped): 0.70 eV/step	1	3/6/94 0:00:00	MRS	REF_BE_1
3038	sn_3d_hq	Tin: Sn (3d5) & Sn (3d3), BE Cu(2p3) = 932.66 eV	1	2/26/94 0:00:00	MRS	REF_BE_1
3039	sn_vb_hq	Tin (Sn): Valence Bands, 0.10 eV/step	1	2/27/94 0:00:00	MRS	REF_BE_1
3040	sn_ws_hq	Tin (Sn): 0.70 eV/step	1	2/26/94 0:00:00	MRS	REF_BE_1
3041	ta_4f_hq	Tantalum: Ta (4f7) & Ta (4f5),BE Cu(2p3)=932.69 eV	1	2/18/94 0:00:00	MRS	REF_BE_1
3042	ta_vb_hq	Tantalum (Ta): Valence Bands, 0.10 eV/step	1	2/19/94 0:00:00	MRS	REF_BE_1
3043	ta_ws_hq	Tantalum (Ta): 0.70 eV/step	1	2/19/94 0:00:00	MRS	REF_BE_1
3044	tb_4d_hq	Terbium: Tb (4d5) & (4d3), BE Cu(2p3)= 932.62 eV	1	3/15/94 0:00:00	MRS	REF_BE_1
3045	tb_vb_hq	Terbium (Tb): Valence Bands, 0.70 eV/step	1	3/15/94 0:00:00	MRS	REF_BE_1
3046	tb_ws_hq	Terbium (Tb): 0.70 eV/step	1	3/15/94 0:00:00	MRS	REF_BE_1
3047	te_3d_hq	Tellurium: Te (3d5) & (3d3), BE Cu (2p3)= 932.65eV	1	2/12/94 0:00:00	MRS	REF_BE_1
3048	te_vb_hq	Tellurium (Te): Valence Bands, 0.20 eV/step	1	2/12/94 0:00:00	MRS	REF_BE_1
3049	te_vb_lo	Tellurium (Te): Valence Bands, 0.20 eV/step	1	2/12/94 0:00:00	MRS	REF_BE_1
3050	te_ws_hq	Tellurium (Te): 0.70 eV/step	1	2/13/94 0:00:00	MRS	REF_BE_1
3051	ti_2p_hq	Titanium: Ti (2p3) & (2p1), BE Cu(2p3)= 932.69 eV	1	2/22/94 0:00:00	MRS	REF_BE_1
3052	ti_vb_hq	Titanium (Ti): Valence Bands, 0.10 eV/step	1	2/22/94 0:00:00	MRS	REF_BE_1
3053	ti_ws_hq	Titanium (Ti): 0.70 eV/step	1	2/7/94 0:00:00	MRS	REF_BE_1
3054	tl_4f_hq	Thallium: Tl (4f7) & (4f5), BE Cu (2p3)= 932.65 eV	1	3/2/94 0:00:00	MRS	REF_BE_1
3055	tl_vb_hq	Thallium (Tl): Valence Bands, 0.10 eV/step	1	3/2/94 0:00:00	MRS	REF_BE_1
3056	tl_ws_hq	Thallium (Tl): 0.70 eV/step	1	3/2/94 0:00:00	MRS	REF_BE_1
3057	tm_4d_hq	Thulmium: Tm (4d), BE Cu (2p3) = 932.67 eV	1	3/19/94 0:00:00	MRS	REF_BE_1
3058	tm_vb_hq	Thulmium (Tm): Valence Bands, 0.05 eV/step	1	3/19/94 0:00:00	MRS	REF_BE_1
3059	tm_ws_hq	Thulmium (Tm): 0.70 eV/step	1	3/19/94 0:00:00	MRS	REF_BE_1
3060	v_2p_hq	Vanadium: V (2p3) & V (2p1), BE Cu(2p3)= 932.63 eV	1	2/21/94 0:00:00	MRS	REF_BE_1
3061	v_vb_hq	Vanadium (V): Valence Bands, 0.10 eV/step	1	2/21/94 0:00:00	MRS	REF_BE_1
3062	v_ws_hq	Vanadium (V): 0.70 eV/step	1	2/21/94 0:00:00	MRS	REF_BE_1
3063	w_4f_hq	Tungsten: W (4f7) & (4f5), BE Cu (2p3) = 932.65 eV	1	3/6/94 0:00:00	MRS	REF_BE_1
3064	w_4f_lo	Tungsten: W (4f7) & (4f5), BE Cu (2p3) = 932.67 eV	1	3/3/94 0:00:00	MRS	REF_BE_1
3065	w_ns_lo	Tungsten: W (4f7) & (4f5), low res, BE Cu2p3=932.7	1	3/3/94 0:00:00	MRS	REF_BE_1
3066	w_vb_hq	Tungsten (W): Valence Bands, 0.05 eV/step	1	3/7/94 0:00:00	MRS	REF_BE_1
3067	w_ws_hq	Tungsten (W): 0.70 eV/step	1	3/7/94 0:00:00	MRS	REF_BE_1
3068	yb_4d_hq	Ytterbium: Yb (4d5) & (4d3), BE Cu(2p3)=932.67 eV	1	3/23/94 0:00:00	MRS	REF_BE_1
3069	yb_4f_hq	Ytterbium: Yb (4f7) & (4f5), BE Cu(2p3)=932.67 eV	1	3/23/94 0:00:00	MRS	REF_BE_1
3070	yb_vb_hq	Ytterbium (Yb): Valence Bands, 0.05 eV/step	1	3/23/94 0:00:00	MRS	REF_BE_1
3071	yb_ws_hq	Ytterbium (Yb): 0.70 eV/step	1	3/23/94 0:00:00	MRS	REF_BE_1
3072	y_2p_hq	Yttrium: Y (2p3) & Y (2p1), BE Cu(2p3)= 932.65 eV	1	3/1/94 0:00:00	MRS	REF_BE_1
3073	y_vb_hq	Yttrium (Y): Valence Bands, 0.10 eV/step	1	3/2/94 0:00:00	MRS	REF_BE_1
3074	y_ws_hq	Yttrium (Y): 0.70 eV/step	1	3/2/94 0:00:00	MRS	REF_BE_1
3075	zn_2p_hq	Zinc: Zn (2p3) & Zn (2p1), BE Cu (2p3) = 932.65 eV	1	3/7/94 0:00:00	MRS	REF_BE_1

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
3076	zn_vb_hq	Zinc (Zn): Valence Bands, 0.05 eV/step	1	3/6/94 0:00:00	MRS	REF_BE_1
3077	zn_ws_hq	Zinc (Zn): 0.70 eV/step	1	3/6/94 0:00:00	MRS	REF_BE_1
3078	zr_3d_hq	Zirconium: Zr(3d5) & (3d3), BE Cu(2p3)= 932.70 eV	1	3/10/94 0:00:00	MRS	REF_BE_1
3079	zr_vb_hq	Zirconium (Zr): Valence Bands, 0.05 eV/step	1	3/10/94 0:00:00	MRS	REF_BE_1
3080	zr_ws_hq	Zirconium (Zr): 0.70 eV/step	1	3/11/94 0:00:00	MRS	REF_BE_1
3081	ag_au_1	Fresh etch of gold to verify calibration for Ag,Rh 35 deg TOA	5	2/28/94 0:00:00	MRS	REF_BE_2
3082	ag_cu_1	Check of Cu Calibration BEs for Ag & Rh work 35 deg TOA	5	2/28/94 0:00:00	MRS	REF_BE_2
3083	ag_cu_2	Check of Cu BEs to verify calibration for Ag 35 deg TOA	5	3/1/94 0:00:00	MRS	REF_BE_2
3084	al_au_1	Fresh etch of gold to verify calibration for Al 90 deg TOA	5	3/3/94 0:00:00	MRS	REF_BE_2
3085	al_au_2	Fresh etch of gold to verify calibration for Al 90 deg TOA	5	3/3/94 0:00:00	MRS	REF_BE_2
3086	al_cu_1	Check of Cu BEs to verify calibration for Al 90 deg TOA	5	3/3/94 0:00:00	MRS	REF_BE_2
3087	al_cu_2	Check of Cu BEs to verify calibration for Al 90 deg TOA	5	3/3/94 0:00:00	MRS	REF_BE_2
3088	as_cu_2	Check of Cu BEs to verify calibr for Hf,Mn, As 90 deg TOA	5	3/10/94 0:00:00	MRS	REF_BE_2
3089	as_cu_3	Check of Cu BEs to verify calibr for Se,As,Hf,Mn, 90 deg TOA	5	3/8/94 0:00:00	MRS	REF_BE_2
3090	au_cu_2	After correcting PEs to to correct calibration 35 deg TOA	6	2/25/94 0:00:00	MRS	REF_BE_2
3091	au_cu_3	After correcting PEs to to correct calibration 35 deg TOA	6	2/25/94 0:00:00	MRS	REF_BE_2
3092	be_cu_2	Check of Cu BEs to verify calibr for Be,Si,Zn,W 90 deg TOA, freshly etched	5	3/7/94 0:00:00	MRS	REF_BE_2
3093	be_cu_3	Check of Cu BEs to verify calibr for Be,Si,Zn,W gun & xtal adj (15K->34Kcps) 90 deg TOA, etched	5	3/7/94 0:00:00	MRS	REF_BE_2
3094	bi_cu_2	Check of Cu BEs to verify calibration for Bi 90 deg TOA	5	3/7/94 0:00:00	MRS	REF_BE_2
3095	bi_cu_3	Check of Cu BEs to verify calibration for Bi repeated after lightly etching	5	3/7/94 0:00:00	MRS	REF_BE_2
3096	b_cu_2	Check of Cu BEs to verify calibrat Ge & B 35 deg TOA	5	2/24/94 0:00:00	MRS	REF_BE_2
3097	cd_au_2	Fresh etch of gold to verify calibr for Cd 35 deg TOA	5	2/14/94 0:00:00	MRS	REF_BE_2
3098	cd_cu_1	Fresh etch of Copper to verify calibration for Cd 35 deg TOA	5	2/10/94 0:00:00	MRS	REF_BE_2
3099	cd_cu_2	Fresh etched Cu BEs to verify calibr for Cd 35 deg TOA	5	2/14/94 0:00:00	MRS	REF_BE_2
3100	co_cu_1	Fresh etch of Copper to verfiy calibration for Co 35 deg TOA	3	2/9/94 0:00:00	MRS	REF_BE_2
3101	co_cu_2	Unetched Copper BE check after Co data and Ti data	1	2/9/94 0:00:00	MRS	REF_BE_2
3102	cr_au_2	Fresh etch of gold to verify calibr for Cr 35 deg TOA	5	2/14/94 0:00:00	MRS	REF_BE_2
3103	cr_cu_1	Fresh etch of Copper to verify calibration for Cr 35 deg TOA	5	2/10/94 0:00:00	MRS	REF_BE_2
3104	cr_cu_2	Fresh etched Cu BEs to verify calibr for Cr 35 deg TOA	5	2/14/94 0:00:00	MRS	REF_BE_2
3105	cr_cu_3	Fresh etched Cu BEs to verify calibr for Cr,Te,Cd 35 deg TOA	5	2/14/94 0:00:00	MRS	REF_BE_2
3106	cu_cu_2	Check of Cu BEs to verify calibration for Cu & Ni 35 deg TOA	5	2/16/94 0:00:00	MRS	REF_BE_2
3107	cu_cu_3	Fresh etch, 90 TOA Cu BEs to verify calibration 35 deg TOA	5	2/16/94 0:00:00	MRS	REF_BE_2
3108	c_au_2	Fresh etch of gold to verify cal for Zr,V,Sb,C,Sc 90 deg TOA	5	3/14/94 0:00:00	MRS	REF_BE_2
3109	c_cu_2	Check of Cu BEs to verify calibr for Zr,V,Sb,C,Sc 90 deg TOA	5	3/14/94 0:00:00	MRS	REF_BE_2
3110	dy_cu_1	Copper (Cu) BE check for Ho, Yb, Dy data 35 deg TOA	6	3/23/94 0:00:00	MRS	REF_BE_2
3111	dy_cu_2	Check of Cu BEs to verify calibration for Yb,Ho,Dy 35 deg TOA	5	3/23/94 0:00:00	MRS	REF_BE_2
3112	fe_au_2	Fresh etch of gold to verify calibration for Fe 35 deg TOA	5	2/10/94 0:00:00	MRS	REF_BE_2
3113	fe_cu_2	Fresh etch of Copper to verify calibration for Fe 35 deg TOA	5	2/10/94 0:00:00	MRS	REF_BE_2
3114	gd_cu_2	Check of Cu BEs to verify calibration for Gd,Tb,Lu 90 deg TOA	6	3/16/94 0:00:00	MRS	REF_BE_2
3115	ge_cu_2	Check of Cu BEs to verify calibrat Ge & B 35 deg TOA	5	2/24/94 0:00:00	MRS	REF_BE_2
3116	ge_cu_3	PEs now correct. Must verify Ge BE. 35 deg TOA	5	2/24/94 0:00:00	MRS	REF_BE_2

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
3117	hf_cu_1	Check of Cu BEs to verify calibr for Se,As,Hf,Mn, 90 deg TOA	5	3/8/94 0:00:00	MRS	REF_BE_2
3118	hf_cu_2	Check of Cu BEs to verify calibr for Hf,Mn, As 90 deg TOA	5	3/10/94 0:00:00	MRS	REF_BE_2
3119	ho_cu_1	Copper (Cu) BE check for Ho, Yb, Dy data 35 deg TOA	6	3/23/94 0:00:00	MRS	REF_BE_2
3120	in_cu_2	Check of Cu BEs to verify calibr. for Pb,In,Sn,Mg 35 deg TOA	6	2/28/94 0:00:00	MRS	REF_BE_2
3121	ir_au_1	Fresh etched Au to verify calibr for Y,W,Ir,Al,Tl 35 deg TOA	6	3/1/94 0:00:00	MRS	REF_BE_2
3122	ir_cu_2	Check of Cu BEs to verify calibration for Ir & Si 90 deg TOA	5	3/4/94 0:00:00	MRS	REF_BE_2
3123	lu_cu_2	Check of Cu BEs to verify calibration for Gd,Tb,Lu 90 deg TOA	6	3/16/94 0:00:00	MRS	REF_BE_2
3124	mg_cu_2	Check of Cu BEs to verify calibr. for Pb,In,Sn,Mg 35 deg TOA	6	2/28/94 0:00:00	MRS	REF_BE_2
3125	mn_au_2	Fresh etch of gold to verify calibr Mn,V,Re,Ta,Nb 35 deg TOA	6	2/21/94 0:00:00	MRS	REF_BE_2
3126	mn_cu_1	Check of Cu BEs to verify calibr for Se,As,Hf,Mn, 90 deg TOA	5	3/8/94 0:00:00	MRS	REF_BE_2
3127	mn_cu_2	Check of Cu BEs to verify calibr for Hf,Mn, As 90 deg TOA	5	3/10/94 0:00:00	MRS	REF_BE_2
3128	mn_cu_3	Check of Cu BEs to verify calibr for Hf,Mn, As 90 deg TOA	5	3/10/94 0:00:00	MRS	REF_BE_2
3129	mo_au_2	Unetched rough gold verification for Mo (90 TOA) 35 deg TOA	5	2/17/94 0:00:00	MRS	REF_BE_2
3130	mo_au_3	Etched rough gold verification for Mo (90 TOA) 35 deg TOA	5	2/17/94 0:00:00	MRS	REF_BE_2
3131	mo_cu_2	Cu BEs verification for Mo (same heavy etched area 35 deg TOA)	5	2/17/94 0:00:00	MRS	REF_BE_2
3132	nb_au_2	Fresh etch of gold to verify calibr Mn,V,Re,Ta,Nb 35 deg TOA	6	2/21/94 0:00:00	MRS	REF_BE_2
3133	nb_cu_2	Check of Cu BEs to verify calibrat Mn,V,Ta,Nb,Re 35 deg TOA	5	2/21/94 0:00:00	MRS	REF_BE_2
3134	ni_au_1	Fresh etch of gold to verify calibr for Ni 35 deg TOA	5	2/14/94 0:00:00	MRS	REF_BE_2
3135	ni_cu_1	Fresh etched Cu BEs to verify calibr for Ni 35 deg TOA	5	2/14/94 0:00:00	MRS	REF_BE_2
3136	ni_cu_2	Check of Cu BEs to verify calibration for Cu & Ni 35 deg TOA	5	2/16/94 0:00:00	MRS	REF_BE_2
3137	pb_cu_2	Check of Cu BEs to verify calibr. for Pb,In,Sn,Mg 35 deg TOA	6	2/28/94 0:00:00	MRS	REF_BE_2
3138	pd_cu_2	Fresh etch of Copper to verify calibration for Pd 35 deg TOA	5	2/10/94 0:00:00	MRS	REF_BE_2
3139	pt_au_2	Previous etched gold to verify calibration for Pt 35 deg TOA	5	2/18/94 0:00:00	MRS	REF_BE_2
3140	pt_cu_2	Check of Cu BEs to verify calibration for Pt 35 deg TOA	5	2/18/94 0:00:00	MRS	REF_BE_2
3141	re_au_2	Fresh etch of gold to verify calibr Mn,V,Re,Ta,Nb 35 deg TOA	6	2/21/94 0:00:00	MRS	REF_BE_2
3142	re_cu_2	Check of Cu BEs to verify calibrat Mn,V,Ta,Nb,Re 35 deg TOA	5	2/21/94 0:00:00	MRS	REF_BE_2
3143	rh_au_1	Fresh etch of gold to verify calibration for Ag,Rh 35 deg TOA	5	2/28/94 0:00:00	MRS	REF_BE_2
3144	rh_cu_1	Check of Cu Calibration BEs for Ag & Rh work 35 deg TOA	5	2/28/94 0:00:00	MRS	REF_BE_2
3145	rh_cu_2	Check of Cu BEs to verify calibration for Rh 35 deg TOA	5	3/1/94 0:00:00	MRS	REF_BE_2
3146	sb_au_2	Fresh etch of gold to verify cal for Zr,V,Sb,C,Sc 90 deg TOA	5	3/14/94 0:00:00	MRS	REF_BE_2
3147	sb_cu_2	Check of Cu BEs to verify calibr for Zr,V,Sb,C,Sc 90 deg TOA	5	3/14/94 0:00:00	MRS	REF_BE_2
3148	sc_au_2	Fresh etch of gold to verify cal for Zr,V,Sb,C,Sc 90 deg TOA	5	3/14/94 0:00:00	MRS	REF_BE_2
3149	sc_cu_2	Check of Cu BEs to verify calibr for Zr,V,Sb,C,Sc 90 deg TOA	5	3/14/94 0:00:00	MRS	REF_BE_2
3150	se_cu_2	Check of Cu BEs to verify calibr for Se,As,Hf,Mn, 90 deg TOA	5	3/8/94 0:00:00	MRS	REF_BE_2
3151	se_cu_3	Check of Cu BEs to verify calibr for Se,As,Hf,Mn, 90 deg TOA	5	3/8/94 0:00:00	MRS	REF_BE_2
3152	si_cu_1	Check of Cu BEs to verify calibration for Si 90 deg TOA	5	3/4/94 0:00:00	MRS	REF_BE_2
3153	si_cu_2	Check of Cu BEs to verify calibr for Be,Si,Zn,W 90 deg TOA, freshly etched	5	3/7/94 0:00:00	MRS	REF_BE_2
3154	si_cu_3	Check of Cu BEs to verify calibr for Be,Si,Zn,W gun & xtal adj (15K->34Kcps) 90 deg TOA, etched	5	3/7/94 0:00:00	MRS	REF_BE_2
3155	sn_cu_2	Check of Cu BEs to verify calibr. for Pb,In,Sn,Mg 35 deg TOA	6	2/28/94 0:00:00	MRS	REF_BE_2
3156	ta_au_2	Fresh etch of gold to verify calibr Mn,V,Re,Ta,Nb 35 deg TOA	6	2/21/94 0:00:00	MRS	REF_BE_2
3157	ta_cu_2	Check of Cu BEs to verify calibrat Mn,V,Ta,Nb,Re 35 deg TOA	5	2/21/94 0:00:00	MRS	REF_BE_2

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
3158	tb_cu_2	Check of Cu BEs to verify calibration for Gd,Tb,Lu 90 deg TOA	6	3/16/94 0:00:00	MRS	REF_BE_2
3159	te_au_2	Fresh etch of gold to verify calibr for Te 35 deg TOA	5	2/14/94 0:00:00	MRS	REF_BE_2
3160	te_cu_1	Fresh etch of Copper to verify calibration for Te 35 deg TOA	5	2/10/94 0:00:00	MRS	REF_BE_2
3161	te_cu_2	Fresh etched Cu BEs to verify calibr for Te 35 deg TOA	5	2/14/94 0:00:00	MRS	REF_BE_2
3162	te_cu_3	Fresh etched Cu BEs to verify calibr for Cr,Te,Cd 35 deg TOA	5	2/14/94 0:00:00	MRS	REF_BE_2
3163	ti_cu_2	Fresh etch of Copper to verify calibration for Co 35 deg TOA	3	2/9/94 0:00:00	MRS	REF_BE_2
3164	ti_cu_3	Unetched Copper BE check after Co data and Ti data	1	2/9/94 0:00:00	MRS	REF_BE_2
3165	tl_au_1	Fresh etched Au to verify calibr for Y,W,Ir,Al,Tl 35 deg TOA	6	3/1/94 0:00:00	MRS	REF_BE_2
3166	tl_cu_2	Check of BEs & PEs for Yttrium & Thallium data 90 deg TOA, etched 1 min at 3 KV	5	3/2/94 0:00:00	MRS	REF_BE_2
3167	tm_cu_1	Check of Cu BEs to verify calibr Yb,Tm,Er,Ho,Dy 90 deg TOA	5	3/18/94 0:00:00	MRS	REF_BE_2
3168	v_au_2	Fresh etch of gold to verify calibr Mn,V,Re,Ta,Nb 35 deg TOA	6	2/21/94 0:00:00	MRS	REF_BE_2
3169	v_cu_2	Check of Cu BEs to verify calibrat Mn,V,Ta,Nb,Re 35 deg TOA	5	2/21/94 0:00:00	MRS	REF_BE_2
3170	w_au_1	Fresh etched Au to verify calibr for Y,W,Ir,Al,Tl 35 deg TOA	6	3/1/94 0:00:00	MRS	REF_BE_2
3171	w_cu_2	Check of Cu BEs to verify calibr for Be,Si,Zn,W 90 deg TOA, freshly etched	5	3/7/94 0:00:00	MRS	REF_BE_2
3172	w_cu_3	Check of Cu BEs to verify calibr for Be,Si,Zn,W gun & xtal adj (15K->34Kcps) 90 deg TOA, etched	5	3/7/94 0:00:00	MRS	REF_BE_2
3173	yb_cu_1	Check of Cu BEs to verify calibr Yb,Tm,Er,Ho,Dy 90 deg TOA	5	3/18/94 0:00:00	MRS	REF_BE_2
3174	yb_cu_2	Copper (Cu) BE check for Ho, Yb, Dy data 35 deg TOA	6	3/23/94 0:00:00	MRS	REF_BE_2
3175	y_au_1	Fresh etched Au to verify calibr for Y,W,Ir,Al,Tl 35 deg TOA	6	3/1/94 0:00:00	MRS	REF_BE_2
3176	y_cu_2	Check of BEs & PEs for Yttrium & Thallium data 90 deg TOA, etched 1 min at 3 KV	5	3/2/94 0:00:00	MRS	REF_BE_2
3177	zn_cu_2	Check of Cu BEs to verify calibr for Be,Si,Zn,W 90 deg TOA, freshly etched	5	3/7/94 0:00:00	MRS	REF_BE_2
3178	zn_cu_3	Check of Cu BEs to verify calibr for Be,Si,Zn,W 90 deg TOA, etched	5	3/7/94 0:00:00	MRS	REF_BE_2
3179	zr_au_2	Fresh etch of gold to verify cal for Zr,V,Sb,C,Sc 90 deg TOA	5	3/14/94 0:00:00	MRS	REF_BE_2
3180	zr_cu_2	Check of Cu BEs to verify calibr for Zr,V,Sb,C,Sc 90 deg TOA	5	3/14/94 0:00:00	MRS	REF_BE_2
3181	armorall	"ARMOR-ALL" Corrosion PROTECTANT SMEARED ON A GOLD PLATEN	6	10/19/85 0:00:00	MRS	RESIDUE
3182	microlab	"MICRO LAB" CLEANING SOLUTION SMEARED ON A GOLD PLATEN	8	10/19/85 0:00:00	MRS	RESIDUE
3183	tapwater	100 mL of TAP WATER (SSL) boiled to dryness with Al foil piece inside	9	11/2/85 0:00:00	MRS	RESIDUE
3184	tap_h2o	100 mL TAP WATER (SSL) EVAPORATED TO DRYNESS onto glass slide	3	10/31/85 0:00:00	MRS	RESIDUE
3185	algaas_1	ONE EPITAXIAL LAYER AlGaAs ON GaAs (AS RECD,35TOA)	10	6/28/88 0:00:00	MRS	SEMICON1
3186	algaas_2	epi-AlGaAs/AlGaAs H2SO4:H2O2:H2O 8:1:1 90 deg TOA	6	12/21/93 0:00:00	MRS	SEMICON1
3187	algaas_3	epi-AlGaAs/AlGaAs: AlGaAs_2 after 2h 380 C in air	5	12/21/93 0:00:00	MRS	SEMICON1
3188	algaas_4	epi-AlGaAs/AlGaAs: AlGaAs_2 after H2O2 + NH3 solns	5	12/21/93 0:00:00	MRS	SEMICON1
3189	algaas_5	epi-AlGaAs/AlGaAs: AlGaAs_3 after 2hr in Ar at 380	5	12/21/93 0:00:00	MRS	SEMICON1
3190	algaas_6	epi-AlGaAs/AlGaAs: AlGaAs_3 after 2h 380C in Air	5	12/21/93 0:00:00	MRS	SEMICON1
3191	algaas_7	AlGaAs/GaAs superlattice (gift) as rec'd 90 TOA	8	4/29/94 0:00:00	MRS	SEMICON1
3192	algaas_8	AlGaAs/GaAs superlattice (gift) 5 min in H2O2/HCl	8	4/29/94 0:00:00	MRS	SEMICON1
3193	algaas_9	AlGaAs/GaAs (gift) Ar+ Ion etched 1min 2KV	11	5/1/94 0:00:00	MRS	SEMICON1
3194	aln_1	Aluminium Nitride (AlN) 99.99% Aldr.Chem.Co. Lot# (pressed into pellet)	10	7/21/94 0:00:00	MRS	SEMICON1
3195	aln_2	AlN coating (as rec'd, 35 deg TOA) Conductive	5	6/11/91 0:00:00	MRS	SEMICON1
3196	aln_4	Bottom of Al_N coating Ion Etch Crater (200 ang depth)	5	6/11/91 0:00:00	MRS	SEMICON1
3197	aln_4a	Quick etch to check true concentration of oxygen in AlN coating	1	6/11/91 0:00:00	MRS	SEMICON1
3198	aln_5	AlN (bottom of crater) high resolution check	2	6/11/91 0:00:00	MRS	SEMICON1



Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
3199	aln_5a	AlN (bottom of crater) high resolution check	1	6/11/91 0:00:00	MRS	SEMICON1
3200	aln_5b	AlN (bottom of crater) high resolution check	1	6/11/91 0:00:00	MRS	SEMICON1
3201	beo_1	BeO (99.99%) 3mm pellet, Aldrich lot# 00213JX, screen, 90 TOA	10	1/28/92 0:00:00	MRS	SEMICON1
3202	beo_2	BeO 99.99% Aldr lot# 00213JX scrn 90 TOA	3	6/13/94 0:00:00	MRS	SEMICON1
3203	bn_1	BORON NITRIDE (BN) CERAMIC PART (90 DEG TOA, ION ETCH: 4 KeV, 10 mA, 2 MIN)	15	12/21/86 0:00:00	MRS	SEMICON1
3204	bn_2	BORON NITRIDE (BN) WHITE SOLID 45 TOA, SCREEN, EXPOSED BULK	5	7/15/87 0:00:00	MRS	SEMICON1
3205	bn_2a	BORON NITRIDE (BN) WHITE SOLID 45 TOA, SCREEN, EXPOSED BULK	2	7/15/87 0:00:00	MRS	SEMICON1
3206	cdo_1	CdO (99.99+%) Aldrich lot #01318EV, 3mm pellet, 35 TOA, screen	4	6/11/91 0:00:00	MRS	SEMICON1
3207	cdo_1a	CdO (99.99+%) Aldrich lot #0138EV 3mm pellet, 35 TOA, screen screen	1	6/11/91 0:00:00	MRS	SEMICON1
3208	cdo_2	CdO pellet (in CdO_01) after removing 80% of HC contam. by ion etching	3	6/12/91 0:00:00	MRS	SEMICON1
3209	cdo_3	CdO (CdO_01) pellet, scrn, after 30 sec 3KV, 10mA ion etch	3	6/12/91 0:00:00	MRS	SEMICON1
3210	cdse_1	CdSe (99.99%) Aldr.Chem.Co.,lot#00323JX As rec'd Electronic Grade, 3 micron powder, pressed pellet	8	7/26/94 0:00:00	MRS	SEMICON1
3211	cdse_2_e	CdSe (99.99%) Aldr Chem Co. lot#00323JX ion etched Electronic grade 3 micron powder pressed pellet	8	7/28/94 0:00:00	MRS	SEMICON1
3212	cdse_3	CdSe/DST (as received, 35 TOA, mesh)	5	3/13/93 0:00:00	MRS	SEMICON1
3213	cdte_1	Cadmium Telluride(CdTe) 99.99% lot#03225CV as recd	11	7/28/94 0:00:00	MRS	SEMICON1
3214	cdte_2_e	CdTe (99.99%) Aldr. Chem. lot#03225CV 30 sec etch TeOx gone after 3 KV 10 sec etch	8	7/28/94 0:00:00	MRS	SEMICON1
3215	cu2o_1	Cu2O (Rare Metallics) Powder on In FOIL, 90 DEG TOA, Conductive, no mesh	4	10/7/87 0:00:00	MRS	SEMICON1
3216	cu2o_2	Cu2O (97%) dark red, 3mm pellet, Aldrich lot# 04602BW, Conductive, 90 TOA	12	8/23/91 0:00:00	MRS	SEMICON1
3217	cucl_1	Cu(I)Cl 99.99% Aldr# 04027AW 3mm plt conduc 90 TOA	10	5/25/94 0:00:00	MRS	SEMICON1
3218	c_1_vb	INDUSTRIAL DIAMOND (C) CLEANED WITH SOLVENTS, 45 DEG TOA	1	1/20/88 0:00:00	MRS	SEMICON1
3219	c_2	CARBON (C) SHEET (GRAPHITE) (90 DEG TOA, SCRAPED WITH RAZOR BLADE)	6	1/19/88 0:00:00	MRS	SEMICON1
3220	c_2a	CARBON (C) SHEET (GRAPHITE) (90 DEG TOA, SCRAPED WITH A RAZOR BLADE)	1	1/19/88 0:00:00	MRS	SEMICON1
3221	c_2b	CARBON (C) SHEET (GRAPHITE) (90 DEG TOA, SCRAPED WITH RAZOR BLADE)	1	1/19/88 0:00:00	MRS	SEMICON1
3222	diamnd_1	DIAMOND (C) (90 DEG TOA, NO SCREEN, CLEANED WITH SOLVENTS)	1	2/18/88 0:00:00	MRS	SEMICON1
3223	diamnd_2	DIAMOND (C) As received, no screen.	1	2/18/88 0:00:00	MRS	SEMICON1
3224	diamnd_3	INDUSTRIAL DIAMOND (LIGHTLY ETCHED) 45 DEG TOA, SCREEN, EXPOSED BULK	3	7/15/87 0:00:00	MRS	SEMICON1
3225	diamnd_4	INDUSTRIAL DIAMOND 45 DEG TOA, SCREEN, ION ETCH 20s 3 KeV	3	7/15/87 0:00:00	MRS	SEMICON1
3226	diamnd_5	INDUSTRIAL DIAMOND (C) CLEANED WITH SOLVENTS, 45 DEG TOA	1	1/20/88 0:00:00	MRS	SEMICON1
3227	diamnd_6	DIAMOND (C) (90 DEG TOA, NO SCREEN, CLEANED WITH SOLVENTS)	1	2/18/88 0:00:00	MRS	SEMICON1
3228	diamnd_7	INDUSTRIAL DIAMOND 45 DEG TOA, SCREEN, ION ETCH 20s 3 KeV	3	7/15/87 0:00:00	MRS	SEMICON1
3229	gaas_1	GaAs wafer (as rec'd, 90 deg TOA)	4	3/27/92 0:00:00	MRS	SEMICON1
3230	gaas_2	FRESHLY EXPOSED BULK OF A GaAs WAFER (90 DEGREE TAKE-OFF-ANGLE)	7	2/6/87 0:00:00	MRS	SEMICON1
3231	gaas_3	CENTER REGION OF POLISHED GaAs WAFER (35 DEG TOA, AS RECEIVED)	4	3/30/88 0:00:00	MRS	SEMICON1
3232	gaas_pat	GaAs Wafer with Poly-Si pattern (AVOIDED PATTERNING)	2	5/26/88 0:00:00	MRS	SEMICON1
3233	gainas_1	GaInAs/InP (gift) as rec'd 90 TOA	8	4/29/94 0:00:00	MRS	SEMICON1
3234	gainas_2	GaInAs/InP (gift)as rec surface etched 1min 2KV 90	11	4/30/94 0:00:00	MRS	SEMICON1
3235	gainas_3	GaInAs/InP (gift)as rec surface etched 4min 2KV 90	7	5/6/94 0:00:00	MRS	SEMICON1
3236	gap100_a	GaP <100> 90 TOA as rec'd	8	5/16/94 0:00:00	MRS	SEMICON1
3237	gap100_b	GaP <100> 90 TOA after 1 min 3 KV etch	8	5/18/94 0:00:00	MRS	SEMICON1
3238	gap100_c	GaP <100> 90 TOA after 1 min 3 KV etch	1	5/18/94 0:00:00	MRS	SEMICON1
3239	gap100_d	GaP <100> 90 TOA after 1 min 3 KV etch	1	5/18/94 0:00:00	MRS	SEMICON1

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
3240	gap111_a	GaP <111> 90 TOA as rec'd	7	5/16/94 0:00:00	MRS	SEMICON1
3241	gap111_b	GaP <111> exposed fract. bulk, not etched, 90 TOA	5	5/23/94 0:00:00	MRS	SEMICON1
3242	gap111_c	GaP <111> exposed fract. bulk, not etched, 90 TOA	4	5/23/94 0:00:00	MRS	SEMICON1
3243	gap111_d	GaP <111> exposed fract. bulk, 1 min 3KV etch 90T	5	5/23/94 0:00:00	MRS	SEMICON1
3244	gasb_ar	GaSb xtal, mirror, as rec'd, 90 TOA Sumitomo Elec	12	4/24/94 0:00:00	MRS	SEMICON1
3245	gasb_blk	GaSb xtal bulk Sumitomo Elec (90 TOA fract in air)	12	4/24/94 0:00:00	MRS	SEMICON1
3246	gasb_b_e	GaSb xtal etched bulk Sumitomo Elec (90TOA fract i	7	4/26/94 0:00:00	MRS	SEMICON1
3247	gasb_m_e	GaSb xtal, mirror, etched, 90 TOA Sumitomo Elec	7	4/26/94 0:00:00	MRS	SEMICON1
3248	gese2_1	GeSe2/DST (as received, mesh, 35 TOA)	5	3/13/93 0:00:00	MRS	SEMICON1
3249	gese_1	GeSe/dst (as received, MESH, 35 toa)	5	3/13/93 0:00:00	MRS	SEMICON1
3250	ge_1	GERMANIUM (Ge) WAFER (SCRAPED, 90 TOA, ION ETCH: 5 KeV, 10 mA, 5 MIN)	15	12/7/86 0:00:00	MRS	SEMICON1
3251	hgs_1	Cinnabar (HgS) lg xtl,fresh bulk,mesh, Ukraine Rus	11	6/17/94 0:00:00	MRS	SEMICON1
3252	hgte_1	HgTe film (gift) as rec'd 90 TOA	6	5/17/94 0:00:00	MRS	SEMICON1
3253	hopg_1	HOPG (freshly delaminated surface) 100 deg TOA	10	12/15/93 0:00:00	MRS	SEMICON1
3254	inp_1	FRESHLY EXPOSED BULK OF AN InP (111) WAFER (90 DEG TOA)	5	8/12/87 0:00:00	MRS	SEMICON1
3255	inp_2	FRESHLY EXPOSED BULK OF AN InP (111) WAFER (90 DEG TOA)	2	8/12/87 0:00:00	MRS	SEMICON1
3256	inp_ar	InP <111> as rec'd Sumitomo Elec 700321-01a	14	4/26/94 0:00:00	MRS	SEMICON1
3257	inp_blk	InP xtal bulk Sumitomo Elec(90TOA,air fract 700321	14	4/24/94 0:00:00	MRS	SEMICON1
3258	inp_b_e	InP xtal etched bulk Sumitomo Elec(90TOA,air fract	6	4/26/94 0:00:00	MRS	SEMICON1
3259	inp_m_e	InP <111> mirror etched Sumitomo Elec 700321-01a	6	4/27/94 0:00:00	MRS	SEMICON1
3260	inp_vb	InP (111) (Sumitomo Electric, 90 TOA, Fresh Bulk)	1	6/8/87 0:00:00	MRS	SEMICON1
3261	insb_ar	InSb xtal mirror as rec'd Sumitomo Elec (90 TOA)	12	4/25/94 0:00:00	MRS	SEMICON1
3262	insb_blk	InSb xtal bulk Sumitomo Elec (90 TOA,fract in air)	12	4/23/94 0:00:00	MRS	SEMICON1
3263	insb_b_e	InSb xtal etched bulk Sumitomo Elec (90TOA,fract i	6	4/26/94 0:00:00	MRS	SEMICON1
3264	insb_m_e	InSb xtal mirror etched Sumitomo Elec (90 TOA)	6	4/27/94 0:00:00	MRS	SEMICON1
3265	insnox_1	ITO/Glass (as rec'd, 35 TOA)	6	2/22/94 0:00:00	MRS	SEMICON1
3266	insnox_2	ITO/Glass (leak in system) as rec'd, 35 TOA	6	2/22/94 0:00:00	MRS	SEMICON1
3267	insnox_3	ITO/Glass (made after repairing Leak) as rec'd	6	2/22/94 0:00:00	MRS	SEMICON1
3268	n-si_1	n-Si<110> CZ 10ohm-cm lot 280292-00-417 Mitsubishi as rec'd 90 deg electron TOA	6	4/29/94 0:00:00	MRS	SEMICON1
3269	n-si_2	n-Si<110> CZ Mitsubishi lot# 280292-00-417 Edge of wafer exposed by fracturing in air 90 TOA	6	4/30/94 0:00:00	MRS	SEMICON1
3270	n-si_2s	n-Si<110>CZ air-fract bulk Mitsu 280292-00-417 90T expanded VB region to reveal small BE shift if any	1	4/30/94 0:00:00	MRS	SEMICON1
3271	n-si_3	n-Si<110> CZ Mitsubishi lot# 280292-00-417 90TOA Fresh bulk-edge after 20sec 3KV ion etch	6	5/9/94 0:00:00	MRS	SEMICON1
3272	n-si_4	OKI n-Type Silicon (100), CZ, 5-8 M-Ohm, 35 toa, Native Oxide present	8	4/18/91 0:00:00	MRS	SEMICON1
3273	nbs_si_1	NBS SRM 1521 B-70: Boron Doped Silicon (8.76 Mega-Ohm, as rec'd)	5	6/25/91 0:00:00	MRS	SEMICON1
3274	nbs_si_2	NBS SRM 1521 B-70: Boron Doped Si (effect of flood gun at 2 eV)	3	6/25/91 0:00:00	MRS	SEMICON1
3275	nbs_si_3	NBS SRM 1521 B-70: p-Si(B) with 2eV FG after Ion Etching	3	6/25/91 0:00:00	MRS	SEMICON1
3276	nbs_si_4	NBS SRM 1521 B-70: p-Si(B) After ion etching (35 toa)	4	6/25/91 0:00:00	MRS	SEMICON1
3277	nio_1	NiO (99.99%) Aldr lot# 00503CW, 3mm pellet, CONDUCTIVE, 90 TOA	11	8/23/91 0:00:00	MRS	SEMICON1
3278	NTV_SIO1	Native SiO2/Si wafer, grazing X-ray angle	1	9/11/92 0:00:00	MRS	SEMICON1
3279	ntv_sio2	Native SiO2/Si wafer, X-ray grazing angle for maximum counts	3	9/11/92 0:00:00	MRS	SEMICON1
3280	ntv_sio3	Native SiO2/Si wafer, Grazing X-ray angle for maximum counts	3	9/11/92 0:00:00	MRS	SEMICON1

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
3281	p-si_1	p-Type Silicon (100): 35 toa, Native Oxide	1	4/18/91 0:00:00	MRS	SEMICON1
3282	p-si_2	p-Si<111> Mitsubishi lot# 280152-00-437 90 TOA (analyzed polished surface as rec'd)	9	4/25/94 0:00:00	MRS	SEMICON1
3283	p-si_2e	p-Si<111>CZ <100ohm-cm Mitsubishi lot280152-00-437 (after 20 sec 3KV ion etch of freshly exposed bulk	5	4/26/94 0:00:00	MRS	SEMICON1
3284	p-si_3	p-Si<111> CZ <100 ohm-cm Mitsubishi 280152-00-437 Freshly exposed bulk, fractured in air 90 TOA	9	4/23/94 0:00:00	MRS	SEMICON1
3285	p-si_4	p-Si<111> Mitsubishi lot# 280152-00-437 90 TOA (after 20 sec 3KV ion etch of polished surface)	5	4/26/94 0:00:00	MRS	SEMICON1
3286	pb2o3_1	Pb2O3 (99.9%) RMC lot# 80310-04, 3mm pellet, screen, 90 TOA	10	2/2/92 0:00:00	MRS	SEMICON1
3287	pbo2_1	PbO2 (95+%) Aldrich Lot# 06811JW, 3mm pellet, CONDUCTIVE, 90 TOA	8	8/14/91 0:00:00	MRS	SEMICON1
3288	pbo_1	PbO (99.999%) Aldrich Lot# 04911PV, 3mm pellet, Semi-Con, screen, 90 TOA	8	1/25/92 0:00:00	MRS	SEMICON1
3289	pbs_1	PbS xtl (Galena, Missouri) fresh bulk, 35 TOA	10	5/13/94 0:00:00	MRS	SEMICON1
3290	sbte_1	SbTe (99%) Aldrich Chem. Co. lot# 1012TV as recd fused 3-20 mm chunks	10	7/21/94 0:00:00	MRS	SEMICON1
3291	sbte_2	SbTe (99+%) Aldrich Chem Co.: freshly peeled Lot #10412TV peeled in air	10	7/26/94 0:00:00	MRS	SEMICON1
3292	se_1	SELENIUM (Se) PELLETT (SCRAPED, 90 TOA, ION ETCH: 10 mA, 4 KeV, 20 SEC)	3	12/13/86 0:00:00	MRS	SEMICON1
3293	se_1a	SELENIUM (Se) PELLETT (SCRAPED, 90 TOA, iON ETCH: 10 mA, 4 KeV, 20 SEC)	3	12/13/86 0:00:00	MRS	SEMICON1
3294	se_1b	SELENIUM (Se) PELLETT (SCRAPED, 90 TOA, ION ETCH: 10 mA, 4 KeV, 20 SEC)	6	12/13/86 0:00:00	MRS	SEMICON1
3295	si3n4_1	OLD OXIDIZED Si3N4 COATING (90 DEG TOA, AS RECEIVED)	6	6/17/88 0:00:00	MRS	SEMICON1
3296	si3n4_2	OLD OXIDIZED Si3N4 COATING (ION ETCHED: 2KV, 4 MIN)	7	6/17/88 0:00:00	MRS	SEMICON1
3297	si3n4_3	Si3N4/Si (5min conc H2O2:HCl:H2O 3:2:5) metal blue 90 toa	8	4/27/94 0:00:00	MRS	SEMICON1
3298	si3n4_4	Si3N4/Si (10min conc HF:MeOH 2:50 cc) metal blue 90 toa	8	4/27/94 0:00:00	MRS	SEMICON1
3299	si3n4_5	Si3N4/Si as rec'd, only gray color seen 90 toa	8	4/27/94 0:00:00	MRS	SEMICON1
3300	SI3N4_6	Si3N4/Si etched 10 min at 2KV 6E(-8) Ar, gray type 90 toa	1	4/27/94 0:00:00	MRS	SEMICON1
3301	sin_u_00	Si3N4 Coating/Glass: <5 min after UV treatment (35 TOA, mesh)	1	11/19/93 0:00:00	MRS	SEMICON1
3302	sin_u_03	Si3N4 Coating/Glass: 3 hr in box after UV treatment (35 TOA, Mesh)	1	11/22/93 0:00:00	MRS	SEMICON1
3303	sin_u_24	Si3N4 Coating/Glass: 24 hr after UV/Ozone treatment (35 TOA, mesh)	1	11/19/93 0:00:00	MRS	SEMICON1
3304	si_1	FRESH EXPOSED BULK OF A SILICON WAFER (0.5 MM THICK, 90 DEG TOA)	7	5/14/87 0:00:00	MRS	SEMICON1
3305	si_2	FRESHLY EXPOSED BULK OF A SILICON WAFER (0.5 MM THICK, 90 DEG TOA)	3	5/14/87 0:00:00	MRS	SEMICON1
3306	si_2p_hf	Silicon (100) wafer, 3% HF etch, 90 TOA	1	11/18/92 0:00:00	MRS	SEMICON1
3307	si_2p_hq	Silicon (UnDoped): Si(2p3)&(2p1),BE Cu(2p3)=932.68 gift from Suzuki-san	1	3/4/94 0:00:00	MRS	SEMICON1
3308	si_3	FRESHLY EXPOSED BULK OF A SILICON WAFER (0.5 MM THICK, 90 DEG TOA)	3	5/15/87 0:00:00	MRS	SEMICON1
3309	si_4	FRESHLY EXPOSED BULK OF A SILICON WAFER (90 DEGREE TAKE-OFF-ANGLE)	5	2/9/87 0:00:00	MRS	SEMICON1
3310	si_bulk	Fresh Bulk of Si wafer: test of resolution	2	1/11/94 0:00:00	MRS	SEMICON1
3311	SI_ETCHD	Silicon (Si) wafer after 100 sec 2KV Ar+ ion etch	1	6/20/88 0:00:00	MRS	SEMICON1
3312	si_hf_1	Silicon (100) wafer, briefly soaked in 3% HF etch, 90 TOA	1	11/18/92 0:00:00	MRS	SEMICON1
3313	si_hf_2	Silicon (100) wafer, briefly soaked in 3% HF etch, 90 TOA	1	11/18/92 0:00:00	MRS	SEMICON1
3314	si_hf_3	Silicon (100) wafer, 3% HF etch, 90 TOA	1	11/18/92 0:00:00	MRS	SEMICON1
3315	si_hirs	Freshly cleaved Si<100> wafer, 10eV pass energy (analyzed exposed bulk, unknown doping)	1	10/16/89 0:00:00	MRS	SEMICON1
3316	si_monox	SiO 1:1 RMC 99.99% lot 70924-70 8min 3KV no mesh	7	5/17/94 0:00:00	MRS	SEMICON1
3317	si_soln1	p-Si (B: 10e14) native oxide(grazing x-rays)dil HF (treated with dilute HF solution)	6	2/9/94 0:00:00	MRS	SEMICON1
3318	si_soln2	n-Si (P: 10e14) native oxide (grazing x-rays) H2O2 (treated with peroxide solution)	5	2/9/94 0:00:00	MRS	SEMICON1
3319	si_soln3	p-Si (P:10e14) native oxide (grazing x-rays)HF buf (Treated with buffered HF solution)	5	2/9/94 0:00:00	MRS	SEMICON1
3320	si_soln4	n-Si (P: 10e14) wafer after (NH4)2S soln treatment grazing X-rays , native oxide	5	2/9/94 0:00:00	MRS	SEMICON1
3321	si_vb_90	Silicon (n-type ?) freshly exposed edge (90 toa)	3	7/16/91 0:00:00	MRS	SEMICON1

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
3322	si_vb_hq	Silicon (Un-doped): Valence Bands, 0.05 eV/step (sample from Suzuki-san)	1	3/6/94 0:00:00	MRS	SEMICON1
3323	si_ws_hq	Silicon (Un-Doped): 0.70 eV/step	1	3/6/94 0:00:00	MRS	SEMICON1
3324	sno2_1	SnO2 (99.995+%) Aldrich Lot# 05903PV, 3mm pellet, screen, 90 TOA	5	7/18/91 0:00:00	MRS	SEMICON1
3325	te_1	TELLURIUM (Te) LUMP (EXPOSED BULK 90 TOA, ETCHED 3 MIN AT 5 KeV 10 mA)	10	4/20/87 0:00:00	MRS	SEMICON1
3326	un_si_2p	Silicon (UnDoped): Si(2p3)&(2p1),BE Cu(2p3)=932.68 gift from Suzuki-san	1	3/4/94 0:00:00	MRS	SEMICON1
3327	un_si_ns	Silicon (Si) wafer, no doping, as rec'd, 90 TOA 90 deg TOA, Repeated ion etched between scans	3	3/5/94 0:00:00	MRS	SEMICON1
3328	UN_SI_VB	Silicon (Un-doped): Valence Bands, 0.05 eV/step	1	3/6/94 0:00:00	MRS	SEMICON1
3329	un_si_ws	Silicon (Si) wafer, no doping, as rec'd, 90 TOA 70 deg TOA, Repeated ion etched between scans	2	3/5/94 0:00:00	MRS	SEMICON1
3330	wo3_1	WO3 (99.995%) Aldrich Lot# 00107KM JV, 3mm pellet, screen, 90 TOA	5	7/18/91 0:00:00	MRS	SEMICON1
3331	zno_1	ZnO (99.999%) Aldrich Lot# HW 04629KV, 3mm pellet, screen, 90 TOA	9	8/13/91 0:00:00	MRS	SEMICON1
3332	zno_2	ZnO (as rec'd) SSI screen, 90 deg TOA	7	12/3/92 0:00:00	MRS	SEMICON1
3333	zns_film	ZnS Coated Film (35 deg TOA) as received	1	9/12/86 0:00:00	MRS	SEMICON1
3334	ag_01	SILVER (Ag) on Mylar (90 DEG TOA, ION ETCHED: 4 KeV, 1 MIN)	2	11/27/86 0:00:00	MRS	SEMICON2
3335	ag_02	SILVER (Ag) FOIL (90 DEG TOA, POLISHED, ION ETCHED: 3 KeV, 30 SEC)	4	11/29/86 0:00:00	MRS	SEMICON2
3336	ag_vb	ION ETCHED SILVER (Ag) ON MYLAR (90 DEG TOA)	1	10/13/87 0:00:00	MRS	SEMICON2
3337	al2o3_01	SAPPHIRE (Al2O3) (AS RECEIVED, 35 DEG TOA, NO MESH, INSIDE CLIP)	4	9/22/87 0:00:00	MRS	SEMICON2
3338	al2o3_02	Fused Al2O3 (as rec'd surface of 1 mm thick plate, screen, 90 DEG TOA)	10	8/20/91 0:00:00	MRS	SEMICON2
3339	al_01	ALUMINUM (Al) WIRE (99.999% 90 DEG TOA, ETCHED AT 4 KV FOR 5 MIN)	1	7/1/88 0:00:00	MRS	SEMICON2
3340	al_02	ALUMINUM (Al) WIRE (99.999%, 90 DEG TOA, ETCHED, FRESHLY EXPOSED BULK)	1	1/27/88 0:00:00	MRS	SEMICON2
3341	al_03	ALUMINUM (Al) INGOT (99.99+%, 4KV etch, THEN CONT. LIGHT ETCHING, 90 TOA)	2	6/21/88 0:00:00	MRS	SEMICON2
3342	al_04	ALUMINUM (Al) WIRE (99.999% 90 DEG TOA, ETCHED, FRESHLY EXPOSED BULK)	1	1/27/88 0:00:00	MRS	SEMICON2
3343	al_oh3	ALUMINUM HYDROXIDE (Al(OH)3) on DST (no mesh, Tech grade, PERFECT PARTS Co)	6	10/20/85 0:00:00	MRS	SEMICON2
3344	ar_implt	Argon Ions/Natural Graphite Crystal (90 TOA) 4KV, 10 min	3	1/12/93 0:00:00	MRS	SEMICON2
3345	as2o3_01	As2O3 (99.995+%) Aldrich lot# 04445CW, 3mm pellet, screen, 90 TOA	11	1/28/92 0:00:00	MRS	SEMICON2
3346	as_1	ARSENIC (As) CHIP: ION ETCHED 2 MIN AT 3 KeV, 90 DEG TOA	10	8/7/86 0:00:00	MRS	SEMICON2
3347	au2o3_01	Au2O3 (Au 86%) Aldr 00306AW, 3 mm pellet, 90 TOA, Semi-Conductive	10	1/25/92 0:00:00	MRS	SEMICON2
3348	au_1	GOLD (Au) ON SILICON (90 DEG TOA, ION ETCHED: 2 KeV, 30 SEC)	8	11/30/86 0:00:00	MRS	SEMICON2
3349	au_2	GOLD ON MYLAR (90 DEG TOA, AS RECEIVED)	3	6/28/88 0:00:00	MRS	SEMICON2
3350	au_vb	GOLD (Au) ON MYLAR (AS RECEIVED, 90 DEG TOA)	4	7/28/86 0:00:00	MRS	SEMICON2
3351	b2o3_01	B2O3 (99.999%) crystal, Aldrich lot# 02829BV, screen, 90 TOA	9	8/23/91 0:00:00	MRS	SEMICON2
3352	beo_01	BeO (99.99%) 3mm pellet, Aldrich lot# 00213JX, screen, 90 TOA	10	1/28/92 0:00:00	MRS	SEMICON2
3353	b_1	BORON (B) CHIP (90 DEG TOA, ION ETCHED: 3 KeV, 10 mA, 3 MIN)	7	1/18/88 0:00:00	MRS	SEMICON2
3354	b_2	BORON (B) CHIP (90 DEG TOA, EXPOSED BULK, LIGHTLY ION ETCHED)	3	6/20/88 0:00:00	MRS	SEMICON2
3355	b_2a	BORON (B) CHIP (90 DEG TOA, EXPOSED BULK, LIGHTLY ION ETCHED)	2	6/20/88 0:00:00	MRS	SEMICON2
3356	cr_02	CHROMIUM (Cr) LUMP (35 DEG TOA, ION ETCHED 10 MIN AT 2 KV)	5	4/7/87 0:00:00	MRS	SEMICON2
3357	cr_1	CHROMIUM (Cr) SHEET (90 DEG TOA, ION ETCHED AT 4 KV FOR 4 MIN)	1	7/1/88 0:00:00	MRS	SEMICON2
3358	cr_1a	CHROMIUM (Cr) SHEET (90 DEG TOA, ION ETCHED 10 MIN AT 4 KV)	2	6/28/88 0:00:00	MRS	SEMICON2
3359	cu2o_01	Cu2O (Rare Metallics) Powder on In FOIL, 90 DEG TOA, Conductive, no mesh	4	10/7/87 0:00:00	MRS	SEMICON2
3360	cu2o_02	Cu2O (97%) dark red, 3mm pellet, Aldrich lot# 04602BW, Conductive, 90 TOA	12	8/23/91 0:00:00	MRS	SEMICON2
3361	cuo_03	CuO (99.99%) Rare Metallics Co. #70924-43, 3mm pellet, CONDUCTIVE, 90 TOA	12	9/7/91 0:00:00	MRS	SEMICON2
3362	cu_1	COPPER (Cu) FOIL (90 DEG TOA, SCRAPED, ION ETCHED: 4 KeV, 1 MIN)	11	11/26/86 0:00:00	MRS	SEMICON2

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
3363	cu_1a	COPPER (Cu) FOIL (90 DEG TOA, ION ETCHED 5 MIN AT 3 KV)	1	6/20/88 0:00:00	MRS	SEMICON2
3364	cu_2	COPPER (Cu) FOIL (90 DEG TOA, ION ETCHED AT 4 KeV FOR 12 MIN)	11	7/10/87 0:00:00	MRS	SEMICON2
3365	cu_oh2	Cu(OH)2 (3 mm pellet, Tech grade) Aldr lot# 11715EW screen 90 TOA	11	9/10/91 0:00:00	MRS	SEMICON2
3366	c_1_vb	INDUSTRIAL DIAMOND (C) CLEANED WITH SOLVENTS, 45 DEG TOA	1	1/20/88 0:00:00	MRS	SEMICON2
3367	c_2	CARBON (C) SHEET (GRAPHITE) (90 DEG TOA, SCRAPED WITH RAZOR BLADE)	6	1/19/88 0:00:00	MRS	SEMICON2
3368	c_2a	CARBON (C) SHEET (GRAPHITE) (90 DEG TOA, SCRAPED WITH A RAZOR BLADE)	1	1/19/88 0:00:00	MRS	SEMICON2
3369	c_2b	CARBON (C) SHEET (GRAPHITE) (90 DEG TOA, SCRAPED WITH RAZOR BLADE)	1	1/19/88 0:00:00	MRS	SEMICON2
3370	c_diam_1	DIAMOND (C) (90 DEG TOA, NO SCREEN, CLEANED WITH SOLVENTS)	1	2/18/88 0:00:00	MRS	SEMICON2
3371	c_diam_2	INDUSTRIAL DIAMOND 45 DEG TOA, SCREEN, ION ETCH 20s 3 KeV	3	7/15/87 0:00:00	MRS	SEMICON2
3372	diamnd_a	DIAMOND (C) (90 DEG TOA, NO SCREEN, CLEANED WITH SOLVENTS)	1	2/18/88 0:00:00	MRS	SEMICON2
3373	diamnd_b	DIAMOND (C) As received, no screen.	1	2/18/88 0:00:00	MRS	SEMICON2
3374	diamnd_c	INDUSTRIAL DIAMOND (LIGHTLY ETCHED) 45 DEG TOA, SCREEN, EXPOSED BULK	3	7/15/87 0:00:00	MRS	SEMICON2
3375	dimnd_et	INDUSTRIAL DIAMOND 45 DEG TOA, SCREEN, ION ETCH 20s 3 KeV	3	7/15/87 0:00:00	MRS	SEMICON2
3376	dimnd_vb	INDUSTRIAL DIAMOND (C) CLEANED WITH SOLVENTS, 45 DEG TOA	1	1/20/88 0:00:00	MRS	SEMICON2
3377	ga2o3_01	Ga2O3 (99.999+) Aldrich lot# 09325MV, 3mm pellet, screen, 90 TOA	12	8/17/91 0:00:00	MRS	SEMICON2
3378	ga_1	GALLIUM (Ga) SHOT FRESHLY CUT & ETCHED UNTIL SURFACE MELTED)	11	6/12/87 0:00:00	MRS	SEMICON2
3379	geo2_01	GeO2 (99.999%) Aldrich lot# 02904BW, 3mm pellet, screen, 90 TOA	11	8/13/91 0:00:00	MRS	SEMICON2
3380	geo2_02	GeO2 (99.999%) Aldr lot# 02904BW, 3mm pellet, screen, 90 TOA	4	8/13/91 0:00:00	MRS	SEMICON2
3381	hopg_1	HOPG (freshly delaminated surface) 100 deg TOA	10	12/15/93 0:00:00	MRS	SEMICON2
3382	in2o3_01	In2O3 (99.999%) Aldrich lot# 07528HY, 3mm pellet, 90 TOA, CONDUCTIVE	10	1/26/92 0:00:00	MRS	SEMICON2
3383	in_1	INDIUM (In) FOIL (90 TOA, EXPOSED BULK, ION ETCHED: 4 KeV, 1 MIN)	11	11/27/86 0:00:00	MRS	SEMICON2
3384	in_1a	INDIUM (In) FOIL (90 TOA, FRESH CUT, ION ETCHED: 4 KeV, 30 SEC)	1	11/29/86 0:00:00	MRS	SEMICON2
3385	mgo_01	MgO (99.99%) Aldrich lot# 00616CW, screen, 90 deg TOA	12	8/22/91 0:00:00	MRS	SEMICON2
3386	mgo_02	MgO (99.99%) Aldrich lot# 00616CW, screen, 90 TOA	13	8/23/91 0:00:00	MRS	SEMICON2
3387	nbs_si_1	NBS SRM 1521 B-70: Boron Doped Silicon (8.76 Mega-Ohm, as rec'd)	5	6/25/91 0:00:00	MRS	SEMICON2
3388	nio_01	NiO (99.99%) Aldr lot# 00503CW, 3mm pellet, CONDUCTIVE, 90 TOA	11	8/23/91 0:00:00	MRS	SEMICON2
3389	ni_1	NICKEL (Ni) FOIL (90 TOA, ION ETCHED: 5 KeV, 10 mA, 6 MIN)	9	11/15/86 0:00:00	MRS	SEMICON2
3390	ni_1a	NICKEL (Ni) FOIL (90 TOA, ION ETCHED: 5 KeV, 10 mA, 6 MIN)	1	11/18/86 0:00:00	MRS	SEMICON2
3391	ni_2	NICKEL (Ni) FILM (90 DEG TOA, 90 DEG ION ETCH: 2 KeV, 10 mA, 3 MIN)	7	3/14/87 0:00:00	MRS	SEMICON2
3392	ni_3	NICKEL FOIL (Ni) (ETCHED 10 min at 3KV & KEPT AT 10(-9) 3 DAYS)	5	11/8/86 0:00:00	MRS	SEMICON2
3393	ni_oh2	Ni(OH)2 (3mm pellet) 99% Aldrich lot# 90 TOA screen	9	6/2/92 0:00:00	MRS	SEMICON2
3394	pb2o3_01	Pb2O3 (99.9%) RMC lot# 80310-04, 3mm pellet, screen, 90 TOA	10	2/2/92 0:00:00	MRS	SEMICON2
3395	pbo2_01	PbO2 (95+%) Aldrich Lot# 06811JW, 3mm pellet, CONDUCTIVE, 90 TOA	8	8/14/91 0:00:00	MRS	SEMICON2
3396	pbo_01	PbO (99.999%) Aldrich Lot# 04911PV, 3mm pellet, Semi-Con, screen, 90 TOA	8	1/25/92 0:00:00	MRS	SEMICON2
3397	pdo_01	PdO (99.999%) Aldrich Lot# 03219JV, 3mm pellet, Semi-Con, screen, 90 TOA	9	8/15/91 0:00:00	MRS	SEMICON2
3398	pdo_02	PdO (99.999%) Aldrich Lot# 03219JV, 3mm pellet, Semi-Con, screen, 90 TOA	1	8/15/91 0:00:00	MRS	SEMICON2
3399	pto2_01	PtO2-xH2O (99.99%) Aldrich Lot# 09605EV, 3mm pellet, Semi-con, 90 TOA	10	8/19/91 0:00:00	MRS	SEMICON2
3400	pt_1	PLATINUM (Pt) FOIL (90 TOA, ION ETCHED: 5 KeV, 10 mA, 2 MIN)	4	11/15/86 0:00:00	MRS	SEMICON2
3401	pt_1a	PLATINUM (Pt) FOIL (90 TOA, ION ETCHED: 5 KeV, 10mA, 2 MIN)	1	11/18/86 0:00:00	MRS	SEMICON2
3402	pt_1b	PLATINUM (Pt) FOIL (90 TOA, ION ETCHED: 5 KeV, 10mA, 2 MIN)	1	11/18/86 0:00:00	MRS	SEMICON2
3403	pt_1bb	PLATINUM (Pt) FOIL (90 TOA, ION ETCHED: 5 KeV, 10mA, 2 MIN)	1	11/18/86 0:00:00	MRS	SEMICON2

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
3404	p_1	PHOSPHORUS (P) (35 DEG TOA, ION ETCHED)	2	7/5/88 0:00:00	MRS	SEMICON2
3405	p_2	PHOSPHORUS (P) CHIP (90 DEG TOA, ION ETCHED AT 3 KV FOR 5 MIN)	1	7/6/88 0:00:00	MRS	SEMICON2
3406	si3n4_01	OLD OXIDIZED Si3N4 COATING (90 DEG TOA, AS RECEIVED)	6	6/17/88 0:00:00	MRS	SEMICON2
3407	si3n4_02	OLD OXIDIZED Si3N4 COATING (ION ETCHED: 2KV, 4 MIN)	7	6/17/88 0:00:00	MRS	SEMICON2
3408	silicone	DIMETHYL SILICONE REFERENCE SAMPLE (35 DEG TOA) NO SCREEN, MASK USED	4	9/22/87 0:00:00	MRS	SEMICON2
3409	sio2_01	(-) SiO2 (10x10x2 mm, polished, from Brazil, screen, 90 TOA, as rec'd)	12	8/21/91 0:00:00	MRS	SEMICON2
3410	sio2_10	200 A SiO2/Si (as rec'd) 10 deg TOA	15	7/20/92 0:00:00	MRS	SEMICON2
3411	sio2_50	200 A SiO2/Si (as rec'd) 50 deg TOA	15	7/20/92 0:00:00	MRS	SEMICON2
3412	sio2_90a	200 A SiO2/Si (as rec'd) 90 deg TOA	9	7/20/92 0:00:00	MRS	SEMICON2
3413	sio2_90b	200 A SiO2/Si (as rec'd) 90 deg TOA	12	7/20/92 0:00:00	MRS	SEMICON2
3414	sio2_90c	200 A SiO2/Si (as rec'd) 90 deg TOA	2	7/20/92 0:00:00	MRS	SEMICON2
3415	sio_ws	Silicon (Si) wafer, no doping, as rec'd, 90 TOA 70 deg TOA, Repeated ion etched between scans	2	3/5/94 0:00:00	MRS	SEMICON2
3416	sno2_01	SnO2 (99.995+%) Aldrich Lot# 05903PV, 3mm pellet, screen, 90 TOA	5	7/18/91 0:00:00	MRS	SEMICON2
3417	sno_01	SnO (99+%) Aldrich Lot# 14613HW, 3mm pellet, CONDUCTIVE, screen, 90 TOA	10	9/9/91 0:00:00	MRS	SEMICON2
3418	teo2_01	TeO2 (99.995%) Aldrich lot# 07812JV, 3mm pellet, screen, 90 TOA	10	8/22/91 0:00:00	MRS	SEMICON2
3419	te_1	TELLURIUM (Te) LUMP (EXPOSED BULK 90 TOA, ETCHED 3 MIN AT 5 KeV 10 mA)	10	4/20/87 0:00:00	MRS	SEMICON2
3420	ti_1	TITANIUM (Ti) FOIL (SCRAPED, 90 DEG TOA, ION ETCH: 5 KeV, 10 mA, 3 MIN)	11	12/4/86 0:00:00	MRS	SEMICON2
3421	ti_1b	TITANIUM (Ti) FOIL (SCRAPED, 90 DEG TOA, ION ETCH: 5 KeV, 10 mA, 3 MIN)	1	12/5/86 0:00:00	MRS	SEMICON2
3422	wo3_01	WO3 (99.995%) Aldrich Lot# 00107KM JV, 3mm pellet, screen, 90 TOA	5	7/18/91 0:00:00	MRS	SEMICON2
3423	w_1	TUNGSTEN (W) SHEET (90 DEG TOA, ION ETCHED AT 3 KV FOR 5 MIN)	1	7/4/88 0:00:00	MRS	SEMICON2
3424	crsi_01	CrSi (15 monolayers Cr/Si(111) 7x7) 90 TOA	11	7/21/92 0:00:00	MRS	SILICIDE
3425	crsi_02	CrSi (15 monolayers Cr/Si(111) 7x7) 90 TOA	2	7/22/92 0:00:00	MRS	SILICIDE
3426	crsi_03	CrSi (15 monolayers Cr/Si(111) 7x7) 90 TOA	7	7/21/92 0:00:00	MRS	SILICIDE
3427	tisi_1	TiSi film (blue-grn,old,as deposit,as rec'd,35 TOA	8	5/14/94 0:00:00	MRS	SILICIDE
3428	tisi_1_e	TiSi film(blue-grn,old,as deposit,5min 3KV etch,35	8	5/14/94 0:00:00	MRS	SILICIDE
3429	tisi_2	TiSi film (gray color, old, annealed, as rec'd, 35	8	5/14/94 0:00:00	MRS	SILICIDE
3430	tisi_2_e	TiSi film (old,gray color,anneal,3min 3KVetch,35T)	8	5/14/94 0:00:00	MRS	SILICIDE
3431	ag2s_01	Ag2S (Argentite, Guanajuato, Mex.) filed bulk	10	6/15/94 0:00:00	MRS	SULFIDE
3432	ag2s_02	Ag2S (Argentite, Guanajuato, Mex.) filed bulk	5	6/15/94 0:00:00	MRS	SULFIDE
3433	as2s3_01	As2S3 (Orpiment) Nevada,USA bulk, mesh, 90 TOA	10	5/24/94 0:00:00	MRS	SULFIDE
3434	as2s3_02	As2S3 (Orpiment) bulk Nevada, USA, mesh 90 TOA	10	5/26/94 0:00:00	MRS	SULFIDE
3435	as2s3_03	As2S3 (Orpiment) bulk Nevada, USA, mesh 90 TOA	2	5/26/94 0:00:00	MRS	SULFIDE
3436	ass_01	As2S2 (Realgar) bulk Nevada,USA mesh 90 TOA	10	5/26/94 0:00:00	MRS	SULFIDE
3437	ass_02	As2S2 (Realgar) bulk Nevada,USA mesh 90 TOA	2	5/26/94 0:00:00	MRS	SULFIDE
3438	cus_01	CuS (Covellite dk blue polished natl xtl)EtOH wipe	11	6/9/94 0:00:00	MRS	SULFIDE
3439	cus_02	CuS (Covellite dk blue polished natl xtl)20s 2KV	14	6/10/94 0:00:00	MRS	SULFIDE
3440	fes2_01	FeS2 xtl (Pyrite, Mexico) fresh bulk, 80 TOA	10	5/13/94 0:00:00	MRS	SULFIDE
3441	hgs_01	Cinnabar (HgS) lg xtl,fresh bulk,mesh, Ukraine Rus	11	6/17/94 0:00:00	MRS	SULFIDE
3442	mos2_01	MOLYBDENUM DI-SULFIDE (Mo_S2) FRESHLY EXPOSED SURFACE OF A POLYMORPHIC SHEEET	2	7/21/87 0:00:00	MRS	SULFIDE
3443	mos2_0s	MoS2 crystal (as rec'd) 90 TOA	1	7/16/93 0:00:00	MRS	SULFIDE
3444	pbs_01	PbS xtl (Galena, Missouri) fresh bulk, 35 TOA	10	5/13/94 0:00:00	MRS	SULFIDE

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
3445	tas2_01	TaS2 xtl (gift) as rec'd 90 TOA	6	6/1/94 0:00:00	MRS	SULFIDE
3446	tas2_02	TaS2 xtl (gift) peeled away two layers, 90 TOA	6	6/1/94 0:00:00	MRS	SULFIDE
3447	zns_film	ZnS Coated Film (35 deg TOA) as received	1	9/12/86 0:00:00	MRS	SULFIDE
3448	bisrcu_1	BiSrCuO (Todai) fresh exposed bulk 90 TOA	11	6/1/94 0:00:00	MRS	SUPERCON
3449	b SCC_01	SINGLE CRYSTAL OF BiSrCaCuO, 90 DEG TOA, ACETONE CLEANED	9	3/5/88 0:00:00	MRS	SUPERCON
3450	b SCC_02	SINGLE CRYSTAL OF BiSrCaCuO, 90 DEG TOA	8	2/4/88 0:00:00	MRS	SUPERCON
3451	b SCC_03	Single Crystal of BiSrCaCuO SCRAPED, MOUNTED ON In FOIL, 15 DEG TOA	9	3/16/88 0:00:00	MRS	SUPERCON
3452	b SCC_04	SINGLE CRYSTAL of BiSrCaCuO (90 DEG TOA, SCRAPED IN AIR)	7	2/5/88 0:00:00	MRS	SUPERCON
3453	b SCC_05	SINGLE CRYSTAL OF BiSrCaCuO (90 DEG TOA, SCRAPED IN AIR)	1	2/5/88 0:00:00	MRS	SUPERCON
3454	b SCC_06	BiSrCaCuO / MgO [100] 2000 ANG THICK (90 TOA, SCRAPED WITH DIAMOND PAPER)	9	5/9/88 0:00:00	MRS	SUPERCON
3455	b SCC_07	BiSrCaCuO / MgO (100) (35 DEG TOA, FRESHLY POLISHED WITH DIAMOND PAPER)	10	6/3/88 0:00:00	MRS	SUPERCON
3456	b SCC_08	BiSrCaCuO SUPERCONDUCTOR (LIGHTLY ETCHED TO REMOVE CARBON, 90 DEG TOA)	12	7/22/88 0:00:00	MRS	SUPERCON
3457	ybc_01	YBaCuO (CPS Co.) pellet: LASER ON 590 nm, 400 mW: Strong Outgassing	6	9/23/89 0:00:00	MRS	SUPERCON
3458	ybc_02	YBaCuO (CPS Co.) pellet NOT EXPOSED to Laser	1	9/23/89 0:00:00	MRS	SUPERCON
3459	ybc_03	YBaCuO (CPS Co.) pellet: LASER ON 590 nm, 700 mW: Strong Outgassing	6	9/23/89 0:00:00	MRS	SUPERCON
3460	ybc_04	YBaCuO (CPS Co.) pellet: LASER Turned OFF	5	9/23/89 0:00:00	MRS	SUPERCON
3461	ybc_05	YBaCuO (CPS Co.) pellet NOT EXPOSED to Laser	1	9/23/89 0:00:00	MRS	SUPERCON
3462	ybc_06	YBCO exposed to 10ppm NO2 at 90% RH for 1 week	4	8/20/92 0:00:00	MRS	SUPERCON
3463	ybc_07	YBCO exposed to 1ppm of SO2 at 90% RH for 1 week	4	8/20/92 0:00:00	MRS	SUPERCON
3464	ybc_2115	SAMPLE "YBC-2115" (AS RECIVED, 35 DEG TOA)	6	2/16/88 0:00:00	MRS	SUPERCON
3465	90_fcs01	(+) 0.50 mm away from max cts (0.0) at 90 TOA 90 deg TOA	5	3/3/94 0:00:00	MRS	SYSTEMCHK
3466	90_fcs02	(+) 0.30 mm away from max cts (0.0) at 90 TOA 90 deg TOA	5	3/3/94 0:00:00	MRS	SYSTEMCHK
3467	90_fcs03	(+) 0.20 mm away from max cts (0.0) at 90 TOA 90 deg TOA	5	3/3/94 0:00:00	MRS	SYSTEMCHK
3468	90_fcs04	(+) 0.10 mm away from max cts (0.0) at 90 TOA 90 deg TOA	5	3/3/94 0:00:00	MRS	SYSTEMCHK
3469	90_fcs05	(+/-) 0.00 mm max cts position at 90 TOA 90 deg TOA	5	3/3/94 0:00:00	MRS	SYSTEMCHK
3470	90_fcs06	(-) 0.10 mm away from max cts (0.0) at 90 TOA 90 deg TOA	5	3/3/94 0:00:00	MRS	SYSTEMCHK
3471	90_fcs07	(-) 0.20 mm away from max cts (0.0) at 90 TOA 90 deg TOA	5	3/3/94 0:00:00	MRS	SYSTEMCHK
3472	90_fcs08	(-) 0.30 mm away from max cts (0.0) at 90 TOA 90 deg TOA	5	3/3/94 0:00:00	MRS	SYSTEMCHK
3473	90_fcs09	(-) 0.50 mm away from max cts (0.0) at 90 TOA 90 deg TOA	5	3/3/94 0:00:00	MRS	SYSTEMCHK
3474	90_foc01	+0.500 mm from max counts at a 90 TOA 35 deg TOA	9	2/28/94 0:00:00	MRS	SYSTEMCHK
3475	90_foc02	+0.300 mm from max counts at a 90 TOA 35 deg TOA	9	2/28/94 0:00:00	MRS	SYSTEMCHK
3476	90_foc03	+0.100 mm from max counts at a 90 TOA 35 deg TOA	9	2/28/94 0:00:00	MRS	SYSTEMCHK
3477	90_foc04	0.0 mm from max counts at a 90 TOA 35 deg TOA	9	2/28/94 0:00:00	MRS	SYSTEMCHK
3478	90_foc05	(-) 0.100 mm from max counts position at 90 TOA 35 deg TOA	9	2/28/94 0:00:00	MRS	SYSTEMCHK
3479	90_foc06	(-) 0.300 mm from max counts position at 90 TOA 35 deg TOA	9	2/28/94 0:00:00	MRS	SYSTEMCHK
3480	90_foc07	(-) 0.500 mm from max counts position at 90 TOA 35 deg TOA	9	2/28/94 0:00:00	MRS	SYSTEMCHK
3481	ag_sb_1	Grazing X-rays, >100 TOA, ion etched, S/B=118	1	5/22/92 0:00:00	MRS	SYSTEMCHK
3482	ag_sb_2	Ag/Si, 114Kcps crt, Graz X-rays, TOA=> 110 deg	8	5/22/92 0:00:00	MRS	SYSTEMCHK
3483	ag_sb_3	Ag/Si, 114Kcps crt, Graz X-rays, TOA=> 110 deg	1	5/22/92 0:00:00	MRS	SYSTEMCHK
3484	ag_sb_4	Ag/Si 17 Kcps 10 deg TOA Grazing X-rays ion etched	1	5/22/92 0:00:00	MRS	SYSTEMCHK
3485	ag_sb_5	Ag/Si ion etched 110 deg TOA	13	7/7/92 0:00:00	MRS	SYSTEMCHK

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
3486	ag_sb_6	Ag/Si ion etched 110 deg TOA	4	7/7/92 0:00:00	MRS	SYSTEMCHK
3487	ag_sb_7	Ag/Si ion etched 110 deg TOA	13	7/7/92 0:00:00	MRS	SYSTEMCHK
3488	cu_bechk	Check of Cu BEs to verify calibration for Cu & Ni 35 deg TOA	6	2/21/94 0:00:00	MRS	SYSTEMCHK
3489	c_buildu	CARBON BUILD-UP ON COPPER (17 HR IN ANAL. CHAMBER)90 DEG TOA, PREVIOUSLY ION ETCHED	1	11/27/86 0:00:00	MRS	SYSTEMCHK
3490	error_01	position 1 for random error check	1	1/5/93 0:00:00	MRS	SYSTEMCHK
3491	error_02	position 2 for random error check	1	1/5/93 0:00:00	MRS	SYSTEMCHK
3492	error_03	position 3 for random error check	1	1/5/93 0:00:00	MRS	SYSTEMCHK
3493	error_04	position 4 for random error check	1	1/5/93 0:00:00	MRS	SYSTEMCHK
3494	error_05	position 5 for random error check	1	1/5/93 0:00:00	MRS	SYSTEMCHK
3495	error_06	position 6 for random error check	1	1/5/93 0:00:00	MRS	SYSTEMCHK
3496	error_07	position 7 for random error check	1	1/5/93 0:00:00	MRS	SYSTEMCHK
3497	err_01	position 1 for random error check	1	1/5/93 0:00:00	MRS	SYSTEMCHK
3498	err_02	position 2 for random error check	1	1/5/93 0:00:00	MRS	SYSTEMCHK
3499	err_03	position 3 for random error check	1	1/5/93 0:00:00	MRS	SYSTEMCHK
3500	err_04	position 4 for random error check	1	1/5/93 0:00:00	MRS	SYSTEMCHK
3501	err_05	position 5 for random error check	1	1/5/93 0:00:00	MRS	SYSTEMCHK
3502	err_06	position 6 for random error check	1	1/5/93 0:00:00	MRS	SYSTEMCHK
3503	err_07	position 7 for random error check	1	1/5/93 0:00:00	MRS	SYSTEMCHK
3504	exp_chk	35 TOA Cu cleaned check of exponent factors	4	6/10/94 0:00:00	MRS	SYSTEMCHK
3505	exp_chk2	35TOA IG now off: ?affect exp factor (3PM-> 10:30am	2	6/10/94 0:00:00	MRS	SYSTEMCHK
3506	focus	Fresh etch of gold to verify calibration for Fe 90 deg TOA	5	3/3/94 0:00:00	MRS	SYSTEMCHK
3507	focus01	+0.30mm up from true focus: clean copper f	3	2/7/94 0:00:00	MRS	SYSTEMCHK
3508	focus02	+0.20mm up from true focus: clean copper f	3	2/7/94 0:00:00	MRS	SYSTEMCHK
3509	focus03	+0.15mm up from true focus: clean copper f	3	2/7/94 0:00:00	MRS	SYSTEMCHK
3510	focus04	+0.10mm up from true focus: clean copper f	3	2/7/94 0:00:00	MRS	SYSTEMCHK
3511	focus05	+0.05mm up from true focus: clean copper f	3	2/7/94 0:00:00	MRS	SYSTEMCHK
3512	focus06	+0.00mm TRUE FOCUS POINT: clean copper f	3	2/7/94 0:00:00	MRS	SYSTEMCHK
3513	focus07	. -0.05mm down from true focus: clean copper	3	2/7/94 0:00:00	MRS	SYSTEMCHK
3514	focus08	. -0.10mm down from true focus: clean copper	3	2/7/94 0:00:00	MRS	SYSTEMCHK
3515	focus09	. -0.15mm down from true focus: clean copper	3	2/7/94 0:00:00	MRS	SYSTEMCHK
3516	focus10	. -0.20mm down from true focus: clean copper	3	2/7/94 0:00:00	MRS	SYSTEMCHK
3517	focus11	. -0.30mm down from true focus: clean copper	3	2/7/94 0:00:00	MRS	SYSTEMCHK
3518	focus_a	Check of BE vs Focus at 90 deg TOA Z=+0.20mm 35 deg TOA	5	2/28/94 0:00:00	MRS	SYSTEMCHK
3519	focus_b	Check of BE vs Focus at 90 deg TOA Z= -0.20mm 35 deg TOA	5	2/28/94 0:00:00	MRS	SYSTEMCHK
3520	focus_c	2nd check of BE vs Focus at 90 deg TOA Z=+0.20mm 35 deg TOA	5	2/28/94 0:00:00	MRS	SYSTEMCHK
3521	focus_d	Max counts: BE vs Focus at 90 deg TOA Z=+0.174 mm 35 deg TOA	5	2/28/94 0:00:00	MRS	SYSTEMCHK
3522	gun_adj	Gun Bragg angle affected by cooling: 0.2ev shift! 35 deg TOA	5	2/24/94 0:00:00	MRS	SYSTEMCHK
3523	noise_01	Test of Dark Current Noise: no sample, only X-rays	1	1/6/94 0:00:00	MRS	SYSTEMCHK
3524	offset_1	using auto v1 curve slopes but changed offsets	5	11/24/92 0:00:00	MRS	SYSTEMCHK
3525	rand_01	position 1 for random error check	1	1/5/93 0:00:00	MRS	SYSTEMCHK
3526	rand_02	position 2 for random error check	1	1/5/93 0:00:00	MRS	SYSTEMCHK



Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
3527	rand_03	position 3 for random error check	1	1/5/93 0:00:00	MRS	SYSTEMCHK
3528	rand_04	position 4 for random error check	1	1/5/93 0:00:00	MRS	SYSTEMCHK
3529	rand_05	position 5 for random error check	1	1/5/93 0:00:00	MRS	SYSTEMCHK
3530	rand_06	position 6 for random error check	1	1/5/93 0:00:00	MRS	SYSTEMCHK
3531	rand_07	position 7 for random error check	1	1/5/93 0:00:00	MRS	SYSTEMCHK
3532	raner_01	position 1 for random error check	1	1/5/93 0:00:00	MRS	SYSTEMCHK
3533	raner_02	position 2 for random error check	1	1/5/93 0:00:00	MRS	SYSTEMCHK
3534	raner_03	position 3 for random error check	1	1/5/93 0:00:00	MRS	SYSTEMCHK
3535	raner_04	position 4 for random error check	1	1/5/93 0:00:00	MRS	SYSTEMCHK
3536	raner_05	position 5 for random error check	1	1/5/93 0:00:00	MRS	SYSTEMCHK
3537	raner_06	position 6 for random error check	1	1/5/93 0:00:00	MRS	SYSTEMCHK
3538	raner_07	position 7 for random error check	1	1/5/93 0:00:00	MRS	SYSTEMCHK
3539	reset_1	Reset to my Trial & Error Values	4	11/24/92 0:00:00	MRS	SYSTEMCHK
3540	scn_test	RES O SCANNED, TIME=60 SEC	1	3/7/91 0:00:00	MRS	SYSTEMCHK
3541	slope_1	attempt to correct res 0 & res 1 v1 slope settings	2	11/20/92 0:00:00	MRS	SYSTEMCHK
3542	slope_10	using new v1 slopes and offsets	1	11/20/92 0:00:00	MRS	SYSTEMCHK
3543	slope_11	using new v1 slopes and offsets	1	11/20/92 0:00:00	MRS	SYSTEMCHK
3544	slope_2	attempt to correct res 0 & res 1 v1 slope settings	1	11/20/92 0:00:00	MRS	SYSTEMCHK
3545	slope_3	attempt to correct res 0 & res 1 v1 slope settings	1	11/20/92 0:00:00	MRS	SYSTEMCHK
3546	slope_4	v1 slope = 0.4	1	11/20/92 0:00:00	MRS	SYSTEMCHK
3547	slope_6	v1 slope = 0.54 v1 offset = 30	1	11/20/92 0:00:00	MRS	SYSTEMCHK
3548	slope_7	v1 slope = 0.54 offset = 40	1	11/20/92 0:00:00	MRS	SYSTEMCHK
3549	slope_8	v1 slope = 0.56 offset = 20	1	11/20/92 0:00:00	MRS	SYSTEMCHK
3550	slope_9	v1 slope=0.60 offset = 20	1	11/20/92 0:00:00	MRS	SYSTEMCHK
3551	spot_off	BE for 250x1000 was today offset by -0.05 eV	1	2/21/94 0:00:00	MRS	SYSTEMCHK
3552	s_to_n_1	S/N check, gold/1mm teflon, ion etched, 35 toa	1	6/4/91 0:00:00	MRS	SYSTEMCHK
3553	s_to_n_2	S/N check, gold/1mm teflon, ion etched, 35 toa	1	6/4/91 0:00:00	MRS	SYSTEMCHK
3554	s_to_n_3	S/N check, dirty Au/Si, 35 deg toa	1	6/5/91 0:00:00	MRS	SYSTEMCHK
3555	s_to_n_4	S/N check, ion etched Au/Si wafer, 35 deg toa	1	6/5/91 0:00:00	MRS	SYSTEMCHK
3556	s_to_n_5	S/N check, Au/mylar, ion etched, 35 deg toa	1	6/5/91 0:00:00	MRS	SYSTEMCHK
3557	s_to_n_7	S/N check, Au/mylar, ion etched, 35 deg toa	1	6/5/91 0:00:00	MRS	SYSTEMCHK
3558	uns_test	RES 0, UNSCANNED, 60 SEC, 128 CH	1	3/7/91 0:00:00	MRS	SYSTEMCHK
3559	xtal_adj	Crystal adjusted to return high counts: Check BEs 35 deg TOA	5	2/21/94 0:00:00	MRS	SYSTEMCHK
3560	xtl_adj2	Crystal & Gun gimbal screws tight,max ct 40Kcps 35 deg TOA	5	2/22/94 0:00:00	MRS	SYSTEMCHK
3561	catio3_1	CaTiO3 xtal (freshly exposed bulk, 90 TOA, scrn)	9	6/23/94 0:00:00	MRS	TITANATE
3562	k2ti4o9	PURE POTASSIUM TITANATE (K2Ti4O9) ADHERED TO DOUBLE SIDED TAPE	4	12/8/86 0:00:00	MRS	TITANATE
3563	srtio3_1	SrTiO3 xtal (freshly exposed bulk, 90 TOA, scrn)	10	5/30/94 0:00:00	MRS	TITANATE
3564	srtio3_2	SrTiO3 xtal (as received, 90 TOA, scrn)	8	6/1/94 0:00:00	MRS	TITANATE
3565	srtio3_3	Yttrium Aluminum Garnet (YAG) crystal	14	8/13/94 0:00:00	MRS	TITANATE
3566	87_07_10	COPPER (Cu) FOIL for Deciding RSFs: 90 DEG TOA, ION ETCHED AT 4 KeV FOR 12 MIN	12	7/10/87 0:00:00	MRS	TRANSMIS
3567	87_09_01	COPPER FOIL, ION ETCHED AT 3 KeV, 5 MIN to Study TRANSMISSION FUNCTION AT 35 DEG TOA	17	9/1/87 0:00:00	MRS	TRANSMIS

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
3568	87_09_10	COPPER (Cu) FOIL ION ETCHED, TEST OF TRANSMIS FUNCT AT 90 TOA (detector saturated sometimes)	9	9/10/87 0:00:00	MRS	TRANSMIS
3569	92_11_24	V1 slope (lense voltage ratio) changed from 0.709 to 0.60 to show effect of bad setup.	1	11/24/92 0:00:00	MRS	TRANSMIS
3570	92_11_25	V1 slope (lense voltage ratio) changed from 0.709 to 0.65 to show effect of bad setup	1	11/24/92 0:00:00	MRS	TRANSMIS
3571	94_01_11	Test of Sensitivity Factor Exponents for Res 2 (PE=50V) & Res 4 (PE=150) using etched Cu	2	1/11/94 0:00:00	MRS	TRANSMIS
3572	94_02_07	Quick check of RSF setup and Exponent Factor	1	2/7/94 0:00:00	MRS	TRANSMIS
3573	94_02_08	Check of rsf setup & exp factor for res 2 (PE=50V)	1	2/7/94 0:00:00	MRS	TRANSMIS
3574	ion_1	Transmission function based on 5KV ion etch	1	4/15/92 0:00:00	MRS	TRANSMIS
3575	ion_2	1KeV CONTINUOUS ION ETCHING OF Cu FOIL, 45 DEG TOA, X-RAYS OFF, 1 mA, 4x4 RASTER, 1.0x10-72	1	10/14/87 0:00:00	MRS	TRANSMIS
3576	ion_3	1 KeV ION ETCHING of Cu FOIL at 90 DEG TOA	1	10/14/87 0:00:00	MRS	TRANSMIS
3577	ion_4	2KeV CONTINUOUS ION ETCHING OF Cu FOIL 90 DEG TOA, X-RAYS OFF, 3mA, 4x4 RASTER, 8.3x10-81	1	10/14/87 0:00:00	MRS	TRANSMIS
3578	ion_5	1KeV CONTINUOUS ION ETCHING Cu FOIL, 90 DEG TOA, X-RAYS OFF, 1 mA, 4x4 RASTER, 1.0x10-7	2	10/14/87 0:00:00	MRS	TRANSMIS
3579	ion_6	1 KeV CONTINUOUS ION ETCHING OF Cu FOIL, 45 DEG TOA, X-RAYS OFF, 1 mA, 4x4 RASTER, 1.0x10-72	1	10/14/87 0:00:00	MRS	TRANSMIS
3580	nickel_1	Etched Nickel: Exponent Study; Compare to Atoms % based on Zn & Cu RSF calibration data	2	5/17/91 0:00:00	MRS	TRANSMIS
3581	v1_slope	Check of V1 slopes (lense voltage ratios) using dirty gold on silicon	5	11/20/92 0:00:00	MRS	TRANSMIS
3582	v2_slope	Check of V1 slopes (lense voltage ratios) using dirty gold on silicon	2	11/20/92 0:00:00	MRS	TRANSMIS
3583	bb1_clnd	Wear Spot on Ball Bearing after Freon Cleaning	1	3/11/91 0:00:00	MRS	TRIBOLGY
3584	bb1_norm	Normal Area on Ball Bearing (near wear marks)	1	3/11/91 0:00:00	MRS	TRIBOLGY
3585	bb1_trk	Depth Profile on Wear Spot on Ball Bearing 2 KV, 10 mA, (Xenon ions)	0	3/12/91 0:00:00	DPR	TRIBOLGY
3586	bb2_etch	Wear Track area on Ball Bearing #2 (ion etched) 40 sec ion etch	4	3/12/91 0:00:00	MRS	TRIBOLGY
3587	bb2_trk1	Wear Area on Inner Race (#2 with Ball Bearing #2)	1	3/12/91 0:00:00	MRS	TRIBOLGY
3588	bb2_trk2	Wear Area on Inner Race (#2 with Ball Bearing #2)	3	3/12/91 0:00:00	MRS	TRIBOLGY
3589	bearin1a	NO.1 Bearing (as received)	1	7/27/93 0:00:00	MRS	TRIBOLGY
3590	bearing1	NO.1 Bearing (as received)	3	7/27/93 0:00:00	MRS	TRIBOLGY
3591	bearing2	NO.2 Bearing (as received)	4	7/27/93 0:00:00	MRS	TRIBOLGY
3592	race1nrm	Normal Area on Race #1 (as received)	7	3/12/91 0:00:00	MRS	TRIBOLGY
3593	race1n_e	Normal Area on Race #1 (after 40 angstrom etch)	7	3/12/91 0:00:00	MRS	TRIBOLGY
3594	race1tra	Wear Area on Race #1 (after 40 sec etch w Xe+)	6	3/12/91 0:00:00	MRS	TRIBOLGY
3595	RACE1TRK	Wear area on Race #1 (as received)	1	3/12/91 0:00:00	MRS	TRIBOLGY
3596	race1t_e	Wear Area on Race #1 (after 40 sec ion etch w Xe+)	4	3/12/91 0:00:00	MRS	TRIBOLGY
3597	showa_1	NO.1 Bearing (as received)	3	7/27/93 0:00:00	MRS	TRIBOLGY
3598	showa_2	NO.2 Bearing (as received)	4	7/27/93 0:00:00	MRS	TRIBOLGY
3599	show_1a	NO.1 Bearing (as received)	1	7/27/93 0:00:00	MRS	TRIBOLGY
3600	li2wo4_1	Lithium Tungstate (Li2WO4) freshly cleaved (mesh)	9	8/18/92 0:00:00	MRS	TUNGSTAT
3601	na2w207	Na2W2O7 (scraped as rec'd pressed sheet, 90 TOA)	4	3/15/93 0:00:00	MRS	TUNGSTAT
3602	na2wo4_1	Sodium Tungstate (Na2WO4) freshly scraped (mesh)	9	8/18/92 0:00:00	MRS	TUNGSTAT
3603	scheeite	Scheeite (CaWO4) crystal bulk	11	8/14/94 0:00:00	MRS	TUNGSTAT
3604	TAO_U_00	Ta2O5 Coating/Glass: <5 min after UV/Ozone treatment (35 TOA, mesh)	1	11/19/93 0:00:00	MRS	UV_OZONE
3605	TAO_U_03	Ta2O5 Coating/glass: 3 hours, after UV/O3 treatment (35 TOA, mesh)	1	11/22/93 0:00:00	MRS	UV_OZONE
3606	TAO_U_24	Ta2O5 Coating/Glass: 24 hr after UV treatment (35 TOA, mesh)	1	11/19/93 0:00:00	MRS	UV_OZONE
3607	ag_vb	Silver (Ag) not scraped, pre-etched 60 min, 90 TOA	1	3/1/94 0:00:00	MRS	VB_ELEM
3608	ag_vb_01	ION ETCHED SILVER (Ag) ON MYLAR (90 DEG TOA)	1	10/13/87 0:00:00	MRS	VB_ELEM

Serial	File Name	Description	No of Spectra	Date	Ident	Sub Dir.
3609	al_vb	Aluminum (Al) scraped & pre-etch >60 min, 90 TOA	1	3/3/94 0:00:00	MRS	VB_ELEM
3610	au_vb	Gold (Au) pre-etched >60min 90 TOA not scraped	1	2/25/94 0:00:00	MRS	VB_ELEM
3611	au_vb_01	GOLD (Au) ON MYLAR (AS RECEIVED, 90 DEG TOA)	1	7/28/86 0:00:00	MRS	VB_ELEM
3612	be_vb	Beryllium (Be) not scraped, etched>60 min, 90 TOA	1	3/5/94 0:00:00	MRS	VB_ELEM
3613	bi_vb	Bismuth (Bi) not scraped, etched 5 min, 90 TOA	1	3/7/94 0:00:00	MRS	VB_ELEM
3614	bi_vb_2	Bismuth (Bi) not scraped, etched 5 min, 90 TOA	1	3/7/94 0:00:00	MRS	VB_ELEM
3615	cd_vb	Cadmium (Cd) 90 TOA, Scraped, 3KV etch >30 min	1	2/14/94 0:00:00	MRS	VB_ELEM
3616	co_vb	Cobalt (Co) 90 TOA, Scraped, ion etched 3 KV >3min	1	2/9/94 0:00:00	MRS	VB_ELEM
3617	cr_vb	Chromium (Cr) 90 TOA, Scraped, 3KV etch >3min	1	2/11/94 0:00:00	MRS	VB_ELEM
3618	cu_vb	Copper (Cu) scraped & etched more than 2 hours 90	1	2/16/94 0:00:00	MRS	VB_ELEM
3619	c_vb	Carbon (C) scraped & etched > 20 min, 90 TOA	1	3/13/94 0:00:00	MRS	VB_ELEM
3620	fe_vb	Iron (Fe)	1	2/10/94 0:00:00	MRS	VB_ELEM
3621	hf_vb	Hafnium (Hf) filed & etched > 60 min, 90 TOA	1	3/9/94 0:00:00	MRS	VB_ELEM
3622	in_vb	Indium (In) not scraped, etched > 50 min 90 TOA	1	2/26/94 0:00:00	MRS	VB_ELEM
3623	ir_vb	Iridium (Ir) filed & etched 5 min, 90 TOA	1	3/3/94 0:00:00	MRS	VB_ELEM
3624	mn_vb	Manganese (Mn) scraped & pre-etched >60 min 90 TOA	1	2/20/94 0:00:00	MRS	VB_ELEM
3625	mo_vb	Molybdenum (Mo) scraped&etched more than 30 min	1	2/17/94 0:00:00	MRS	VB_ELEM
3626	nb_vb	Niobium (Nb) scraped & pre-etched >60 min 90 TOA	1	2/20/94 0:00:00	MRS	VB_ELEM
3627	ni_vb	Nickel (Ni) scraped&etched more than 30min	1	2/16/94 0:00:00	MRS	VB_ELEM
3628	pb_vb	Lead (Pb) scraped & etched > 50 min 90 TOA	1	2/26/94 0:00:00	MRS	VB_ELEM
3629	pt_vb	Platinum (Pt) scraped & etched more than 30 min	1	2/18/94 0:00:00	MRS	VB_ELEM
3630	rh_vb	Rhodium (Rh) /Ni/Al: only etched 3 min, 90 TOA	1	3/1/94 0:00:00	MRS	VB_ELEM
3631	ru_1__vb	Ruthenium (Ru) powder pressed into disk 70 deg TOA	2	1/28/94 0:00:00	MRS	VB_ELEM
3632	sb_vb	Antimony (Sb) scraped & etched > 60 min, 90 TOA	1	3/13/94 0:00:00	MRS	VB_ELEM
3633	siovb	xxx (xx) 90 TOA, Scraped & Etched 3KV 3-5min 90 deg TOA, Repeated ion etched between scans	1	1/27/94 0:00:00	MRS	VB_ELEM
3634	sio_vb	Silicon (Si) wafer, no doping, as rec'd 90 TOA 90 deg TOA, Repeated ion etched between scans	1	3/5/94 0:00:00	MRS	VB_ELEM
3635	si_vb	Silicon (Si) no scrape,no doping,etch>60min,90 TOA	1	3/6/94 0:00:00	MRS	VB_ELEM
3636	sn_vb	Tin (Sn) scraped & etched >50min 90 TOA	1	2/27/94 0:00:00	MRS	VB_ELEM
3637	ta_vb	Tantalum (Ta) scraped & pre-etched >60 min 90 TOA	1	2/19/94 0:00:00	MRS	VB_ELEM
3638	te_vb	Tellurium (Te) 90 TOA, Scraped, 3KV etch >3min	1	2/12/94 0:00:00	MRS	VB_ELEM
3639	ti_vb	Titanium (Ti) 90 TOA, scraped, etched 3 KV >5 min	1	2/8/94 0:00:00	MRS	VB_ELEM
3640	tl_vb	Thallium (Tl) 90 TOA, Scraped, 3KV etch >10min	1	3/2/94 0:00:00	MRS	VB_ELEM
3641	v_vb	Vanadium (V) scraped & pre-etched >40 min 90 TOA	1	2/21/94 0:00:00	MRS	VB_ELEM
3642	w_vb	Tungsten (W) filed & etched >60 min, 90 TOA	1	3/7/94 0:00:00	MRS	VB_ELEM
3643	y_vb	Yttrium (Y) 90 TOA, Scraped, 3KV etch >80min	1	3/2/94 0:00:00	MRS	VB_ELEM
3644	zn_vb	Zinc (Zn) filed & etched > 60 min, 90 TOA	1	3/6/94 0:00:00	MRS	VB_ELEM
3645	zr_vb	Zirconium (Zr) filed & etched >60 min, 90 TOA	1	3/11/94 0:00:00	MRS	VB_ELEM
3646	zro2_01	ZrO2 (99.9%, HfO2 <100ppm) Aldrich lot# 02310BV, 3mm pellet, screen, 90 TOA	9	8/15/91 0:00:00	MRS	VB_OXIDE
3647	ag_vb	ION ETCHED SILVER (Ag) ON MYLAR (90 DEG TOA)	1	10/13/87 0:00:00	MRS	VB_SEMIC
3648	au_vb	GOLD (Au) ON MYLAR (AS RECEIVED, 90 DEG TOA)	4	7/28/86 0:00:00	MRS	VB_SEMIC
3649	c_1_vb	INDUSTRIAL DIAMOND (C) CLEANED WITH SOLVENTS, 45 DEG TOA	1	1/20/88 0:00:00	MRS	VB_SEMIC

Serial	File Name	Description	No of Spectra	Date	Ident	SubDir.
3650	inp_vb	InP (111) (Sumitomo Electric, 90 TOA, Fresh Bulk)	1	6/8/87 0:00:00	MRS	VB_SEMIC
3651	sio_vb	Silicon (Si) wafer, no doping, as rec'd 90 TOA 90 deg TOA, Repeated ion etched between scans	1	3/5/94 0:00:00	MRS	VB_SEMIC
3652	si_vb_90	Silicon (n-type ?) freshly exposed edge (90 toa)	3	7/16/91 0:00:00	MRS	VB_SEMIC
3653	c_zeol_1	Carbon/Zeolite #1 (as rec'd, 90 deg TOA, screen)	5	6/24/92 0:00:00	MRS	ZEOLITE
3654	c_zeol_2	Carbon/Zeolite #2 (as rec'd, 90 deg TOA, screen)	5	6/25/92 0:00:00	MRS	ZEOLITE
3655	c_zeol_3	Carbon/Zeolite #3 (as rec'd, 90 deg TOA, screen)	5	6/25/92 0:00:00	MRS	ZEOLITE
3656	c_zeol_4	Carbon/Zeolite #4 (as rec'd, 90 deg TOA, screen)	5	6/25/92 0:00:00	MRS	ZEOLITE
3657	mordenit	Synthetic Mordenite 33 (pressed into pellet, screen, 90 TOA)	5	11/27/92 0:00:00	MRS	ZEOLITE
3658	ms5a	Zeolite "MS-5A" [KE-254] + 1C(7.7 wt%) impregnated	4	7/15/92 0:00:00	MRS	ZEOLITE
3659	msn25	Alumino-Silicate N-25 (pressed into pellet, screen, 90 TOA)	7	12/3/92 0:00:00	MRS	ZEOLITE
3660	pt_zeol	Pt metal / zeolite: analysis area continuously moved to minimize damage.	1	2/5/92 0:00:00	MRS	ZEOLITE
3661	talc_01	Natural Talc (untreated, pressed into pellet, screen, 90 TOA)	7	12/3/92 0:00:00	MRS	ZEOLITE
3662	talc_02	HF Treated Talc (pressed into pellet, screen, 90 TOA)	6	12/4/92 0:00:00	MRS	ZEOLITE
3663	x_zeol1a	Zeolite X (Ca,Na exchanged) (WE-884)	2	7/15/92 0:00:00	MRS	ZEOLITE
3664	x_zeol_1	Zeolite X (Ca,Na exchanged) (WE-884)	3	7/15/92 0:00:00	MRS	ZEOLITE
3665	x_zeol_2	Zeolite X (Na exchanged) [WE-894]	3	7/15/92 0:00:00	MRS	ZEOLITE
3666	y_zeol_1	Zeolite Y (Na exchanged) [Mizuka sieve Y-500]	3	7/15/92 0:00:00	MRS	ZEOLITE
3667	zeolit_1	Zeolite (1uM, cubic) pellet (gc press)	6	4/19/94 0:00:00	MRS	ZEOLITE
3668	zeolit_2	Black colored zeolite (uncrushed, single chip)	3	8/25/92 0:00:00	MRS	ZEOLITE
3669	zeolit_3	White Zeolite (pressed into pellet, used SSI mesh)	3	8/25/92 0:00:00	MRS	ZEOLITE
3670	zsm5_001	Zeolite ZSM-5 (not-treated, pressed into pellet, screen, 90 TOA)	7	11/28/92 0:00:00	MRS	ZEOLITE
3671	cu_oh2	Cu(OH)2 (3 mm pellet, Tech grade) Aldr lot# 11715EW screen 90 TOA	11	9/10/91 0:00:00	MRS	_INCOMIN
3672	si3n4_3	Si3N4/Si (5min conc H2O2:HCl:H2O 3:2:5) metal blue 90 toa	8	4/27/94 0:00:00	MRS	_INCOMIN
3673	si3n4_4	Si3N4/Si (10min conc HF:MeOH 2:50 cc) metal blue 90 toa	8	4/27/94 0:00:00	MRS	_INCOMIN
3674	si3n4_5	Si3N4/Si as rec'd, only gray color seen 90 toa	8	4/27/94 0:00:00	MRS	_INCOMIN
3675	si3n4_6	Si3N4/Si etched 10 min at 2KV 6E(-8) Ar, gray type 90 toa	8	4/27/94 0:00:00	MRS	_INCOMIN